



Dust Detector Flash MCU

BA45F4140

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Features

CPU Features

- Operating voltage
 - ♦ $f_{SYS}=4\text{MHz}$: 2.2V~5.5V
 - ♦ $f_{SYS}=8\text{MHz}$: 2.2V~5.5V
 - ♦ $f_{SYS}=12\text{MHz}$: 2.7V~5.5V
- Up to 0.33 μs instruction cycle with 12MHz system clock at $V_{DD}=5\text{V}$
- Power down and wake-up functions to reduce power consumption
- Oscillator types
 - ♦ Internal High Speed 4/8/12MHz RC – HIRC
 - ♦ Internal Low Speed 32kHz RC – LIRC
- Multi-mode operation: FAST, SLOW, IDLE and SLEEP
- Fully integrated internal oscillators require no external components
- All instructions executed in 1~3 instruction cycles
- Table read instructions
- 115 powerful instructions
- 8-level subroutine nesting
- Bit manipulation instruction

Peripheral Features

- Flash Program Memory: 4K \times 16
- Data Memory: 512 \times 8
- True EEPROM Memory: 512 \times 8
- In Application Programming – IAP
- Watchdog Timer function
- 15 bidirectional I/O lines
- Two external interrupt lines shared with I/O pins
- Sink current generator for constant current output
- Dust Detector AFE including three operational amplifiers
- Multiple Timer Modules for time measurement, input capture, compare match output, PWM output function or single pulse output function
 - ♦ Three 10-bit PTM (PTM0~PTM2) are used for particle size width capture function
 - ♦ One 10-bit PTM (PTM3)
 - ♦ Dual 10-bit CTM (CTM0~CTM1)
- Universal Serial Interface Module – USIM for SPI, I²C or UART communication
- Dual Time Base functions for generation of fixed time interrupt signals
- 4 external channel 12-bit resolution A/D converter with internal reference voltage V_{BG}
- Temperature Sensor with internal reference voltage
- Integrated Multiplier/Divider Unit – MDU
- Three Over Voltage Protection – OVP
- Internal LDO provides fixed 2.2V/2.5V/3.3V/3.6V output

- High driving current outputs
- Low voltage reset function – LVR
- Low voltage detect function – LVD
- Package types: 16-pin NSOP, 24-pin SSOP

General Description

The BA45F4140 is a Flash Memory A/D type 8-bit high performance RISC architecture microcontroller, designed especially for dust sensor applications.

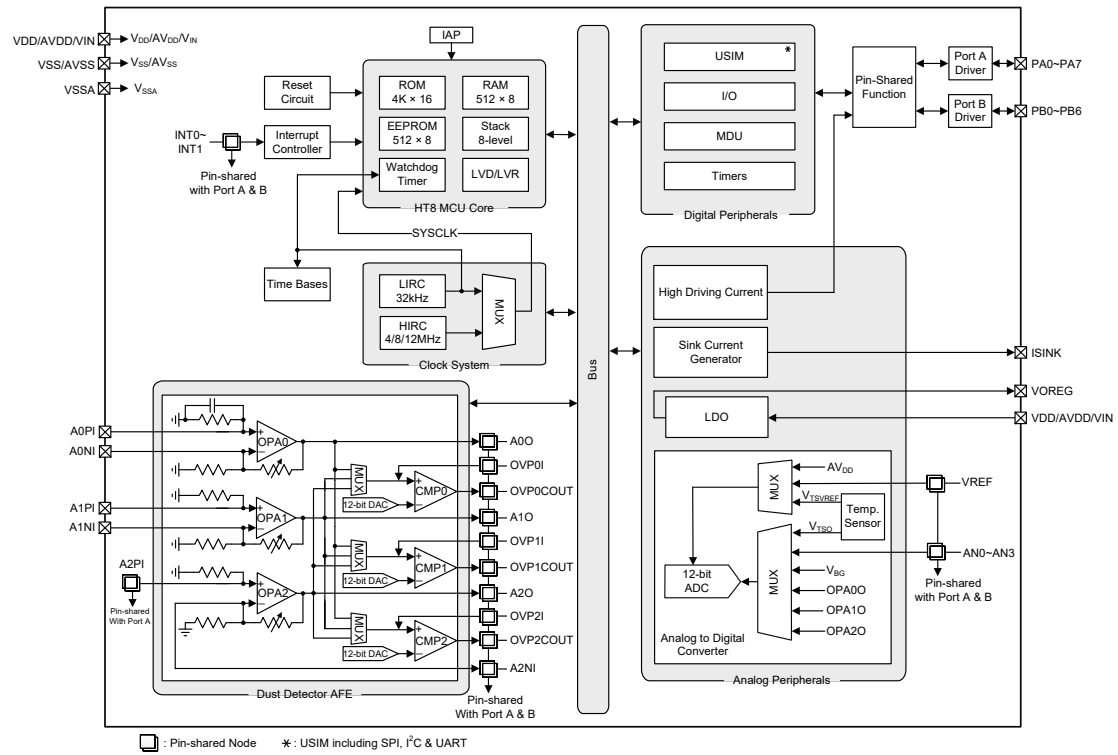
For memory features, the Flash Memory offers users the convenience of multi-programming features. Other memory includes an area of RAM Data Memory as well as an area of true EEPROM memory for storage of non-volatile data such as serial numbers, calibration data etc.

Analog features include a multi-channel 12-bit A/D converter with an integrated temperature sensor circuit, three comparators, three operational amplifiers and three D/A converters function. Multiple and extremely flexible Timer Modules provide timing, pulse generation and PWM generation functions. Communication with the outside world is catered for by including fully integrated SPI, I²C and UART interface functions, these popular interfaces which provide designers with a means of easy communication with external peripheral hardware. In addition, an internal LDO function provides various fixed voltage options to the internal modules and external devices. Protective features such as an internal Watchdog Timer, Low Voltage Reset and Low Voltage Detector coupled with excellent noise immunity and ESD protection ensure that reliable operation is maintained in hostile electrical environments.

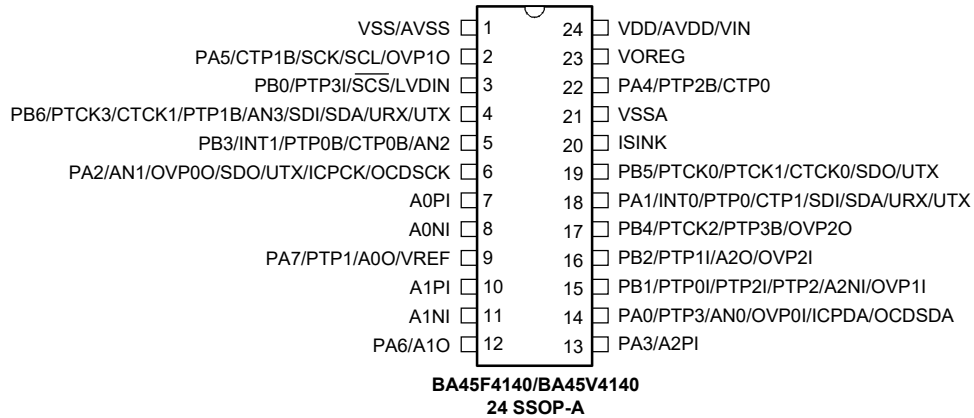
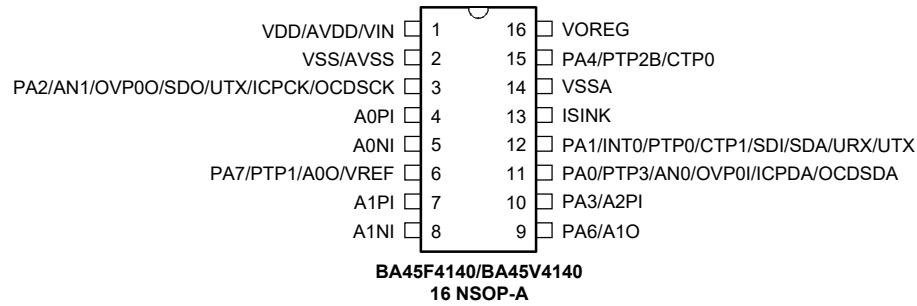
The device also includes fully integrated high and low speed oscillators which require no external components for their implementation. The ability to operate and switch dynamically between a range of operating modes using different clock sources gives users the ability to optimise microcontroller operation and minimise power consumption.

The inclusion of flexible I/O programming features, Time-Base functions, 16-bit MDU, Over Voltage Protection function, Sink Current Generator, High Driving Current along with many other features ensure that the device will find excellent use in the dust sensor applications.

Block Diagram



Pin Assignment



- Note: 1. If the pin-shared pin functions have multiple outputs simultaneously, the desired pin-shared function is determined by the corresponding software control bits.
2. The OCDSDA and OCDSCK pins are supplied for the OCDS dedicated pins.
3. For less pin-count package types there will be unbonded pins which should be properly configured to avoid unwanted current consumption resulting from floating input condition. Refer to the “Standby Current Considerations” and “Input/Output Ports” sections.

Pin Description

The function of each pin is listed in the following table, however the details behind how each pin is configured is contained in other sections of the datasheet. Note that where more than one package type exists the table will reflect the situation for the larger package type.

Pin Name	Function	OPT	I/T	O/T	Description
PA0/PTP3/AN0/OVP0I/ICPDA/OCDSDA	PA0	PAWU PAPU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	PTP3	PAS0	—	CMOS	PTM3 output
	AN0	PAS0	AN	—	A/D Converter external analog input
	OVP0I	PAS0	AN	—	OVP signal input
	ICPDA	—	ST	CMOS	ICP data/address pin
OCDSDA	—	ST	CMOS	OCDS data/address pin	

Pin Name	Function	OPT	I/T	O/T	Description
PA1/INT0/PTP0/CTP1/ SDI/SDA/URX/UTX	PA1	PAWU PAPU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	INT0	PAS0 INTC0 INTEG	ST	—	External Interrupt 0 input
	PTP0	PAS0	—	CMOS	PTM0 output
	CTP1	PAS0	—	CMOS	CTM1 output
	SDI	PAS0 IFS	ST	—	SPI serial data input
	SDA	PAS0 IFS	ST	NMOS	I ² C data line
PA2/AN1/OVP00/SDO/ UTX/ICPCK/OCDSCK	URX/UTX	PAS0 IFS	ST	CMOS	UART serial data input in full-duplex communication or UART serial data input/output in Single Wire Mode communication
	PA2	PAWU PAPU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	AN1	PAS0	AN	—	A/D Converter external analog input
	OVP00	PAS0	—	CMOS	OVP comparator output
	SDO	PAS0	—	CMOS	SPI serial data output
	UTX	PAS0	—	CMOS	UART serial data output
	ICPCK	—	ST	—	ICP clock pin
OCDSCK	—	ST	—	OCDS clock input	
PA3/A2PI	PA3	PAWU PAPU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	A2PI	PAS0	AN	—	DD Operational Amplifier 2 positive input
PA4/CTP0/PTP2B	PA4	PAWU PAPU PAS1	ST	CMOS NMOS	General purpose I/O with high current driver output. Register enabled pull-up and wake-up
	CTP0	PAS1	—	CMOS	CTM0 output
	PTP2B	PAS1	—	CMOS	PTM2 inverting output
PA5/CTP1B/SCK/ SCL/OVP10	PA5	PAWU PAPU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	CTP1B	PAS1	—	CMOS	CTM1 inverting output
	SCK	PAS1	ST	CMOS	SPI serial clock
	SCL	PAS1	ST	CMOS	I ² C clock line
	OVP10	PAS1	—	CMOS	OVP comparator output
PA6/A10	PA6	PAWU PAPU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	A10	PAS1	—	CMOS	DD Operational Amplifier 1 output
PA7/PTP1/A00/VREF	PA7	PAWU PAPU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	PTP1	PAS1	—	CMOS	PTM1 output
	A00	PAS1	—	CMOS	DD Operational Amplifier 0 output
	VREF	PAS1	AN	—	A/D Converter external reference voltage

Pin Name	Function	OPT	I/T	O/T	Description
PB0/PTP3I/SCS/LVDIN	PB0	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	PTP3I	PBS0	ST	—	PTM3 capture input
	SCS	PBS0	ST	CMOS	SPI slave device select
	LVDIN	PBS0	AN	—	LVD input
PB1/PTP0I/PTP2I/ PTP2/A2NI/OVP1I	PB1	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	PTP0I	PBS0 IFS	ST	—	PTM0 capture input
	PTP2I	PBS0 IFS	ST	—	PTM2 capture input
	PTP2	PBS0	—	CMOS	PTM2 output
	A2NI	PBS0	AN	—	DD Operational Amplifier 2 negative input
OVP1I	PBS0	AN	—	OVP signal input	
PB2/PTP1I/A2O/OVP2I	PB2	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	PTP1I	PBS0 IFS	ST	—	PTM1 capture input
	A2O	PBS0	—	CMOS	DD Operational Amplifier 2 output
	OVP2I	PBS0	AN	—	OVP signal input
PB3/INT1/PTP0B/ CTP0B/AN2	PB3	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	INT1	PBS0 INTC0 INTEG	ST	—	External Interrupt 1
	PTP0B	PBS0	—	CMOS	PTM0 inverting output
	CTP0B	PBS0	—	CMOS	CTM0 inverting output
AN2	PBS0	AN	—	A/D Converter external analog input	
PB4/PTCK2/PTP3B/OVP2O	PB4	PBPU PBS1	ST	CMOS	General purpose I/O. Register enabled pull-up
	PTCK2	PBS1	ST	—	PTM2 clock input
	PTP3B	PBS1	—	CMOS	PTM3 inverted output
	OVP2O	PBS1	—	CMOS	OVP comparator output
PB5/PTCK0/PTCK1/ CTCK0/SDO/UTX	PB5	PBPU PBS1	ST	CMOS	General purpose I/O. Register enabled pull-up
	PTCK0	PBS1	ST	—	PTM0 clock input
	PTCK1	PBS1	ST	—	PTM1 clock input
	CTCK0	PBS1	ST	—	CTM0 clock input
	SDO	PBS1	—	CMOS	SPI serial data output
UTX	PBS1	—	CMOS	UART serial data output	

Pin Name	Function	OPT	I/T	O/T	Description
PB6/PTCK3/CTCK1/PTP1B/ AN3/SDI/SDA/URX/UTX	PB6	PBPU PBS1	ST	CMOS	General purpose I/O. Register enabled pull-up
	PTCK3	PBS1	ST	—	PTM3 clock input
	CTCK1	PBS1	ST	—	CTM1 clock input
	PTP1B	PBS1	—	CMOS	PTM1 inverted output
	AN3	PBS1	AN	—	A/D Converter external analog input
	SDI	PBS1 IFS	ST	—	SPI serial data input
	SDA	PBS1 IFS	ST	NMOS	I ² C data line
URX/UTX	PBS1 IFS	ST	CMOS	UART serial data input in full-duplex communication or UART serial data input/output in Single Wire Mode communication	
A0NI	A0NI	—	AN	—	DD Operational Amplifier 0 negative input
A0PI	A0PI	—	AN	—	DD Operational Amplifier 0 positive input
A1NI	A1NI	—	AN	—	DD Operational Amplifier 1 negative input
A1PI	A1PI	—	AN	—	DD Operational Amplifier 1 positive input
ISINK	ISINK	—	—	AN	Sink current source
VDD/AVDD/VIN	VDD	—	PWR	—	Positive power supply
	AVDD	—	PWR	—	Analog positive power supply
	VIN	—	PWR	—	LDO input voltage
VOREG	VOREG	—	PWR	—	LDO output voltage
VSSA	VSSA	—	PWR	—	NMOS driver and Sink Current Generator analog power supply, ground
VSS/AVSS	VSS	—	PWR	—	Digital negative power supply
	AVSS	—	PWR	—	Analog negative power supply

Legend: I/T: Input type;

OPT: Optional by register option;

ST: Schmitt Trigger input;

NMOS: NMOS output;

O/T: Output type;

PWR: Power;

CMOS: CMOS output;

AN: Analog signal.

Absolute Maximum Ratings

Supply Voltage	V _{SS} -0.3V to 6.0V
Input Voltage	V _{SS} -0.3V to V _{DD} +0.3V
Storage Temperature.....	-60°C to 150°C
Operating Temperature.....	-40°C to 85°C
I _{OH} Total	-80mA
I _{OL} Total	80mA
Total Power Dissipation	500mW

Note: These are stress ratings only. Stresses exceeding the range specified under “Absolute Maximum Ratings” may cause substantial damage to the device. Functional operation of the device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency, pin load conditions, temperature and program instruction type, etc., can all exert an influence on the measured values.

Operating Voltage Characteristics

 $T_a = -40^{\circ}\text{C} \sim 85^{\circ}\text{C}$

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{DD}	Operating Voltage – HIRC	$f_{SYS}=4\text{MHz}$	2.2	—	5.5	V
		$f_{SYS}=8\text{MHz}$	2.2	—	5.5	V
		$f_{SYS}=12\text{MHz}$	2.7	—	5.5	V
	Operating Voltage – LIRC	$f_{SYS}=32\text{kHz}$	2.2	—	5.5	V

Operating Current Characteristics

 $T_a = -40^{\circ}\text{C} \sim 85^{\circ}\text{C}$

Symbol	Operating Mode	Test Conditions		Min	Typ	Max.	Unit	
		V_{DD}	Conditions					
I_{DD}	SLOW Mode – LIRC (LVR Enable)	2.2V	$f_{SYS}=32\text{kHz}$	—	21	26	μA	
		3V		—	22	27	μA	
		5V		—	24	30	μA	
	FAST Mode – HIRC	2.2V	$f_{SYS}=4\text{MHz}$	—	0.21	0.24	mA	
				3V	—	0.28	0.32	mA
				5V	—	0.50	0.55	mA
		2.2V	$f_{SYS}=8\text{MHz}$	—	0.40	0.45	mA	
				3V	—	0.57	0.64	mA
				5V	—	1.02	1.10	mA
		2.7V	$f_{SYS}=12\text{MHz}$	—	0.73	0.80	mA	
				3V	—	0.82	0.92	mA
				5V	—	1.48	1.65	mA

Note: When using the characteristic table data, the following notes should be taken into consideration:

1. Any digital inputs are setup in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Operating Current values are measured using a continuous NOP instruction program loop.

Standby Current Characteristics

 $T_a = 25^{\circ}\text{C}$, unless otherwise specified

Symbol	Standby Mode	Test Conditions		Min.	Typ.	Max	Max. @85°C	Unit
		V_{DD}	Conditions					
I_{STB}	SLEEP Mode	2.2V	WDT on	—	1.3	1.8	3.4	μA
		3V		—	1.7	2.1	4.0	μA
		5V		—	3.0	3.5	6.2	μA
	IDLE0 Mode – LIRC	2.2V	f_{SUB} on	—	1.4	1.9	3.6	μA
		3V		—	1.8	2.2	4.2	μA
		5V		—	3.3	3.9	6.6	μA

Symbol	Standby Mode	Test Conditions		Min.	Typ.	Max.	Max. @85°C	Unit
		V _{DD}	Conditions					
I _{STB}	IDLE1 Mode – HIRC	2.2V	f _{SUB} on, f _{SYS} = 4MHz	—	110	140	160	μA
		3V		—	180	210	240	μA
		5V		—	360	390	430	μA
		2.2V	f _{SUB} on, f _{SYS} = 8MHz	—	250	280	300	μA
		3V		—	380	410	440	μA
		5V		—	720	770	820	μA
		2.7V	f _{SUB} on, f _{SYS} = 12MHz	—	360	390	420	μA
		3V		—	540	580	610	μA
5V	—	1070		1130	1180	μA		

Note: When using the characteristic table data, the following notes should be taken into consideration:

1. Any digital inputs are setup in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Standby Current values are taken after a HALT instruction execution thus stopping all instruction execution.

A.C. Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency and temperature etc., can all exert an influence on the measured values.

High Speed Internal Oscillator – HIRC – Frequency Accuracy

During the program writing operation the writer will trim the HIRC oscillator at a user selected HIRC frequency and user selected voltage of either 3V or 5V.

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit		
		V _{DD}	Temp.						
f _{HIRC}	4MHz Writer Trimmed HIRC Frequency	3V/5V	25°C	-1%	4	+1%	MHz		
			-40°C~85°C	-2%	4	+2%			
		2.2V~5.5V	25°C	-2.5%	4	+2.5%			
			-40°C~85°C	-3%	4	+3%			
		8MHz Writer Trimmed HIRC Frequency	3V/5V	25°C	-1%	8		+1%	MHz
				-40°C~85°C	-2%	8		+2%	
	2.2V~5.5V		25°C	-2.5%	8	+2.5%			
			-40°C~85°C	-3%	8	+3%			
	12MHz Writer Trimmed HIRC Frequency		5V	25°C	-1%	12	+1%	MHz	
				-40°C~85°C	-2%	12	+2%		
		2.7V~5.5V	25°C	-2.5%	12	+2.5%			
			-40°C~85°C	-3%	12	+3%			

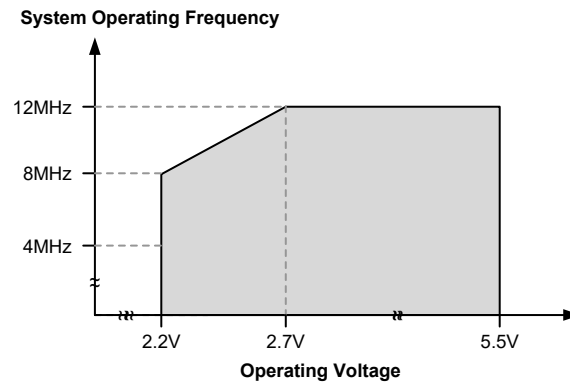
Note: 1. The 3V/5V values for V_{DD} are provided as these are the two selectable fixed voltages at which the HIRC frequency is trimmed by the writer.

2. The row below the 3V/5V trim voltage row is provided to show the values for the full V_{DD} range operating voltage. It is recommended that the trim voltage is fixed at 3V for application voltage ranges from 2.2V to 3.6V and fixed at 5V for application voltage ranges from 3.3V to 5.5V.
3. The minimum and maximum tolerance values provided in the table are only for the frequency at which the writer trims the HIRC oscillator. After trimming at this chosen specific frequency any change in HIRC oscillator frequency using the oscillator register control bits by the application program will give a frequency tolerance to within ±20%.

Low Speed Internal Oscillator Characteristics – LIRC – Frequency Accuracy

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Temp.				
f _{LIRC}	LIRC Frequency	3V	25°C	-2%	32	+2%	kHz
		2.2V~5.5V	-40°C~85°C	-7%	32	+7%	kHz
t _{START}	LIRC Start Up Time	—	-40°C~85°C	—	—	100	μs

Operating Frequency Characteristic Curve



System Start Up Time Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
t _{SST}	System Start-up Time Wake-up from condition where f _{sys} is off	—	f _{sys} =f _H ~f _H /64, f _H =f _{HIRC}	—	16	—	t _{HIRC}
		—	f _{sys} =f _{sub} =f _{LIRC}	—	2	—	t _{LIRC}
	System Start-up Time Wake-up from condition where f _{sys} is on	—	f _{sys} =f _H ~f _H /64, f _H =f _{HIRC}	—	2	—	t _H
		—	f _{sys} =f _{sub} =f _{LIRC}	—	2	—	t _{sub}
	System Speed Switch Time FAST to SLOW Mode or SLOW to FAST Mode	—	f _{HIRC} switches from off → on	—	16	—	t _{HIRC}
t _{RSTD}	System Reset Delay Time Reset Source from Power-on Reset or LVR Hardware Reset	—	RR _{POR} =5V/ms	14	16	18	ms
	System Reset Delay Time LVRC/WDT Software Reset	—	—	—	—	—	—
	System Reset Delay Time (Reset Source from WDT Overflow)	—	—	14	16	18	ms

- Note: 1. For the System Start-up time values, whether f_{sys} is on or off depends upon the mode type and the chosen f_{sys} system oscillator. Details are provided in the System Operating Modes section.
2. The time units, shown by the symbols t_{HIRC} etc., are the inverse of the corresponding frequency values as provided in the above tables. For example t_{HIRC}=1/f_{HIRC}, t_{sys}=1/f_{sys} etc.
3. If the LIRC is used as the system clock, then an additional LIRC start up time, t_{START}, as provided in the LIRC frequency table, must be added to the t_{SST} time in the table above.
4. The System Speed Switch Time is effectively the time taken for the newly activated oscillator to start up.

Input/Output Characteristics

Input/Output D.C Characteristics

Ta=-40°C~85°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{IL}	Input Low Voltage for I/O Ports except PA4 Pin	5V	—	0	—	1.5	V
		—	—	0	—	0.2V _{DD}	
V _{IH}	Input High Voltage for I/O Ports except PA4 Pin	5V	—	3.5	—	5.0	V
		—	—	0.8V _{DD}	—	V _{DD}	
I _{OL}	Sink Current for I/O Ports except PA4 Pin	3V	V _{OL} =0.1V _{DD}	16	32	—	mA
		5V		32	65	—	
I _{OH}	Source Current for I/O Ports except PA4 Pin	3V	V _{OH} =0.9V _{DD}	-4	-8	—	mA
		5V		-8	-16	—	
R _{PH}	Pull-high Resistance for I/O Ports except PA4 Pin ^(Note)	3V	—	20	60	100	kΩ
		5V		10	30	50	
I _{LEAK}	Input Leakage Current for I/O Ports except PA4 Pin	5V	V _{IN} =V _{DD} or V _{IN} =V _{SS}	—	—	±1	μA
t _{TCK}	TM Clock Input Pin Minimum Pulse Width	—	—	0.3	—	—	μs
t _{INT}	External Interrupt Minimum Pulse Width	—	—	10	—	—	μs
t _{TPI}	PTMn TPI Input Pin Minimum Pulse Width (n=0, 1, 2)	—	—	50	—	—	ns
	PTMn TPI Input Pin Minimum Pulse Width (n=3)	—	—	0.3	—	—	μs
f _{TMCLK}	TM Maximum Timer Clock Source Frequency	5V	—	—	—	1	f _{sys}
t _{CPW}	TM Minimum Capture Pulse Width	—	—	t _{CPW} ⁽²⁾	—	—	μs
t _{SRESET}	Minimum Software Reset Width to Reset	—	—	45	90	120	μs

Note: 1. The R_{PH} internal pull high resistance value is calculated by connecting to ground and enabling the input pin with a pull-up resistor and then measuring the pin current at the specified supply voltage level. Dividing the voltage by this measured current provides the R_{PH} value.

2. If PTnCAPTS=0, then t_{CPW}=max(2×t_{TMCLK}, t_{TPI})

If PTnCAPTS=1, then t_{CPW}=max(2×t_{TMCLK}, t_{TCK})

Ex1: If PTnCAPTS=0, f_{TMCLK}=16MHz, t_{TPI}=0.05μs, then t_{CPW}=max(0.125μs, 0.05μs)=0.125μs

Ex2: If PTnCAPTS=1, f_{TMCLK}=16MHz, t_{TCK}=0.3μs, then t_{CPW}=max(0.125μs, 0.3μs)=0.3μs

Ex3: If PTnCAPTS=0, f_{TMCLK}=8MHz, t_{TPI}=0.05μs, then t_{CPW}=max(0.25μs, 0.05μs)=0.25μs

Ex4: If PTnCAPTS=0, f_{TMCLK}=4MHz, t_{TPI}=0.05μs, then t_{CPW}=max(0.5μs, 0.05μs)=0.5μs

Where t_{TMCLK}=1/f_{TMCLK}

Input/Output (With I/O Driver) Electrical Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{IL}	Input Low Voltage for PA4 Pin	5V	—	0	—	1.5	V
		—	—	0	—	0.2V _{DD}	
V _{IH}	Input High Voltage for PA4 Pin	5V	—	3.5	—	5.0	V
		—	—	0.8V _{DD}	—	V _{DD}	
I _{OL1}	Sink Current for REM Pin	3V	V _{OL} =0.5V, REMEN bit=1, PAS4=1, CHPCLK=4MHz	360	500	—	mA
		5V	V _{OL} =0.5V, REMEN bit=0, PAS4=1	360	500	—	

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
I _{OL2}	Sink Current for PA4 Pin	3V	V _{OL} =0.1V _{DD} , PAS4=1	16	32	—	mA
		5V		32	65	—	mA
I _{OH}	Source Current for PA4 Pin	3V	V _{OL} =0.9V _{DD} , PAS4=1	-4	-8	—	mA
		5V		-8	-16	—	mA
R _{PH}	Pull-high Resistance for PA4 Pin (Note)	3V	—	20	60	100	kΩ
		5V	—	10	30	50	
I _{LEAK}	Input Leakage Current for PA4 Pin	5V	V _{IN} =V _{SS} or V _{IN} =V _{DD}	—	—	±1	μA
t _{READYB}	PA4 High Current Output Function Stable Time	—	CHPCLK=4MHz, READYB bit changes from 0 to 1 and then to 0 again	350	—	—	μs

Note: The R_{PH} internal pull high resistance value is calculated by connecting to ground and enabling the input pin with a pull-up resistor and then measuring the input current at the specified supply voltage level. Dividing the voltage by this measured current provides the R_{PH} value.

Memory Characteristics

T_a=-40°C~85°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{DD}	V _{DD} for Read/Write	—	—	2.2	—	5.5	V
Flash Program Memory							
t _{FWR}	Write Time	—	FWERTS bit=0	—	2.2	2.7	ms
		—	FWERTS bit=1	—	3.0	3.6	ms
t _{FER}	Erase Time	—	FWERTS bit=0	—	3.2	3.9	ms
		—	FWERTS bit=1	—	3.7	4.5	ms
E _P	Cell Endurance	—	—	100K	—	—	E/W
t _{RETD}	ROM Data Retention Time	—	T _a =25°C	—	40	—	Year
t _{ACTV}	ROM Activation Time – Wake-up from Power Down Mode ⁽¹⁾	—	—	1	—	2	t _{LIRC}
Data EEPROM Memory							
t _{EERD}	EEPROM read time	—	—	—	—	4	t _{SYS}
t _{EEWR}	Write Time (byte mode)	—	EWERTS bit=0	—	5.4	6.6	ms
		—	EWERTS bit=1	—	6.7	8.1	ms
	Write Time (page mode)	—	EWERTS bit=0	—	2.2	2.7	ms
		—	EWERTS bit=1	—	3.0	3.6	ms
t _{EEER}	Erase Time	—	EWERTS bit=0	—	3.2	3.9	ms
		—	EWERTS bit=1	—	3.7	4.5	ms
E _P	Cell Endurance	—	—	100K	—	—	E/W ⁽²⁾
t _{RETD}	ROM Data Retention Time	—	T _a =25°C	—	40	—	Year
RAM Data Memory							
V _{DR}	RAM Data Retention Voltage	—	—	1.0	—	—	V

Note: 1. The ROM activation time t_{ACTV} should be added when calculating the total system start-up time of a wake-up from the power down mode.

2. “E/W” means Erase/Write times.

LVD & LVR Electrical Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{LVR}	Low Voltage Reset Voltage	—	LVR enable, voltage select 2.1V	-5%	2.1	+5%	V
			LVR enable, voltage select 2.55V		2.55		
			LVR enable, voltage select 3.15V		3.15		
			LVR enable, voltage select 3.8V		3.8		
V _{LVD}	Low Voltage Detection Voltage	—	LVD enable, voltage select 2.2V	-5%	2.2	+5%	V
			LVD enable, voltage select 2.4V		2.4		
			LVD enable, voltage select 2.7V		2.7		
			LVD enable, voltage select 3.0V		3.0		
			LVD enable, voltage select 3.3V		3.3		
			LVD enable, voltage select 3.6V		3.6		
			LVD enable, voltage select 4.0V		4.0		
I _{LVR/LVDBG}	Operating Current	3V	LVD enable, LVR enable, VBGEN=0	—	—	18	μA
		5V	—	—	20	25	
		3V	LVD enable, LVR enable, VBGEN=1	—	—	150	μA
		5V	—	—	180	200	
t _{LVDS}	LVDO Stable Time	—	For LVR enable, VBGEN=0, LVD off → on	—	—	18	μs
			For LVR disable, VBGEN=0, LVD off → on	—	—	150	
t _{LVR}	Minimum Low Voltage Width to Reset	—	TLVR[1:0]=00B	120	240	480	μs
			TLVR[1:0]=01B	0.5	1.0	2.0	
			TLVR[1:0]=10B	1	2	4	ms
			TLVR[1:0]=11B	2	4	8	
t _{LVD}	Minimum Low Voltage Width to Interrupt	—	—	60	120	240	μs
I _{LVR}	Additional Current for LVR Enable	—	LVD disable, VBGEN=0	—	—	24	μA
I _{LVD}	Additional Current for LVD Enable	—	LVR disable, VBGEN=0	—	—	24	μA

A/D Converter Electrical Characteristics

Ta=-40°C~85°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{DD}	Operating Voltage	—	—	2.2	—	5.5	V
V _{ADI}	A/D Converter Input Voltage	—	—	0	—	V _{REF}	V
V _{REF}	A/D Converter Reference Voltage	—	—	2.2	—	V _{DD}	V
N _R	Resolution	—	—	—	—	12	Bit
DNL	A/D Converter Differential Non-linearity	—	V _{REF} =AV _{DD} , t _{ADCK} =0.5μs	-3	—	+3	LSB
INL	A/D Converter Integral Non-linearity	—	V _{REF} =AV _{DD} , t _{ADCK} =0.5μs	-4	—	+4	LSB
I _{ADC}	Additional Current for A/D Converter Enable	2.2V	No load, t _{ADCK} =0.5μs	—	300	500	μA
		3V		—	450	600	
		5V		—	850	1000	
t _{ADCK}	A/D Converter Clock Period	—	AN≠temperature sensor output	0.5	—	10.0	μs
		—	AN=temperature sensor output	3.8	4.0	4.2	
t _{ON2ST}	A/D Converter On-to-Start Time	—	—	4	—	—	μs

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
t _{ADC}	A/D Conversion Time (Including A/D Sample and Hold Time)	—	AN≠temperature sensor output	—	16	—	t _{ADCK}
		—	AN=temperature sensor output	—	66	—	

Temperature Sensor Characteristics

T_a=-40°C~85°C, typical=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{DD}	Temperature Sensor Operating Voltage	—	—	2.2	—	5.5	V
I _{TS}	Temperature Sensor Operating Current	3V	TSEN=ADCEN=1, t _{ADCK} =4μs, A/D converter included	—	1260	1950	μA
		5V		—	1490	2250	
t _{TSS}	Temperature Sensor Turn on Stable Time	3V	—	—	—	100	μs
		5V	—	—	—	100	
V _{TSVREF}	Temperature Sensor Reference Voltage	3V	—	-5%	1.212	+5%	V
		5V	—	-5%	1.212	+5%	
T _{ACC}	Temperature Accuracy (Error) ^(Note)	2.7V~4.5V	V _{REF} =V _{TSVREF} , T _a =0°C~70°C	-2.0	—	+2.0	°C
		2.7V~5.5V		-2.5	—	+2.5	
		—	V _{REF} =V _{TSVREF} , T _a =-40°C~85°C	—	±4.0	—	
		2.7V~4.5V		-4.0	—	+4.0	
TS _{Noise}	Temperature Noise	3V	No average	—	0.4	—	°C (p-p)
		5V		—	0.6	—	

Note: The temperature accuracy T_{ACC} is defined as the error between the actual temperature and the temperature obtained by the conversion of the ADC code through the formula.

Internal Reference Voltage Characteristics

T_a=-40°C~85°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{BG}	Bandgap Reference Voltage	—	—	-5%	1.23	+5%	V

Note: The V_{BG} voltage is used as the A/D converter internal signal input.

Sink Current Generator Electrical Characteristics

Ta=-40°C~85°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
I _{SINK}	Sink Current for ISINK Pin	5V	Ta=25°C, V _{ISINK} =3.0V, ISGDATA[4:0]=00000B, ISST=0	4.75	5.00	5.25	mA
		—	Ta=-40°C~85°C, V _{ISINK} =1.0V~4.5V, ISGDATA[4:0]=00000B, ISST=0	4.1	5.0	5.9	
		—	Ta=-40°C~85°C, V _{ISINK} =0.7V~1.0V, ISGDATA[4:0]=00000B, ISST=0	3.75	5.00	5.25	
		5V	Ta=25°C, V _{ISINK} =3.0V, ISGDATA[4:0]=11111B, ISST=1	330	360	390	
		—	Ta=-40°C~85°C, V _{ISINK} =1.0V~4.5V, ISGDATA[4:0]=11111B, ISST=1	295	360	425	
		—	Ta=-40°C~85°C, V _{ISINK} =0.7V~1.0V, ISGDATA[4:0]=11111B, ISST=1	270	360	390	

LDO Electrical characteristics

V_{IN}=V_{OUT}+0.3V, C_{LOAD}=4.7μF, Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{IN}	Supply Voltage	—	—	2.5	—	5.5	V
V _{OUT}	Output Voltage	—	Ta=25°C, I _{LOAD} =1mA, V _{OUT} =2.2V	-2%	2.2	2%	V
			Ta=-40°C~85°C, I _{LOAD} =1mA, V _{OUT} =2.2V	-5%	2.2	5%	V
			Ta=25°C, I _{LOAD} =1mA, V _{OUT} =2.5V	-2%	2.5	2%	V
			Ta=-40°C~85°C, I _{LOAD} =1mA, V _{OUT} =2.5V	-2%	2.5	2%	V
			Ta=25°C, I _{LOAD} =1mA, V _{OUT} =3.3V	-2%	3.3	2%	V
			Ta=-40°C~85°C, I _{LOAD} =1mA, V _{OUT} =3.3V	-5%	3.3	5%	V
			Ta=25°C, I _{LOAD} =1mA, V _{OUT} =3.6V	-2%	3.6	2%	V
			Ta=-40°C~85°C, I _{LOAD} =1mA, V _{OUT} =3.6V	-5%	3.6	5%	V
I _Q	Quiescent Current	5V	Ta=25°C, No load	—	—	6	μA
			Ta=-40°C~85°C, No load	—	—	15	μA
I _{OUT}	Output Current	—	V _{IN} =2.5V, ΔV _{OUT} =0.1V, V _{OUT} =2.2V	10	—	—	mA
			V _{IN} =2.8V, ΔV _{OUT} =0.1V, V _{OUT} =2.5V	15	—	—	mA
			V _{IN} =3.6V, ΔV _{OUT} =0.1V, V _{OUT} =3.3V	30	—	—	mA
			V _{IN} =3.9V, ΔV _{OUT} =0.1V, V _{OUT} =3.6V	35	—	—	mA
TC	Temperature Coefficient	—	Ta=-40°C~85°C, I _{LOAD} =10mA	—	±1.5	±2	mV/°C

Note: Load regulation is measured at a constant junction temperature, using pulse testing with a low ON time and is guaranteed up to the maximum power dissipation. Power dissipation is determined by the input/output differential voltage and the output current. Guaranteed maximum power dissipation will not be available over the full input/output range. The maximum allowable power dissipation at any ambient temperature is $P_D=(T_{J(MAX)}-T_a)/\theta_{JA}$.

Over Voltage Protection Electrical characteristics

Ta=-40°C~85°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{VREFn}	D/A Converter Reference Voltage	—	—	2.2	—	V _{DD}	V
I _{OVp}	Operating Current	3V	OVPnEN=1 (n=0, 1, 2)	—	300	450	μA
		5V	OVPnEN=1 (n=0, 1, 2)	—	500	750	μA
V _{OS}	Input Offset Voltage	3V	With calibration	-2	—	2	mV
		5V	With calibration	-2	—	2	mV
V _{HYS}	Hysteresis	3V	HYSn[1:0]=00B (n=0, 1, 2)	0	0	5	mV
		5V	HYSn[1:0]=00B (n=0, 1, 2)	0	0	5	mV
		3V	HYSn[1:0]=01B (n=0, 1, 2)	15	30	45	mV
		5V	HYSn[1:0]=01B (n=0, 1, 2)	15	30	45	mV
		3V	HYSn[1:0]=10B (n=0, 1, 2)	30	60	90	mV
		5V	HYSn[1:0]=10B (n=0, 1, 2)	30	60	90	mV
		3V	HYSn[1:0]=11B (n=0, 1, 2)	40	90	130	mV
		5V	HYSn[1:0]=11B (n=0, 1, 2)	40	90	130	mV
V _{CM}	Common Mode Voltage Range	3V	—	V _{SS}	—	V _{DD} -1	V
		5V	—	V _{SS}	—	V _{DD} -1	V
DNL	Differential Nonlinearity	3V	V _{VREFn} =V _{DD} @ 25°C	—	—	±3	LSB
		5V	V _{VREFn} =V _{DD} @ 25°C	—	—	±3	LSB
INL	Integral Nonlinearity	3V	V _{VREFn} =V _{DD} @ 25°C	—	—	±4	LSB
		5V	V _{VREFn} =V _{DD} @ 25°C	—	—	±4	LSB
t _{RP}	OVP Response Time	3V	OVPnDA[11:0]=800H, OVPnDEB[2:0]=000B, V _{VREFn} =V _{DD} , OVP input=0.1V~1.6V	—	1.0	1.8	μs
		5V	OVPnDA[11:0]=B33H, OVPnDEB[2:0]=000B, V _{VREFn} =V _{DD} , OVP input=2.1V~3.6V	—	1.0	1.8	μs

Dust Detector AFE Electrical Characteristics

 V_{DD}=5V, Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{DD}	Operating Voltage	—	—	2.2	—	5.5	V
I _{OPA}	Operating Current	5V	DDAmBW[1:0]=00B (m=0, 1, 2), no load	—	3.0	5.0	μA
			DDAmBW[1:0]=01B (m=0, 1, 2), no load	—	10	16	μA
			DDAmBW[1:0]=10B (m=0, 1, 2), no load	—	80	128	μA
			DDAmBW[1:0]=11B (m=0, 1, 2), no load	—	200	320	μA
V _{OS}	Input Offset Voltage	5V	Without calibration, (DDAmOF[5:0]=100000B) (m=0, 1, 2)	-15	—	15	mV
			With calibration	-4	—	4	mV
I _{OS}	Input Offset Current	5V	V _{IN} =1/2V _{CM}	—	1	10	nA
V _{CM}	Common Mode Voltage Range	5V	DDAmBW[1:0]=00, 01, 10, 11 (m=0, 1, 2)	V _{SS}	—	V _{DD} -1.4	V

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
PSRR	Power Supply Rejection Ratio	5V	DDAmBW[1:0]=00, 01, 10, 11 (m=0, 1, 2)	50	70	—	dB
CMRR	Common Mode Rejection Ratio	5V	DDAmBW[1:0]=00, 01, 10, 11 (m=0, 1, 2)	50	80	—	dB
A _{OL}	Open Loop Gain	5V	DDAmBW[1:0]=00, 01, 10, 11 (m=0, 1, 2)	60	80	—	dB
SR	Slew Rate	5V	R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW[1:0]=00 (m=0, 1, 2)	0.5	1.5	—	V/ms
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW[1:0]=01 (m=0, 1, 2)	5	15	—	V/ms
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW[1:0]=10 (m=0, 1, 2)	180	500	—	V/ms
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW[1:0]=11 (m=0, 1, 2)	600	1800	—	V/ms
GBW	Gain Bandwidth	5V	R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW[1:0]=00 (m=0, 1, 2)	2.5	5.0	—	kHz
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW[1:0]=01 (m=0, 1, 2)	20	40	—	kHz
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW[1:0]=10 (m=0, 1, 2)	400	600	—	kHz
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW[1:0]=11 (m=0, 1, 2)	1300	2000	—	kHz
V _{OR}	Maximum Output Voltage Range	5V	DDAmBW[1:0]=00, 01 (m=0, 1, 2), R _{LOAD} =5kΩ to V _{DD} /2	V _{SS} +140	—	V _{DD} -160	mV
			DDAmBW[1:0]=10, 11 (m=0, 1, 2), R _{LOAD} =5kΩ to V _{DD} /2	V _{SS} +120	—	V _{DD} -140	mV
I _{SC}	Output Short Circuit Current	5V	R _{LOAD} =5.1Ω, DDAmBW[1:0]=00, 01 (m=0, 1, 2)	±6	±12	—	mA
			R _{LOAD} =5.1Ω, DDAmBW[1:0]=10, 11 (m=0, 1, 2)	±10	±20	—	mA

Note: These parameters are characterized but not tested.

V_{DD}=2.2V~5.5V, T_a=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
I _{OPA}	Operating Current	—	DDAmBW [1:0]=00B (m=0, 1, 2), no load	—	2.5	4.0	μA
			DDAmBW [1:0]=01B (m=0, 1, 2), no load	—	10	16	μA
			DDAmBW [1:0]=10B (m=0, 1, 2), no load	—	80	128	μA
			DDAmBW [1:0]=11B (m=0, 1, 2), no load	—	200	320	μA
V _{OS}	Input Offset Voltage	3V	Without calibration (DDAmOF[5:0]=100000B) (m=0, 1, 2)	-15	—	15	mV
		5V					
		3V	With calibration	-2	—	2	mV
		5V					
I _{OS}	Input Offset Current	—	V _{IN} =1/2V _{CM}	—	1	10	nA
V _{CM}	Common Mode Voltage Range	—	DDAmBW [1:0]=00, 01, 10, 11 (m=0, 1, 2)	V _{SS}	—	V _{DD} -1.4	V
PSRR	Power Supply Rejection Ratio	—	DDAmBW [1:0]=00, 01, 10, 11 (m=0, 1, 2)	50	70	—	dB

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
CMRR	Common Mode Rejection Ratio	—	DDAmBW [1:0]=00, 01, 10, 11 (m=0, 1, 2)	50	80	—	dB
A _{OL}	Open Loop Gain	—	DDAmBW [1:0]=00, 01, 10, 11 (m=0, 1, 2)	60	80	—	dB
SR	Slew Rate	—	R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW [1:0]=00 (m=0, 1, 2)	0.5	1.5	—	V/ms
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW [1:0]=01 (m=0, 1, 2)	5	15	—	V/ms
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW [1:0]=10 (m=0, 1, 2)	180	500	—	V/ms
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW [1:0]=11 (m=0, 1, 2)	600	1800	—	V/ms
GBW	Gain Bandwidth	—	R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW [1:0]=00 (m=0, 1, 2)	2	5	—	kHz
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW [1:0]=01 (m=0, 1, 2)	15	40	—	kHz
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW [1:0]=10 (m=0, 1, 2)	250	600	—	kHz
			R _{LOAD} =1MΩ, C _{LOAD} =60pF, DDAmBW [1:0]=11 (m=0, 1, 2)	800	2000	—	kHz
V _{OR}	Maximum Output Voltage Range	—	DDAmBW [1:0]=00, 01 (m=0, 1, 2), R _{LOAD} =5kΩ to V _{DD} /2	V _{SS} +140	—	V _{DD} -160	mV
			DDAmBW [1:0]=10, 11 (m=0, 1, 2), R _{LOAD} =5kΩ to V _{DD} /2	V _{SS} +120	—	V _{DD} -140	mV
I _{SC}	Output Short Circuit Current	—	R _{LOAD} =5.1Ω, DDAmBW[1:0]=00, 01 (m=0, 1, 2)	±1.2	±12	—	mA
			R _{LOAD} =5.1Ω, DDAmBW[1:0]=10, 11 (m=0, 1, 2)	±2	±20	—	mA

Note: These parameters are characterized but not tested.

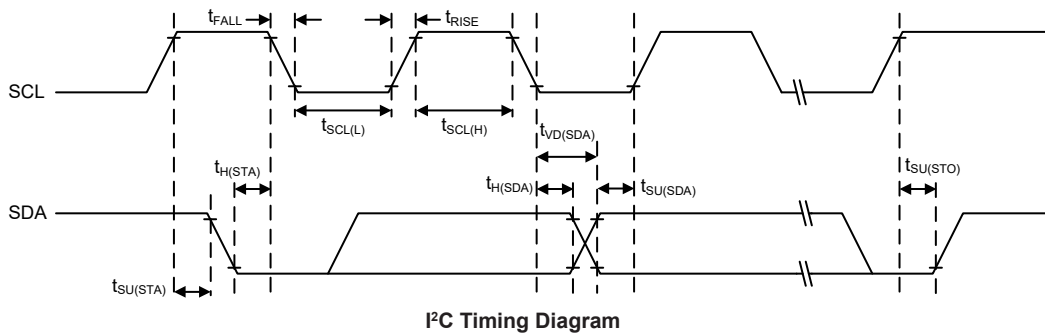
I²C Electrical Characteristics

T_a=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
f _{I2C}	I ² C Standard Mode (100kHz) f _{sys} Frequency <small>(Note)</small>	—	No clock debounce	2	—	—	MHz
		—	2 system clock debounce	4	—	—	MHz
		—	4 system clock debounce	4	—	—	MHz
	I ² C Fast Mode (400kHz) f _{sys} Frequency <small>(Note)</small>	—	No clock debounce	4	—	—	MHz
		—	2 system clock debounce	8	—	—	MHz
		—	4 system clock debounce	8	—	—	MHz
f _{SCL}	SCL Clock Frequency	3V/5V	Standard mode	—	—	100	kHz
			Fast mode	—	—	400	
t _{SCL(H)}	SCL Clock High Time	3V/5V	Standard mode	3.5	—	—	μs
			Fast mode	0.9	—	—	
t _{SCL(L)}	SCL Clock Low Time	3V/5V	Standard mode	3.5	—	—	μs
			Fast mode	0.9	—	—	
t _{FALL}	SCL and SDA Fall Time	3V/5V	Standard mode	—	—	1.3	μs
			Fast mode	—	—	0.34	

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
t _{RISE}	SCL and SDA Rise Time	3V/5V	Standard mode	—	—	1.3	μs
			Fast mode	—	—	0.34	
t _{SU(SDA)}	SDA Data Setup Time	3V/5V	Standard mode	0.25	—	—	μs
			Fast mode	0.1	—	—	
t _{H(SDA)}	SDA Data Hold Time	3V/5V	—	0.1	—	—	μs
t _{VD(SDA)}	SDA Data Valid Time	3V/5V	—	—	—	0.6	μs
t _{SU(STA)}	Start Condition Setup Time	3V/5V	Standard mode	3.5	—	—	μs
			Fast mode	0.6	—	—	
t _{H(STA)}	Start Condition Hold Time	3V/5V	Standard mode	4.0	—	—	μs
			Fast mode (f _{SYS} ≥8MHz)	0.6	—	—	
			Fast mode (f _{SYS} <8MHz)	0.8	—	—	
t _{SU(STO)}	Stop Condition Setup Time	3V/5V	Standard mode	3.5	—	—	μs
			Fast mode	0.6	—	—	

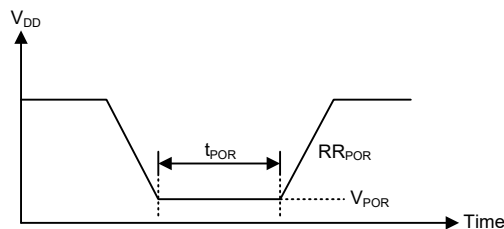
Note: Using the debounce function can make the transmission more stable and reduce the probability of communication failure due to interference.



Power-on Reset Characteristics

T_a=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{POR}	V _{DD} Start Voltage to Ensure Power-on Reset	—	—	—	—	100	mV
RR _{POR}	V _{DD} Rising Rate to Ensure Power-on Reset	—	—	0.035	—	—	V/ms
t _{POR}	Minimum Time for V _{DD} Stays at V _{POR} to Ensure Power-on Reset	—	—	1	—	—	ms



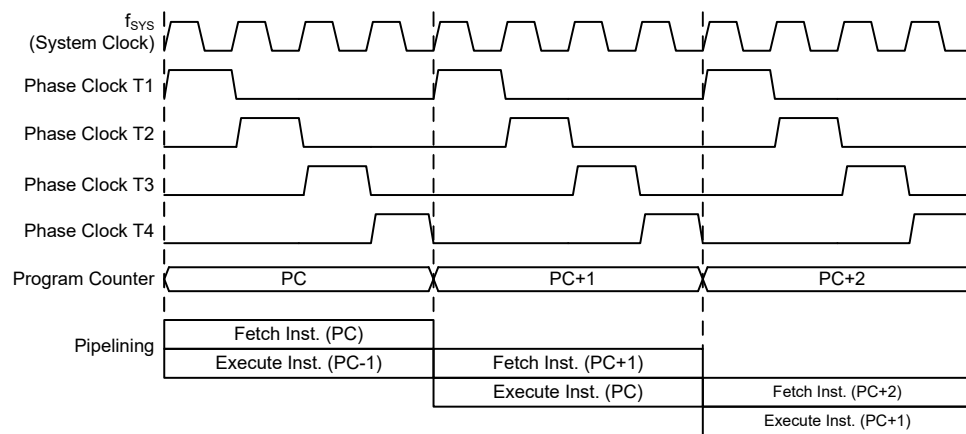
System Architecture

A key factor in the high-performance features of the Holtek range of microcontrollers is attributed to their internal system architecture. The range of the device take advantage of the usual features found within RISC microcontrollers providing increased speed of operation and enhanced performance. The pipelining scheme is implemented in such a way that instruction fetching and instruction execution are overlapped, hence instructions are effectively executed in one or two cycles for most of the standard or extended instructions respectively, with the exception of branch or call instructions which need one more cycle. An 8-bit wide ALU is used in practically all instruction set operations, which carries out arithmetic operations, logic operations, rotation, increment, decrement, branch decisions, etc. The internal data path is simplified by moving data through the Accumulator and the ALU. Certain internal registers are implemented in the Data Memory and can be directly or indirectly addressed. The simple addressing methods of these registers along with additional architectural features ensure that a minimum of external components is required to provide a functional I/O and A/D control system with maximum reliability and flexibility. This makes the device suitable for affordable, high-volume production for controller applications.

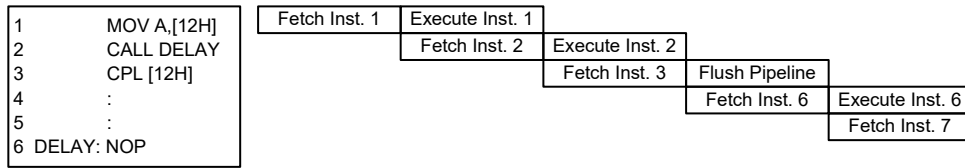
Clocking and Pipelining

The main system clock, derived from either a HIRC or LIRC oscillator is subdivided into four internally generated non-overlapping clocks, T1~T4. The Program Counter is incremented at the beginning of the T1 clock during which time a new instruction is fetched. The remaining T2~T4 clocks carry out the decoding and execution functions. In this way, one T1~T4 clock cycle forms one instruction cycle. Although the fetching and execution of instructions takes place in consecutive instruction cycles, the pipelining structure of the microcontroller ensures that instructions are effectively executed in one instruction cycle. The exception to this are instructions where the contents of the Program Counter are changed, such as subroutine calls or jumps, in which case the instruction will take one more instruction cycle to execute.

For instructions involving branches, such as jump or call instructions, two machine cycles are required to complete instruction execution. An extra cycle is required as the program takes one cycle to first obtain the actual jump or call address and then another cycle to actually execute the branch. The requirement for this extra cycle should be taken into account by programmers in timing sensitive applications.



System Clocking and Pipelining



Instruction Fetching

Program Counter

During program execution, the Program Counter is used to keep track of the address of the next instruction to be executed. It is automatically incremented by one each time an instruction is executed except for instructions, such as “JMP” or “CALL” that demands a jump to a non-consecutive Program Memory address. Only the lower 8 bits, known as the Program Counter Low Register, are directly addressable by the application program.

When executing instructions requiring jumps to non-consecutive addresses such as a jump instruction, a subroutine call, interrupt or reset, etc., the microcontroller manages program control by loading the required address into the Program Counter. For conditional skip instructions, once the condition has been met, the next instruction, which has already been fetched during the present instruction execution, is discarded and a dummy cycle takes its place while the correct instruction is obtained.

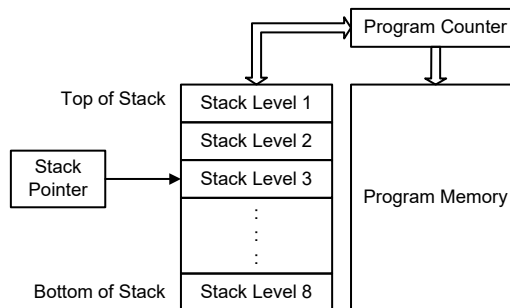
Program Counter	
Program Counter High Byte	PCL Register
PC11~PC8	PCL7~PCL0

Program Counter

The lower byte of the Program Counter, known as the Program Counter Low register or PCL, is available for program control and is a readable and writeable register. By transferring data directly into this register, a short program jump can be executed directly; however, as only this low byte is available for manipulation, the jumps are limited to the present page of memory that is 256 locations. When such program jumps are executed it should also be noted that a dummy cycle will be inserted. Manipulating the PCL register may cause program branching, so an extra cycle is needed to pre-fetch.

Stack

This is a special part of the memory which is used to save the contents of the Program Counter only. The stack is organized into 8 levels and neither part of the data nor part of the program space, and is neither readable nor writeable. The activated level is indexed by the Stack Pointer, and is neither readable nor writeable. At a subroutine call or interrupt acknowledge signal, the contents of the Program Counter are pushed onto the stack. At the end of a subroutine or an interrupt routine, signaled by a return instruction, RET or RETI, the Program Counter is restored to its previous value from the stack. After a device reset, the Stack Pointer will point to the top of the stack.



If the stack is full and an enabled interrupt takes place, the interrupt request flag will be recorded but the acknowledge signal will be inhibited. When the Stack Pointer is decremented, by RET or RETI, the interrupt will be serviced. This feature prevents stack overflow allowing the programmer to use the structure more easily. However, when the stack is full, a CALL subroutine instruction can still be executed which will result in a stack overflow. Precautions should be taken to avoid such cases which might cause unpredictable program branching.

If the stack is overflow, the first Program Counter save in the stack will be lost.

Arithmetic and Logic Unit – ALU

The arithmetic-logic unit or ALU is a critical area of the microcontroller that carries out arithmetic and logic operations of the instruction set. Connected to the main microcontroller data bus, the ALU receives related instruction codes and performs the required arithmetic or logical operations after which the result will be placed in the specified register. As these ALU calculation or operations may result in carry, borrow or other status changes, the status register will be correspondingly updated to reflect these changes. The ALU supports the following functions:

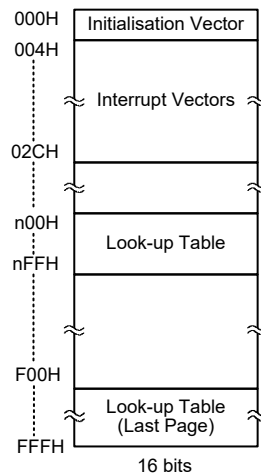
- Arithmetic operations:
ADD, ADDM, ADC, ADCM, SUB, SUBM, SBC, SBCM, DAA,
LADD, LADDM, LADC, LADCM, LSUB, LSUBM, LSBC, LSBCM, LDAA
- Logic operations:
AND, OR, XOR, ANDM, ORM, XORM, CPL, CPLA,
LAND, LANDM, LOR, LORM, LXOR, LXORM, LCPL, LCPLA
- Rotation:
RRA, RR, RRCA, RRC, RLA, RL, RLCA, RLC,
LRR, LRRCA, LRRCA, LRRCA, LRLA, LRL, LRLCA, LRLC
- Increment and Decrement:
INCA, INC, DECA, DEC,
LINCA, LINC, LDECA, LDEC
- Branch decision:
JMP, SZ, SZA, SNZ, SIZ, SDZ, SIZA, SDZA, CALL, RET, RETI,
LSNZ, LSZ, LSZA, LSIZ, LSIZA, LSDZ, LSDZA

Flash Program Memory

The Program Memory is the location where the user code or program is stored. For the device the Program Memory is Flash type, which means it can be programmed and re-programmed a large number of times, allowing users the convenience of code modification on the same device. By using the appropriate programming tools, the Flash device offers users the flexibility to conveniently debug and develop their applications while also offering a means of field programming and updating.

Structure

The Program Memory has a capacity of $4K \times 16$ bits. The Program Memory is addressed by the Program Counter and also contains data, table information and interrupt entries. Table data, which can be setup in any location within the Program Memory, is addressed by a separate table pointer register.



Program Memory Structure

Special Vectors

Within the Program Memory, certain locations are reserved for the reset and interrupts. The location 000H is reserved for use by the device reset for program initialisation. After a device reset is initiated, the program will jump to this location and begin execution.

Look-up Table

Any location within the Program Memory can be defined as a look-up table where programmers can store fixed data. To use the look-up table, the table pointer must first be setup by placing the address of the look up data to be retrieved in the table pointer register, TBLP and TBHP. These registers define the total address of the look-up table.

After setting up the table pointer, the table data can be retrieved from the Program Memory using the corresponding table read instruction such as “TABRD [m]” or “TABRDL [m]” respectively when the memory [m] is located in Sector 0. If the memory [m] is located in other sectors, the data can be retrieved from the program memory using the corresponding extended table read instruction such as “LTABRD [m]” or “LTABRDL [m]” respectively. When the instruction is executed, the lower order table byte from the Program Memory will be transferred to the user defined Data Memory register [m] as specified in the instruction. The higher order table data byte from the Program Memory will be transferred to the TBLH special register. Any unused bits in this transferred higher order byte will be read as “0”.

The accompanying diagram illustrates the addressing data flow of the look-up table.

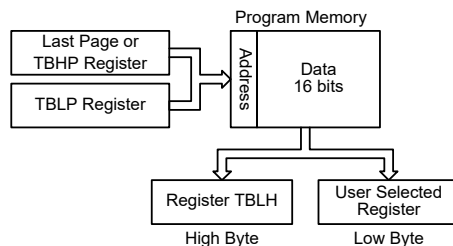


Table Program Example

The following example shows how the table pointer and table data is defined and retrieved from the microcontroller. This example uses raw table data located in the Program Memory which is stored there using the ORG statement. The value at this ORG statement is “0F00H” which refers to the start address of the last page within the 4K Program Memory of the microcontroller. The table pointer low byte register is setup here to have an initial value of “06H”. This will ensure that the first data read from the data table will be at the Program Memory address “0F06H” or 6 locations after the start of the last page. Note that the value for the table pointer is referenced to the specific address pointed by the TBHP and TBLP registers if the “TABRD [m]” or “LTABRD [m]” instruction is being used. The high byte of the table data which in this case is equal to zero will be transferred to the TBLH register automatically when the “TABRD [m]” or “LTABRD [m]” instruction is executed. Because the TBLH register is a read/write register and can be restored, care should be taken to ensure its protection if both the main routine and Interrupt Service Routine use table read instructions. If using the table read instructions, the Interrupt Service Routines may change the value of the TBLH and subsequently cause errors if used again by the main routine. As a rule it is recommended that simultaneous use of the table read instructions should be avoided. However, in situations where simultaneous use cannot be avoided, the interrupts should be disabled prior to the execution of any main routine table-read instructions. Note that all table related instructions require two instruction cycles to complete their operation.

Table Read Program Example

```

tempreg1 db?      ; temporary register #1
tempreg2 db?      ; temporary register #2
:
:
mov a,06h         ; initialise table pointer - note that this address is referenced
mov tblp,a        ; to the last page or the page that tbhp pointed
mov a,0Fh         ; initialise high table pointer
mov tbhp,a
:
:
tabrd tempreg1    ; transfers value in table referenced by table pointer
                  ; data at program memory address "0F06H" transferred to tempreg1 and TBLH
dec tblp          ; reduce value of table pointer by one
tabrd tempreg2    ; transfers value in table referenced by table pointer
                  ; data at program memory address "0F05H" transferred to tempreg2 and TBLH
                  ; in this example the data "1Ah" is transferred to tempreg1 and data "0Fh"
                  ; to tempreg2
:
:
org 0F00h         ; sets initial address of program memory
dc 00Ah, 00Bh, 00Ch, 00Dh, 00Eh, 00Fh, 01Ah, 01Bh
:
:

```

In Circuit Programming – ICP

The provision of Flash type Program Memory provides the user with a means of convenient and easy upgrades and modifications to their programs on the same device.

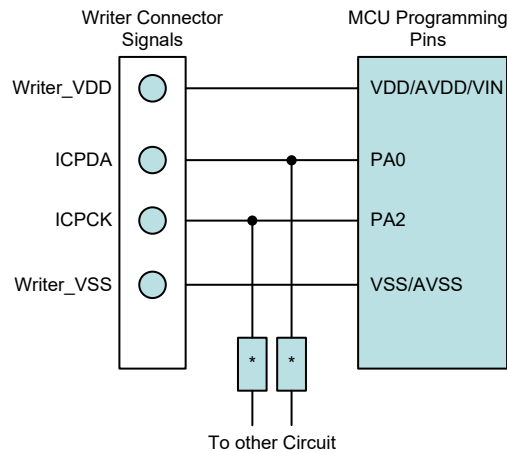
As an additional convenience, Holtek has provided a means of programming the microcontroller in-circuit using a 4-pin interface. This provides manufacturers with the possibility of manufacturing their circuit boards complete with a programmed or un-programmed microcontroller, and then programming or upgrading the program at a later stage. This enables product manufacturers to easily keep their manufactured products supplied with the latest program releases without removal and re-insertion of the device.

The Holtek Flash MCU to Writer Programming Pin correspondence table is as follows:

Holtek Writer Pins	MCU Programming Pins	Pin Description
ICPDA	PA0	Programming Serial Data/Address
ICPCK	PA2	Programming Clock
VDD	VDD/AVDD/VIN	Power Supply
VSS	VSS/AVSS	Ground

The Program Memory can be programmed serially in-circuit using this 4-wire interface. Data is downloaded and uploaded serially on a single pin with an additional line for the clock. Two additional lines are required for the power supply and one line for the reset. The technical details regarding the in-circuit programming of the device is beyond the scope of this document and will be supplied in supplementary literature.

During the programming process, the user must take care of the ICPDA and ICPCK pins for data and clock programming purposes to ensure that no other outputs are connected to these two pins.



Note: * may be resistor or capacitor. The resistance of * must be greater than 1kΩ or the capacitance of * must be less than 1nF.

On-Chip Debug Support – OCDS

There is an EV chip which is used to emulate the real MCU device. The EV chip device also provides an “On-Chip Debug” function to debug the device during the development process. The EV chip and the real MCU device are almost functionally compatible except for “On-Chip Debug” function. Users can use the EV chip device to emulate the real chip device behavior by connecting the OCDSDA and OCDSCK pins to the Holtek HT-IDE development tools. The OCDSDA pin is the OCDS Data/Address input/output pin while the OCDSCK pin is the OCDS clock input pin. When users use the EV chip for debugging, other functions which are shared with the OCDSDA and OCDSCK pins in the device will have no effect in the EV chip. However, the two OCDS pins which are pin-shared with the ICP programming pins are still used as the Flash Memory programming pins for ICP. For more detailed OCDS information, refer to the corresponding document named “Holtek e-Link for 8-bit MCU OCDS User’s Guide”.

Holtek e-Link Pins	EV Chip Pins	Pin Description
OCDSDA	OCDSDA	On-Chip Debug Support Data/Address input/output
OCDSCK	OCDSCK	On-Chip Debug Support Clock input
VDD	VDD/AVDD/VIN	Power Supply
VSS	VSS/AVSS	Ground

In Application Programming – IAP

Flash type Program Memory provides the user with a means of convenient and easy upgrades and modifications to their programs on the same device. The provision of IAP function offers users the convenience of Flash Memory multi-programming features. The convenience of the IAP function is that it can execute the updated program procedure using its internal firmware, without requiring an external Program Writer or PC. In addition, the IAP interface can also be any type of communication protocol, such as UART, using I/O pins. Regarding the internal firmware, the user can select versions provided by Holtek or create their own. The following section illustrates the procedures regarding how to implement the IAP firmware.

Flash Memory Read/Write Size

The Flash memory Erase and Write operations are carried out in a page format while the Read operation is carried out in a word format. The page size and write buffer size are both assigned with a capacity of 32 words. Note that the Erase operation should be executed before the Write operation is executed.

When the Flash Memory Erase/Write Function is successfully enabled, the CFWEN bit will be set high. When the CFWEN bit is set high, the data can be written into the write buffer. The FWT bit is used to initiate the write process and then indicate the write operation status. This bit is set high by application programs to initiate a write process and will be cleared by hardware if the write process is finished.

The Read operation can be carried out by executing a specific read procedure. The FRDEN bit is used to enable the read function and the FRD bit is used to initiate the read process by application programs and then indicate the read operation status. When the read process is finished, this bit will be cleared by hardware.

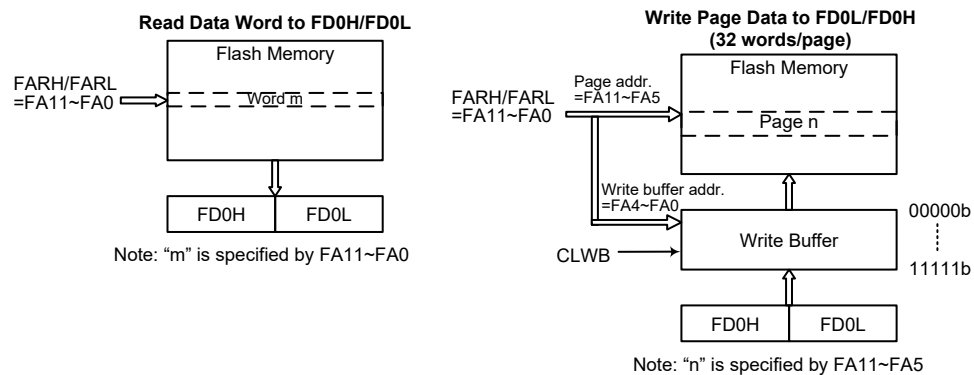
Operations	Format
Erase	32 words/page
Write	32 words/time
Read	1 word/time

Note: Page size = Write buffer size = 32 words.

IAP Read/Erase/Write Format

Page	FARH	FARL [7:5]	FARL [4:0]
0	0000 0000	000	Tag Address
1	0000 0000	001	
2	0000 0000	010	
3	0000 0000	011	
4	0000 0000	100	
5	0000 0000	101	
6	0000 0000	110	
7	0000 0000	111	
8	0000 0001	000	
9	0000 0001	001	
:	:	:	
:	:	:	
126	0000 1111	110	
127	0000 1111	111	

Page Number and Address Selection



Flash Memory IAP Read/Write Structure

Write Buffer

The write buffer is used to store the written data temporarily when executing the write operation. The Write Buffer can be filled with written data after the Flash Memory Erase/Write Function has been successfully enabled by executing the Flash Memory Erase/Write Function Enable procedure. The write buffer can be cleared by configuring the CLWB bit in the FC2 register. The CLWB bit can be set high to enable the Clear Write Buffer procedure. When the procedure is finished this bit will be cleared to low by the hardware. It is recommended that the write buffer should be cleared by setting the CLWB bit high before the write buffer is used for the first time or when the data in the write buffer is updated.

The write buffer size is 32 words corresponding to a page. The write buffer address is mapped to a specific Flash memory page specified by the memory address bits, FA11~FA5. The data written into the FD0L and FD0H registers will be loaded into the write buffer. When data is written into the high byte data register, FD0H, it will result in the data stored in the high and low byte data registers both being written into the write buffer. It will also cause the flash memory address to be incremented by one, after which the new address will be loaded into the FARH and FARL address registers. When the flash memory address reaches the page boundary, 11111b of a page with 32 words, the address will now not be incremented but will stop at the last address of the page. At this point a new page address should be specified for any other erase/write operations.

After a write process is finished, the write buffer will automatically be cleared by the hardware. Note that the write buffer should be cleared manually by the application program when the data written into the flash memory is incorrect in the data verification step. The data should again be written into the write buffer after the write buffer has been cleared when the data is found to be incorrect during the data verification step.

IAP Flash Program Memory Registers

There are two address registers, four 16-bit data registers and three control registers. The address and data registers are located in Sector 0 while the control registers are located in Sector 1. Read and Write operations to the Flash memory are carried out using 16-bit data operations using the address and data registers and the control register. Several registers control the overall operation of the internal Flash Program Memory. As the FARH/FARL and FDnH/FDnL registers are located in Sector 0, they can be directly accessed in the same way as any other Special Function Register. The FC0, FC1 and FC2 registers, being located in Sector 1, can be addressed directly only using the corresponding extended instructions or can be read from or written to indirectly using the MP1H/MP1L or MP2H/MP2L Memory Pointer pairs and Indirect Addressing Register, IAR1 or IAR2.

Register Name	Bit							
	7	6	5	4	3	2	1	0
FC0	CFWEN	FMOD2	FMOD1	FMOD0	FWPEN	FWT	FRDEN	FRD
FC1	D7	D6	D5	D4	D3	D2	D1	D0
FC2	—	—	—	—	—	—	FWERTS	CLWB
FARL	FA7	FA6	FA5	FA4	FA3	FA2	FA1	FA0
FARH	—	—	—	—	FA11	FA10	FA9	FA8
FD0L	D7	D6	D5	D4	D3	D2	D1	D0
FD0H	D15	D14	D13	D12	D11	D10	D9	D8
FD1L	D7	D6	D5	D4	D3	D2	D1	D0
FD1H	D15	D14	D13	D12	D11	D10	D9	D8
FD2L	D7	D6	D5	D4	D3	D2	D1	D0
FD2H	D15	D14	D13	D12	D11	D10	D9	D8
FD3L	D7	D6	D5	D4	D3	D2	D1	D0
FD3H	D15	D14	D13	D12	D11	D10	D9	D8

IAP Register List

• FARL Register

Bit	7	6	5	4	3	2	1	0
Name	FA7	FA6	FA5	FA4	FA3	FA2	FA1	FA0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **FA7~FA0**: Flash memory address bit 7 ~ bit 0

• FARH Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	FA11	FA10	FA9	FA8
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as “0”

Bit 3~0 **FA11~FA8**: Flash memory address bit 11 ~ bit 8

• **FD0L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0:** The first Flash memory data word bit 7 ~ bit 0
 Note that data written into the low byte data register FD0L will only be stored in the FD0L register and not loaded into the lower 8-bit write buffer.

• **FD0H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D15~D8:** The first Flash memory data word bit 15 ~ bit 8
 Note that when 8-bit data is written into the high byte data register FD0H, the whole 16 bits of data stored in the FD0H and FD0L registers will simultaneously be loaded into the 16-bit write buffer after which the contents of the Flash memory address register pair, FARH and FARL, will be incremented by one.

• **FD1L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0:** The second Flash memory data word bit 7 ~ bit 0

• **FD1H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D15~D8:** The second Flash memory data word bit 15 ~ bit 8

• **FD2L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0:** The third Flash memory data word bit 7 ~ bit 0

• **FD2H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D15~D8:** The third Flash memory data word bit 15 ~ bit 8

• **FD3L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: The fourth Flash memory data word bit 7 ~ bit 0

• **FD3H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D15~D8**: The fourth Flash memory data word bit 15 ~ bit 8

• **FC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	CFWEN	FMOD2	FMOD1	FMOD0	FWPEN	FWT	FRDEN	FRD
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **CFWEN**: Flash Memory Erase/Write enable control

0: Flash memory erase/write function is disabled

1: Flash memory erase/write function has been successfully enabled

When this bit is cleared to 0 by application program, the Flash memory write function is disabled. Note that writing a “1” into this bit results in no action. This bit is used to indicate the Flash memory write function status. When this bit is set to 1 by the hardware, it means that the Flash memory write function is enabled successfully. Otherwise, the Flash memory write function is disabled if the bit is zero.

Bit 6~4 **FMOD2~FMOD0**: Flash memory mode selection

000: Write Mode

001: Page Erase Mode

010: Reserved

011: Read Mode

100: Reserved

101: Reserved

110: Flash memory Erase/Write function Enable Mode

111: Reserved

These bits are used to select the Flash Memory operation modes. Note that the “Flash memory Erase/Write function Enable Mode” should first be successfully enabled before the Erase or Write Flash memory operation is executed.

Bit 3 **FWPEN**: Flash memory Erase/Write function enable procedure Trigger

0: Erase/Write function enable procedure is not triggered or procedure timer times out

1: Erase/Write function enable procedure is triggered and procedure timer starts to count

This bit is used to activate the Flash memory Erase/Write function enable procedure and an internal timer. It is set by the application programs and then cleared by hardware when the internal timer times out. The correct patterns must be written into the FD1L/FD1H, FD2L/FD2H and FD3L/FD3H register pairs respectively as soon as possible after the FWPEN bit is set high.

Bit 2 **FWT**: Flash memory write initiate control

0: Do not initiate Flash memory write or indicating that a Flash memory write process has completed

1: Initiate Flash memory write process

This bit is set by software and cleared to 0 by the hardware when the Flash memory write process has completed.

Bit 1 **FRDEN**: Flash memory read enable control
 0: Flash memory read disable
 1: Flash memory read enable

This is the Flash memory Read Enable Bit which must be set high before any Flash memory read operations are carried out. Clearing this bit to zero will inhibit Flash memory read operations.

Bit 0 **FRD**: Flash memory read initiate control
 0: Do not initiate Flash memory read or indicating that a Flash memory read process has completed
 1: Initiate Flash memory read process

This bit is set by software and cleared to 0 by the hardware when the Flash memory read process has completed.

- Note: 1. The FWT, FRDEN and FRD bits cannot be set to “1” at the same time with a single instruction.
 2. Ensure that the f_{SUB} clock is stable before executing the erase/write operation.
 3. Note that the CPU will be stopped when a read, write or erase operation is successfully activated.
 4. Ensure that the read/erase/write operation is totally complete before executing other operations.

• **FC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: Chip reset pattern
 When a specific value of “55H” is written into this register, a reset signal will be generated to reset the whole chip.

• **FC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	FWERTS	CLWB
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”

Bit 1 **FWERTS**: Erase time and Write time select
 0: Erase time is 3.2ms (t_{FER}) / Write time is 2.2ms (t_{FWR})
 1: Erase time is 3.7ms (t_{FER}) / Write time is 3.0ms (t_{FWR})

Bit 0 **CLWB**: Flash memory write buffer clear control
 0: Do not initiate a Write Buffer Clear process or indicating that a Write Buffer Clear process has completed
 1: Initiate Write Buffer Clear process

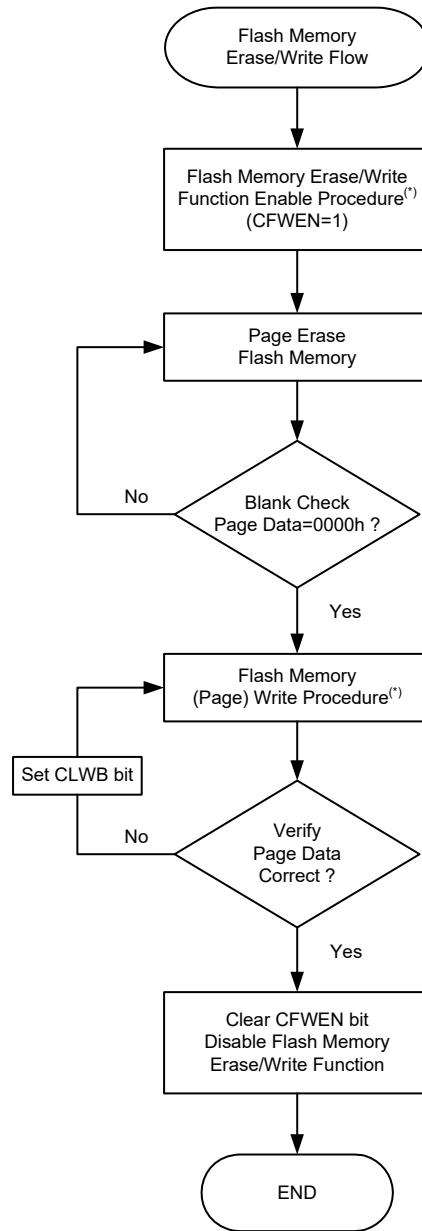
This bit is set by software and cleared to 0 by hardware when the Write Buffer Clear process has completed.

Flash Memory Erase/Write Flow

It is important to understand the Flash memory Erase/Write flow before the Flash memory contents are updated. Users can refer to the corresponding operation procedures when developing their IAP program to ensure that the flash memory contents are correctly updated.

Flash Memory Erase/Write Flow Descriptions

1. Activate the “Flash Memory Erase/Write function enable procedure” first. When the Flash Memory Erase/Write function is successfully enabled, the CFWEN bit in the FC0 register will automatically be set high by hardware. After this, Erase or Write operations can be executed on the Flash memory. Refer to the “Flash Memory Erase/Write Function Enable Procedure” for details.
2. Configure the flash memory address to select the desired erase page, tag address and then erase this page. For a page erase operation, set the FARL and FARH registers to specify the start address of the erase page, then write dummy data into the FD0H register to tag address. The current address will be internally incremented by one after each dummy data is written into the FD0H register. When the address reaches the page boundary, 11111b, the address will not be further incremented but stop at the last address of the page. Note that the write operation to the FD0H register is used to tag address, it must be implemented to determine which addresses to be erased.
3. Execute a Blank Check operation to ensure whether the page erase operation is successful or not. The “TABRD” instruction should be executed to read the flash memory contents and to check if the contents is 0000h or not. If the flash memory page erase operation fails, users should go back to Step 2 and execute the page erase operation again.
4. Write data into the specific page. Refer to the “Flash Memory Write Procedure” for details.
5. Execute the “TABRD” instruction to read the flash memory contents and check if the written data is correct or not. If the data read from the flash memory is different from the written data, it means that the page write operation has failed. The CLWB bit should be set high to clear the write buffer and then write the data into the specific page again if the write operation has failed.
6. Clear the CFWEN bit to disable the Flash Memory Erase/Write function enable mode if the current page Erase and Write operations are complete if no more pages need to be erased or written.



Flash Memory Erase/Write Flow

Note: The Flash Memory Erase/Write Function Enable procedure and Flash Memory Write procedure will be described in the following sections.

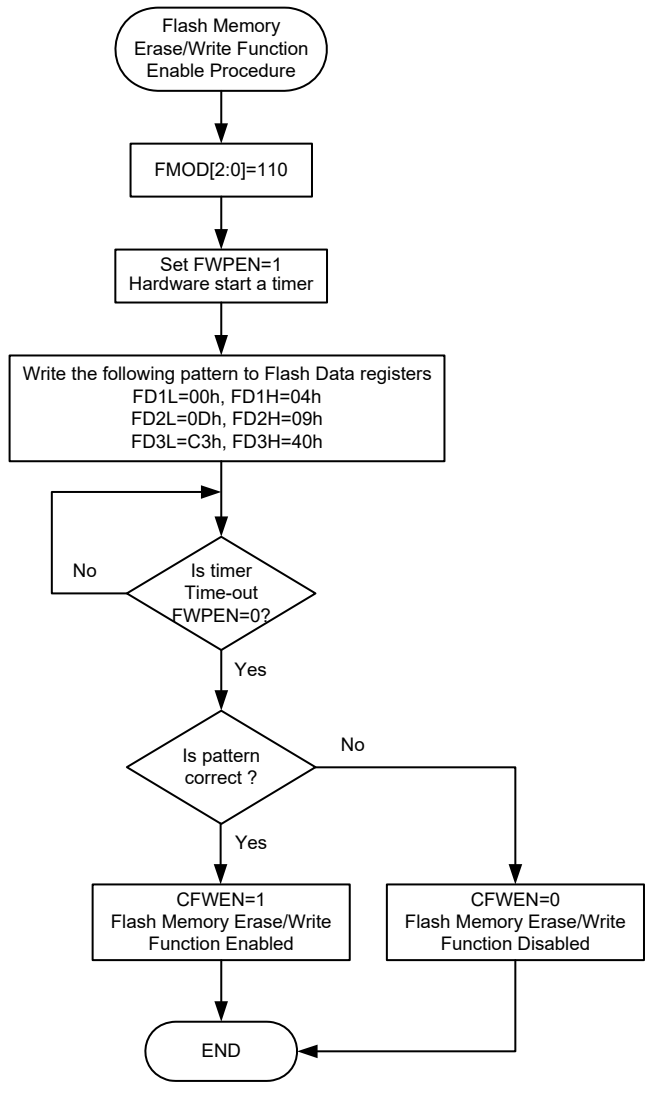
Flash Memory Erase/Write Function Enable Procedure

The Flash Memory Erase/Write Function Enable Mode is specially designed to prevent the flash memory contents from being wrongly modified. In order to allow users to change the Flash memory data using the IAP control registers, users must first enable the Flash memory Erase/Write function.

Flash Memory Erase/Write Function Enable Procedure Description

1. Write data “110” to the FMOD [2:0] bits in the FC0 register to select the Flash Memory Erase/Write Function Enable Mode.
2. Set the FWPEN bit in the FC0 register to “1” to activate the Flash Memory Erase/Write Function. This will also activate an internal timer.
3. Write the correct data pattern into the Flash data registers, FD1L~FD3L and FD1H~FD3H, as soon as possible after the FWPEN bit is set high. The enable Flash memory erase/write function data pattern is 00H, 0DH, C3H, 04H, 09H and 40H corresponding to the FD1L~FD3L and FD1H~FD3H registers respectively.
4. Once the timer has timed out, the FWPEN bit will automatically be cleared to 0 by hardware regardless of the input data pattern.
5. If the written data pattern is incorrect, the Flash memory erase/write function will not be enabled successfully and the above steps should be repeated. If the written data pattern is correct, the Flash memory erase/write function will be enabled successfully.
6. Once the Flash memory write function is enabled, the Flash memory contents can be updated by executing the page erase and write operations using the IAP control registers.

To disable the Flash memory write function, the CFWEN bit in the FC0 register can be cleared. There is no need to execute the above procedure.



Flash Memory Erase/Write Function Enable Procedure

Flash Memory Write Procedure

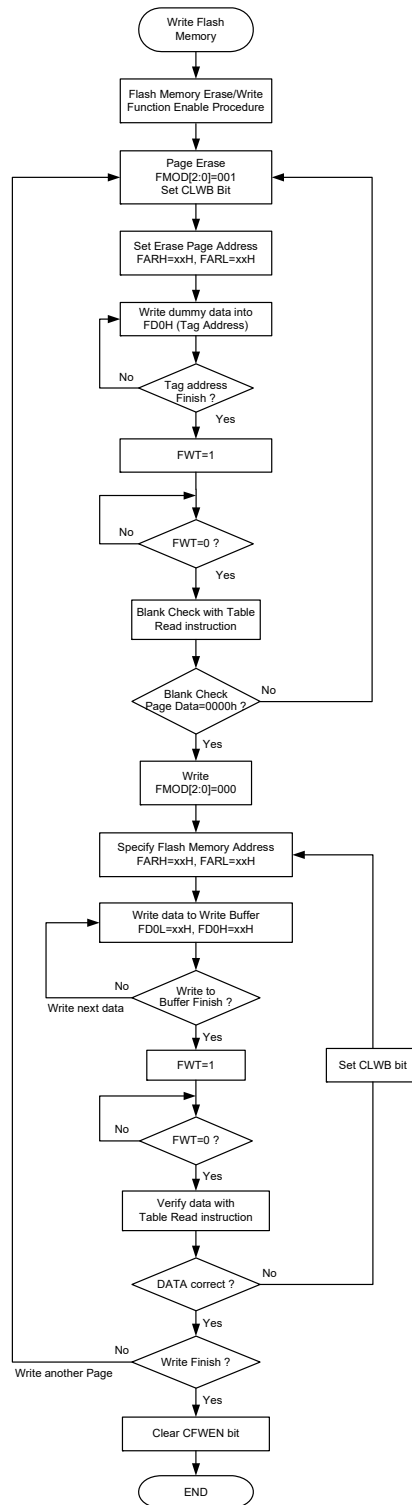
After the Flash memory erase/write function has been successfully enabled as the CFWEN bit is set high, the data to be written into the flash memory can be loaded into the write buffer. The selected flash memory page data should be erased by properly configuring the IAP control registers before the data write procedure is executed.

The write buffer size is 32 words, known as a page, whose address is mapped to a specific flash memory page specified by the memory address bits, FA11~FA5. It is important to ensure that the page where the write buffer data is located is the same one which the memory address bits, FA11~FA5, specify.

Flash Memory Consecutive Write Description

The maximum amount of write data is 32 words for each write operation. The write buffer address will be automatically incremented by one when consecutive write operations are executed. The start address of a specific page should first be written into the FARL and FARH registers. Then the data word should first be written into the FD0L register and then the FD0H register. At the same time the write buffer address will be incremented by one and then the next data word can be written into the FD0L and FD0H registers for the next address without modifying the address register pair, FARH and FARL. When the write buffer address reaches the page boundary the address will not be further incremented but will stop at the last address of the page.

1. Activate the “Flash Memory Erase/Write function enable procedure”. Check the CFWEN bit value and then execute the erase/write operations if the CFWEN bit is set high. Refer to the “Flash Memory Erase/Write function enable procedure” for more details.
2. Set the FMOD field to “001” to select the erase operation and set the CLWB bit high to clear the write buffer. Set the FWT bit high to erase the desired page which is specified by the FARH and FARL registers and has been tagged address. Wait until the FWT bit goes low.
3. Execute a Blank Check operation using the table read instruction to ensure that the erase operation has successfully completed.
Go to step 2 if the erase operation is not successful.
Go to step 4 if the erase operation is successful.
4. Set the FMOD field to “000” to select the write operation.
5. Setup the desired start address in the FARH and FARL registers. Write the desired data words consecutively into the FD0L and FD0H registers within a page as specified by their consecutive addresses. The maximum written data number is 32 words.
6. Set the FWT bit high to write the data words from the write buffer to the flash memory. Wait until the FWT bit goes low.
7. Verify the data using the table read instruction to ensure that the write operation has successfully completed.
If the write operation has not successfully completed, set the CLWB bit high to clear the write buffer and then go to step 5.
Go to step 8 if the write operation is successful.
8. Clear the CFWEN bit low to disable the Flash memory erase/write function.



Flash Memory Consecutive Write Procedure

- Note: 1. When the erase or write operation is successfully activated, all CPU operations will temporarily cease.
 2. It will take certain time for the FWT bit state changing from high to low in the erase or write operation, which can be selected by the FWERTS bit in the FC2 register.

Flash Memory Non-Consecutive Write Description

The main difference between Flash Memory Consecutive and Non-Consecutive Write operations is whether the data words to be written are located in consecutive addresses or not. If the data to be written is not located in consecutive addresses the desired address should be re-assigned after a data word is successfully written into the Flash Memory.

A two data word non-consecutive write operation is taken as an example here and described as follows:

1. Activate the “Flash Memory Erase/Write function enable procedure”. Check the CFWEN bit value and then execute the erase/write operation if the CFWEN bit is set high. Refer to the “Flash Memory Erase/Write function enable procedure” for more details.
2. Set the FMOD field to “001” to select the erase operation and set the CLWB bit high to clear the write buffer. Set the FWT bit high to erase the desired page which is specified by the FARH and FARL registers and has been tagged address. Wait until the FWT bit goes low.
3. Execute a Blank Check operation using the table read instruction to ensure that the erase operation has successfully completed.

Go to step 2 if the erase operation is not successful.

Go to step 4 if the erase operation is successful.

4. Set the FMOD field to “000” to select the write operation.
5. Setup the desired address ADDR1 in the FARH and FRARL registers. Write the desired data word DATA1 first into the FD0L register and then into the FD0H register.
6. Set the FWT bit high to transfer the data word from the write buffer to the flash memory. Wait until the FWT bit goes low.
7. Verify the data using the table read instruction to ensure that the write operation has successfully completed.

If the write operation has not successfully completed, set the CLWB bit high to clear the write buffer and then go to step 5.

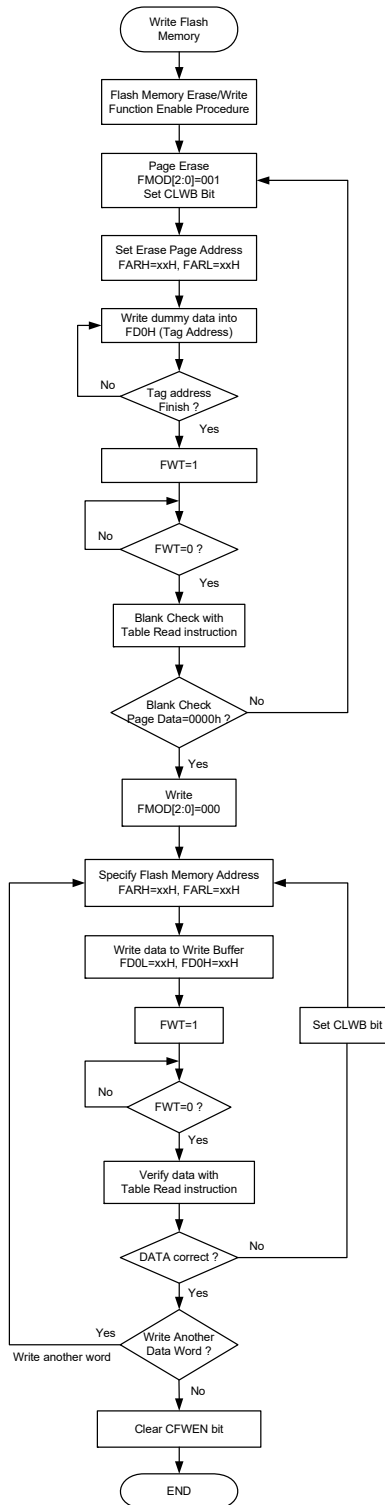
Go to step 8 if the write operation is successful.

8. Setup the desired address ADDR2 in the FARH and FRARL registers. Write the desired data word DATA2 first into the FD0L register and then into the FD0H register.
9. Set the FWT bit high to transfer the data word from the write buffer to the flash memory. Wait until the FWT bit goes low.
10. Verify the data using the table read instruction to ensure that the write operation has successfully completed.

If the write operation has not successfully completed, set the CLWB bit high to clear the write buffer and then go to step 8.

Go to step 11 if the write operation is successful.

11. Clear the CFWEN bit low to disable the Flash memory erase/write function.



Flash Memory Non-Consecutive Write Procedure

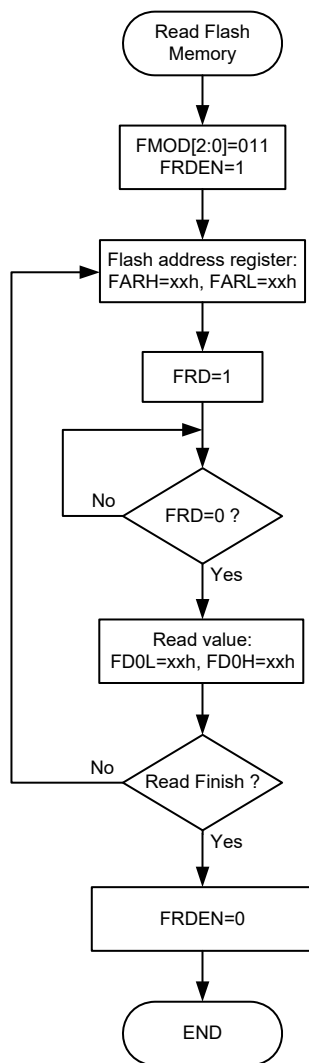
- Note: 1. When the erase or write operation is successfully activated, all CPU operations will temporarily cease.
 2. It will take certain time for the FWT bit state changing from high to low in the erase or write operation, which can be selected by the FWERTS bit in the FC2 register.

Important Points to Note for Flash Memory Write Operations

1. The “Flash Memory Erase/Write Function Enable Procedure” must be successfully activated before the Flash Memory erase/write operation is executed.
2. The Flash Memory erase operation is executed to erase a whole page.
3. The whole write buffer data will be written into the flash memory in a page format. The corresponding address cannot exceed the page boundary.
4. After the data is written into the flash memory the flash memory contents must be read out using the table read instruction, TABRD, and checked if it is correct or not. If the data written into the flash memory is incorrect, the write buffer should be cleared by setting the CLWB bit high and then writing the data again into the write buffer. Then activate a write operation on the same flash memory page without erasing it. The data check, buffer clear and data re-write steps should be repeatedly executed until the data written into the flash memory is correct.
5. The system frequency should be setup to the maximum application frequency when data write and data check operations are executed using the IAP function.

Flash Memory Read Procedure

To activate the Flash Memory Read procedure, the FMOD field should be set to “011” to select the flash memory read mode and the FRDEN bit should be set high to enable the read function. The desired flash memory address should be written into the FARH and FARL registers and then the FRD bit should be set high. After this the flash memory read operation will be activated. The data stored in the specified address can be read from the data registers, FD0H and FD0L, when the FRD bit goes low. There is no need to first activate the Flash Memory Erase/Write Function Enable Procedure before the flash memory read operation is executed.



Flash Memory Read Procedure

- Note: 1. When the read operation is successfully activated, all CPU operations will temporarily cease.
2. It will take a typical time of three instruction cycles for the FRD bit state changing from high to low.

Data Memory

The Data Memory is a volatile area of 8-bit wide RAM internal memory and is the location where temporary information is stored.

Categorized into two types, the first of these is an area of RAM, known as the Special Function Data Memory. These registers have fixed locations and are necessary for correct operation of the device. Many of these registers can be read from and written to directly under program control, however, some remain protected from user manipulation. The second area of Data Memory is known as the General Purpose Data Memory, which is reserved for general purpose use. All locations within this area are read and write accessible under program control.

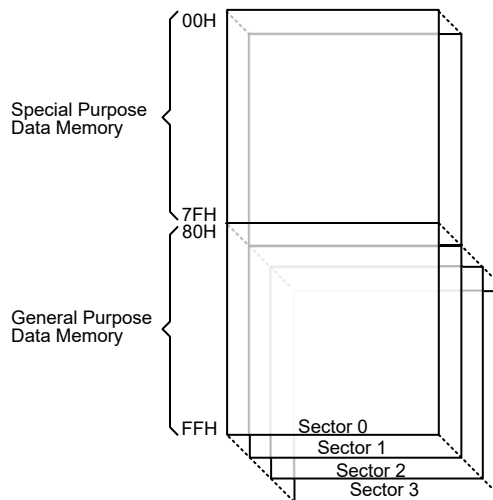
Structure

The Data Memory is subdivided into two sectors, all of which are implemented in 8-bit wide Memory. The address range of the Special Purpose Data Memory for the device is from 00H to 7FH while the General Purpose Data Memory address range is from 80H to FFH.

Switching between the different Data Memory sectors is achieved by setting the Memory Pointers to the correct value if using the indirect addressing method. The start address of the Data Memory for the device is the address 00H.

Special Purpose Data Memory	General Purpose Data Memory	
Located Sectors	Capacity	Sector: Address
0, 1	512×8	0: 80H~FFH 1: 80H~FFH 2: 80H~FFH 3: 80H~FFH

Data Memory Summary



Data Memory Structure

Data Memory Addressing

For the device that supports the extended instructions, there is no Bank Pointer for Data Memory. For Data Memory the desired Sector is pointed by the MP1H or MP2H register and the certain Data Memory address in the selected sector is specified by the MP1L or MP2L register when using indirect addressing access.

Direct Addressing can be used in all sectors using the extended instructions which can address all available data memory space. For the accessed data memory which is located in any data memory sectors except sector 0, the extended instructions can be used to access the data memory instead of using the indirect addressing access. The main difference between standard instructions and extended instructions is that the data memory address “m” in the extended instructions has 10 valid bits for this device, the high byte indicates a sector and the low byte indicates a specific address.

General Purpose Data Memory

All microcontroller programs require an area of read/write memory where temporary data can be stored and retrieved for use later. It is this area of RAM memory that is known as General Purpose Data Memory. This area of Data Memory is fully accessible by the user programming for both reading and writing operations. By using the bit operation instructions individual bits can be set or reset under program control giving the user a large range of flexibility for bit manipulation in the Data Memory.

Special Purpose Data Memory

This area of Data Memory is where registers, necessary for the correct operation of the microcontroller, are stored. Most of the registers are both readable and writeable but some are protected and are readable only, the details of which are located under the relevant Special Function Register section. Note that for locations that are unused, any read instruction to these addresses will return the value “00H”.

	Sector 0	Sector 1
00H	IAR0	FC0
01H	MP0	FC1
02H	IAR1	FC2
03H	MP1L	FARL
04H	MP1H	FARH
05H	ACC	FD0L
06H	PCL	FD0H
07H	TBLP	FD1L
08H	TBLH	FD1H
09H	TBHP	FD2L
0AH	STATUS	FD2H
0BH		FD3L
0CH	IAR2	FD3H
0DH	MP2L	
0EH	MP2H	
0FH	RSTFC	OVP0C0
10H		OVP0C1
11H	SCC	OVP0C2
12H	HIRCC	OVP0DAL
13H	ORMC	OVP0DAH
14H	PA	
15H	PAC	
16H	PAPU	OVP1C0
17H	PAWU	OVP1C1
18H	PB	OVP1C2
19H	PBC	OVP1DAL
1AH	PBPU	OVP1DAH
1BH	PAS	
1CH	NMSR	
1DH		OVP2C0
1EH		OVP2C1
1FH	INTEG	OVP2C2
20H	INTC0	OVP2DAL
21H	INTC1	OVP2DAH
22H	INTC2	
23H	MF10	
24H	MF11	PTM0C0
25H	MF12	PTM0C1
26H	MF13	PTM0C2
27H	MF14	PTM0DL
28H	MF15	PTM0DH
29H		PTM0AL
2AH		PTM0AH
2BH	SADC0	PTM0BL
2CH	SADC1	PTM0BH
2DH	SADC2	PTM0RPL
2EH	SADOL	PTM0RPH
2FH	SADOH	
30H		
31H		PTM1C0
32H		PTM1C1
33H		PTM1C2
34H		PTM1DL
35H		PTM1DH
36H	PSCR	PTM1AL
37H	TB0C	PTM1AH
38H	TB1C	PTM1BL
39H	WDTC	PTM1BH
3AH	REGC	PTM1RPL
3BH		PTM1RPH
3CH		
3DH	EEAL	
3EH	EEAH	
3FH	EED	

	Sector 0	Sector 1
40H		EEC
41H		
42H	CTM0C0	
43H	CTM0C1	PTM2C0
44H	CTM0DL	PTM2C1
45H	CTM0DH	PTM2C2
46H	CTM0AL	PTM2DL
47H	CTM0AH	PTM2DH
48H	CTM1C0	PTM2AL
49H	CTM1C1	PTM2AH
4AH	CTM1DL	PTM2BL
4BH	CTM1DH	PTM2BH
4CH	CTM1AL	PTM2RPL
4DH	CTM1AH	PTM2RPH
4EH		
4FH		
50H	SIMC0	PTM3C0
51H	SIMC1/UUCR1	PTM3C1
52H	SIMD/UTXR_RXR	PTM3DL
53H	SIMA/SIMC2/UUCR2	PTM3DH
54H	UUCR3	PTM3AL
55H	SIMTOC/UBRG	PTM3AH
56H	UUSR	PTM3RPL
57H		PTM3RPH
58H		
59H	MDUWR0	
5AH	MDUWR1	
5BH	MDUWR2	
5CH	MDUWR3	
5DH	MDUWR4	
5EH	MDUWR5	
5FH	MDUWCTRL	
60H		
61H		
62H	ISGENC	
63H	ISGDATA	
64H		
65H		
66H	DDOC	
67H	DDA0C	
68H	DDA1C	
69H	DDA2C	
6AH	DDPGAC0	
6BH	DDPGAC1	
6CH	DDA0VOS	
6DH	DDA1VOS	
6EH	DDA2VOS	
6FH	DDPGAC2	
70H		
71H	PAS0	
72H	PAS1	
73H	PBS0	
74H	PBS1	
75H		
76H	IFS	
77H		
78H	LVRC	
79H	LVDC	
7AH	TLVRC	
7BH		
7CH		
7DH		
7EH		
7FH		

□ : Unused, read as 00H

▣ : Reserved, cannot be changed

Special Purpose Data Memory

Special Function Register Description

Most of the Special Function Register details will be described in the relevant functional section; however several registers require a separate description in this section.

Indirect Addressing Registers – IAR0, IAR1, IAR2

The Indirect Addressing Registers, IAR0, IAR1 and IAR2, although having their locations in normal RAM register space, do not actually physically exist as normal registers. The method of indirect addressing for RAM data manipulation uses these Indirect Addressing Registers and Memory Pointers, in contrast to direct memory addressing, where the actual memory address is specified. Actions on the IAR0, IAR1 and IAR2 registers will result in no actual read or write operation to these registers but rather to the memory location specified by their corresponding Memory Pointers, MP0, MP1L/MP1H or MP2L/MP2H. Acting as a pair, IAR0 and MP0 can together access data only from Sector 0 while the IAR1 register together with the MP1L/MP1H register pair and IAR2 register together with the MP2L/MP2H register pair can access data from any Data Memory Sector. As the Indirect Addressing Registers are not physically implemented, reading the Indirect Addressing Registers will return a result of “00H” and writing to the registers will result in no operation.

Memory Pointers – MP0, MP1L/MP1H, MP2L/MP2H

Five Memory Pointers, known as MP0, MP1L, MP1H, MP2L, MP2H, are provided. These Memory Pointers are physically implemented in the Data Memory and can be manipulated in the same way as normal registers providing a convenient way with which to address and track data. When any operation to the relevant Indirect Addressing Registers is carried out, the actual address that the microcontroller is directed to is the address specified by the related Memory Pointer. MP0, together with Indirect Addressing Register, IAR0, are used to access data from Sector 0, while MP1L/MP1H together with IAR1 and MP2L/MP2H together with IAR2 are used to access data from all sectors according to the corresponding MP1H or MP2H register. Direct Addressing can be used in all sectors using the extended instructions which can address all available data memory space.

The following example shows how to clear a section of four Data Memory locations already defined as locations `adres1` to `adres4`.

Indirect Addressing Program Example

Example 1

```
data .section 'data'
adres1 db ?
adres2 db ?
adres3 db ?
adres4 db ?
block db ?
code .section at 0 'code'
org 00h
start:
    mov a, 04h           ; setup size of block
    mov block, a
    mov a, offset adres1 ; Accumulator loaded with first RAM address
    mov mp0, a          ; setup memory pointer with first RAM address
loop:
    clr IAR0            ; clear the data at address defined by MP0
    inc mp0             ; increase memory pointer
    sdz block           ; check if last memory location has been cleared
    jmp loop
continue:
```

Example 2

```

data .section 'data'
adres1 db ?
adres2 db ?
adres3 db ?
adres4 db ?
data .section 'data'
block db ?
code .section at 0 'code'
org 00h
start:
    mov a, 04h                ; setup size of block
    mov block, a
    mov a, 01h                ; setup the memory sector
    mov mplh, a
    mov a, offset adres1     ; Accumulator loaded with first RAM address
    mov mp1l, a              ; setup memory pointer with first RAM address
loop:
    clr IAR1                 ; clear the data at address defined by MPLL
    inc mp1l                 ; increment memory pointer MPLL
    sdz block                ; check if last memory location has been cleared
    jmp loop
continue:
    :

```

The important point to note here is that in the examples shown above, no reference is made to specific Data Memory addresses.

Direct Addressing Program Example Using Extended Instructions

```

data .section 'data'
temp db ?
code .section at 0 'code'
org 00h
start:
    lmov a, [m]              ; move [m] data to acc
    lsub a, [m+1]            ; compare [m] and [m+1] data
    snz c                    ; [m]>[m+1]?
    jmp continue            ; no
    lmov a, [m]              ; yes, exchange [m] and [m+1] data
    mov temp, a
    lmov a, [m+1]
    lmov [m], a
    mov a, temp
    lmov [m+1], a
continue:
    :

```

Note: Here “m” is a data memory address located in any data memory sectors. For example, m=1F0H, it indicates address 0F0H in Sector 1.

Accumulator – ACC

The Accumulator is central to the operation of any microcontroller and is closely related with operations carried out by the ALU. The Accumulator is the place where all intermediate results from the ALU are stored. Without the Accumulator it would be necessary to write the result of each calculation or logical operation such as addition, subtraction, shift, etc., to the Data Memory resulting in higher programming and timing overheads. Data transfer operations usually involve the temporary storage function of the Accumulator; for example, when transferring data between one user-defined register and another, it is necessary to do this by passing the data through the Accumulator as no direct transfer between two registers is permitted.

Program Counter Low Register – PCL

To provide additional program control functions, the low byte of the Program Counter is made accessible to programmers by locating it within the Special Purpose area of the Data Memory. By manipulating this register, direct jumps to other program locations are easily implemented. Loading a value directly into this PCL register will cause a jump to the specified Program Memory location, however, as the register is only 8-bit wide, only jumps within the current Program Memory page are permitted. When such operations are used, note that a dummy cycle will be inserted.

Look-up Table Registers – TBLP, TBHP, TBLH

These three special function registers are used to control operation of the look-up table which is stored in the Program Memory. TBLP and TBHP are the table pointers and indicate the location where the table data is located. Their value must be setup before any table read commands are executed. Their value can be changed, for example using the “INC” or “DEC” instructions, allowing for easy table data pointing and reading. TBLH is the location where the high order byte of the table data is stored after a table read data instruction has been executed. Note that the lower order table data byte is transferred to a user defined location.

Option Memory Mapping Register – ORMC

The ORMC register is used to enable Option Memory Mapping function. The Option Memory capacity is 64 words. When a specific pattern of 55H and AAH is consecutively written into this register, the Option Memory Mapping function will be enabled and then the Option Memory code can be read by using the table read instruction. The Option Memory addresses 00H~3FH will be mapped to Program Memory last page addresses C0H~FFH.

To successfully enable the Option Memory Mapping function, the specific pattern of 55H and AAH must be written into the ORMC register in two consecutive instruction cycles. It is therefore recommended that the global interrupt bit EMI should first be cleared before writing the specific pattern, and then set high again at a proper time according to users’ requirements after the pattern is successfully written. An internal timer will be activated when the pattern is successfully written. The mapping operation will be automatically finished after a period of $4 \times t_{LIRC}$. Therefore, users should read the data in time, otherwise the Option Memory Mapping function needs to be restarted. After the completion of each consecutive write operation to the ORMC register, the timer will recount.

When the table read instructions are used to read the Option Memory code, both “TABRD [m]” and “TABRDL [m]” instructions can be used. However, care must be taken if the “TABRD [m]” instruction is used, the table pointer defined by the TBHP register must be referenced to the last page. Refer to corresponding sections about the table read instruction for more details.

• ORMC Register

Bit	7	6	5	4	3	2	1	0
Name	ORMC7	ORMC6	ORMC5	ORMC4	ORMC3	ORMC2	ORMC1	ORMC0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **ORMC7~ORMC0**: Option Memory Mapping special pattern
 When a special pattern of 55H and AAH is written into this register, the Option Memory access will be enabled. Note that the register content will be cleared after the MCU is woken up from the IDLE/SLEEP mode.

Status Register – STATUS

This 8-bit register contains the SC flag, CZ flag, zero flag (Z), carry flag (C), auxiliary carry flag (AC), overflow flag (OV), power down flag (PDF), and watchdog time-out flag (TO). These arithmetic/logical operation and system management flags are used to record the status and operation of the microcontroller.

With the exception of the TO and PDF flags, bits in the status register can be altered by instructions like most other registers. Any data written into the status register will not change the TO or PDF flag. In addition, operations related to the status register may give different results due to the different instruction operations. The TO flag can be affected only by a system power-up, a WDT time-out or by executing the “CLR WDT” or “HALT” instruction. The PDF flag is affected only by executing the “HALT” or “CLR WDT” instruction or during a system power-up.

The Z, OV, AC, C, SC and CZ flags generally reflect the status of the latest operations.

- C is set if an operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation; otherwise C is cleared. C is also affected by a rotate through carry instruction.
- AC is set if an operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction; otherwise AC is cleared.
- Z is set if the result of an arithmetic or logical operation is zero; otherwise Z is cleared.
- OV is set if an operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa; otherwise OV is cleared.
- PDF is cleared by a system power-up or executing the “CLR WDT” instruction. PDF is set by executing the “HALT” instruction.
- TO is cleared by a system power-up or executing the “CLR WDT” or “HALT” instruction. TO is set by a WDT time-out.
- CZ is the operational result of different flags for different instructions. Refer to register definitions for more details.
- SC is the result of the “XOR” operation which is performed by the OV flag and the MSB of the current instruction operation result.

In addition, on entering an interrupt sequence or executing a subroutine call, the status register will not be pushed onto the stack automatically. If the contents of the status register are important and if the subroutine can corrupt the status register, precautions must be taken to correctly save it.

• STATUS Register

Bit	7	6	5	4	3	2	1	0
Name	SC	CZ	TO	PDF	OV	Z	AC	C
R/W	R/W	R/W	R	R	R/W	R/W	R/W	R/W
POR	x	x	0	0	x	x	x	x

“x”: unknown

Bit 7 **SC:** The result of the “XOR” operation which is performed by the OV flag and the MSB of the instruction operation result

Bit 6 **CZ:** The operational result of different flags for different instructions
 For SUB/SUBM/LSUB/LSUBM instructions, the CZ flag is equal to the Z flag.
 For SBC/SBCM/LSBC/LSBCM instructions, the CZ flag is the “AND” operation result which is performed by the previous operation CZ flag and current operation zero flag.
 For other instructions, the CZ flag will not be affected.

Bit 5	TO: Watchdog Time-out flag 0: After power up or executing the “CLR WDT” or “HALT” instruction 1: A watchdog time-out occurred
Bit 4	PDF: Power down flag 0: After power up or executing the “CLR WDT” instruction 1: By executing the “HALT” instruction
Bit 3	OV: Overflow flag 0: No overflow 1: An operation results in a carry into the highest-order bit but not a carry out of the highest-order bit or vice versa
Bit 2	Z: Zero flag 0: The result of an arithmetic or logical operation is not zero 1: The result of an arithmetic or logical operation is zero
Bit 1	AC: Auxiliary flag 0: No auxiliary carry 1: An operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction
Bit 0	C: Carry flag 0: No carry-out 1: An operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation The “C” flag is also affected by a rotate through carry instruction.

EEPROM Data Memory

This device contains an area of internal EEPROM Data Memory. EEPROM is by its nature a non-volatile form of re-programmable memory, with data retention even when its power supply is removed. By incorporating this kind of data memory, a whole new host of application possibilities are made available to the designer. The availability of EEPROM storage allows information such as product identification numbers, calibration values, specific user data, system setup data or other product information to be stored directly within the product microcontroller. The process of reading and writing data to the EEPROM memory has been reduced to a very trivial affair.

EEPROM Data Memory Structure

The EEPROM Data Memory capacity is 512×8 bits for the device. Unlike the Program Memory and RAM Data Memory, the EEPROM Data Memory is not directly mapped into memory space and is therefore not directly addressable in the same way as the other types of memory. Read and Write operations to the EEPROM are carried out in either the byte mode or page mode determined by the mode selection bit, MODE, in the control register, EEC.

EEPROM Registers

Four registers control the overall operation of the internal EEPROM Data Memory. These are the address registers, EEAL and EEAH, the data register, EED and a single control register, EEC. As both the EEAH, EEAL and EED registers are located in Sector 0, they can be directly accessed in the same way as any other Special Function Register. The EEC register however, being located in Sector 1, can only be read from or written to indirectly using the MP1L/MP1H or MP2L/MP2H Memory Pointer and Indirect Addressing Register, IAR1/IAR2. Because the EEC control register is located at address 40H in Sector 1, the MP1L or MP2L Memory Pointer must first be set to the value 40H and the MP1H or MP2H Memory Pointer high byte set to the value, 01H, before any operations on the EEC register are executed.

Register Name	Bit							
	7	6	5	4	3	2	1	0
EEAL	EEAL7	EEAL6	EEAL5	EEAL4	EEAL3	EEAL2	EEAL1	EEAL0
EEAH	—	—	—	—	—	—	—	EEAH0
EED	D7	D6	D5	D4	D3	D2	D1	D0
EEC	EWERTS	EREN	ER	MODE	WREN	WR	RDEN	RD

EEPROM Register List
• EEAL Register

Bit	7	6	5	4	3	2	1	0
Name	EEAL7	EEAL6	EEAL5	EEAL4	EEAL3	EEAL2	EEAL1	EEAL0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **EEAL7~EEAL0**: Data EEPROM low byte address bit 7 ~ bit 0
 Data EEPROM address bit 7 ~ bit 0

• EEAH Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	EEAH0
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as “0”
 Bit 0 **EEAH0**: Data EEPROM high byte address bit 0
 Data EEPROM address bit 8

• EED Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: Data EEPROM data bit 7 ~ bit 0

• EEC Register

Bit	7	6	5	4	3	2	1	0
Name	EWERTS	EREN	ER	MODE	WREN	WR	RDEN	RD
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **EWERTS**: EEPROM Erase time and Write time select
 0: Erase time is 3.2ms (t_{EEER}) / Write time is 2.2ms (t_{EEWR})
 1: Erase time is 3.7ms (t_{EEER}) / Write time is 3.0ms (t_{EEWR})

Bit 6 **EREN**: Data EEPROM erase enable
 0: Disable
 1: Enable

This bit is used to enable data EEPROM erase function and must be set high before erase operations are carried out. This bit will be automatically reset to zero by the hardware after the erase cycle has finished. Clearing this bit to zero will inhibit data EEPROM erase operations.

- Bit 5 **ER**: EEPROM erase control
 0: Erase cycle has finished
 1: Activate an erase cycle
When this bit is set high by the application program, an erase cycle will be activated. This bit will be automatically reset to zero by the hardware after the erase cycle has finished. Setting this bit high will have no effect if the EREN has not first been set high.
- Bit 4 **MODE**: EEPROM Operation mode select
 0: Byte operation mode
 1: Page operation mode
This is the EEPROM Page operation mode select bit and when set high by the application program will select the Page write or erase or read function. Otherwise, the EEPROM is the byte write or read function. The EEPROM page buffer size is 16 bytes.
- Bit 3 **WREN**: Data EEPROM write enable
 0: Disable
 1: Enable
This is the Data EEPROM Write Enable Bit which must be set high before Data EEPROM write operations are carried out. Clearing this bit to zero will inhibit Data EEPROM write operations. Note that this bit will automatically be reset to zero by hardware after the write cycle has finished.
- Bit 2 **WR**: EEPROM write control
 0: Write cycle has finished
 1: Activate a write cycle
This is the Data EEPROM Write Control Bit and when set high by the application program will activate a write cycle. This bit will be automatically reset to zero by the hardware after the write cycle has finished. Setting this bit high will have no effect if the WREN has not first been set high.
- Bit 1 **RDEN**: Data EEPROM read enable
 0: Disable
 1: Enable
This is the Data EEPROM Read Enable Bit which must be set high before Data EEPROM read operations are carried out. Clearing this bit to zero will inhibit Data EEPROM read operations.
- Bit 0 **RD**: EEPROM read control
 0: Read cycle has finished
 1: Activate a read cycle
This is the Data EEPROM Read Control Bit and when set high by the application program will activate a read cycle. This bit will be automatically reset to zero by the hardware after the read cycle has finished. Setting this bit high will have no effect if the RDEN bit has not first been set high.

- Note: 1. The EREN, ER, WREN, WR, RDEN and RD cannot be set high at the same time in one instruction.
2. Ensure that the f_{SUB} clock is stable before executing the erase/write operation.
3. Ensure that the erase/write operation is totally complete before changing the contents of the EEPROM related registers or activating the IAP function.

Reading Operation from the EEPROM

Reading data from the EEPROM can be implemented by two modes for this device, byte read mode or page read mode, which is controlled by the EEPROM operation mode selection bit, MODE, in the EEC register.

Byte Read Mode

The EEPROM byte read operation can be executed when the mode selection bit, MODE, is cleared to zero. For a byte read operation the desired EEPROM address should first be placed in the EEAH and EEAL registers, as well as the read enable bit, RDEN, in the EEC register should be set high to enable the read function. Then setting the RD bit high will initiate the EEPROM byte read operation. Note that setting the RD bit high only will not initiate a read operation if the RDEN bit is not set high. When the read cycle terminates, the RD bit will automatically be cleared to zero and the EEPROM data can be read from the EED register. The data will remain in the EED register until another read or write operation is executed. The application program can poll the RD bit to determine when the data is valid for reading.

Page Read Mode

The EEPROM page read operation can be executed when the mode selection bit, MODE, is set high. The page size can be up to 16 bytes for the page read operation. For a page read operation the start address of the desired EEPROM page should first be placed in the EEAH and EEAL registers, as well as the read enable bit, RDEN, in the EEC register should be set high to enable the read function. Then setting the RD bit high will initiate the EEPROM page read operation. Note that setting the RD bit high only will not initiate a read operation if the RDEN bit is not set high. When the current byte read cycle terminates, the RD bit will automatically be cleared indicating that the EEPROM data can be read from the EED register, and the current address will be incremented by one by hardware. The data which is stored in the next EEPROM address can continuously be read when the RD bit is again set high without reconfiguring the EEPROM address and RDEN control bit. The application program can poll the RD bit to determine when the data is valid for reading.

The EEPROM address higher 5 bits are used to specify the desired page location while the lower 4 bits are used to point to the actual address. In the page read operation mode the lower 4-bit address value will automatically be incremented by one. However, the higher 5-bit address value will not be incremented by hardware. When the EEPROM address lower 4-bit value which is internally incremented by one in the page mode reaches the page boundary, known as 0FH, the EEPROM address lower 4-bit value will stop at 0FH. The EEPROM address will not “roll over”.

Page Erase Operation to the EEPROM

The EEPROM page erase operation can be executed when the mode selection bit, MODE, is set high. The EEPROM is capable of a 16-byte page erase. The internal page buffer will be cleared by hardware after power on reset. When the EEPROM erase enable control bit, namely EREN, is changed from “1” to “0”, the internal page buffer will also be cleared. Note that when the EREN bit is changed from “0” to “1”, the internal page buffer will not be cleared. The EEPROM address higher 5 bits are used to specify the desired page location while the lower 4 bits are used to point to the actual address. In the page erase operation mode the lower 4-bit address value will automatically be incremented by one after each dummy data byte is written into the EED register. However, the higher 5-bit address value will not be incremented by hardware. When the EEPROM address lower 4-bit value which is internally incremented by one in the page mode reaches the page boundary, known as 0FH, the EEPROM address lower 4-bit value will stop at 0FH. The EEPROM address will not “roll over”.

For page erase operations the start address of the desired EEPROM page should first be placed in the EEAH and EEAL register, then the dummy data to be written should be placed in the EED register. The maximum data length for a page is 16 bytes. Note that the write operation to the EED register is used to tag address, it must be implemented to determine which addresses to be erased. When the page dummy data is completely written, then the EREN bit in the EEC register should be set high to enable erase operations and the ER bit must be immediately set high to initiate the EEPROM erase process. These two instructions must be executed in two consecutive instruction cycles to activate an erase operation successfully. The global interrupt enable bit EMI should also first be cleared before implementing an erase operation and then set again after a valid erase activation procedure has completed.

Note: The above steps must be executed sequentially to successfully complete the page erase operation, refer to the corresponding programming example.

As the EEPROM erase cycle is controlled using an internal timer whose operation is asynchronous to microcontroller system clock, a certain time will elapse before the data will have been erased from the EEPROM. Detecting when the erase cycle has finished can be implemented either by polling the ER bit in the EEC register or by using the EEPROM interrupt. When the erase cycle terminates, the ER bit will be automatically cleared to zero by the microcontroller, informing the user that the page data has been erased. The application program can therefore poll the ER bit to determine when the erase cycle has ended. After the erase operation is finished, the EREN bit will be set low by hardware. The Data EEPROM erased page content will all be zero after a page erase operation.

Write Operation to the EEPROM

Writing data to the EEPROM can be implemented by two modes for this device, byte write mode or page write mode, which is controlled by the EEPROM operation mode selection bit, MODE, in the EEC register.

Byte Write Mode

The EEPROM byte write operation can be executed when the mode selection bit, MODE, is cleared to zero. For byte write operations the desired EEPROM address should first be placed in the EEAH and EEAL registers, then the data to be written should be placed in the EED register. To write data to the EEPROM, the write enable bit, WREN, in the EEC register must first be set high to enable the write function. After this, the WR bit in the EEC register must be immediately set high to initiate a write cycle. These two instructions must be executed in two consecutive instruction cycles to activate a write operation successfully. The global interrupt bit EMI should also first be cleared before implementing any write operations, and then set high again after a valid write activation procedure has completed. Note that setting the WR bit high only will not initiate a write cycle if the WREN bit is not set.

Note: The above steps must be executed sequentially to successfully complete the byte write operation, refer to the corresponding programming example.

As the EEPROM write cycle is controlled using an internal timer whose operation is asynchronous to microcontroller system clock, a certain time will elapse before the data will have been written into the EEPROM. Detecting when the write cycle has finished can be implemented either by polling the WR bit in the EEC register or by using the EEPROM interrupt. When the write cycle terminates, the WR bit will be automatically cleared to zero by the microcontroller, informing the user that the data has been written to the EEPROM. The application program can therefore poll the WR bit to determine when the write cycle has ended. After the write operation is finished, the WREN bit will be set low by hardware. Note that a byte erase operation will automatically be executed before a byte write operation is successfully activated.

Page Write Mode

Before a page write operation is executed, it is important to ensure that a relevant page erase operation has been successfully executed. The EEPROM page write operation can be executed when the mode selection bit, MODE, is set high. The EEPROM is capable of a 16-byte page write. The internal page buffer will be cleared by hardware after power on reset. When the EEPROM write enable control bit, namely WREN, is changed from “1” to “0”, the internal page buffer will also be cleared. Note that when the WREN bit is changed from “0” to “1”, the internal page buffer will not be cleared. A page write is initiated in the same way as a byte write initiation except that the EEPROM data can be written up to 16 bytes. The EEPROM address higher 5 bits are used to specify the desired page location while the lower 4 bits are used to point to the actual address. In the page write operation mode the lower 4-bit address value will automatically be incremented by one after each data byte is written into the EED register. However, the higher 5-bit address value will not be incremented by hardware. When the EEPROM address lower 4-bit value which is internally incremented by one in the page mode reaches the page boundary, known as 0FH, the EEPROM address lower 4-bit value will stop at 0FH. The EEPROM address will not “roll over”. At this point any data write operations to the EED register will be invalid.

For page write operations the start address of the desired EEPROM page should first be placed in the EEAH and EEAL registers, then the data to be written should be placed in the EED register. The maximum data length for a page is 16 bytes. Note that when a data byte is written into the EED register, then the data in the EED register will be loaded into the internal page buffer and the current address value will automatically be incremented by one. When the page data is completely written into the page buffer, then the WREN bit in the EEC register should be set high to enable write operations and the WR bit must be immediately set high to initiate the EEPROM write process. These two instructions must be executed in two consecutive instruction cycles to activate a write operation successfully. The global interrupt enable bit EMI should also first be cleared before implementing any write operations, and then set high again after a valid write activation procedure has completed. Note that setting the WR bit high only will not initiate a write cycle if the WREN bit is not set.

Note: The above steps must be executed sequentially to successfully complete the page write operation, refer to the corresponding programming example.

As the EEPROM write cycle is controlled using an internal timer whose operation is asynchronous to microcontroller system clock, a certain time will elapse before the data will have been written into the EEPROM. Detecting when the write cycle has finished can be implemented either by polling the WR bit in the EEC register or by using the EEPROM interrupt. When the write cycle terminates, the WR bit will be automatically cleared to zero by the microcontroller, informing the user that the data has been written to the EEPROM. The application program can therefore poll the WR bit to determine when the write cycle has ended. After the write operation is finished, the WREN bit will be set low by hardware.

Write Protection

Protection against inadvertent write operation is provided in several ways. After the device is powered-on the Write Enable bit in the control register will be cleared preventing any write operations. Also at power-on the Memory Pointer high byte register, MP1H or MP2H, will be reset to zero, which means that Data Memory Sector 0 will be selected. As the EEPROM control register is located in Sector 1, this adds a further measure of protection against spurious write operations. During normal program operation, ensuring that the Write Enable bit in the control register is cleared will safeguard against incorrect write operations.

EEPROM Interrupt

The EEPROM erase/write interrupt is generated when an EEPROM erase or write cycle has ended. The EEPROM interrupt must first be enabled by setting the DEE bit in the relevant interrupt register. However as the EEPROM is contained within a Multi-function Interrupt, the associated multi-function interrupt enable bit must also be set. When an EEPROM erase or write cycle ends, the DEF request flag and its associated multi-function interrupt request flag will both be set. If the global, EEPROM and Multi-function interrupts are enabled and the stack is not full, a jump to the associated Multi-function Interrupt vector will take place. When the interrupt is serviced only the Multi-function interrupt flag will be automatically reset, the EEPROM interrupt flag must be manually reset by the application program. More details can be obtained in the Interrupt section.

Programming Considerations

Care must be taken that data is not inadvertently written to the EEPROM. Protection can be enhanced by ensuring that the Write Enable bit is normally cleared to zero when not writing. Also the Memory Pointer high byte register, MP1H or MP2H, could be normally cleared to zero as this would inhibit access to Sector 1 where the EEPROM control register exists. Although certainly not necessary, consideration might be given in the application program to the checking of the validity of new write data by a simple read back process.

When writing data the WR bit must be set high immediately after the WREN bit has been set high, to ensure the write cycle executes correctly. The global interrupt bit EMI should also be cleared before a write or erase cycle is executed and then set again after a valid write or erase activation procedure has completed. Note that the device should not enter the IDLE or SLEEP mode until the EEPROM read, erase or write operation is totally complete. Otherwise, the EEPROM read, erase or write operation will fail.

Programming Examples

Reading a Data Byte from the EEPROM – Polling Method

```
MOV A, 040H           ; setup memory pointer low byte MP1L
MOV MP1L, A           ; MP1 points to EEC register
MOV A, 01H            ; setup memory pointer high byte MP1H
MOV MP1H, A
CLR IAR1.4            ; clear MODE bit, select byte operation mode
MOV A, EEPROM_ADRES_H ; user defined high byte address
MOV EEAH, A
MOV A, EEPROM_ADRES_L ; user defined low byte address
MOV EEAL, A
SET IAR1.1            ; set RDEN bit, enable read operations
SET IAR1.0            ; start Read Cycle - set RD bit
BACK:
SZ IAR1.0             ; check for read cycle end
JMP BACK
CLR IAR1              ; disable EEPROM read function
CLR MP1H
MOV A, EED            ; move read data to register
MOV READ_DATA, A
```

Reading a Data Page from the EEPROM – Polling Method

```
MOV A, 040H           ; setup memory pointer low byte MP1L
MOV MP1L, A           ; MP1 points to EEC register
MOV A, 01H            ; setup memory pointer high byte MP1H
MOV MP1H, A
SET IAR1.4            ; set MODE bit, select page operation mode
MOV A, EEPROM_ADRES_H ; user defined high byte address
```

```

MOV EEAH, A
MOV A, EEPROM_ADRES_L    ; user defined low byte address
MOV EEAL, A
SET IAR1.1                ; set RDEN bit, enable read operations
; ~~~~ The data length can be up to 16 bytes (Start) ~~~~
CALL READ
CALL READ
:
:
JMP PAGE_READ_FINISH
; ~~~~ The data length can be up to 16 bytes (End) ~~~~
READ:
SET IAR1.0                ; start Read Cycle - set RD bit
BACK:
SZ IAR1.0                 ; check for read cycle end
JMP BACK
MOV A, EED                ; move read data to register
MOV READ_DATA, A
RET
:
PAGE_READ_FINISH:
CLR IAR1                  ; disable EEPROM read function
CLR MP1H

```

Erasing a Data Page to the EEPROM – Polling Method

```

MOV A, 040H              ; setup memory pointer low byte MP1L
MOV MP1L, A              ; MP1 points to EEC register
MOV A, 01H               ; setup memory pointer high byte MP1H
MOV MP1H, A
SET IAR1.4               ; set MODE bit, select page operation mode
MOV A, EEPROM_ADRES_H   ; user defined high byte address
MOV EEAH, A
MOV A, EEPROM_ADRES_L   ; user defined low byte address
MOV EEAL, A
; ~~~~ The data length can be up to 16 bytes (Start) ~~~~
CALL WRITE_BUF
CALL WRITE_BUF
:
:
JMP Erase_START
; ~~~~ The data length can be up to 16 bytes (End) ~~~~
WRITE_BUF:
MOV A, EEPROM_DATA      ; user defined data, erase mode don't care data value
MOV EED, A
RET
:
Erase_START:
CLR EMI
SET IAR1.6               ; set EREN bit, enable erase operations
SET IAR1.5               ; start Erase Cycle - set ER bit - executed immediately
; after setting EREN bit

SET EMI
BACK:
SZ IAR1.5                ; check for erase cycle end
JMP BACK
CLR MP1H

```

Writing a Data Byte to the EEPROM – Polling Method

```
MOV A, 040H           ; setup memory pointer low byte MP1L
MOV MP1L, A           ; MP1 points to EEC register
MOV A, 01H            ; setup memory pointer high byte MP1H
MOV MP1H, A
CLR IAR1.4            ; clear MODE bit, select byte operation mode
MOV A, EEPROM_ADRES_H ; user defined high byte address
MOV EEAH, A
MOV A, EEPROM_ADRES_L ; user defined low byte address
MOV EEAL, A
MOV A, EEPROM_DATA    ; user defined data
MOV EED, A
CLR EMI
SET IAR1.3            ; set WREN bit, enable write operations
SET IAR1.2            ; start Write Cycle - set WR bit - executed immediately
                        ; after setting WREN bit

SET EMI
BACK:
SZ IAR1.2             ; check for write cycle end
JMP BACK
CLR MP1H
```

Writing a Data Page to the EEPROM – Polling Method

```
MOV A, 040H           ; setup memory pointer low byte MP1L
MOV MP1L, A           ; MP1 points to EEC register
MOV A, 01H            ; setup memory pointer high byte MP1H
MOV MP1H, A
SET IAR1.4            ; set MODE bit, select page operation mode
MOV A, EEPROM_ADRES_H ; user defined high byte address
MOV EEAH, A
MOV A, EEPROM_ADRES_L ; user defined low byte address
MOV EEAL, A
; ~~~~ The data length can be up to 16 bytes (Start) ~~~~
CALL WRITE_BUF
CALL WRITE_BUF
:
:
JMP WRITE_START
; ~~~~ The data length can be up to 16 bytes (End) ~~~~
WRITE_BUF:
MOV A, EEPROM_DATA    ; user defined data
MOV EED, A
RET
:
WRITE_START:
CLR EMI
SET IAR1.3            ; set WREN bit, enable write operations
SET IAR1.2            ; start Write Cycle - set WR bit - executed immediately
                        ; after setting WREN bit

SET EMI
BACK:
SZ IAR1.2             ; check for write cycle end
JMP BACK
CLR MP1H
```

Oscillators

Various oscillator options offer the user a wide range of functions according to their various application requirements. The flexible features of the oscillator functions ensure that the best optimisation can be achieved in terms of speed and power saving. Oscillator selections and operation are selected only through a combination of configuration options and relevant control registers.

Oscillator Overview

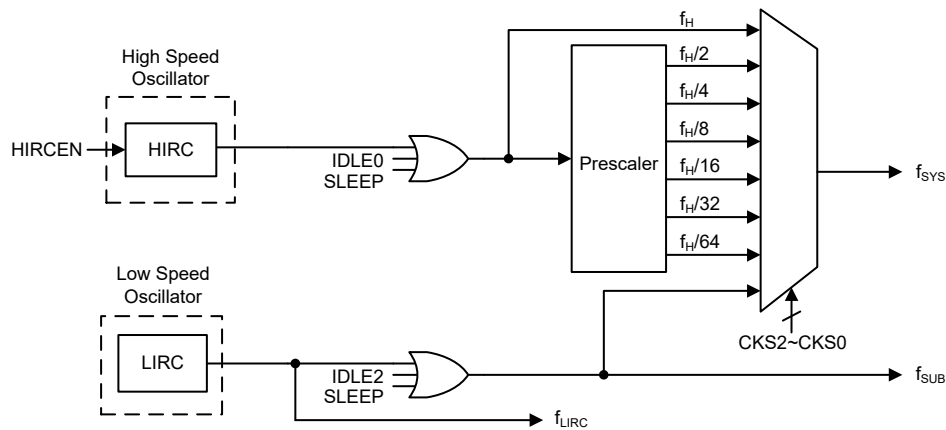
In addition to being the source of the main system clock the oscillators also provide clock sources for the Watchdog Timer and Time Base Interrupts. Fully integrated internal oscillators requiring no external components are provided to form a wide range of both fast and slow system oscillators. The higher frequency oscillators provide higher performance but carry with it the disadvantage of higher power requirements, while the opposite is of course true for the lower frequency oscillators. With the capability of dynamically switching between fast and slow system clock, the device have the flexibility to optimize the performance/power ratio, a feature especially important in power sensitive portable applications.

Type	Name	Frequency
Internal High Speed RC	HIRC	4/8/12MHz
Internal Low Speed RC	LIRC	32kHz

Oscillator Types

System Clock Configurations

There are two oscillator sources, one high speed oscillator and one low speed oscillator. The high speed system clocks is sourced from the internal 4/8/12MHz RC oscillator, HIRC. The low speed oscillator is the internal 32kHz RC oscillator, LIRC. Selecting whether the low or high speed oscillator is used as the system oscillator is implemented using the CKS2~CKS0 bits in the SCC register and as the system clock can be dynamically selected.



System Clock Configurations

Internal High Speed RC Oscillator – HIRC

The internal RC oscillator is a fully integrated system oscillator requiring no external components. The internal RC oscillator has three fixed frequencies of 4MHz, 8MHz and 12MHz, which are selected by HIRC1~HIRC0 bits in the HIRCC register. These bit must be setup to match the selected configuration option frequency to ensure that the HIRC frequency accuracy specified in the A.C. Characteristics is achieved. Device trimming during the manufacturing process and the inclusion of

internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised.

Internal 32kHz Oscillator – LIRC

The Internal 32kHz System Oscillator is a fully integrated RC oscillator with a typical frequency of 32kHz, requiring no external components for its implementation. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised.

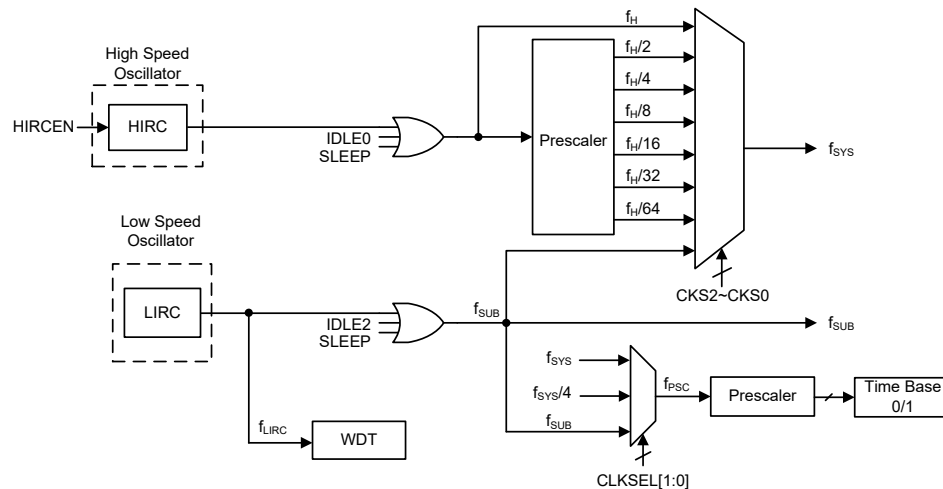
Operating Modes and System Clocks

Present day applications require that their microcontrollers have high performance but often still demand that they consume as little power as possible, conflicting requirements that are especially true in battery powered portable applications. The fast clocks required for high performance will by their nature increase current consumption and of course vice versa, lower speed clocks reduce current consumption. As Holtek has provided the device with both high and low speed clock sources and the means to switch between them dynamically, users can optimise the operation of their microcontroller to achieve the best performance/power ratio.

System Clocks

The device has many different clock sources for both the CPU and peripheral function operation. By providing the user with a wide range of clock options using register programming, a clock system can be configured to obtain maximum application performance.

The main system clock, can come from a high frequency, f_H , or low frequency, f_{SUB} , source, and is selected using the CKS2~CKS0 bits in the SCC register. The high speed system clock is sourced from the HIRC oscillator. The low speed system clock is sourced from the LIRC oscillator. The other choice, which is a divided version of the high speed system oscillator has a range of $f_H/2 \sim f_H/64$.



Device Clock Configurations

Note: When the system clock source f_{SYS} is switched to f_{SUB} from f_H , the high speed oscillator will stop to conserve the power or continue to oscillate to provide the clock source, $f_H \sim f_H/64$, for peripheral circuit to use, which is determined by configuring the corresponding high speed oscillator enable control bit.

System Operation Modes

There are six different modes of operation for the microcontroller, each one with its own special characteristics and which can be chosen according to the specific performance and power requirements of the application. There are two modes allowing normal operation of the microcontroller, the FAST Mode and SLOW Mode. The remaining four modes, the SLEEP, IDLE0, IDLE1 and IDLE2 Mode are used when the microcontroller CPU is switched off to conserve power.

Operation Mode	CPU	Register Setting			f _{sys}	f _H	f _{sub}	f _{LIRC}
		FHIDEN	FSIDEN	CKS2~CKS0				
FAST	On	x	x	000~110	f _H ~f _H /64	On	On	On
SLOW	On	x	x	111	f _{sub}	On/Off ⁽¹⁾	On	On
IDLE0	Off	0	1	000~110	Off	Off	On	On
				111	On			
IDLE1	Off	1	1	xxx	On	On	On	On
IDLE2	Off	1	0	000~110	On	On	Off	On
				111	Off			
SLEEP	Off	0	0	xxx	Off	Off	Off	On ⁽²⁾

“x”: Don't care

Note: 1. The f_H clock will be switched on or off by configuring the corresponding oscillator enable bit in the SLOW mode.

2. The f_{LIRC} can be on since the WDT function is always enabled even in the SLEEP mode.

FAST Mode

This is one of the main operating modes where the microcontroller has all of its functions operational and where the system clock is provided by the internal high speed oscillator. This mode operates allowing the microcontroller to operate normally with a clock source coming from the HIRC oscillator. The high speed oscillator will however first be divided by a ratio ranging from 1 to 64, the actual ratio being selected by the CKS2~CKS0 bits in the SCC register. Although a high speed oscillator is used, running the microcontroller at a divided clock ratio reduces the operating current.

SLOW Mode

This is also a mode where the microcontroller operates normally although now with a slower speed clock source. The clock source used will be from f_{sub}. The f_{sub} clock is derived from the LIRC oscillator.

SLEEP Mode

The SLEEP Mode is entered when a HALT instruction is executed and when the FHIDEN and FSIDEN bit are low. In the SLEEP mode the CPU will be stopped. The f_{sub} clock provided to the peripheral function will also be stopped, too. However the f_{LIRC} clock can still continue to operate if the WDT function is always enabled.

IDLE0 Mode

The IDLE0 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is low and the FSIDEN bit in the SCC register is high. In the IDLE0 Mode the CPU will be switched off but the low speed oscillator will be turned on to drive some peripheral functions.

IDLE1 Mode

The IDLE1 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is high. In the IDLE1 Mode the CPU will be switched off but both the high and low speed oscillators will be turned on to provide a clock source to keep some peripheral functions operational.

IDLE2 Mode

The IDLE2 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is low. In the IDLE2 Mode the CPU will be switched off but the high speed oscillator will be turned on to provide a clock source to keep some peripheral functions operational.

Control Registers

The registers, SCC and HIRCC, are used to control the system clock and the corresponding oscillator configurations.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SCC	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
HIRCC	—	—	—	—	HIRC1	HIRC0	HIRCF	HIRCEN

System Operating Mode Control Register List

• **SCC Register**

Bit	7	6	5	4	3	2	1	0
Name	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
R/W	R/W	R/W	R/W	—	—	—	R/W	R/W
POR	0	0	0	—	—	—	0	0

Bit 7~5 **CKS2~CKS0**: System clock selection

- 000: f_H
- 001: $f_H/2$
- 010: $f_H/4$
- 011: $f_H/8$
- 100: $f_H/16$
- 101: $f_H/32$
- 110: $f_H/64$
- 111: f_{SUB}

These three bits are used to select which clock is used as the system clock source. In addition to the system clock source directly derived from f_H or f_{SUB} , a divided version of the high speed system oscillator can also be chosen as the system clock source.

Bit 4~2 Unimplemented, read as “0”

Bit 1 **FHIDEN**: High frequency oscillator control when CPU is switched off
 0: Disable
 1: Enable

This bit is used to control whether the high speed oscillator is activated or stopped when the CPU is switched off by executing a “HALT” instruction.

Bit 0 **FSIDEN**: Low frequency oscillator control when CPU is switched off
 0: Disable
 1: Enable

This bit is used to control whether the low speed oscillator is activated or stopped when the CPU is switched off by executing a “HALT” instruction.

Note: A certain delay is required before the relevant clock is successfully switched to the target clock source after any clock switching setup using the CKS2~CKS0 bits. A proper delay time must be arranged before executing the following operations which require immediate reaction with the target clock source.

Clock switching delay time = $4 \times t_{SYS} + [0 \sim (1.5 \times t_{CURR} + 0.5 \times t_{TAR})]$, Where t_{CURR} indicates the current clock period, t_{TAR} indicates the target clock period and the t_{SYS} indicates the current system clock period.

• **HIRCC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	HIRC1	HIRC0	HIRCF	HIRCEN
R/W	—	—	—	—	R/W	R/W	R	R/W
POR	—	—	—	—	0	0	0	1

Bit 7~4 Unimplemented, read as “0”

Bit 3~2 **HIRC1~HIRC0**: HIRC frequency selection
 00: 4MHz
 01: 8MHz
 10: 12MHz
 11: 4MHz

When the HIRC oscillator is enabled or the HIRC frequency selection is changed by the application program, the clock frequency will automatically be changed after the HIRCF flag is set to 1. It is recommended that the HIRC frequency selected by these bits is the same as the frequency determined by the configuration option to keep the HIRC frequency accuracy specified in the A.C. characteristics.

Bit 1 **HIRCF**: HIRC oscillator stable flag
 0: HIRC unstable
 1: HIRC stable

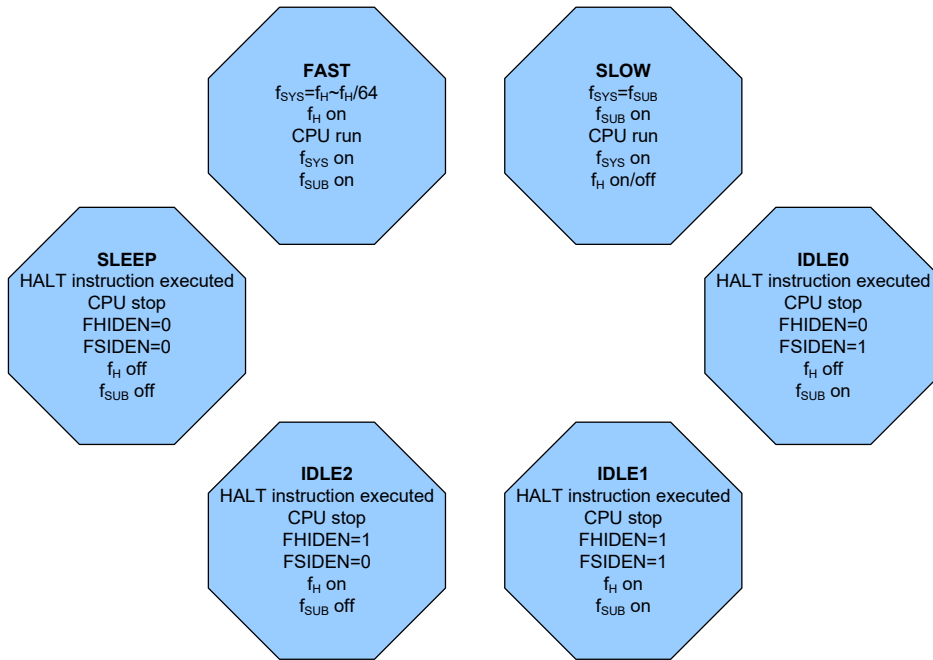
This bit is used to indicate whether the HIRC oscillator is stable or not. When the HIRCEN bit is set to 1 to enable the HIRC oscillator or the HIRC frequency selection is changed by the application program, the HIRCF bit will first be cleared to 0 and then set to 1 after the HIRC oscillator is stable.

Bit 0 **HIRCEN**: HIRC oscillator enable control
 0: Disable
 1: Enable

Operating Mode Switching

The device can switch between operating modes dynamically allowing the user to select the best performance/power ratio for the present task in hand. In this way microcontroller operations that do not require high performance can be executed using slower clocks thus requiring less operating current and prolonging battery life in portable applications.

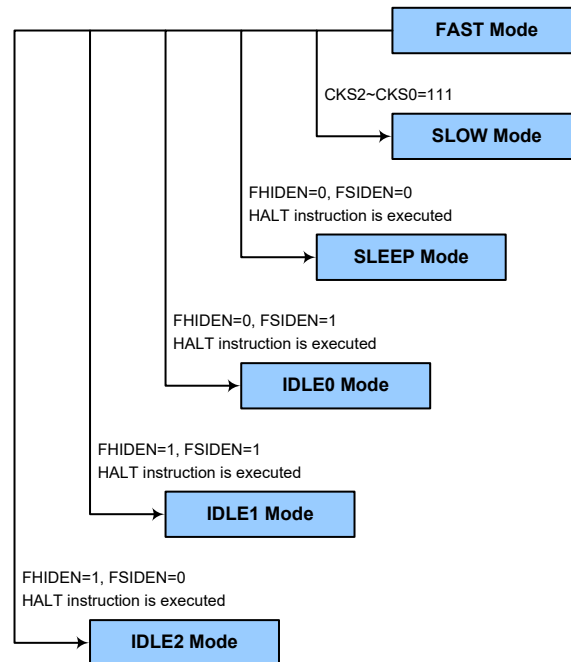
In simple terms, Mode Switching between the FAST Mode and SLOW Mode is executed using the CKS2~CKS0 bits in the SCC register while Mode Switching from the FAST/SLOW Mode to the SLEEP/IDLE Mode is executed via the HALT instruction. When a HALT instruction is executed, whether the device enter the IDLE Mode or the SLEEP Mode is determined by the condition of the FHIDEN and FSIDEN bits in the SCC register.



FAST Mode to SLOW Mode Switching

When running in the FAST Mode, which uses the high speed system oscillator, and therefore consumes more power, the system clock can switch to run in the SLOW Mode by set the CKS2~CKS0 bits to “111” in the SCC register. This will then use the low speed system oscillator which will consume less power. Users may decide to do this for certain operations which do not require high performance and can subsequently reduce power consumption.

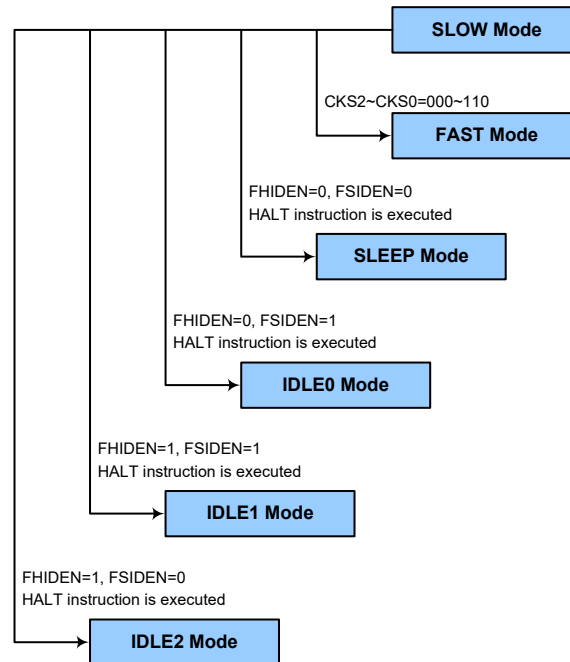
The SLOW Mode is sourced from the LIRC oscillator and therefore requires this oscillator to be stable before full mode switching occurs.



SLOW Mode to FAST Mode Switching

In SLOW mode the system clock is derived from f_{SUB} . When system clock is switched back to the FAST mode from f_{SUB} , the CKS2~CKS0 bits should be set to “000”~“110” and then the system clock will respectively be switched to $f_H \sim f_H/64$.

However, if f_H is not used in SLOW mode and thus switched off, it will take some time to re-oscillate and stabilise when switching to the FAST mode from the SLOW Mode. This is monitored using the HIRCF bit in the HIRCC register. The time duration required for the high speed system oscillator stabilization is specified in the System Start Up Time Characteristics.



Entering the SLEEP Mode

There is only one way for the device to enter the SLEEP Mode and that is to execute the “HALT” instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to “0”. In this mode all the clocks and functions will be switched off except the WDT function. When this instruction is executed under the conditions described above, the following will occur:

- The system clock will be stopped and the application program will stop at the “HALT” instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

Entering the IDLE0 Mode

There is only one way for the device to enter the IDLE0 Mode and that is to execute the “HALT” instruction in the application program with the FHIDEN bit in the SCC register equal to “0” and the FSIDEN bit in the SCC register equal to “1”. When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be stopped and the application program will stop at the “HALT” instruction, but the f_{SUB} clock will be on.

- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

Entering the IDLE1 Mode

There is only one way for the device to enter the IDLE1 Mode and that is to execute the “HALT” instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to “1”. When this instruction is executed under the conditions described above, the following will occur:

- The f_H and f_{SUB} clocks will be on but the application program will stop at the “HALT” instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

Entering the IDLE2 Mode

There is only one way for the device to enter the IDLE2 Mode and that is to execute the “HALT” instruction in the application program with the FHIDEN bit in the SCC register equal to “1” and the FSIDEN bit in the SCC register equal to “0”. When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be on but the f_{SUB} clock will be off and the application program will stop at the “HALT” instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

Standby Current Considerations

As the main reason for entering the SLEEP or IDLE Mode is to keep the current consumption of the device to as low a value as possible, perhaps only in the order of several micro-amps in the SLEEP and IDLE0 modes, there are other considerations which must also be taken into account by the circuit designer if the power consumption is to be minimised. Special attention must be made to the I/O pins on the device. All high-impedance input pins must be connected to either a fixed high or low level as any floating input pins could create internal oscillations and result in increased current consumption. This also applies to the device which has different package types, as there may be unbonded pins. These must either be setup as outputs or if setup as inputs must have pull-high resistors connected.

Care must also be taken with the loads, which are connected to I/O pins, which are setup as outputs. These should be placed in a condition in which minimum current is drawn or connected only to external circuits that do not draw current, such as other CMOS inputs.

In the IDLE1 and IDLE2 modes the high speed oscillator is on, if the peripheral function clock source is derived from the high speed oscillator, the additional standby current will also be perhaps in the order of several hundred micro-amps.

Wake-up

To minimise power consumption the device can enter the SLEEP or any IDLE Mode, where the CPU will be switched off. However, when the device is woken up again, it will take a considerable time for the original system oscillator to restart, stabilise and allow normal operation to resume.

After the system enters the SLEEP or IDLE Mode, it can be woken up from one of various sources listed as follows:

- An external falling edge on Port A
- A system interrupt
- A WDT overflow

When the device executes the “HALT” instruction, the PDF flag will be set high. The PDF flag will be cleared to 0 if the device experiences a system power-up or executes the clear Watchdog Timer instruction. If the system is woken up by a WDT overflow, a Watchdog Timer reset will be initiated and the TO flag will be set high. The TO flag is set if a WDT time-out occurs and causes a wake-up that only resets the Program Counter and Stack Pointer, other flags remain in their original status.

Each pin on Port A can be set using the PAWU register to permit a negative transition on the pin to wake-up the system. When a pin wake-up occurs, the program will resume execution at the instruction following the “HALT” instruction. If the system is woken up by an interrupt, then two possible situations may occur. The first is where the related interrupt is disabled or the interrupt is enabled but the stack is full, in which case the program will resume execution at the instruction following the “HALT” instruction. In this situation, the interrupt which woke-up the device will not be immediately serviced, but will rather be serviced later when the related interrupt is finally enabled or when a stack level becomes free. The other situation is where the related interrupt is enabled and the stack is not full, in which case the regular interrupt response takes place. If an interrupt request flag is set high before entering the SLEEP or IDLE Mode, the wake-up function of the related interrupt will be disabled.

Watchdog Timer

The Watchdog Timer is provided to prevent program malfunctions or sequences from jumping to unknown locations, due to certain uncontrollable external events such as electrical noise.

Watchdog Timer Clock Source

The Watchdog Timer clock source is provided by the internal clock, f_{LIRC} which is sourced from the LIRC oscillator. The LIRC internal oscillator has an approximate frequency of 32kHz and this specified internal clock period can vary with V_{DD} , temperature and process variations. The Watchdog Timer source clock is then subdivided by a ratio of 2^8 to 2^{18} to give longer timeouts, the actual value being chosen using the WS2~WS0 bits in the WDTC register.

Watchdog Timer Control Register

A single register, WDTC, controls the required time-out period as well as the enable WDT and reset MCU operation.

• **WDTC Register**

Bit	7	6	5	4	3	2	1	0
Name	WE4	WE3	WE2	WE1	WE0	WS2	WS1	WS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	0	1	1

Bit 7~3 **WE4~WE0**: WDT function software control

01010/10101: Enable

Others: Reset MCU

When these bits are changed to any other values due to environmental noise the microcontroller will be reset; this reset operation will be activated after a delay time, t_{SRESET} , and the WRF bit in the RSTFC register will be set high.

Bit 2~0 **WS2~WS0**: WDT time-out period selection

000: $2^8/f_{LIRC}$

001: $2^{10}/f_{LIRC}$

010: $2^{12}/f_{LIRC}$

011: $2^{14}/f_{LIRC}$

100: $2^{15}/f_{LIRC}$

101: $2^{16}/f_{LIRC}$

110: $2^{17}/f_{LIRC}$

111: $2^{18}/f_{LIRC}$

These three bits determine the division ratio of the Watchdog Timer source clock, which in turn determines the timeout period.

• **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

“x”: unknown

Bit 7~3 Unimplemented, read as “0”

Bit 2 **LVRF**: LVR function reset flag

Refer to the Low Voltage Reset section.

Bit 1 **LRF**: LVR control register software reset flag

Refer to the Low Voltage Reset section.

Bit 0 **WRF**: WDT Control register software reset flag

0: Not occur

1: Occurred

This bit is set high by the WDT Control register software reset and cleared by the application program. Note that this bit can only be cleared to zero by the application program.

Watchdog Timer Operation

The Watchdog Timer operates by providing a device reset when its timer overflows. This means that in the application program and during normal operation the user has to strategically clear the Watchdog Timer before it overflows to prevent the Watchdog Timer from executing a reset. This is done using the clear watchdog instruction. If the program malfunctions for whatever reason, jumps to an unknown location, or enters an endless loop, the clear instruction will not be executed in the correct manner, in which case the Watchdog Timer will overflow and reset the device. There are five bits, WE4~WE0, in the WDTC register to offer the enable and reset control of the Watchdog Timer. The WDT function will be enabled if the WE4~WE0 bits are set to a value of 01010B or 10101B. If the WE4~WE0 bits are set to any other values, other than 01010B and 10101B, it will reset the device after a delay time, t_{SRESET} . After power on these bits will have a value of 01010B.

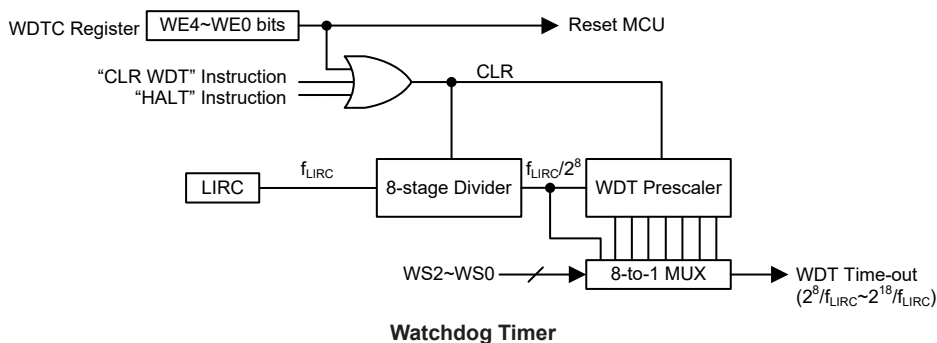
WE4~WE0 Bits	WDT Function
10101B or 01010B	Enable
Any other values	Reset MCU

Watchdog Timer Function Control

Under normal program operation, a Watchdog Timer time-out will initialise a device reset and set the status bit TO. However, if the system is in the SLEEP or IDLE Mode, when a Watchdog Timer time-out occurs, the TO bit in the status register will be set and only the Program Counter and Stack Pointer will be reset. Three methods can be adopted to clear the contents of the Watchdog Timer. The first is a WDTC software reset, which means a certain value except 01010B and 10101B written into the WE4~WE0 bit filed, the second is using the Watchdog Timer software clear instruction and the third is via a HALT instruction.

There is only one method of using software instruction to clear the Watchdog Timer. That is to use the single “CLR WDT” instruction to clear the WDT.

The maximum time out period is when the 2^{18} division ratio is selected. As an example, with a 32kHz LIRC oscillator as its source clock, this will give a maximum watchdog period of around 8 seconds for the 2^{18} division ratio, and a minimum timeout of 8ms for the 2^8 division ratio.



Reset and Initialisation

A reset function is a fundamental part of any microcontroller ensuring that the device can be set to some predetermined condition irrespective of outside parameters. The most important reset condition is after power is first applied to the microcontroller. In this case, internal circuitry will ensure that the microcontroller, after a short delay, will be in a well-defined state and ready to execute the first program instruction. After this power-on reset, certain important internal registers will be set to defined states before the program commences. One of these registers is the Program Counter, which will be reset to zero forcing the microcontroller to begin program execution from the lowest Program Memory address.

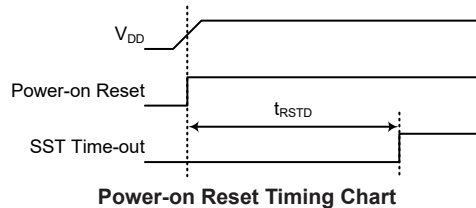
Another reset exists in the form of a Low Voltage Reset, LVR, where a full reset, is implemented in situations where the power supply voltage falls below a certain threshold. Another type of reset is when the Watchdog Timer overflows and resets the microcontroller. All types of reset operations result in different register conditions being setup.

Reset Functions

There are several ways in which a microcontroller reset can occur, through events occurring internally.

Power-on Reset

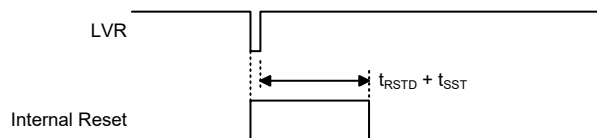
The most fundamental and unavoidable reset is the one that occurs after power is first applied to the microcontroller. As well as ensuring that the Program Memory begins execution from the first memory address, a power-on reset also ensures that certain other registers are preset to known conditions. All the I/O port and port control registers will power up in a high condition ensuring that all pins will be first set to inputs.



Low Voltage Reset – LVR

The microcontroller contains a low voltage reset circuit in order to monitor the supply voltage of the device and provides an MCU reset should the value fall below a certain predefined level. The LVR function is always enabled in FAST and SLOW Mode with a specific LVR voltage V_{LVR} . If the supply voltage of the device drops to within a range of $0.9V \sim V_{LVR}$ such as might occur when changing the battery, the LVR will automatically reset the device internally and the LVRF bit in the RSTFC register will also be set high. For a valid LVR signal, a low voltage, i.e., a voltage in the range between $0.9V \sim V_{LVR}$ must exist for greater than the value t_{LVR} specified in the LVD/LVR Electrical Characteristics. If the low voltage state does not exceed this value, the LVR will ignore the low supply voltage and will not perform a reset function. The actual V_{LVR} value can be selected by the LVS7~LVS0 bits in the LVRC register.

If the LVS7~LVS0 bits are changed to some different values by environmental noise, the LVR will reset the device after a delay time, t_{SRESET} . When this happens, the LRF bit in the RSTFC register will be set high. After power on the register will have the value of 01010101B. Note that the LVR function will be automatically disabled when the device enters the IDLE or SLEEP mode.


Low Voltage Reset Timing Chart
• LVRC Register

Bit	7	6	5	4	3	2	1	0
Name	LVS7	LVS6	LVS5	LVS4	LVS3	LVS2	LVS1	LVS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	1	0	1

Bit 7~0 **LVS7~LVS0**: LVR voltage select

01010101: 2.1V

00110011: 2.55V

10011001: 3.15V

10101010: 3.8V

Any other value: Generates MCU reset – register is reset to POR value

When an actual low voltage condition occurs, as specified by one of the four defined LVR voltage values above, an MCU reset will be generated. The reset operation will be activated after the low voltage condition keeps more than a t_{LVR} time. In this situation the register contents will remain the same after such a reset occurs.

Any register value, other than the four defined LVR values above, will also result in the generation of an MCU reset. The reset operation will be activated after a delay time, t_{SRESET} . However in this situation the register contents will be reset to the POR value.

• TLVRC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	TLVR1	TLVR0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	1

Bit 7~2 Unimplemented, read as “0”

Bit 1~0 **TLVR1~TLVR0**: Minimum low voltage width to reset time (t_{LVR}) selection

00: $(7\sim8) \times t_{LIRC}$

01: $(31\sim32) \times t_{LIRC}$

10: $(63\sim64) \times t_{LIRC}$

11: $(127\sim128) \times t_{LIRC}$

• RSTFC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

“x”: unknown

Bit 7~3 Unimplemented, read as “0”

Bit 2 **LVRF**: LVR function reset flag

0: Not occurred

1: Occurred

This bit is set high when a specific Low Voltage Reset situation condition occurs. This bit can only be cleared to zero by the application program.

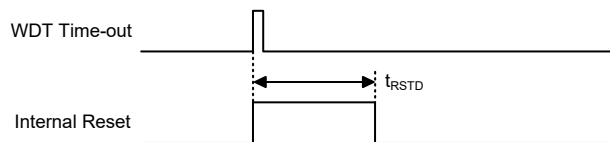
- Bit 1 **LRF**: LVR control register software reset flag
 0: Not occurred
 1: Occurred
 This bit is set high if the LVRC register contains any non-defined LVRC register values. This in effect acts like a software-reset function. This bit can only be cleared to zero by the application program.
- Bit 0 **WRF**: WDT control register software reset flag
 Refer to the Watchdog Timer Control Register section.

In Application Programming Reset

When a specific value of “55H” is written into the FC1 register, a reset signal will be generated to reset the whole device. Refer to the IAP section for more associated details.

Watchdog Time-out Reset during Normal Operation

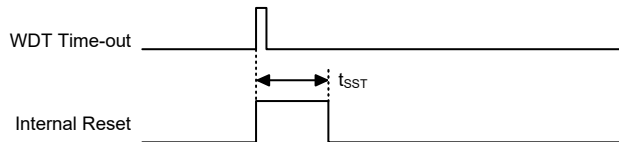
The Watchdog time-out Reset during normal operation in the FAST or SLOW mode, the Watchdog time-out flag TO will be set high.



WDT Time-out Reset during Normal Operation Timing Chart

Watchdog Time-out Reset during SLEEP or IDLE Mode

The Watchdog time-out Reset during SLEEP or IDLE Mode is a little different from other kinds of reset. Most of the conditions remain unchanged except that the Program Counter and the Stack Pointer will be cleared to zero and the TO and PDF flags will be set high. Refer to the System Start Up Time Characteristics for t_{SST} details.



WDT Time-out Reset during SLEEP or IDLE Mode Timing Chart

Reset Initial Conditions

The different types of reset described affect the reset flags in different ways. These flags, known as PDF and TO are located in the status register and are controlled by various microcontroller operations, such as the SLEEP or IDLE Mode function or Watchdog Timer. The reset flags are shown in the table:

TO	PDF	Reset Conditions
0	0	Power-on reset
u	u	LVR reset during FAST or SLOW Mode operation
1	u	WDT time-out reset during FAST or SLOW Mode operation
1	1	WDT time-out reset during IDLE or SLEEP Mode operation

“u”: Unchanged

The following table indicates the way in which the various components of the microcontroller are affected after a power-on reset occurs.

Item	Condition after Reset
Program Counter	Reset to zero
Interrupts	All interrupts will be disabled
WDT, Time Bases	Clear after reset, WDT begins counting
Timer Modules	All Timer Modules will be turned off
Input/Output Ports	I/O ports will be setup as inputs
Stack Pointer	Stack Pointer will point to the top of the stack

The different kinds of resets all affect the internal registers of the microcontroller in different ways. To ensure reliable continuation of normal program execution after a reset occurs, it is important to know what condition the microcontroller is in after a particular reset occurs. The following table describes how each type of reset affects each of the microcontroller internal registers.

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
IAR0	0000 0000	0000 0000	uuuu uuuu
MP0	0000 0000	0000 0000	uuuu uuuu
IAR1	0000 0000	0000 0000	uuuu uuuu
MP1L	0000 0000	0000 0000	uuuu uuuu
MP1H	0000 0000	0000 0000	uuuu uuuu
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBLH	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBHP	---- xxxx	---- uuuu	---- uuuu
STATUS	xx00 xxxx	uu1u uuuu	uu11 uuuu
IAR2	0000 0000	0000 0000	uuuu uuuu
MP2L	0000 0000	0000 0000	uuuu uuuu
MP2H	0000 0000	0000 0000	uuuu uuuu
RSTFC	---- -x00	---- -uuu	---- -uuu
SCC	000- --00	000- --00	uuu- --uu
HIRCC	---- 0001	---- 0001	---- uuuu
ORMC	0000 0000	0000 0000	0000 0000
PA	1111 1111	1111 1111	uuuu uuuu
PAC	1111 1111	1111 1111	uuuu uuuu
PAPU	0000 0000	0000 0000	uuuu uuuu
PAWU	0000 0000	0000 0000	uuuu uuuu
PB	-111 1111	-111 1111	-uuu uuuu
PBC	-111 1111	-111 1111	-uuu uuuu
PBPU	-000 0000	-000 0000	-uuu uuuu
PAS	---0 ----	---0 ----	---u ----
NMSR	11-- -000	11-- -000	uu-- -uuu
INTEG	---- 0000	---- 0000	---- uuuu
INTC0	-000 0000	-000 0000	-uuu uuuu
INTC1	0000 0000	0000 0000	uuuu uuuu
INTC2	0000 0000	0000 0000	uuuu uuuu
MFI0	--00 --00	--00 --00	--uu --uu
MFI1	--00 --00	--00 --00	--uu --uu
MFI2	--00 --00	--00 --00	--uu --uu

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
MF13	0000 0000	0000 0000	uuuu uuuu
MF14	0000 0000	0000 0000	uuuu uuuu
MF15	0000 0000	0000 0000	uuuu uuuu
SADC0	0000 0000	0000 0000	uuuu uuuu
SADC1	0000 0000	0000 0000	uuuu uuuu
SADC2	--00 -100	--00 -100	--uu -uuu
SADOL	xxxx ----	xxxx ----	uuuu ---- (ADRFS=0)
			uuuu uuuu (ADRFS=1)
SADOH	xxxx xxxx	xxxx xxxx	uuuu uuuu (ADRFS=0)
			---- uuuu (ADRFS=1)
PSCR	---- --00	---- --00	---- --uu
TB0C	0--- -000	0--- -000	u--- -uuu
TB1C	0--- -000	0--- -000	u--- -uuu
WDTC	0101 0011	0101 0011	uuuu uuuu
REGC	0--- -000	0--- -000	u--- -uuu
EEAL	0000 0000	0000 0000	uuuu uuuu
EEAH	---- ---0	---- ---0	---- ---u
EED	0000 0000	0000 0000	uuuu uuuu
CTM0C0	0000 0000	0000 0000	uuuu uuuu
CTM0C1	0000 0000	0000 0000	uuuu uuuu
CTM0DL	0000 0000	0000 0000	uuuu uuuu
CTM0DH	---- --00	---- --00	---- --uu
CTM0AL	0000 0000	0000 0000	uuuu uuuu
CTM0AH	---- --00	---- --00	---- --uu
CTM1C0	0000 0000	0000 0000	uuuu uuuu
CTM1C1	0000 0000	0000 0000	uuuu uuuu
CTM1DL	0000 0000	0000 0000	uuuu uuuu
CTM1DH	---- --00	---- --00	---- --uu
CTM1AL	0000 0000	0000 0000	uuuu uuuu
CTM1AH	---- --00	---- --00	---- --uu
SIMC0	1110 0000	1110 0000	uuuu uuuu
SIMC1 (UMD=0)	1000 0001	1000 0001	uuuu uuuu
UUCR1* (UMD=1)	0000 00x0	0000 00x0	uuuu uuuu
SIMD/UTXR_RXR	xxxx xxxx	xxxx xxxx	uuuu uuuu
SIMA/SIMC2/UUCR2	0000 0000	0000 0000	uuuu uuuu
UUCR3	---- ---0	---- ---0	---- ---u
SIMTOC (UMD=0)	0000 0000	0000 0000	uuuu uuuu
UBRG* (UMD=1)	xxxx xxxx	xxxx xxxx	uuuu uuuu
UUSR	0000 1011	0000 1011	uuuu uuuu
MDUWR0	xxxx xxxx	0000 0000	uuuu uuuu
MDUWR1	xxxx xxxx	0000 0000	uuuu uuuu
MDUWR2	xxxx xxxx	0000 0000	uuuu uuuu
MDUWR3	xxxx xxxx	0000 0000	uuuu uuuu
MDUWR4	xxxx xxxx	0000 0000	uuuu uuuu
MDUWR5	xxxx xxxx	0000 0000	uuuu uuuu
MDUWCTRL	00-- ----	00-- ----	uu-- ----

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
ISGENC	0 - - - - - 0	0 - - - - - 0	u - - - - - u
ISGDATA	- - 00 0000	- - 00 0000	- - uu uuuu
DDOC	0 - - - 0000	0 - - - 0000	u - - - uuuu
DDA0C	0000 - 000	0000 - 000	uuuu - uuu
DDA1C	0000 - 000	0000 - 000	uuuu - uuu
DDA2C	0000 - 000	0000 - 000	uuuu - uuu
DDPGAC0	- - 00 0000	- - 00 0000	- - uu uuuu
DDPGAC1	- - - 0 0000	- - - 0 0000	- - - u uuuu
DDA0VOS	0010 0000	0010 0000	uuuu uuuu
DDA1VOS	0010 0000	0010 0000	uuuu uuuu
DDA2VOS	0010 0000	0010 0000	uuuu uuuu
DDPGAC2	- - 00 0000	- - 00 0000	- - uu uuuu
PAS0	0000 0000	0000 0000	uuuu uuuu
PAS1	0000 0000	0000 0000	uuuu uuuu
PBS0	0000 0000	0000 0000	uuuu uuuu
PBS1	- - 00 0000	- - 00 0000	- - uu uuuu
IFS	- - - - 0000	- - - - 0000	- - - - uuuu
LVRC	0101 0101	0101 0101	uuuu uuuu
LVDC	- - 00 0000	- - 00 0000	- - uu uuuu
TLVRC	- - - - - 01	- - - - - 01	- - - - - uu
FC0	0000 0000	0000 0000	uuuu uuuu
FC1	0000 0000	0000 0000	uuuu uuuu
FC2	- - - - - 00	- - - - - 00	- - - - - uu
FARL	0000 0000	0000 0000	uuuu uuuu
FARH	- - - - 0000	- - - - 0000	- - - - uuuu
FD0L	0000 0000	0000 0000	uuuu uuuu
FD0H	0000 0000	0000 0000	uuuu uuuu
FD1L	0000 0000	0000 0000	uuuu uuuu
FD1H	0000 0000	0000 0000	uuuu uuuu
FD2L	0000 0000	0000 0000	uuuu uuuu
FD2H	0000 0000	0000 0000	uuuu uuuu
FD3L	0000 0000	0000 0000	uuuu uuuu
FD3H	0000 0000	0000 0000	uuuu uuuu
OVP0C0	000- 0000	000- 0000	uuu- uuuu
OVP0C1	0001 0000	0001 0000	uuuu uuuu
OVP0C2	- - - - 0000	- - - - 0000	- - - - uuuu
OVP0DAL	0000 0000	0000 0000	uuuu uuuu
OVP0DAH	- - - - 0000	- - - - 0000	- - - - uuuu
OVP1C0	000- 0000	000- 0000	uuu- uuuu
OVP1C1	0001 0000	0001 0000	uuuu uuuu
OVP1C2	- - - - 0000	- - - - 0000	- - - - uuuu
OVP1DAL	0000 0000	0000 0000	uuuu uuuu
OVP1DAH	- - - - 0000	- - - - 0000	- - - - uuuu
OVP2C0	000- 0000	000- 0000	uuu- uuuu
OVP2C1	0001 0000	0001 0000	uuuu uuuu
OVP2C2	- - - - 0000	- - - - 0000	- - - - uuuu
OVP2DAL	0000 0000	0000 0000	uuuu uuuu
OVP2DAH	- - - - 0000	- - - - 0000	- - - - uuuu
PTM0C0	0000 0 - - -	0000 0 - - -	uuuu u - - -

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
PTM0C1	0000 0000	0000 0000	uuuu uuuu
PTM0C2	---- -000	---- -000	---- -uuu
PTM0DL	0000 0000	0000 0000	uuuu uuuu
PTM0DH	---- --00	---- --00	---- --uu
PTM0AL	0000 0000	0000 0000	uuuu uuuu
PTM0AH	---- --00	---- --00	---- --uu
PTM0BL	0000 0000	0000 0000	uuuu uuuu
PTM0BH	---- --00	---- --00	---- --uu
PTM0RPL	0000 0000	0000 0000	uuuu uuuu
PTM0RPH	---- --00	---- --00	---- --uu
PTM1C0	0000 0---	0000 0---	uuuu u---
PTM1C1	0000 0000	0000 0000	uuuu uuuu
PTM1C2	---- -000	---- -000	---- -uuu
PTM1DL	0000 0000	0000 0000	uuuu uuuu
PTM1DH	---- --00	---- --00	---- --uu
PTM1AL	0000 0000	0000 0000	uuuu uuuu
PTM1AH	---- --00	---- --00	---- --uu
PTM1BL	0000 0000	0000 0000	uuuu uuuu
PTM1BH	---- --00	---- --00	---- --uu
PTM1RPL	0000 0000	0000 0000	uuuu uuuu
PTM1RPH	---- --00	---- --00	---- --uu
EEC	0000 0000	0000 0000	uuuu uuuu
PTM2C0	0000 0---	0000 0---	uuuu u---
PTM2C1	0000 0000	0000 0000	uuuu uuuu
PTM2C2	---- -000	---- -000	---- -uuu
PTM2DL	0000 0000	0000 0000	uuuu uuuu
PTM2DH	---- --00	---- --00	---- --uu
PTM2AL	0000 0000	0000 0000	uuuu uuuu
PTM2AH	---- --00	---- --00	---- --uu
PTM2BL	0000 0000	0000 0000	uuuu uuuu
PTM2BH	---- --00	---- --00	---- --uu
PTM2RPL	0000 0000	0000 0000	uuuu uuuu
PTM2RPH	---- --00	---- --00	---- --uu
PTM3C0	0000 0---	0000 0---	uuuu u---
PTM3C1	0000 0000	0000 0000	uuuu uuuu
PTM3DL	0000 0000	0000 0000	uuuu uuuu
PTM3DH	---- --00	---- --00	---- --uu
PTM3AL	0000 0000	0000 0000	uuuu uuuu
PTM3AH	---- --00	---- --00	---- --uu
PTM3RPL	0000 0000	0000 0000	uuuu uuuu
PTM3RPH	---- --00	---- --00	---- --uu

Note: “u” stands for unchanged

“x” stands for unknown

“.” stands for unimplemented

*: The UUCR1 and SIMC1 registers share the same memory address while the UBRG and SIMTOC registers share the same memory address. The default value of the UUCR1 or UBRG register can be obtained when the UMD bit is set high by application program after a reset.

Input/Output Ports

Holtek microcontrollers offer considerable flexibility on their I/O ports. With the input or output designation of every pin fully under user program control, pull-high selections for all ports and wake-up selections on certain pins, the user is provided with an I/O structure to meet the needs of a wide range of application possibilities.

The device provides bidirectional input/output lines labeled with port names PA~PB. These I/O ports are mapped to the RAM Data Memory with specific addresses as shown in the Special Purpose Data Memory table. All of these I/O ports can be used for input and output operations. For input operation, these ports are non-latching, which means the inputs must be ready at the T2 rising edge of instruction “MOV A, [m]”, where m denotes the port address. For output operation, all the data is latched and remains unchanged until the output latch is rewritten.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PA	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
PAC	PAC7	PAC6	PAC5	PAC4	PAC3	PAC2	PAC1	PAC0
PAPU	PAPU7	PAPU6	PAPU5	PAPU4	PAPU3	PAPU2	PAPU1	PAPU0
PAWU	PAWU7	PAWU6	PAWU5	PAWU4	PAWU3	PAWU2	PAWU1	PAWU0
PB	—	PB6	PB5	PB4	PB3	PB2	PB1	PB0
PBC	—	PBC6	PBC5	PBC4	PBC3	PBC2	PBC1	PBC0
PBPU	—	PBPU6	PBPU5	PBPU4	PBPU3	PBPU2	PBPU1	PBPU0
PAS	—	—	—	PAS4	—	—	—	—
NMSR	REMCHPS1	REMCHPS0	—	—	—	REMDS	ENREM	READYB

“—”: Unimplemented, read as “0”

I/O Logic Function Register List

Pull-high Resistors

Many product applications require pull-high resistors for their switch inputs usually requiring the use of an external resistor. To eliminate the need for these external resistors, all I/O pins, when configured as a digital input have the capability of being connected to an internal pull-high resistor. These pull-high resistors are selected using the relevant pull-high control registers and are implemented using weak PMOS transistors.

Note that the pull-high resistor can be controlled by the relevant pull-high control register only when the pin-shared functional pin is selected as a digital input or NMOS output. Otherwise, the pull-high resistors cannot be enabled.

• PxPU Register

Bit	7	6	5	4	3	2	1	0
Name	PxPU7	PxPU6	PxPU5	PxPU4	PxPU3	PxPU2	PxPU1	PxPU0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

PxPU_n: I/O Port x Pin pull-high function control

0: Disable

1: Enable

The PxPU_n bit is used to control the pin pull-high function. Here the “x” can be A or B. However, the actual available bits for each I/O Port may be different.

Port A Wake-up

The HALT instruction forces the microcontroller into the SLEEP or IDLE Mode which preserves power, a feature that is important for battery and other low-power applications. Various methods exist to wake-up the microcontroller, one of which is to change the logic condition on one of the Port A pins from high to low. This function is especially suitable for applications that can be woken up via external switches. Each pin on Port A can be selected individually to have this wake-up feature using the PAWU register.

Note that the wake-up function can be controlled by the wake-up control registers only when the pin is selected as a general purpose input and the MCU enters the IDLE or SLEEP mode.

• PAWU Register

Bit	7	6	5	4	3	2	1	0
Name	PAWU7	PAWU6	PAWU5	PAWU4	PAWU3	PAWU2	PAWU1	PAWU0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **PAWU7~PAWU0**: PA7~PA0 wake-up function control
 0: Disable
 1: Enable

I/O Port Control Registers

Each I/O port has its own control register known as PAC~PBC, to control the input/output configuration. With this control register, each CMOS output, NMOS output or input can be reconfigured dynamically under software control. Each pin of the I/O ports is directly mapped to a bit in its associated port control register. For the I/O pin to function as an input, the corresponding bit of the control register must be written as a “1”. This will then allow the logic state of the input pin to be directly read by instructions. When the corresponding bit of the control register is written as a “0”, the I/O pin will be setup as a CMOS output or a NMOS output for PA4 Pin. If the pin is currently setup as an output, instructions can still be used to read the output register. However, it should be noted that the program will in fact only read the status of the output data latch and not the actual logic status of the output pin.

• PxC Register

Bit	7	6	5	4	3	2	1	0
Name	PxC7	PxC6	PxC5	PxC4	PxC3	PxC2	PxC1	PxC0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	1	1	1	1	1	1	1	1

PxCn: I/O Port x pin type selection
 0: Output
 1: Input

The PxCn bit is used to control the pin type selection. Here the “x” can be A or B. However, the actual available bits for each I/O Port may be different.

PA4 Pin High Current Output Function Control

The device has a control register known as PAS, to control the CMOS/NMOS output configuration. With this control register, each CMOS output or NMOS output structures can be reconfigured dynamically under software control. This pin is directly mapped to a bit in its associated port control register. For the I/O pin to function as a NMOS output structure, the corresponding bit of the control register must be written as a “1”. This will then allow the logic state of the input pin to be directly read by instructions. When the corresponding bit of the control register is written as a “0”, the I/O

pin will be setup as a CMOS output. If the pin is currently setup as an output, instructions can still be used to read the output register. However, it should be noted that the program will in fact only read the status of the output data latch and not the actual logic status of the output pin.

When the NMOS output is selected by PAS4 bit, the frequency of the Din signal must be less than 56kHz, and the control signal source is from the Din signal, which is selected as PA4 or CTP0 pin by the REMDS bit.

PA4 Pin High Current Output Function Registers

Register Name	Bit							
	7	6	5	4	3	2	1	0
PAS	—	—	—	PAS4	—	—	—	—
NMSR	REMCHPS1	REMCHPS0	—	—	—	REMDS	REMEN	READYB

PA4 Pin High Current Output Function Selection Register List

• PAS Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	PAS4	—	—	—	—
R/W	—	—	—	R/W	—	—	—	—
POR	—	—	—	0	—	—	—	—

- Bit 7~5 Unimplemented, read as “0”
- Bit 4 **PAS4**: PA4 output type selection bit
0: CMOS
1: NMOS
- Bit 3~0 Unimplemented, read as “0”

• NMSR Register

Bit	7	6	5	4	3	2	1	0
Name	REMCHPS1	REMCHPS0	—	—	—	REMDS	REMEN	READYB
R/W	R/W	R/W	—	—	—	R/W	R/W	R
POR	1	1	—	—	—	0	0	0

- Bit 7~6 **REMCHPS1~REMCHPS0**: REM charge pump frequency divider selection
00: $f_H/1$ (HIRC=4MHz)
01: $f_H/2$ (HIRC=8MHz)
10: $f_H/3$ (HIRC=12MHz)
11: Reserved

These bits are used to select the frequency source of the internal charge pump. It should be note that users must set these two bits correctly before enable the REMEN bit and remains the frequency equal to 4MHz.
- Bit 5~3 Unimplemented, read as “0”
- Bit 2 **REMDS**: Din signal source selection
0: PA4
1: CTP0

It should be note that the frequency of the Din signal must be less than 56kHz.
- Bit 1 **REMEN**: Internal charge pump switch on/off control
0: Disable
1: Enable

This bit is used to enable the internal charge pump circuit and is only available when the PA4 pin is configured as an NMOS type output by clearing the PAC4 bit to zero and setting the PAS4 bit high. When a HALT instruction is executed, the charge pump circuit will be turned off automatically until the MCU is woken up.

- Note: 1. When the V_{DD} is powered by less than 3V, REMEN bit must be set high to enable Internal Charge Pump. The REM_OUT outputs V_{CP} or DV_{SS} signal according to the D_C TAL to drive NMOS output.
2. When V_{DD} is powered by 3V or above, REMEN bit must be set to zero to disable the Internal Charge Pump. The REM_OUT outputs V_{DD} or DV_{SS} signal according to the D_C TAL to drive NMOS output. If REMEN is set high, it may cause IC damage.
3. Before enabling REMEN bit, users can refer to “REMCHPS1~ REMCHPS0” bits for correct setting.

Bit 0 **READYB**: PA4 pin high current output function ready flag

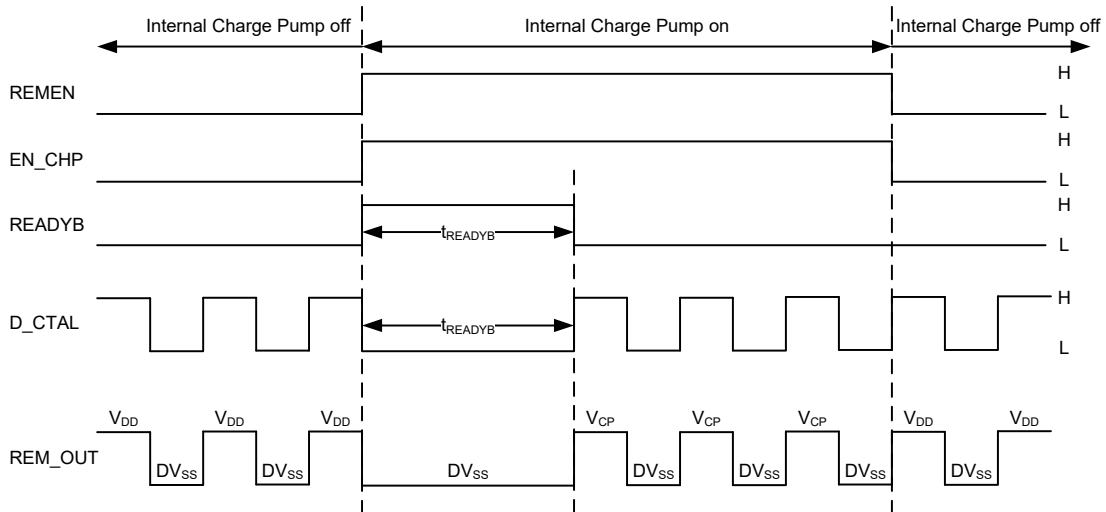
- 0: Ready
- 1: Not ready

This bit is used to indicate that whether the NMOS output driver is ready to deliver the data signal or not. This bit is only available when the REMEN bit has been set high and the output function is NMOS type. When the high current output function is enabled, including a wake-up from the IDLE/SLEEP mode or an output function switch from CMOS to NMOS type with the REMEN bit set high, a certain period delay is necessary for the NMOS output driver to become stable before the data signal is sent to the PA4 output pin. Ensure that the NMOS output driver is ready by polling the READYB bit before delivering the data signal. Note that in CMOS output function the READYB bit is not available and is always read as “0”.

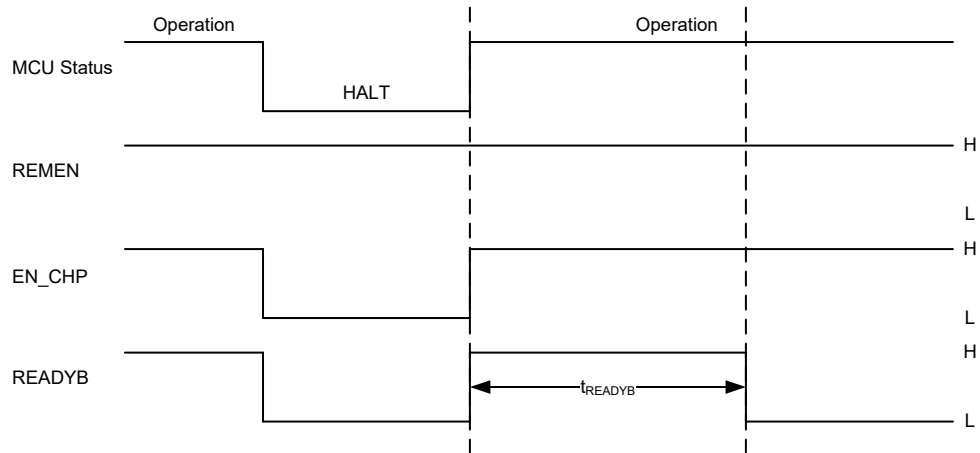
When in the NMOS output mode and the REMEN bit changes from “0” to “1”, the charge pump will be activated, the READYB bit will first be set to “1”, after a certain period delay, known as t_{READYB} , it will be cleared to “0” indicating that the REM_OUT output is V_{CP} , which means that D_C TAL signal can be input to control the NMOS on/off output state.

When the charge pump is done, if the REMEN bit remains at “1”, users need’n to determine the READYB flag, or the REMEN bit switches from “1” to “0”, then the charge pump will be turned off and users need’n to determine the READYB flag.

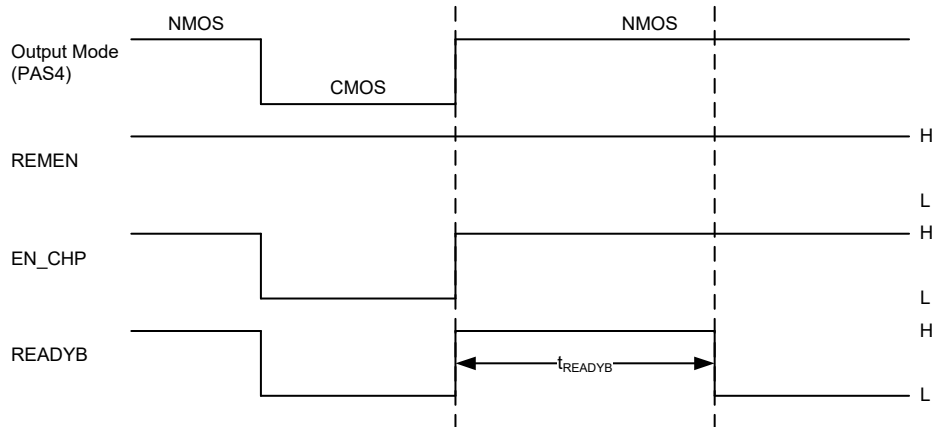
More details regarding the relationship between the relevant register settings and the internal charge pump control will be described in the I/O Pin Structures section.



When REMEN bit is equal to “1” and a HALT instruction is executed, the charge pump circuit will be turned off. After the MCU is woken up, the charge pump must be re-enabled. The READYB bit will first be set to “1”, after a certain period delay, known as t_{READYB} , it will be cleared to “0”, which means that D_C TAL signal can be input to control the NMOS on/off output state.



When REMEN bit is equal to “1” and in the CMOS output mode, the charge pump circuit will be turned off. When returns in NMOS output mode, the charge pump must be re-enabled. The READYB bit will first be set to “1”, after a certain period delay, known as t_{READYB} , it will be cleared to “0”, which means that D_CTAL signal can be input to control the NMOS on/off output state.



Pin-shared Functions

The flexibility of the microcontroller range is greatly enhanced by the use of pins that have more than one function. Limited numbers of pins can force serious design constraints on designers but by supplying pins with multi-functions, many of these difficulties can be overcome. For these pins, the desired function of the multi-function I/O pins is selected by a series of registers via the application program control.

Pin-shared Function Selection Registers

The limited number of supplied pins in a package can impose restrictions on the amount of functions a certain device can contain. However by allowing the same pins to share several different functions and providing a means of function selection, a wide range of different functions can be incorporated into even relatively small package sizes. The device includes Port “x” Output Function Selection register “n”, labeled as P_xS_n, and Input Function Selection register, labeled as IFS, which can select the desired functions of the multi-function pin-shared pins.

The most important point to note is to make sure that the desired pin-shared function is properly selected and also deselected. For most pin-shared functions, to select the desired pin-shared function, the pin-shared function should first be correctly selected using the corresponding pin-shared control register. After that the corresponding peripheral functional setting should be configured and then the peripheral function can be enabled. However, a special point must be noted for some digital input pins, such as INTn, xTCKn, PTPnI etc, which share the same pin-shared control configuration with their corresponding general purpose I/O functions when setting the relevant pin-shared control bit fields. To select these pin functions, in addition to the necessary pin-shared control and peripheral functional setup aforementioned, they must also be setup as an input by setting the corresponding bit in the I/O port control register. To correctly deselect the pin-shared function, the peripheral function should first be disabled and then the corresponding pin-shared function control register can be modified to select other pin-shared functions.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PAS0	PAS07	PAS06	PAS05	PAS04	PAS03	PAS02	PAS01	PAS00
PAS1	PAS17	PAS16	PAS15	PAS14	PAS13	PAS12	PAS11	PAS10
PBS0	PBS07	PBS06	PBS05	PBS04	PBS03	PBS02	PBS01	PBS00
PBS1	—	—	PBS15	PBS14	PBS13	PBS12	PBS11	PBS10
IFS	—	—	—	—	IFS3	IFS2	IFS1	IFS0

Pin-shared Function Selection Register List

• **PAS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PAS07	PAS06	PAS05	PAS04	PAS03	PAS02	PAS01	PAS00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7~6 **PAS07~PAS06:** PA3 Pin-Shared function selection
00: PA3
01: A2PI
10: PA3
11: PA3
- Bit 5~4 **PAS05~PAS04:** PA2 Pin-Shared function selection
00: PA2
01: OVP00
10: AN1
11: SDO/UTX
- Bit 3~2 **PAS03~PAS02:** PA1 Pin-Shared function selection
00: PA1/INT0
01: PTP0
10: CTP1
11: SDI/SDA/URX/UTX
- Bit 1~0 **PAS01~PAS00:** PA0 Pin-Shared function selection
00: PA0
01: PTP3
10: OVP01
11: AN0

• **PAS1 Register**

Bit	7	6	5	4	3	2	1	0
Name	PAS17	PAS16	PAS15	PAS14	PAS13	PAS12	PAS11	PAS10
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PAS17~PAS16:** PA7 Pin-Shared function selection

00: PA7
01: A00
10: PTP1
11: VREF

Bit 5~4 **PAS15~PAS14:** PA6 Pin-Shared function selection

00: PA6
01: A10
10: PA6
11: PA6

Bit 3~2 **PAS13~PAS12:** PA5 Pin-Shared function selection

00: PA5
01: CTP1B
10: OVP10
11: SCK/SCL

Bit 1~0 **PAS11~PAS10:** PA4 Pin-Shared function selection

00: PA4
01: CTP0
10: PTP2B
11: PA4

• **PBS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PBS07	PBS06	PBS05	PBS04	PBS03	PBS02	PBS01	PBS00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PBS07~PBS06:** PB3 Pin-Shared function selection

00: PB3/INT1
01: PTP0B
10: CTP0B
11: AN2

Bit 5~4 **PBS05~PBS04:** PB2 Pin-Shared function selection

00: PB2/PTP1I
01: A20
10: OVP2I
11: PB2/PTP1I

Bit 3~2 **PBS03~PBS02:** PB1 Pin-Shared function selection

00: PB1/PTP0I/PTP2I
01: PTP2
10: A2NI
11: OVP1I

Bit 1~0 **PBS01~PBS00:** PB0 Pin-Shared function selection

00: PB0/PTP3I
01: \overline{SCS}
10: LVDIN
11: PB0/PTP3I

• **PBS1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	PBS15	PBS14	PBS13	PBS12	PBS11	PBS10
R/W	—	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

- Bit 7~6 Unimplemented, read as “0”
- Bit 5~4 **PBS15~PBS14:** PB6 Pin-Shared function selection
 00: PB6/PTCK3/CTCK1
 01: PTP1B
 10: AN3
 11: SDI/SDA/URX/UTX
- Bit 3~2 **PBS13~PBS12:** PB5 Pin-Shared function selection
 00: PB5/PTCK0/PTCK1/CTCK0
 01: SDO/UTX
 10: PB5/PTCK0/PTCK1/CTCK0
 11: PB5/PTCK0/PTCK1/CTCK0
- Bit 1~0 **PBS11~PBS10:** PB4 Pin-Shared function selection
 00: PB4/PTCK2
 01: PTP3B
 10: OVP2O
 11: PB4/PTCK2

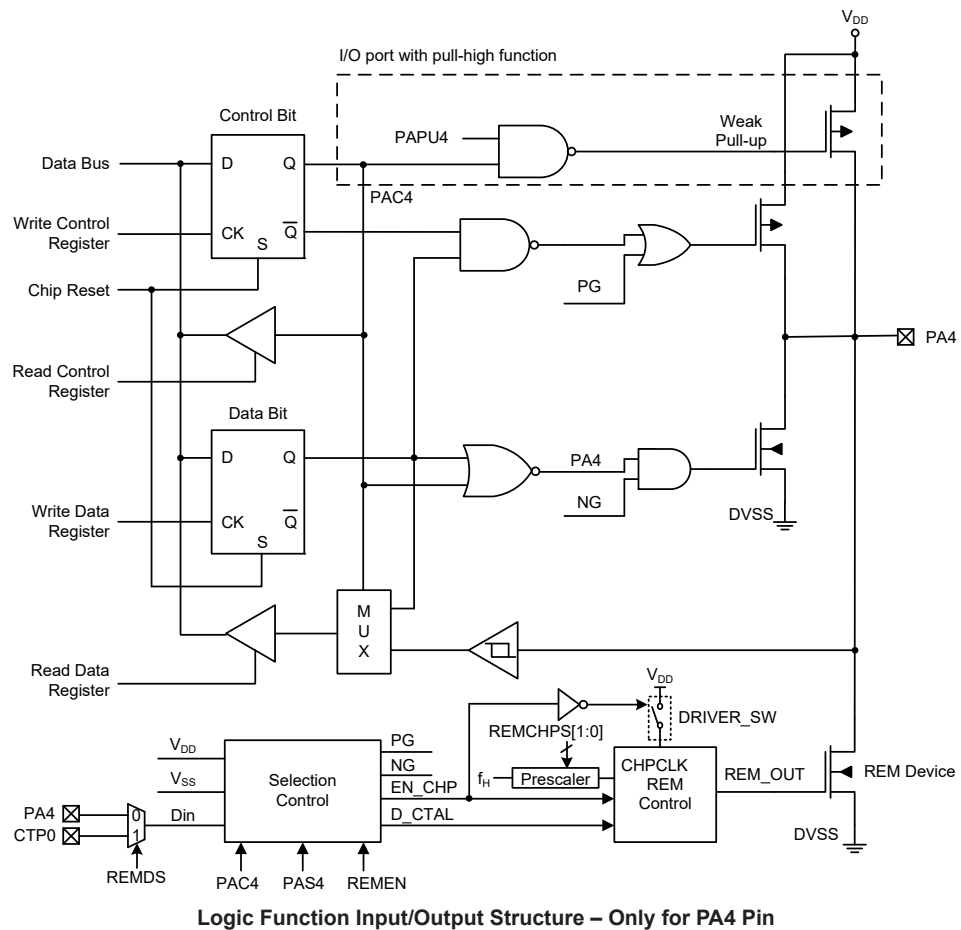
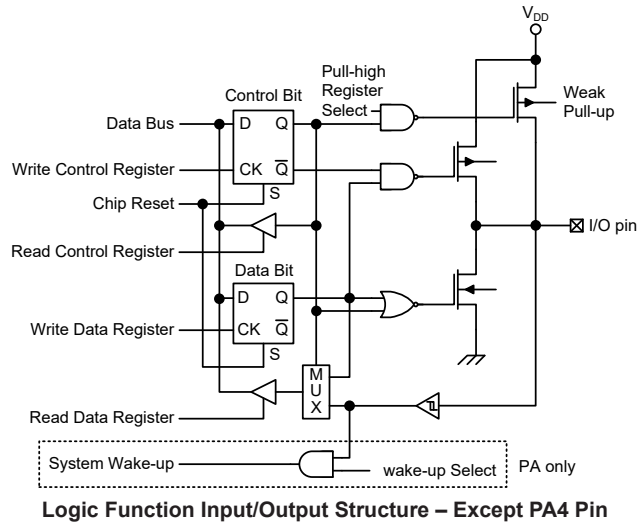
• **IFS Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	IFS3	IFS2	IFS1	IFS0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

- Bit 7~4 Unimplemented, read as “0”
- Bit 3 **IFS3:** PTP2I input source pin selection
 0: OVP2O
 1: PB1
- Bit 2 **IFS2:** PTP1I input source pin selection
 0: OVP1O
 1: PB2
- Bit 1 **IFS1:** PTP0I input source pin selection
 0: OVP0O
 1: PB1
- Bit 0 **IFS0:** SDI/SDA/URX/UTX input source pin selection
 0: PA1
 1: PB6

I/O Pin Structures

The accompanying diagram illustrates the internal structure of the I/O logic function. As the exact logical construction of the I/O pin will differ from this drawing, it is supplied as a guide only to assist with the functional understanding of the I/O logic function. The wide range of pin-shared structures does not permit all types to be shown.



Modes	Selection Control							REM Control		
	Input			Output				Internal Charge Pump Circuit	REM_OUT	REM_OUT Voltage
	PAC4	PAS4	REMEN	PG	NG	D_CTAL	EN_CHP			
CMOS	0	0	x	0	1	0	0	Off	0	DV _{SS}
NMOS	0	1	0	1	0	Din	0	Off	Din	V _{DD} /DV _{SS}
			1							1
Input	1	x	x	1	0	0	0	Off	0	DV _{SS}

“x”: Don't care

Note: 1. V_{CP} is the charge pump voltage.
 2. REM charge pump clock=4MHz.

Programming Considerations

Within the user program, one of the first things to consider is port initialisation. After a reset, all of the I/O data and port control registers will be set high. This means that all I/O pins will default to an input state, the level of which depends on the other connected circuitry and whether pull-high selections have been chosen. If the port control registers are then programmed to setup some pins as outputs, these output pins will have an initial high output value unless the associated port data registers are first programmed. Selecting which pins are inputs and which are outputs can be achieved byte-wide by loading the correct values into the appropriate port control register or by programming individual bits in the port control register using the “SET [m].i” and “CLR [m].i” instructions. Note that when using these bit control instructions, a read-modify-write operation takes place. The microcontroller must first read in the data on the entire port, modify it to the required new bit values and then rewrite this data back to the output ports.

Port A has the additional capability of providing wake-up function. When the device is in the SLEEP or IDLE Mode, various methods are available to wake the device up. One of these is a high to low transition of any of the Port A pins. Single or multiple pins on Port A can be setup to have this function.

Timer Modules – TM

One of the most fundamental functions in any microcontroller device is the ability to control and measure time. To implement time related functions the device includes several Timer Modules, generally abbreviated to the name TM. The TMs are multi-purpose timing units and serve to provide operations such as Timer/Counter, Input Capture, Compare Match Output and Single Pulse Output as well as being the functional unit for the generation of PWM signals. Each of the TMs has two interrupts. The addition of input and output pins for TM ensures that users are provided with timing units with a wide and flexible range of features.

The common features of the different TM types are described here with more detailed information provided in the individual Compact and Periodic TM sections.

Introduction

The device contains two TM units and each individual TM can be categorised as a certain type, namely Compact Type TM or Periodic Type TM. Although similar in nature, the different TM types vary in their feature complexity. The common features to all of the Compact and Periodic Type TMs will be described in this section and the detailed operation regarding each of the TM types will be described in separate sections. The main features and differences between the two types of TMs are summarised in the accompanying table.

Function	CTM	PTM
Timer/Counter	√	√
Input Capture	—	√
Compare Match Output	√	√
PWM Output	—	√
Single Pulse Output	√	√
PWM Alignment	Edge	Edge
PWM Adjustment Period & Duty	Duty or Period	Duty or Period

TM Function Summary

CTMn (n=0~1)	PTMn (n=0~3)
10-bit CTM	10-bit PTM

TM Name/Type Reference

TM Operation

The different types of TM offer a diverse range of functions, from simple timing operations to PWM signal generation. The key to understanding how the TM operates is to see it in terms of a free running counter whose value is then compared with the value of pre-programmed internal comparators. When the free running count-up counter has the same value as the pre-programmed comparator, known as a compare match situation, a TM interrupt signal will be generated which can clear the counter and perhaps also change the condition of the TM output pin. The internal TM counter is driven by a user selectable clock source, which can be an internal clock or an external pin.

TM Clock Source

The clock source which drives the main counter in the each TM can originate from various sources. The selection of the required clock source is implemented using the xTnCK2~xTnCK0 bits in the xTMn control registers, where “x” stands for C or P type TM and “n” stands for the specific TM serial number. The clock source can be a ratio of the system clock f_{SYS} or the internal high clock f_{IH} , the f_{SUB} clock source or the external xTCKn pin. The xTCKn pin clock source is used to allow an external signal to drive the TM as an external clock source or for event counting.

TM Interrupts

Each of the Compact or Periodic type TM has two internal interrupts, the internal comparator A or comparator P, which generate a TM interrupt when a compare match condition occurs. When a TM interrupt is generated, it can be used to clear the counter and also to change the state of the TM output pin.

TM External Pins

Each of the TMs, irrespective of what type, has one TM input pin, with the label xTCKn. The xTMn input pin, xTCKn, is essentially a clock source for the xTMn and is selected using the xTnCK2~xTnCK0 bits in the xTMnC0 register. This external TM input pin allows an external clock source to drive the internal TM. The xTCKn input pin can be chosen to have either a rising or falling active edge. The xTCKn pin is also used as the external trigger input pin in single pulse output mode.

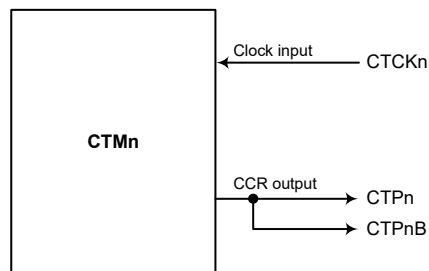
The other PTMn input pin, PTPnI, is the capture input whose active edge can be a rising edge, a falling edge or both rising and falling edges and the active edge transition type is selected using the PTnIO1~PTnIO0 bits in the PTMnC1 register. There is another capture input, PTCKn, for PTM capture input mode, which can be used as the external trigger input source.

The TMs each have two output pins, xTPn and xTPnB. The xTPnB pin outputs the inverted signal of the xTPn. When the TM is in the Compare Match Output Mode, these pins can be controlled by the TM to switch to a high or low level or to toggle when a compare match situation occurs. The external xTPn and xTPnB output pin are also the pins where the TM generates the PWM output waveform.

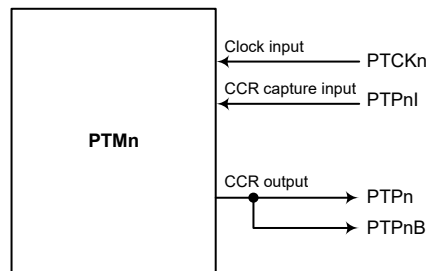
As the TM input and output pins are pin-shared with other functions, the TM input and output functions must first be setup using the relevant pin-shared function selection bits described in the Pin-shared Function section. The details of the pin-shared function selection are described in the pin-shared function section.

CTM		PTM	
Input	Output	Input	Output
CTCK0 CTCK1	CTP0, CTP0B CTP1, CTP1B	PTCK0, PTP0I PTCK1, PTP1I PTCK2, PTP2I PTCK3, PTP3I	PTP0, PTP0B PTP1, PTP1B PTP2, PTP2B PTP3, PTP3B

TM External Pins



CTMn Function Pin Block Diagram (n=0~1)

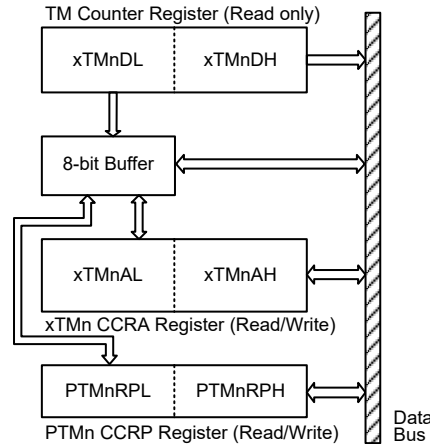


PTMn Function Pin Block Diagram (n=0~3)

Programming Considerations

The TM Counter Registers and the Compare CCRA and CCRP register, all have a low and high byte structure. The high bytes can be directly accessed, but as the low bytes can only be accessed via an internal 8-bit buffer, reading or writing to these register pairs must be carried out in a specific way. The important point to note is that data transfer to and from the 8-bit buffer and its related low byte only takes place when a write or read operation to its corresponding high byte is executed.

As the CCRA and CCRP registers are implemented in the way shown in the following diagram and accessing these register pairs is carried out in a specific way as described above, it is recommended to use the "MOV" instruction to access the CCRA and CCRP low byte registers, named xTMnAL and PTMnRPL, using the following access procedures. Accessing the CCRA or CCRP low byte registers without following these access procedures will result in unpredictable values.

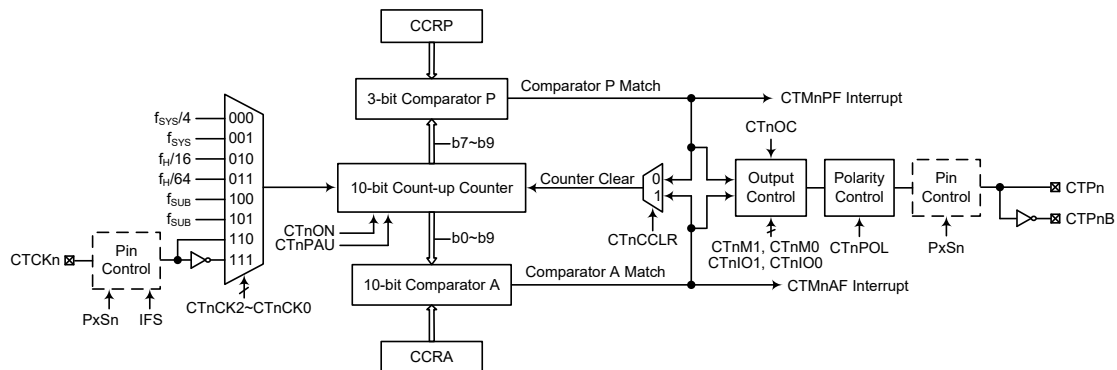


The following steps show the read and write procedures:

- Writing Data to CCRA or CCRP
 - ♦ Step 1. Write data to low byte xTMnAL or PTMnRPL
 - Note that here data is only written to the 8-bit buffer.
 - ♦ Step 2. Write data to high byte xTMnAH or PTMnRPH
 - Here data is written directly to the high byte registers and simultaneously data is latched from the 8-bit buffer to the low byte registers.
- Reading Data from the Counter Registers and CCRA or CCRP
 - ♦ Step 1. Read data from the high byte xTMnDH, xTMnAH or PTMnRPH
 - Here data is read directly from the high byte registers and simultaneously data is latched from the Low Byte register into the 8-bit buffer.
 - ♦ Step 2. Read data from the low byte xTMnDL, xTMnAL or PTMnRPL
 - This step reads data from the 8-bit buffer.

Compact Type TM – CTM

Although the simplest form of the TM types, the Compact TM type still contains three operating modes, which are Compare Match Output, Timer/Event Counter and PWM Output modes. The Compact TM can be controlled with an external input pin and can drive two external output pins.



- Note: 1. As the CTMn external pins are pin-shared with other functions, the relevant pin-shared control bits should be properly configured before using these pins.
 2. The CTPnB is the inverted signal of the CTPn.

10-bit Compact Type TM Block Diagram (n=0~1)

Compact Type TM Operation

At its core is a 10-bit count-up counter which is driven by a user selectable internal or external clock source. There are also two internal comparators with the names, Comparator A and Comparator P. These comparators will compare the value in the counter with CCRP and CCRA registers. The CCRP is 3-bit wide whose value is compared with the highest three bits in the counter while the CCRA is 10-bit wide and therefore compares with all counter bits.

The only way of changing the value of the 10-bit counter using the application program, is to clear the counter by changing the CTnON bit from low to high. The counter will also be cleared automatically by a counter overflow or a compare match with one of its associated comparators. When these conditions occur, a CTM interrupt signal will also usually be generated. The Compact Type TM can operate in a number of different operational modes, can be driven by different clock sources including an input pin and can also control two output pins. All operating setup conditions are selected using relevant internal registers.

Compact Type TM Register Description

Overall operation of the Compact Type TM is controlled using a series of registers. A read only register pair exists to store the internal counter 10-bit value, while a read/write register pair exists to store the internal 10-bit CCRA value. The remaining two registers are control registers which setup the different operating and control modes as well as the three CCRP bits.

Register Name	Bit							
	7	6	5	4	3	2	1	0
CTMnC0	CTnPAU	CTnCK2	CTnCK1	CTnCK0	CTnON	CTnRP2	CTnRP1	CTnRP0
CTMnC1	CTnM1	CTnM0	CTnIO1	CTnIO0	CTnOC	CTnPOL	CTnDPX	CTnCCLR
CTMnDL	D7	D6	D5	D4	D3	D2	D1	D0
CTMnDH	—	—	—	—	—	—	D9	D8
CTMnAL	D7	D6	D5	D4	D3	D2	D1	D0
CTMnAH	—	—	—	—	—	—	D9	D8

10-bit Compact TM Register List (n=0~1)

• CTMnC0 Register

Bit	7	6	5	4	3	2	1	0
Name	CTnPAU	CTnCK2	CTnCK1	CTnCK0	CTnON	CTnRP2	CTnRP1	CTnRP0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **CTnPAU**: CTMn Counter Pause Control

0: Run
 1: Pause

The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the CTMn will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

Bit 6~4 **CTnCK2~CTnCK0**: Select CTMn Counter clock

000: $f_{SYS}/4$
 001: f_{SYS}
 010: $f_H/16$
 011: $f_H/64$
 100: f_{SUB}
 101: f_{SUB}
 110: CTCKn rising edge clock
 111: CTCKn falling edge clock

These three bits are used to select the clock source for the CTMn. The external pin clock source can be chosen to be active on the rising or falling edge. The clock source f_{SYS} is the system clock, while f_{IH} and f_{SUB} are other internal clocks, the details of which can be found in the oscillator section.

Bit 3 **CTnON:** CTMn Counter On/Off Control
 0: Off
 1: On

This bit controls the overall on/off function of the CTMn. Setting the bit high enables the counter to run, clearing the bit disables the CTMn. Clearing this bit to zero will stop the counter from counting and turn off the CTMn which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again.

If the CTMn is in the Compare Match Output Mode or the PWM Output Mode then the CTMn output pin will be reset to its initial condition, as specified by the CTnOC bit, when the CTnON bit changes from low to high.

Bit 2~0 **CTnRP2~CTnRP0:** CTMn CCRP 3-bit register, compared with the CTMn Counter bit 9 ~ bit 7 Comparator P Match Period
 000: 1024 CTMn clocks
 001: 128 CTMn clocks
 010: 256 CTMn clocks
 011: 384 CTMn clocks
 100: 512 CTMn clocks
 101: 640 CTMn clocks
 110: 768 CTMn clocks
 111: 896 CTMn clocks

These three bits are used to setup the value on the internal CCRP 3-bit register, which are then compared with the internal counter's highest three bits. The result of this comparison can be selected to clear the internal counter if the CTnCCLR bit is set to zero. Setting the CTnCCLR bit to zero ensures that a compare match with the CCRP values will reset the internal counter. As the CCRP bits are only compared with the highest three counter bits, the compare values exist in 128 clock cycle multiples. Clearing all three bits to zero is in effect allowing the counter to overflow at its maximum value.

• **CTMnC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	CTnM1	CTnM0	CTnIO1	CTnIO0	CTnOC	CTnPOL	CTnDPX	CTnCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **CTnM1~CTnM0:** Select CTMn Operating Mode
 00: Compare Match Output Mode
 01: Undefined
 10: PWM Output Mode
 11: Timer/Counter Mode

These bits setup the required operating mode for the CTMn. To ensure reliable operation the CTMn should be switched off before any changes are made to the CTnM1 and CTnM0 bits. In the Timer/Counter Mode, the CTMn output pin state is undefined.

Bit 5~4 **CTnIO1~CTnIO0:** Select CTMn external pin function
 Compare Match Output Mode
 00: No change
 01: Output low
 10: Output high
 11: Toggle output

PWM Output Mode
00: PWM Output inactive state
01: PWM Output active state
10: PWM Output
11: Undefined

Timer/Counter Mode
Unused

These two bits are used to determine how the CTMn external pin changes state when a certain condition is reached. The function that these bits select depends upon in which mode the CTMn is running.

In the Compare Match Output Mode, the CTnIO1 and CTnIO0 bits determine how the CTMn output pin changes state when a compare match occurs from the Comparator A. The CTMn output pin can be setup to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the bits are both zero, then no change will take place on the output. The initial value of the CTMn output pin should be setup using the CTnOC bit in the CTnMC1 register. Note that the output level requested by the CTnIO1 and CTnIO0 bits must be different from the initial value setup using the CTnOC bit otherwise no change will occur on the CTMn output pin when a compare match occurs. After the CTMn output pin changes state it can be reset to its initial level by changing the level of the CTnON bit from low to high.

In the PWM Output Mode, the CTnIO1 and CTnIO0 bits determine how the CTMn output pin changes state when a certain compare match condition occurs. The PWM output function is modified by changing these two bits. It is necessary to only change the values of the CTnIO1 and CTnIO0 bits only after the CTMn has been switched off. Unpredictable PWM outputs will occur if the CTnIO1 and CTnIO0 bits are changed when The CTMn is running.

Bit 3 **CTnOC**: CTPn Output control bit

Compare Match Output Mode

0: Initial low
1: Initial high

PWM Output Mode

0: Active low
1: Active high

This is the output control bit for the CTMn output pin. Its operation depends upon whether CTMn is being used in the Compare Match Output Mode or in the PWM Output Mode. It has no effect if the CTMn is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the CTMn output pin before a compare match occurs. In the PWM Output Mode it determines if the PWM signal is active high or active low.

Bit 2 **CTPnOL**: CTPn Output polarity Control

0: Non-invert
1: Invert

This bit controls the polarity of the CTPn output pin. When the bit is set high the CTMn output pin will be inverted and not inverted when the bit is zero. It has no effect if the CTMn is in the Timer/Counter Mode.

Bit 1 **CTnDPX**: CTMn PWM period/duty Control

0: CCRP – period; CCRA – duty
1: CCRP – duty; CCRA – period

This bit determines which of the CCRA and CCRP registers are used for period and duty control of the PWM waveform.

Bit 0 **CTnCCLR**: Select CTMn Counter clear condition

0: CTM Comparatror P match
1: CTM Comparatror A match

This bit is used to select the method which clears the counter. Remember that the Compact TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the CTnCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The CTnCCLR bit is not used in the PWM Output Mode.

• **CTMnDL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0:** CTMn Counter Low Byte Register bit 7 ~ bit 0
CTMn 10-bit Counter bit 7 ~ bit 0

• **CTMnDH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R	R
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”
Bit 1~0 **D9~D8:** CTMn Counter High Byte Register bit 1 ~ bit 0
CTMn 10-bit Counter bit 9 ~ bit 8

• **CTMnAL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0:** CTMn CCRA Low Byte Register bit 7 ~ bit 0
CTMn 10-bit CCRA bit 7 ~ bit 0

• **CTMnAH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”
Bit 1~0 **D9~D8:** CTMn CCRA High Byte Register bit 1 ~ bit 0
CTMn 10-bit CCRA bit 9 ~ bit 8

Compact Type TM Operating Modes

The Compact Type TM can operate in one of three operating modes, Compare Match Output Mode, PWM Output Mode or Timer/Counter Mode. The operating mode is selected using the CTnM1 and CTnM0 bits in the CTMnC1 register.

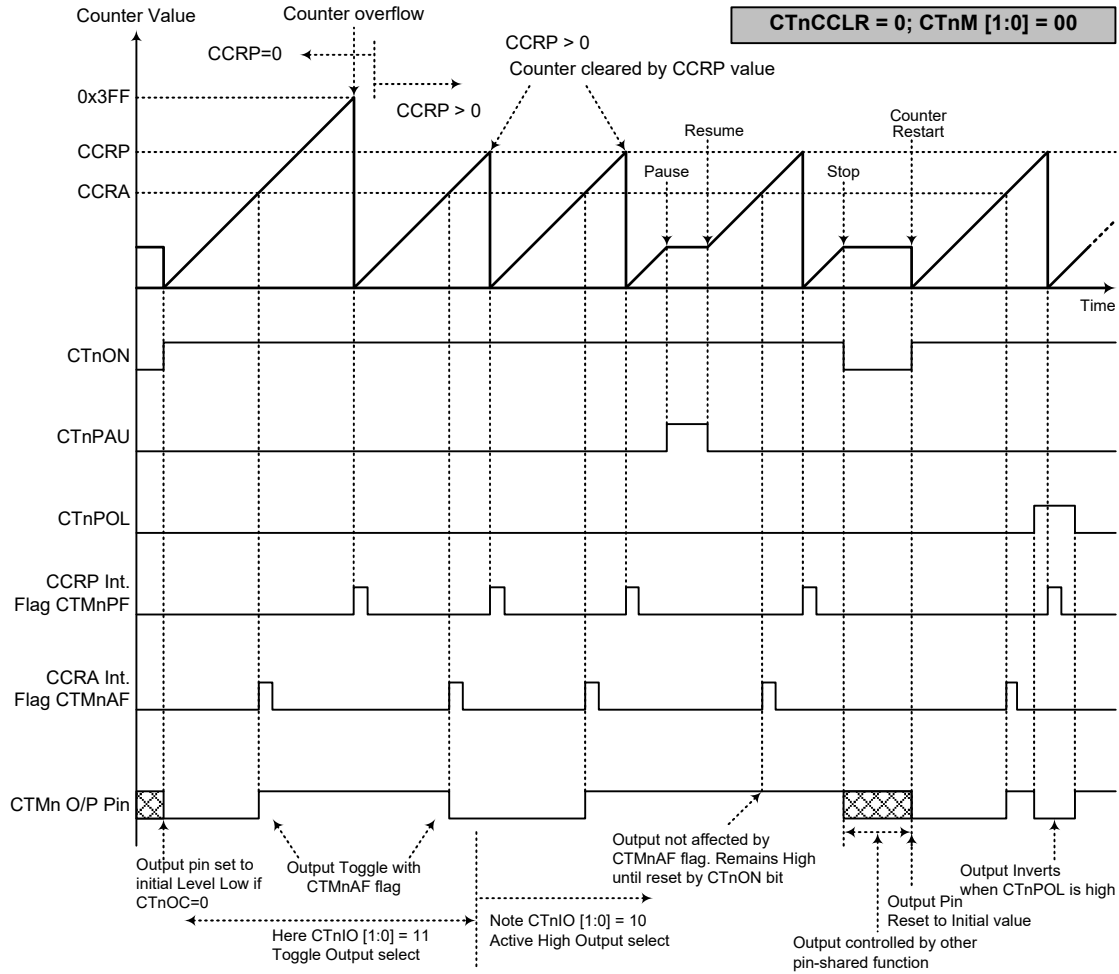
Compare Match Output Mode

To select this mode, bits CTnM1 and CTnM0 in the CTMnC1 register, should be set to 00 respectively. In this mode once the counter is enabled and running it can be cleared by three methods. These are a counter overflow, a compare match from Comparator A and a compare match from Comparator P. When the CTnCCLR bit is low, there are two ways in which the counter can be cleared. One is when a compare match occurs from Comparator P, the other is when the CCRP bits are all zero which allows the counter to overflow. Here both CTnMAF and CTnMPF interrupt request flags for the Comparator A and Comparator P respectively, will both be generated.

If the CTnCCLR bit in the CTMnC1 register is high then the counter will be cleared when a compare match occurs from Comparator A. However, here only the CTMnAF interrupt request flag will be generated even if the value of the CCRP bits is less than that of the CCRA registers. Therefore when CTnCCLR is high no CTMnPF interrupt request flag will be generated.

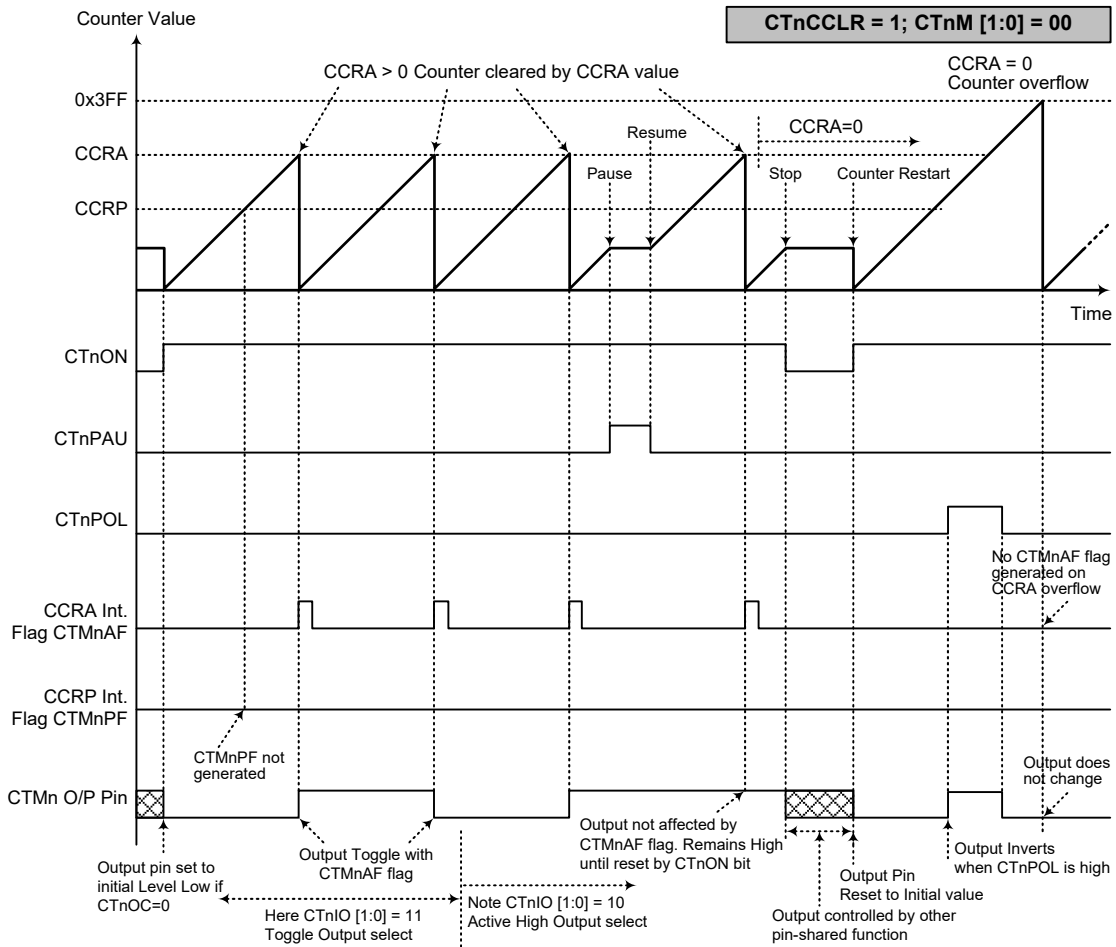
If the CCRA bits are all zero, the counter will overflow when it reaches its maximum 10-bit, 3FF Hex, value, however here the CTMnAF interrupt request flag will not be generated.

As the name of the mode suggests, after a comparison is made, the CTMn output pin will change state. The CTMn output pin condition however only changes state when a CTMnAF interrupt request flag is generated after a compare match occurs from Comparator A. The CTMnPF interrupt request flag, generated from a compare match occurs from Comparator P, will have no effect on the CTMn output pin. The way in which the CTMn output pin changes state are determined by the condition of the CTnIO1 and CTnIO0 bits in the CTMnC1 register. The CTMn output pin can be selected using the CTnIO1 and CTnIO0 bits to go high, to go low or to toggle from its present condition when a compare match occurs from Comparator A. The initial condition of the CTMn output pin, which is setup after the CTnON bit changes from low to high, is setup using the CTnOC bit. Note that if the CTnIO1 and CTnIO0 bits are zero then no pin change will take place.



Compare Match Output Mode – CTnCCR=0

- Note: 1. With CTnCCR=0, a Comparator P match will clear the counter
 2. The CTMn output pin is controlled only by the CTMnAF flag
 3. The output pin reset to initial state by a CTnON bit rising edge
 4. n=0~1



Compare Match Output Mode – CTnCCLR=1

- Note: 1. With CTnCCLR=1, a Comparator A match will clear the counter
 2. The CTMn output pin is controlled only by the CTMnAF flag
 3. The output pin reset to initial state by a CTnON bit rising edge
 4. The CTMnPF flags is not generated when CTnCCLR=1
 5. n=0~1

Timer/Counter Mode

To select this mode, bits CTnM1 and CTnM0 in the CTMnC1 register should be set to 11 respectively. The Timer/Counter Mode operates in an identical way to the Compare Match Output Mode generating the same interrupt flags. The exception is that in the Timer/Counter Mode the CTMn output pin is not used. Therefore the above description and Timing Diagrams for the Compare Match Output Mode can be used to understand its function. As the CTMn output pin is not used in this mode, the pin can be used as a normal I/O pin or other pin-shared function.

PWM Output Mode

To select this mode, bits CTnM1 and CTnM0 in the CTnMC1 register should be set to 10 respectively. The PWM function within the CTMn is useful for applications which require functions such as motor control, heating control, illumination control etc. By providing a signal of fixed frequency but of varying duty cycle on the CTMn output pin, a square wave AC waveform can be generated with varying equivalent DC RMS values.

As both the period and duty cycle of the PWM waveform can be controlled, the choice of generated waveform is extremely flexible. In the PWM Output Mode, the CTnCCLR bit has no effect on the PWM operation. Both of the CCRA and CCRP registers are used to generate the PWM waveform, one register is used to clear the internal counter and thus control the PWM waveform frequency, while the other one is used to control the duty cycle. Which register is used to control either frequency or duty cycle is determined using the CTnDPX bit in the CTMnC1 register. The PWM waveform frequency and duty cycle can therefore be controlled by the values in the CCRA and CCRP registers.

An interrupt flag, one for each of the CCRA and CCRP, will be generated when a compare match occurs from either Comparator A or Comparator P. The CTnOC bit in the CTMnC1 register is used to select the required polarity of the PWM waveform while the two CTnIO1 and CTnIO0 bits are used to enable the PWM output or to force the CTMn output pin to a fixed high or low level. The CTnPOL bit is used to reverse the polarity of the PWM output waveform.

• **10-bit CTMn, PWM Output Mode, Edge-aligned Mode, CTnDPX=0**

CCRP	1~7	0
Period	CCRP×128	1024
Duty	CCRA	

If $f_{SYS}=8\text{MHz}$, CTMn clock source is $f_{SYS}/4$, CCRP=2 and CCRA=128,

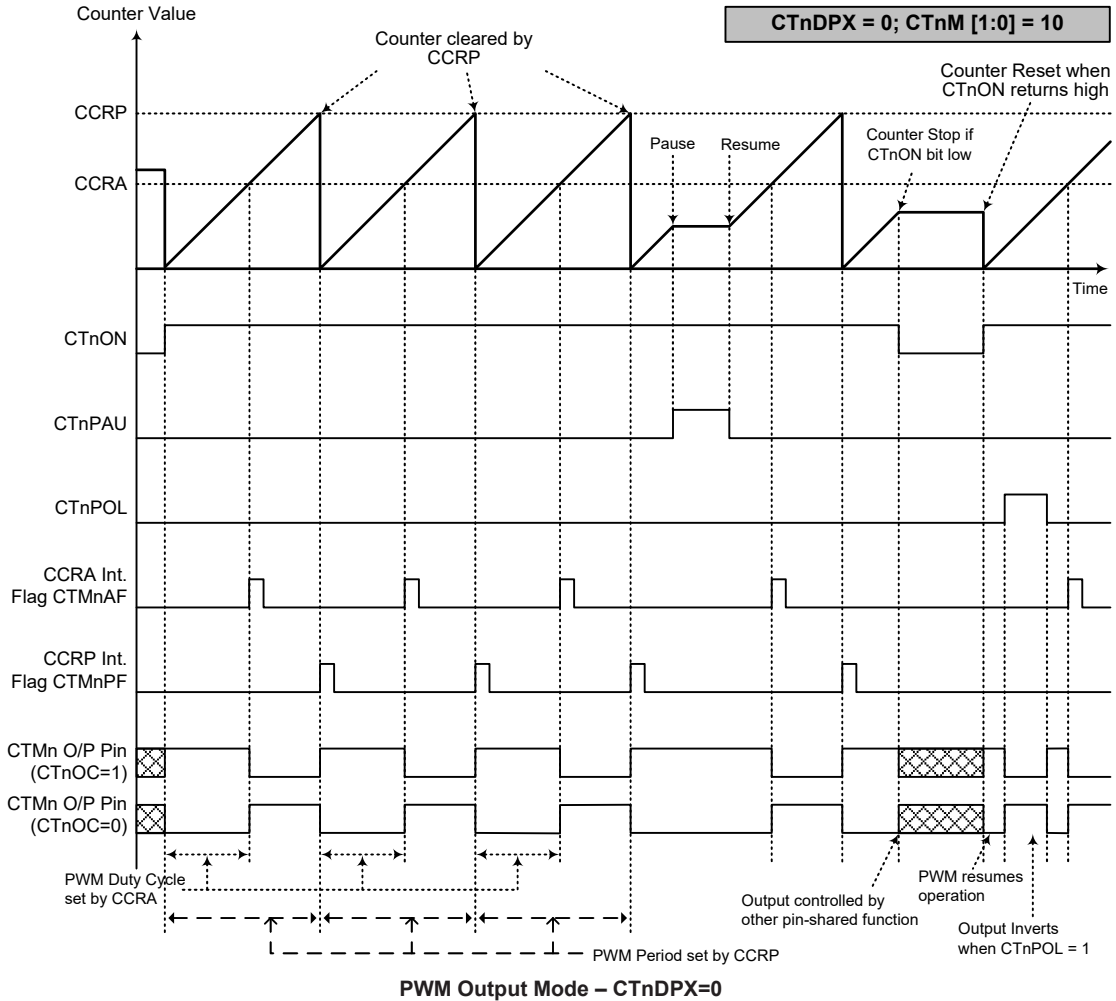
The CTMn PWM output frequency= $(f_{SYS}/4)/(2 \times 128)=f_{SYS}/1024=7.8125\text{kHz}$, duty= $128/(2 \times 128)=50\%$.

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.

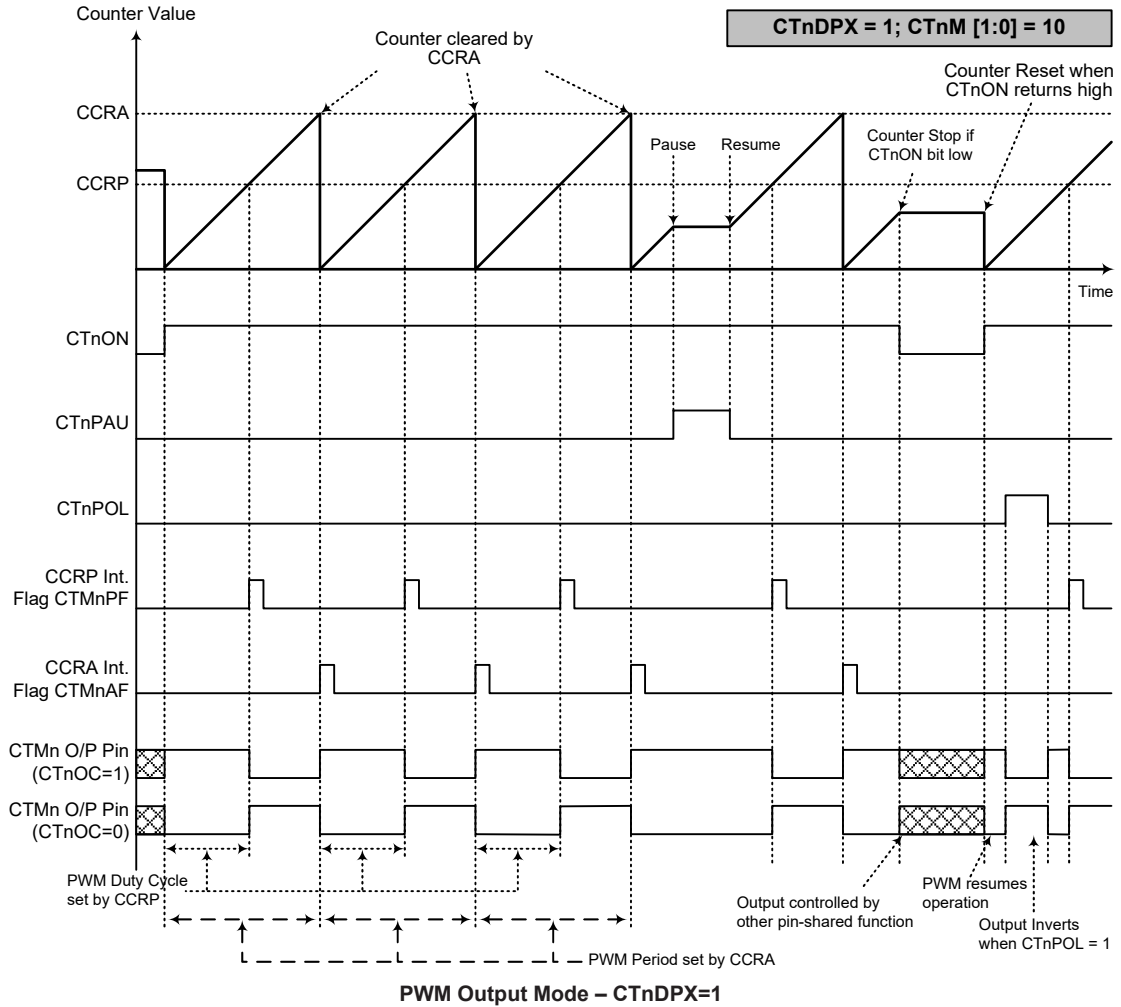
• **10-bit CTMn, PWM Output Mode, Edge-aligned Mode, CTnDPX=1**

CCRP	1~7	0
Period	CCRA	
Duty	CCRP×128	1024

The PWM output period is determined by the CCRA register value together with the CTMn clock while the PWM duty cycle is defined by the CCRP register value.



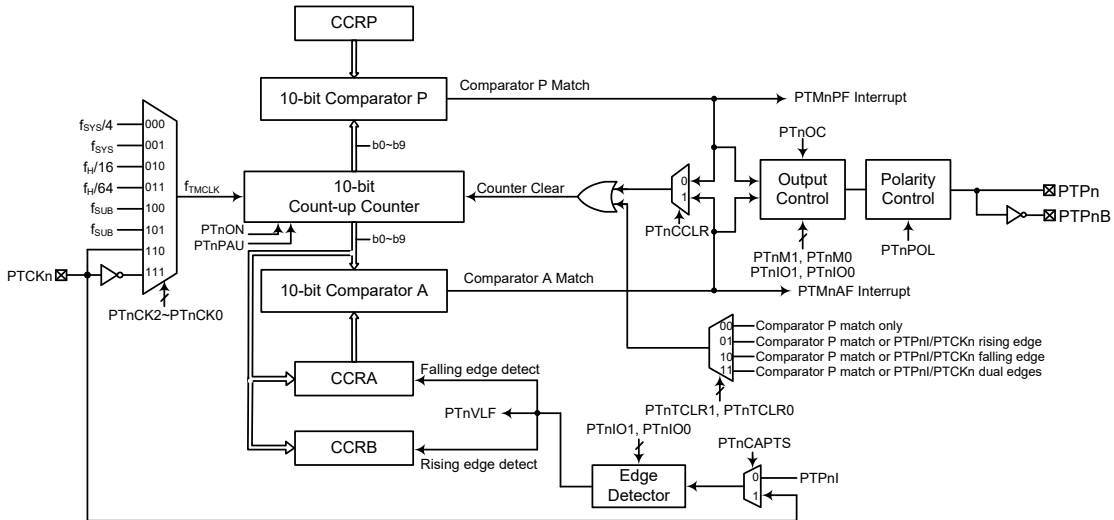
- Note: 1. Here CTnDPX=0 – Counter cleared by CCRP
 2. A counter clear sets the PWM Period
 3. The internal PWM function continues running even when CTnIO[1:0]=00 or 01
 4. The CTnCCLR bit has no influence on PWM operation
 5. n=0~1



- Note: 1. Here CTnDPX=1 – Counter cleared by CCRA
 2. A counter clear sets the PWM Period
 3. The internal PWM function continues even when CTnIO[1:0]=00 or 01
 4. The CTnCCLR bit has no influence on PWM operation
 5. n=0~1

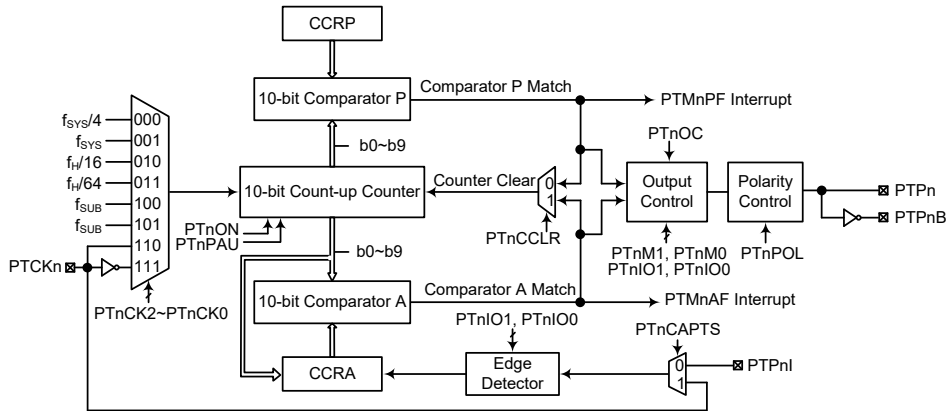
Periodic Type TM – PTM

The Periodic Type TM contains five operating modes, which are Compare Match Output, Timer/Event Counter, Capture Input, Single Pulse Output and PWM Output modes. The Periodic TM can also be controlled with two external input pins and can drive two external output pins.



- Note: 1. The PTMn external pins are pin-shared with other functions, so before using the PTMn function the pin-shared function registers must be set properly to enable the PTMn pin function.
 2. The PTPnB is the inverted output of the PTPn.
 3. The PTPnI signal can be from the Over Voltage Protection Circuit signal OVPnO.

Periodic Type TM Block Diagram (n=0~2)



- Note: 1. The PTMn external pins are pin-shared with other functions, so before using the PTMn function the pin-shared function registers must be set properly to enable the PTMn pin function.
 2. The PTPnB is the inverted output of the PTPn.
 3. The PTPnI signal can be from the Over Voltage Protection Circuit signal OVPnO.

Periodic Type TM Block Diagram (n=3)

Periodic TM Operation

The size of Periodic TM is 10-bit wide and its core is a 10-bit count-up counter which is driven by a user selectable internal or external clock source. There are also two internal comparators with the names, Comparator A and Comparator P. These comparators will compare the value in the counter with CCRP and CCRA registers. The CCRP and CCRA comparators are 10-bit wide whose value is respectively compared with all counter bits.

The only way of changing the value of the 10-bit counter using the application program is to clear the counter by changing the PTnON bit from low to high. The counter will also be cleared automatically by a counter overflow or a compare match with one of its associated comparators or the active trigger edge in Capture input mode by PTnTCLR[1:0]. When these conditions occur, a PTM interrupt signal will also usually be generated. The Periodic Type TM can operate in a number of different operational modes, can be driven by different clock sources including two input pins and also control more than one output pins. All operating setup conditions are selected using relevant internal registers.

Periodic Type TM Register Description

Overall operation of the Periodic Type TM is controlled using a series of registers. A read only register pair exists to store the internal 10-bit counter value, while three read/write register pairs exist to store the internal 10-bit CCRA value, CCRP value and CCRB value. The remaining three registers are control registers which setup the different operating and control modes.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PTMnC0	PTnPAU	PTnCK2	PTnCK1	PTnCK0	PTnON	—	—	—
PTMnC1	PTnM1	PTnM0	PTnIO1	PTnIO0	PTnOC	PTnPOL	PTnCAPTS	PTnCCLR
PTMnC2	—	—	—	—	—	PTnTCLR1	PTnTCLR0	PTnVLF
PTMnDL	D7	D6	D5	D4	D3	D2	D1	D0
PTMnDH	—	—	—	—	—	—	D9	D8
PTMnAL	D7	D6	D5	D4	D3	D2	D1	D0
PTMnAH	—	—	—	—	—	—	D9	D8
PTMnRPL	D7	D6	D5	D4	D3	D2	D1	D0
PTMnRPH	—	—	—	—	—	—	D9	D8

10-bit Periodic TM Register List (n=0~3)

• PTMnC0 Register (n=0~3)

Bit	7	6	5	4	3	2	1	0
Name	PTnPAU	PTnCK2	PTnCK1	PTnCK0	PTnON	—	—	—
R/W	R/W	R/W	R/W	R/W	R/W	—	—	—
POR	0	0	0	0	0	—	—	—

Bit 7 **PTnPAU**: PTMn Counter Pause control
 0: Run
 1: Pause

The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the PTMn will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

Bit 6~4 **PTnCK2~PTnCK0**: Select PTMn Counter clock
 000: $f_{SYS}/4$
 001: f_{SYS}
 010: $f_H/16$
 011: $f_H/64$
 100: f_{SUB}
 101: f_{SUB}
 110: PTCKn rising edge clock
 111: PTCKn falling edge clock

These three bits are used to select the clock source for the PTMn. The external pin clock source can be chosen to be active on the rising or falling edge. The clock source f_{SYS} is the system clock, while f_H and f_{SUB} are other internal clocks, the details of which can be found in the oscillator section.

Bit 3 **PTnON**: PTMn Counter On/Off control
 0: Off
 1: On

This bit controls the overall on/off function of the PTMn. Setting the bit high enables the counter to run while clearing the bit disables the PTMn. Clearing this bit to zero will stop the counter from counting and turn off the PTMn which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again.

If the PTMn is in the Compare Match Output Mode, PWM Output Mode or Single Pulse Output Mode then the PTMn output pin will be reset to its initial condition, as specified by the PTnOC bit, when the PTnON bit changes from low to high.

Bit 2~0 Unimplemented, read as “0”

• **PTMnC1 Register (n=0~2)**

Bit	7	6	5	4	3	2	1	0
Name	PTnM1	PTnM0	PTnIO1	PTnIO0	PTnOC	PTnPOL	PTnCAPTS	PTnCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PTnM1~PTnM0**: Select PTMn Operating Mode
 00: Compare Match Output Mode
 01: Capture input mode
 10: PWM Output Mode or Single Pulse Output Mode
 11: Timer/Counter Mode

These bits setup the required operating mode for the PTMn. To ensure reliable operation the PTMn should be switched off before any changes are made to the PTnM1 and PTnM0 bits. In the Timer/Counter Mode, the PTMn output pin state is undefined.

Bit 5~4 **PTnIO1~PTnIO0**: Select PTMn external pin function
 Compare Match Output Mode
 00: No change
 01: Output low
 10: Output high
 11: Toggle output

PWM Output Mode/Single Pulse Output Mode
 00: PWM output inactive state
 01: PWM output active state
 10: PWM output
 11: Single Pulse Output

Capture Input Mode

PTnTCLR[1:0]=00B:

- 00: Input capture at rising edge of PTPnI or PTCKn, and the counter value will be latched into CCRA
- 01: Input capture at falling edge of PTPnI or PTCKn, and the counter value will be latched into CCRA
- 10: Input capture at both falling and rising edges of PTPnI or PTCKn, and the counter value will be latched into CCRA
- 11: Input capture disabled

PTnTCLR[1:0]=01B, 10B or 11B:

- 00: Input capture at rising edge of PTPnI or PTCKn, and the counter value will be latched into CCRB
- 01: Input capture at falling edge of PTPnI or PTCKn, and the counter value will be latched into CCRA
- 10: Input capture at both falling and rising edges of PTPnI or PTCKn, and the counter value will be latched into CCRA at falling edge or CCRB at rising edge
- 11: Input capture disabled

Timer/Counter Mode

Unused

These two bits are used to determine how the PTMn external pin changes state when a certain condition is reached. The function that these bits select depends upon in which mode the PTMn is running.

In the Compare Match Output Mode, the PTnIO1 and PTnIO0 bits determine how the PTMn output pin changes state when a compare match occurs from the Comparator A. The PTMn output pin can be setup to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the bits are both zero, then no change will take place on the output. The initial value of the PTMn output pin should be setup using the PTnOC bit in the PTMnC1 register. Note that the output level requested by the PTnIO1 and PTnIO0 bits must be different from the initial value setup using the PTnOC bit otherwise no change will occur on the PTMn output pin when a compare match occurs. After the PTMn output pin changes state, it can be reset to its initial level by changing the level of the PTnON bit from low to high.

In the PWM Output Mode, the PTnIO1 and PTnIO0 bits determine how the TM output pin changes state when a certain compare match condition occurs. The PTMn output function is modified by changing these two bits. It is necessary to only change the values of the PTnIO1 and PTnIO0 bits only after the PTMn has been switched off. Unpredictable PWM outputs will occur if the PTnIO1 and PTnIO0 bits are changed when the PTMn is running.

Bit 3 **PTnOC**: PTMn PTPn Output control

Compare Match Output Mode

- 0: Initial low
- 1: Initial high

PWM Output Mode/Single Pulse Output Mode

- 0: Active low
- 1: Active high

This is the output control bit for the PTMn output pin. Its operation depends upon whether PTMn is being used in the Compare Match Output Mode or in the PWM Output Mode/Single Pulse Output Mode. It has no effect if the PTMn is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the PTMn output pin before a compare match occurs. In the PWM Output Mode/Single Pulse Output Mode it determines if the PWM signal is active high or active low. In the Single Pulse Output Mode it determines the logic level of the PTMn output when the PTnON bit changes from low to high.

- Bit 2 **PTnPOL**: PTMn PTPn Output polarity control
 0: Non-inverted
 1: Inverted
 This bit controls the polarity of the PTPn output pin. When the bit is set high the PTMn output pin will be inverted and not inverted when the bit is zero. It has no effect if the PTMn is in the Timer/Counter Mode.
- Bit 1 **PTnCAPTS**: PTM Capture Trigger Source Selection
 0: From PTPnI input signal
 1: From PTCKn input
- Bit 0 **PTnCCLR**: PTMn Counter Clear condition selection
 0: Comparator P match
 1: Comparator A match
 This bit is used to select the method which clears the counter. Remember that the Periodic TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the PTnCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The PTnCCLR bit is not used in the PWM Output or Single Pulse Output.

• **PTMnC1 Register (n=3)**

Bit	7	6	5	4	3	2	1	0
Name	PTnM1	PTnM0	PTnIO1	PTnIO0	PTnOC	PTnPOL	PTnCAPTS	PTnCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7~6 **PTnM1~PTnM0**: PTMn operating mode selection
 00: Compare Match Output Mode
 01: Capture Input Mode
 10: PWM Output Mode or Single Pulse Output Mode
 11: Timer/Counter Mode
 These bits setup the required operating mode for the PTMn. To ensure reliable operation the PTMn should be switched off before any changes are made to the PTnM1 and PTnM0 bits. In the Timer/Counter Mode, the PTMn output pin state is undefined.
- Bit 5~4 **PTnIO1~PTnIO0**: PTMn external pin function selection
 Compare Match Output Mode
 00: No change
 01: Output low
 10: Output high
 11: Toggle output
 PWM Output Mode/Single Pulse Output Mode
 00: PWM output inactive state
 01: PWM output active state
 10: PWM output
 11: Single Pulse Output
 Capture Input Mode
 00: Input capture at rising edge of PTPnI or PTCKn
 01: Input capture at falling edge of PTPnI or PTCKn
 10: Input capture at rising/falling edge of PTPnI or PTCKn
 11: Input capture disabled
 Timer/Counter Mode
 Unused

These two bits are used to determine how the PTMn output pin changes state when a certain condition is reached. The function that these bits select depends upon in which mode the PTMn is running.

In the Compare Match Output Mode, the PTnIO1 and PTnIO0 bits determine how the PTMn output pin changes state when a compare match occurs from the Comparator A. The PTMn output pin can be setup to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the bits are both zero, then no change will take place on the output. The initial value of the PTMn output pin should be setup using the PTnOC bit in the PTMnC1 register. Note that the output level requested by the PTnIO1 and PTnIO0 bits must be different from the initial value setup using the PTnOC bit otherwise no change will occur on the PTMn output pin when a compare match occurs. After the PTMn output pin changes state, it can be reset to its initial level by changing the level of the PTnON bit from low to high.

In the PWM Output Mode, the PTnIO1 and PTnIO0 bits determine how the PTMn output pin changes state when a certain compare match condition occurs. The PTMn output function is modified by changing these two bits. It is necessary to only change the values of the PTnIO1 and PTnIO0 bits only after the PTM has been switched off. Unpredictable PWM outputs will occur if the PTnIO1 and PTnIO0 bits are changed when the PTM is running.

- Bit 3 **PTnOC**: PTM PTPn output control
 Compare Match Output Mode
 0: Initial low
 1: Initial high
 PWM Output Mode/Single Pulse Output Mode
 0: Active low
 1: Active high

This is the output control bit for the PTMn output pin. Its operation depends upon whether PTMn is being used in the Compare Match Output Mode or in the PWM Output Mode/Single Pulse Output Mode. It has no effect if the PTMn is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the PTMn output pin before a compare match occurs. In the PWM Output Mode it determines if the PWM signal is active high or active low. In the Single Pulse Output Mode it determines the logic level of the PTMn output pin when the PTnON bit changes from low to high.

- Bit 2 **PTnPOL**: PTMn PTPn output polarity control
 0: Non-invert
 1: Invert

This bit controls the polarity of the PTPn output pin. When the bit is set high the PTMn output pin will be inverted and not inverted when the bit is zero. It has no effect if the PTMn is in the Timer/Counter Mode.

- Bit 1 **PTnCAPTS**: PTMn capture trigger source selection
 0: From PTPnI pin
 1: From PTCKn pin

- Bit 0 **PTnCCLR**: PTMn counter clear condition selection
 0: Comparator P match
 1: Comparator A match

This bit is used to select the method which clears the counter. Remember that the Periodic TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the PTnCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The PTnCCLR bit is not used in the PWM Output, Single Pulse Output or Capture Input Mode.

• **PTMnC2 Register (n=0~2)**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	PTnTCLR1	PTnTCLR0	PTnVLF
R/W	—	—	—	—	—	R/W	R/W	R
POR	—	—	—	—	—	0	0	0

Bit 7~3 Unimplemented, read as “0”

Bit 2~1 **PTnTCLR1~PTnTCLR0**: Select PTMn Counter clear condition in capture input mode only

- 00: Comparator P match
- 01: Comparator P match or PTCKn/PTPnI rising edge
- 10: Comparator P match or PTCKn/PTPnI falling edge
- 11: Comparator P match or PTCKn/PTPnI dual edges

Note that these bits selection can be available only when the PTMn operates in the Capture Input Mode.

Bit 0 **PTnVLF**: PTMn counter value latch edge flag

- 0: Falling edge trigger the counter value latch
- 1: Rising edge trigger the counter value latch

When the PTnTCLR1~PTnTCLR0 bits equal to 00B, ignore this flag status.

• **PTMnDL Register (n=0~3)**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTMn Counter Low Byte Register bit 7 ~ bit 0

PTMn 10-bit Counter bit 7 ~ bit 0

• **PTMnDH Register (n=0~3)**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R	R
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”

Bit 1~0 **D9~D8**: PTMn Counter High Byte Register bit 1 ~ bit 0

PTMn 10-bit Counter bit 9 ~ bit 8

• **PTMnAL Register (n=0~3)**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTMn CCRA Low Byte Register bit 7 ~ bit 0

PTMn 10-bit CCRA bit 7 ~ bit 0

• **PTMnAH Register (n=0~3)**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”

Bit 1~0 **D9~D8**: PTMn CCRA High Byte Register bit 1 ~ bit 0
PTMn 10-bit CCRA bit 9 ~ bit 8

• **PTMnRPL Register (n=0~3)**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTMn CCRP Low Byte Register bit 7 ~ bit 0
PTMn 10-bit CCRP bit 7 ~ bit 0

• **PTMnRPH Register (n=0~3)**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”

Bit 1~0 **D9~D8**: PTMn CCRP High Byte Register bit 1 ~ bit 0
PTMn 10-bit CCRP bit 9 ~ bit 8

Periodic Type TM Operation Modes

The Periodic Type TM can operate in one of five operating modes, Compare Match Output Mode, PWM Output Mode, Single Pulse Output Mode, Capture Input Mode or Timer/Counter Mode. The operating mode is selected using the PTnM1 and PTnM0 bits in the PTMnC1 register.

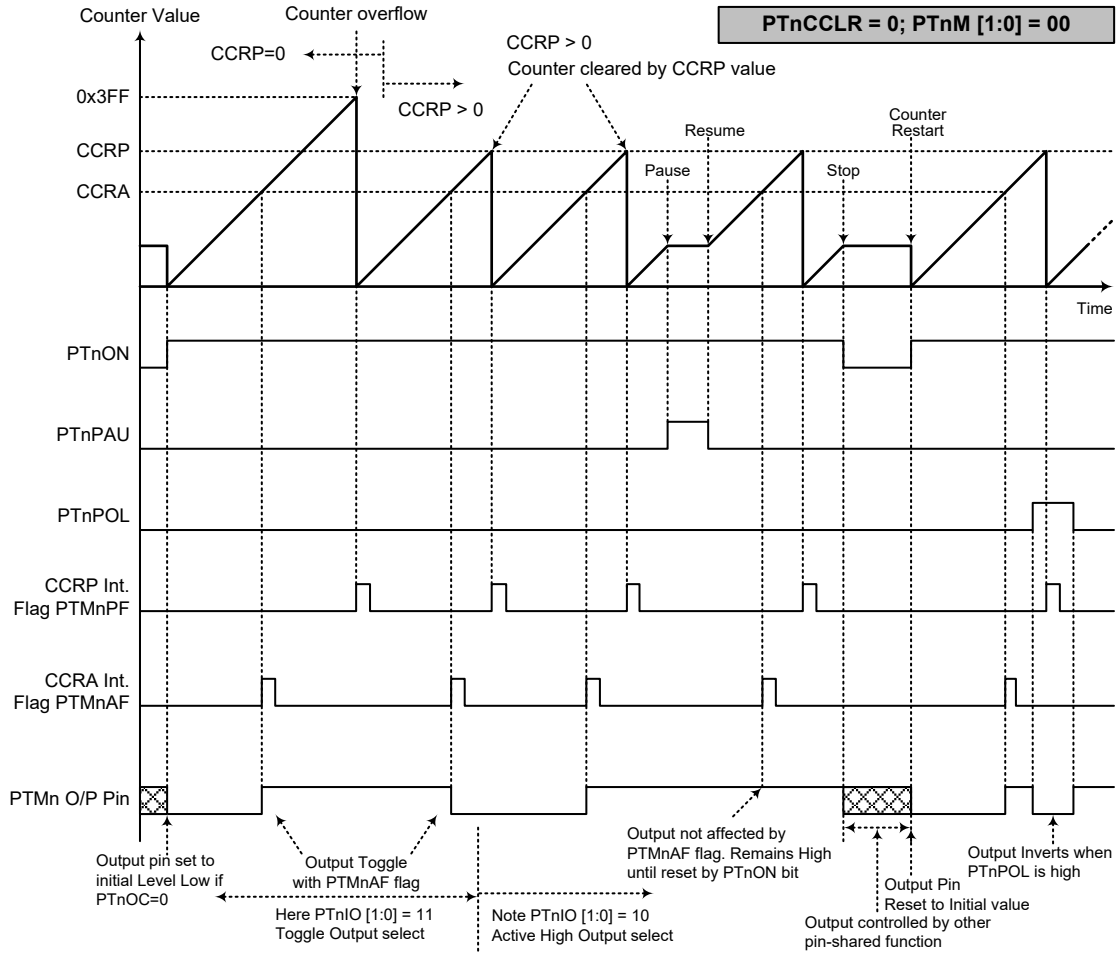
Compare Match Output Mode

To select this mode, bits PTnM1 and PTnM0 in the PTMnC1 register, should be set to 00 respectively. In this mode once the counter is enabled and running it can be cleared by three methods. These are a counter overflow, a compare match from Comparator A and a compare match from Comparator P. When the PTnCCLR bit is low, there are two ways in which the counter can be cleared. One is when a compare match from Comparator P, the other is when the CCRP bits are all zero which allows the counter to overflow. Here both PTMnAF and PTMnPF interrupt request flags for Comparator A and Comparator P respectively, will both be generated.

If the PTnCCLR bit in the PTMnC1 register is high then the counter will be cleared when a compare match occurs from Comparator A. However, here only the PTMnAF interrupt request flag will be generated even if the value of the CCRP bits is less than that of the CCRA registers. Therefore when PTnCCLR is high no PTMnPF interrupt request flag will be generated. In the Compare Match Output Mode, the CCRA can not be set to “0”.

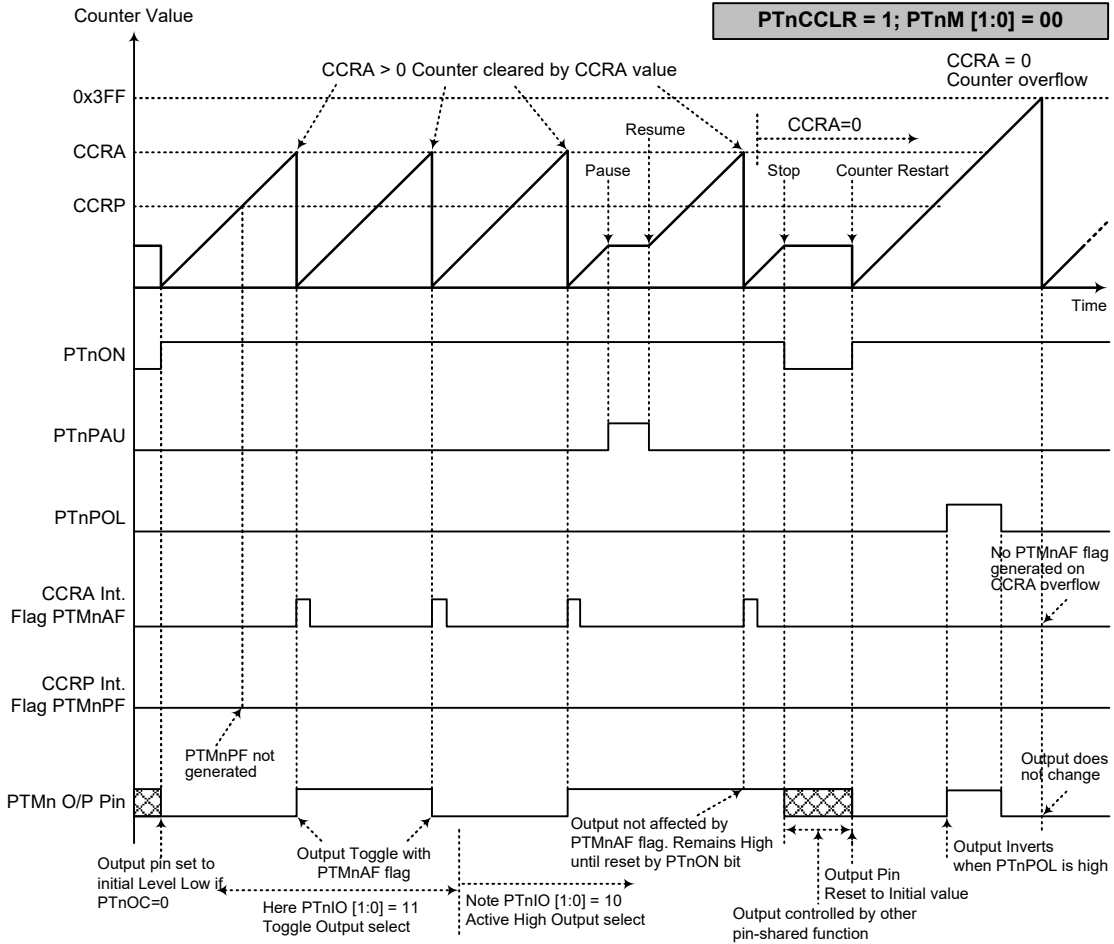
If the CCRA bits are all zero, the counter will overflow when it reaches its maximum 10-bit, 3FF Hex, value, however here the PTMnAF interrupt request flag will not be generated.

As the name of the mode suggests, after a comparison is made, the PTMn output pin will change state. The PTMn output pin condition however only changes state when a PTMnAF interrupt request flag is generated after a compare match occurs from Comparator A. The PTMnPF interrupt request flag, generated from a compare match occurs from Comparator P, will have no effect on the PTMn output pin. The way in which the PTMn output pin changes state are determined by the condition of the PTnIO1 and PTnIO0 bits in the PTMnC1 register. The PTMn output pin can be selected using the PTnIO1 and PTnIO0 bits to go high, to go low or to toggle from its present condition when a compare match occurs from Comparator A. The initial condition of the PTMn output pin, which is setup after the PTnON bit changes from low to high, is setup using the PTnOC bit. Note that if the PTnIO1 and PTnIO0 bits are zero then no pin change will take place.



Compare Match Output Mode – PTnCCLR=0

- Note: 1. With PTnCCLR=0, a Comparator P match will clear the counter
 2. The PTMn output pin is controlled only by the PTMnAF flag
 3. The output pin is reset to its initial state by a PTnON bit rising edge
 4. n=0~3



Compare Match Output Mode – PTnCCR=1

- Note: 1. With PTnCCR=1, a Comparator A match will clear the counter
 2. The PTMn output pin is controlled only by the PTMnAF flag
 3. The output pin is reset to its initial state by a PTnON bit rising edge
 4. A PTMnPF flag is not generated when PTnCCR=1
 5. n=0~3

Timer/Counter Mode

To select this mode, bits PTnM1 and PTnM0 in the PTMnC1 register should be set to 11 respectively. The Timer/Counter Mode operates in an identical way to the Compare Match Output Mode generating the same interrupt flags. The exception is that in the Timer/Counter Mode the PTMn output pin is not used. Therefore the above description and Timing Diagrams for the Compare Match Output Mode can be used to understand its function. As the PTMn output pin is not used in this mode, the pin can be used as a normal I/O pin or other pin-shared function.

PWM Output Mode

To select this mode, bits PTnM1 and PTnM0 in the PTMnC1 register should be set to 10 respectively. The PWM function within the PTMn is useful for applications which require functions such as motor control, heating control, illumination control, etc. By providing a signal of fixed frequency but of varying duty cycle on the PTMn output pin, a square wave AC waveform can be generated with varying equivalent DC RMS values.

As both the period and duty cycle of the PWM waveform can be controlled, the choice of generated waveform is extremely flexible. In the PWM Output Mode, the PTnCCLR bit has no effect as the PWM period. Both of the CCRP and CCRA registers are used to generate the PWM waveform, one register is used to clear the internal counter and thus control the PWM waveform frequency, while the other one is used to control the duty cycle. The PWM waveform frequency and duty cycle can therefore be controlled by the values in the CCRA and CCRP registers.

An interrupt flag, one for each of the CCRA and CCRP, will be generated when a compare match occurs from either Comparator A or Comparator P. The PTnOC bit in the PTMnC1 register is used to select the required polarity of the PWM waveform while the two PTnIO1 and PTnIO0 bits are used to enable the PWM output or to force the PTMn output pin to a fixed high or low level. The PTnPOL bit is used to reverse the polarity of the PWM output waveform.

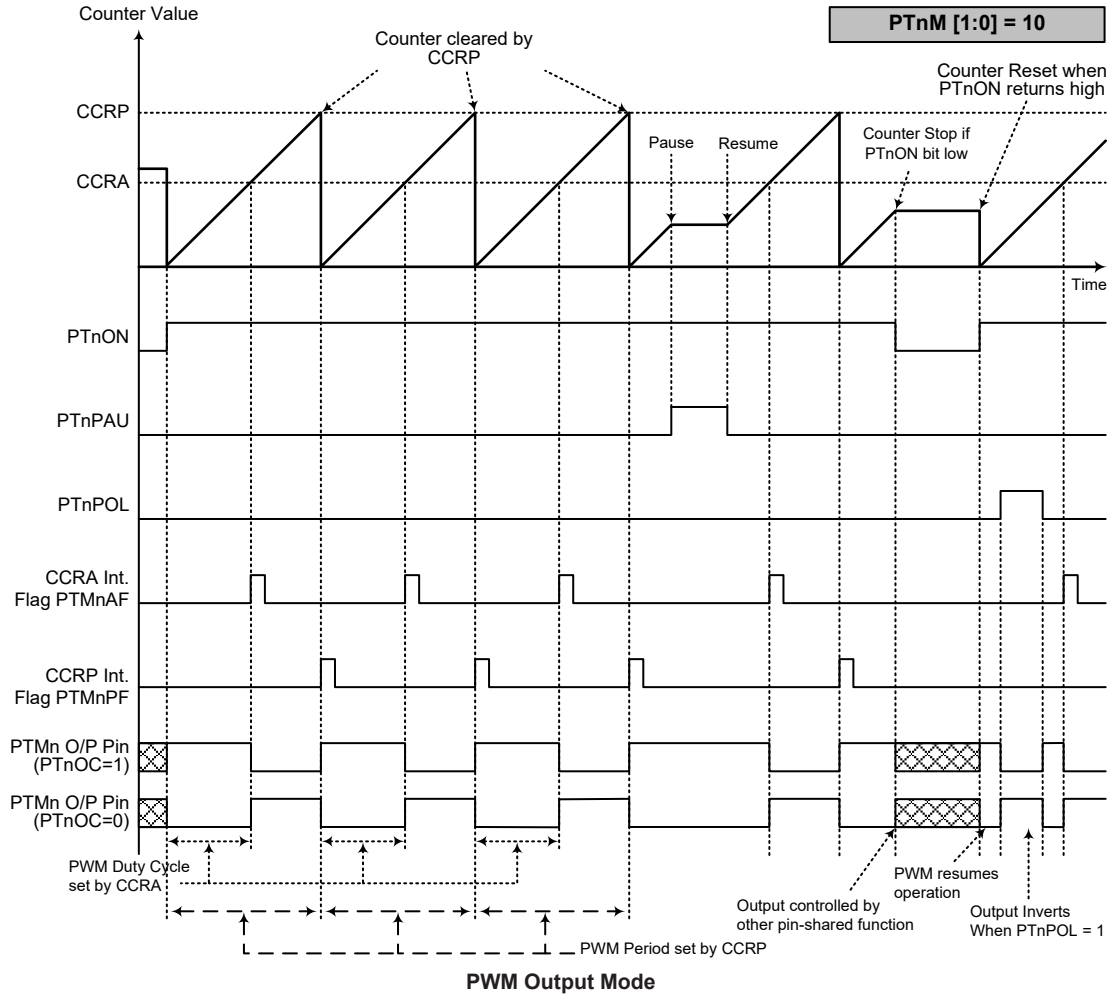
• **10-bit PTMn, PWM Output Mode, Edge-aligned Mode (n=0~3)**

CCRP	1~1023	0
Period	1~1023	1024
Duty	CCRA	

If $f_{SYS}=8\text{MHz}$, PTMn clock source select $f_{SYS}/4$, CCRP=512 and CCRA=128,

The PTMn PWM output frequency= $(f_{SYS}/4)/512=f_{SYS}/2048=4\text{kHz}$, duty= $128/512=25\%$,

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.



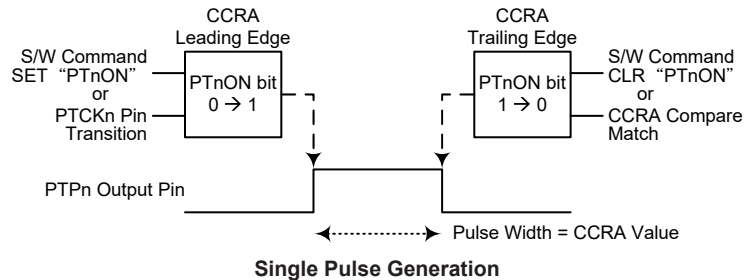
- Note:
1. The counter is cleared by CCRP
 2. A counter clear sets the PWM Period
 3. The internal PWM function continues running even when PTnIO[1:0]=00 or 01
 4. The PTnCCLR bit has no influence on PWM operation
 5. n=0~3

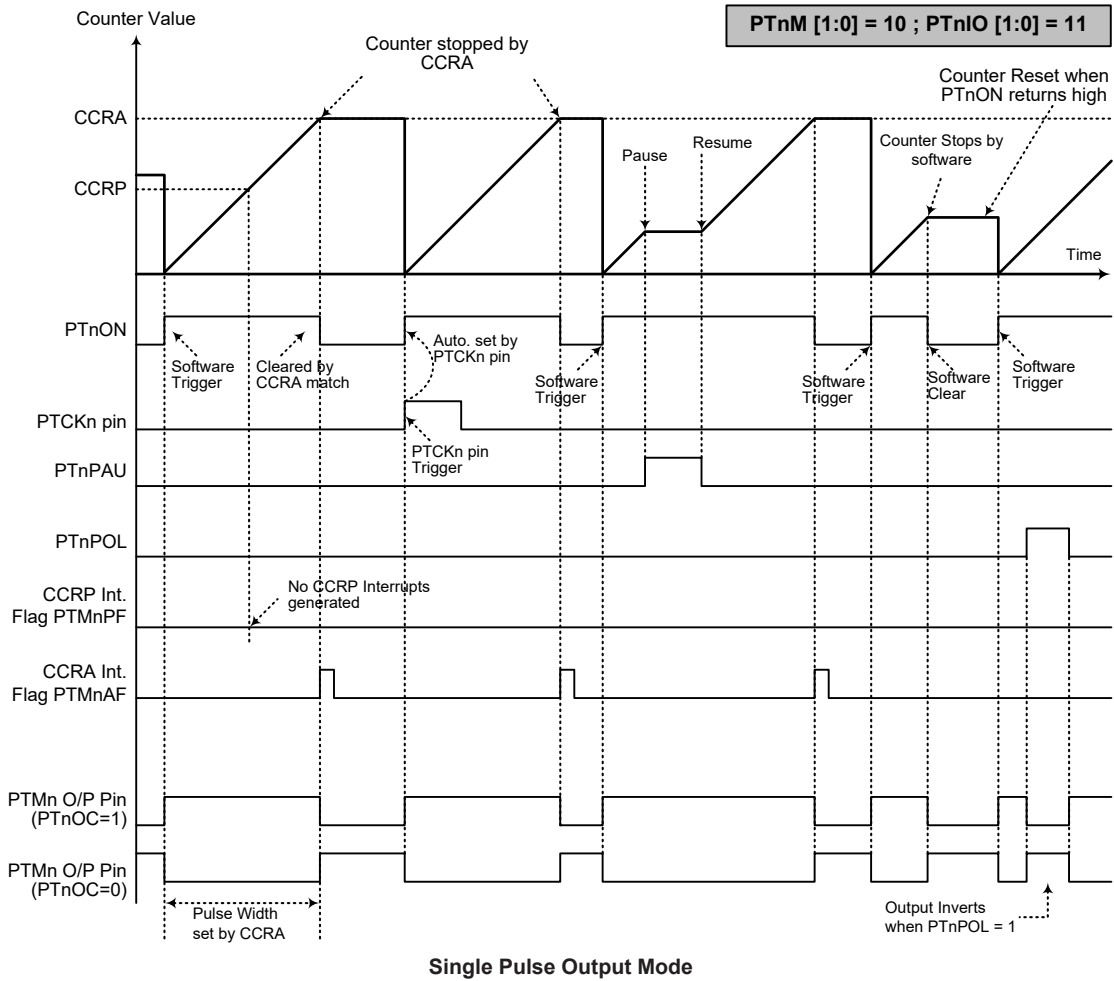
Single Pulse Output Mode

To select this mode, bits PTnM1 and PTnM0 in the PTMnC1 register should be set to 10 respectively and also the PTnIO1 and PTnIO0 bits should be set to 11 respectively. The Single Pulse Output Mode, as the name suggests, will generate a single shot pulse on the PTMn output pin.

The trigger for the pulse output leading edge is a low to high transition of the PTnON bit, which can be implemented using the application program. However in the Single Pulse Output Mode, the PTnON bit can also be made to automatically change from low to high using the external PTCKn pin, which will in turn initiate the Single Pulse output. When the PTnON bit transitions to a high level, the counter will start running and the pulse leading edge will be generated. The PTnON bit should remain high when the pulse is in its active state. The generated pulse trailing edge will be generated when the PTnON bit is cleared to zero, which can be implemented using the application program or when a compare match occurs from Comparator A.

However a compare match from Comparator A will also automatically clear the PTnON bit and thus generate the Single Pulse output trailing edge. In this way the CCRA value can be used to control the pulse width. A compare match from Comparator A will also generate a PTMn interrupt. The counter can only be reset back to zero when the PTnON bit changes from low to high when the counter restarts. In the Single Pulse Output Mode CCRP is not used. The PTnCCLR is not used in this Mode.





- Note: 1. Counter stopped by CCRA
 2. CCRP is not used
 3. The pulse triggered by the PTCKn pin or by setting the PTnON bit high
 4. A PTCKn pin active edge will automatically set the PTnON bit high
 5. In the Single Pulse Output Mode, PTnIO[1:0] must be set to "11" and can not be changed
 6. n=0~3

Capture Input Mode (n=0~2)

To select this mode bits PTnM1 and PTnM0 in the PTMnC1 register should be set to 01 respectively. This mode enables external or internal signals to capture and store the present value of the internal counter and can therefore be used for applications such as pulse width measurements. The external or internal signal is supplied on the PTPnI or PTCKn pin which is selected using the PTnCAPTS bit in the PTMnC1 register, whose active edge can be either a rising edge, a falling edge or both rising and falling edges; the active edge transition type is selected using the PTnIO1 and PTnIO0 bits in the PTMnC1 register. The counter is started when the PTnON bit changes from low to high which is initiated using the application program.

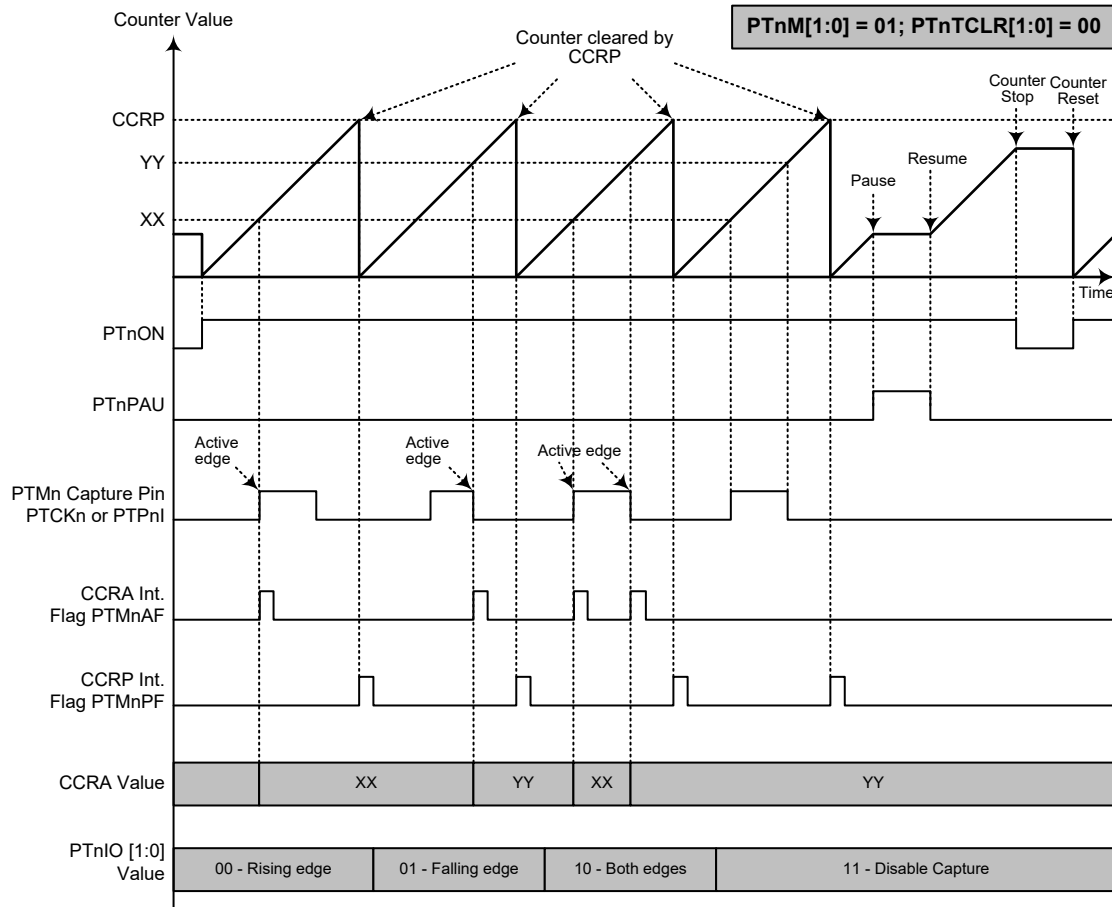
The PTnIO1 and PTnIO0 bits decide which active edge transition type to be latched and interrupted. The PTnTCLR1 and PTTCLR0 bits decide the condition that the counter reset back to zero. The present counter value latched into CCRA or CCRB is decided by both PTnIO1~PTnIO0 and PTnTCLR1~PTnTCLR0 setting. The PTnIO1~PTnIO0 and PTnTCLR1~PTnTCLR0 are independent on and uninfluenced each other.

When the required edge transition appears on the PTCKn or PTPnI pin the present value in the counter will be latched into the CCRA registers or CCRB registers and a PTMn interrupt generated. Irrespective of what events occur on the PTCKn or PTPnI pin, the counter will continue to free run until the PTnON bit changes from high to low. When a CCRP compare match occurs the counter will reset back to zero; in this way the CCRP value can be used to control the maximum counter value. When a CCRP compare match occurs from Comparator P, a PTM interrupt will also be generated. Counting the number of overflow interrupt signals from the CCRP can be a useful method in measuring long pulse widths. The PTnIO1 and PTnIO0 bits can select the active trigger edge on the PTCKn or PTPnI pin to be a rising edge, falling edge or both edge types. If the PTnIO1 and PTnIO0 bits are both set high, then no capture operation will take place irrespective of what happens on the PTCKn or PTPnI pin, however it must be noted that the counter will continue to run.

If the capture pulse width is less than two timer clock cycles, it may be ignored by hardware. The timer clock source must be equal to or less than 50MHz, otherwise the counter may fail to count.

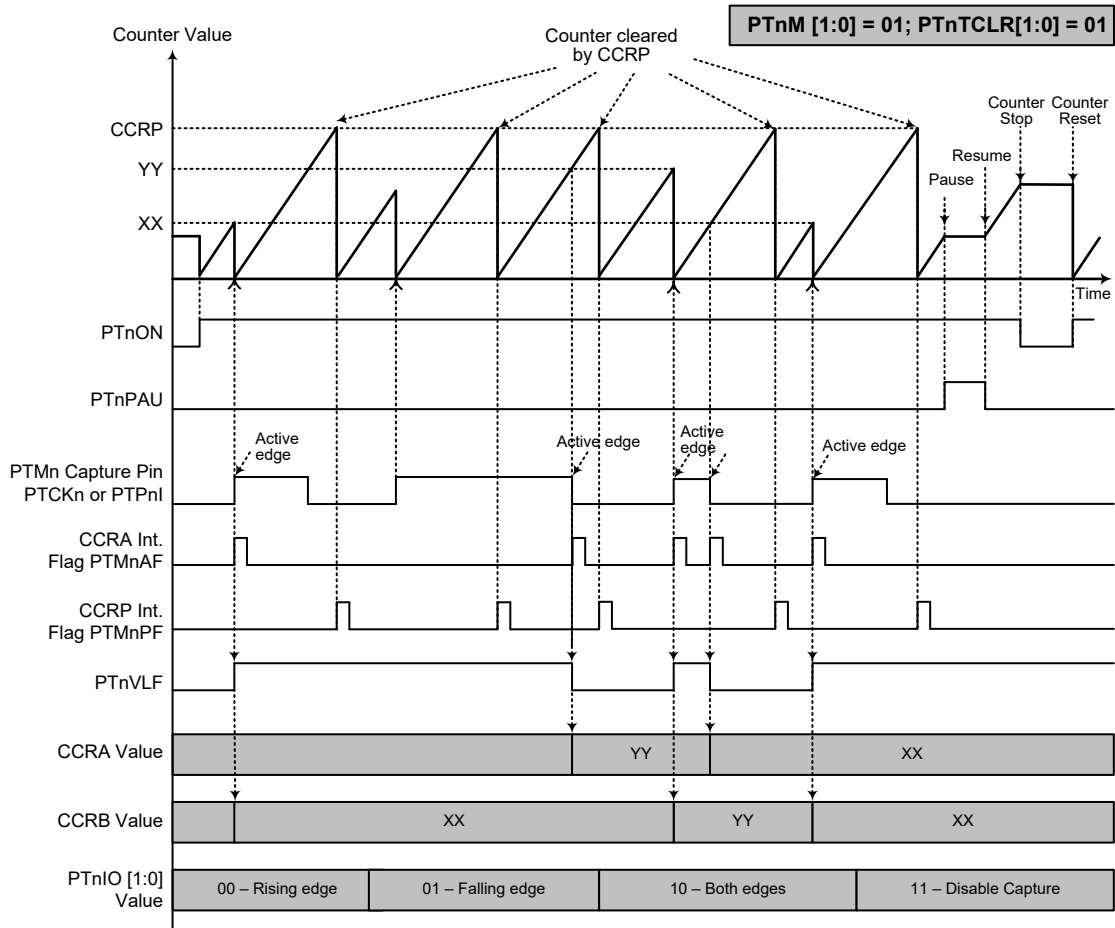
As the PTCKn or PTPnI pin is pin shared with other functions, care must be taken if the PTMn is in the Capture Input Mode. This is because if the pin is setup as an output, then any transitions on this pin may cause an input capture operation to be executed. The PTnCCLR, PTnOC and PTnPOL bits are not used in this Mode.

There are some considerations that should be noted. If PTCKn is used as the capture input source, then it cannot be selected as the PTMn clock source. If the captured pulse width is less than 2 timer clock periods, it may be ignored by hardware. After the counter value is latched to the CCRA or CCRB registers by an active capture edge, the PTMnAF flag will be set high and the PTnVLF flag status will be changed after 0.5 timer clock periods. The delay time from the active capture edge received to the action of latching counter value to CCRA or CCRB registers is less than 1.5 timer clock periods.



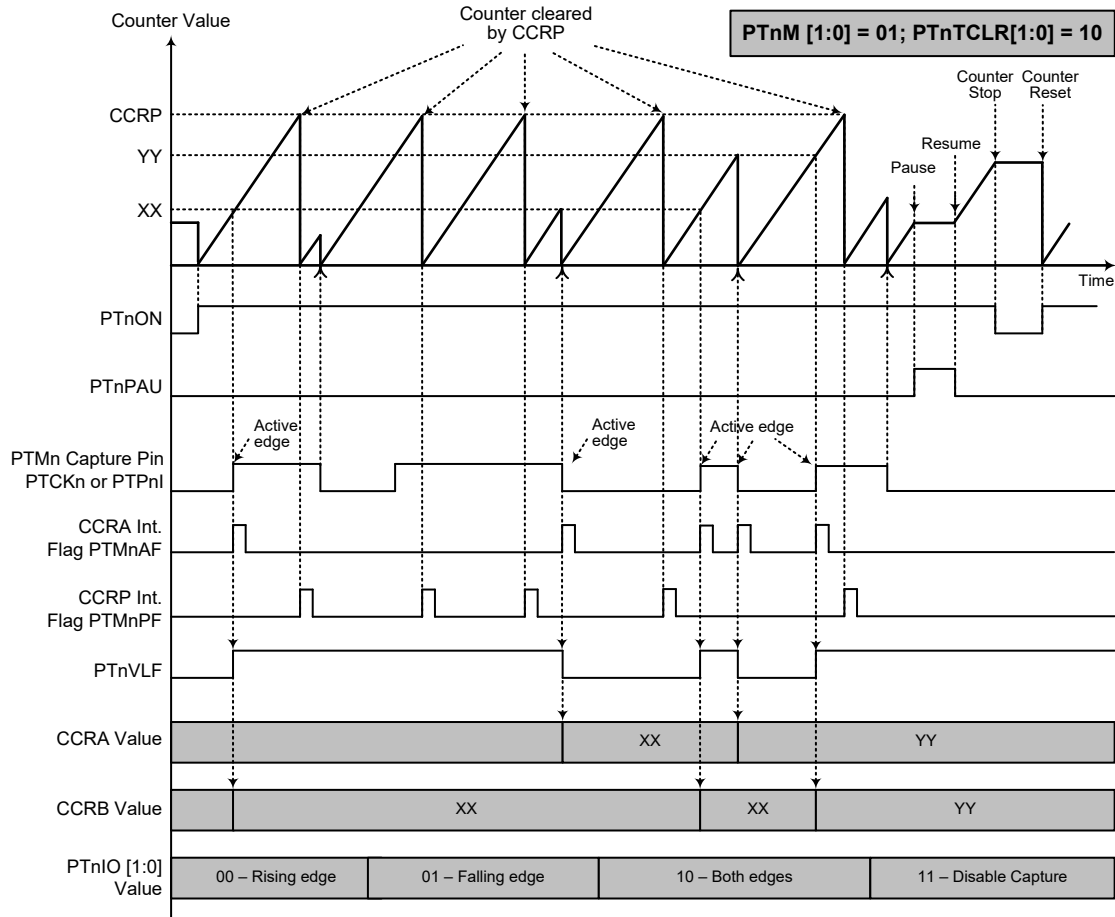
Capture Input Mode – PTnTCLR[1:0]=00 (n=0~2)

- Note: 1. PTnM[1:0]=01, PTnTCLR[1:0]=00 and active edge set by the PTnIO[1:0] bits
 2. A PTMn Capture input active edge transfers the counter value to CCRA
 3. Comparator P match will clear the counter
 4. PTnCCLR bit is not used
 5. No output function – PTnOC and PTnPOL bits are not used
 6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero
 7. Ignore the PTnVLF bit status when PTnTCLR[1:0]=00
 8. The capture input mode cannot be used if the selected PTM counter clock is not available



Capture Input Mode – PTnTCLR[1:0]=01 (n=0~2)

- Note: 1. PTnM[1:0]=01, PTnTCLR[1:0]=01 and active edge set by the PTIO[1:0] bits
2. A PTMn Capture input active edge transfers the counter value to CCRA or CCRB
3. Comparator P match or PTMn capture input pin rising edge will clear the counter
4. PTnCCLR bit is not used
5. No output function – PTnOC and PTnPOL bits are not used
6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero.
7. The capture input mode cannot be used if the selected PTM counter clock is not available



Capture Input Mode – PTnTCLR[1:0]=10 (n=0~2)

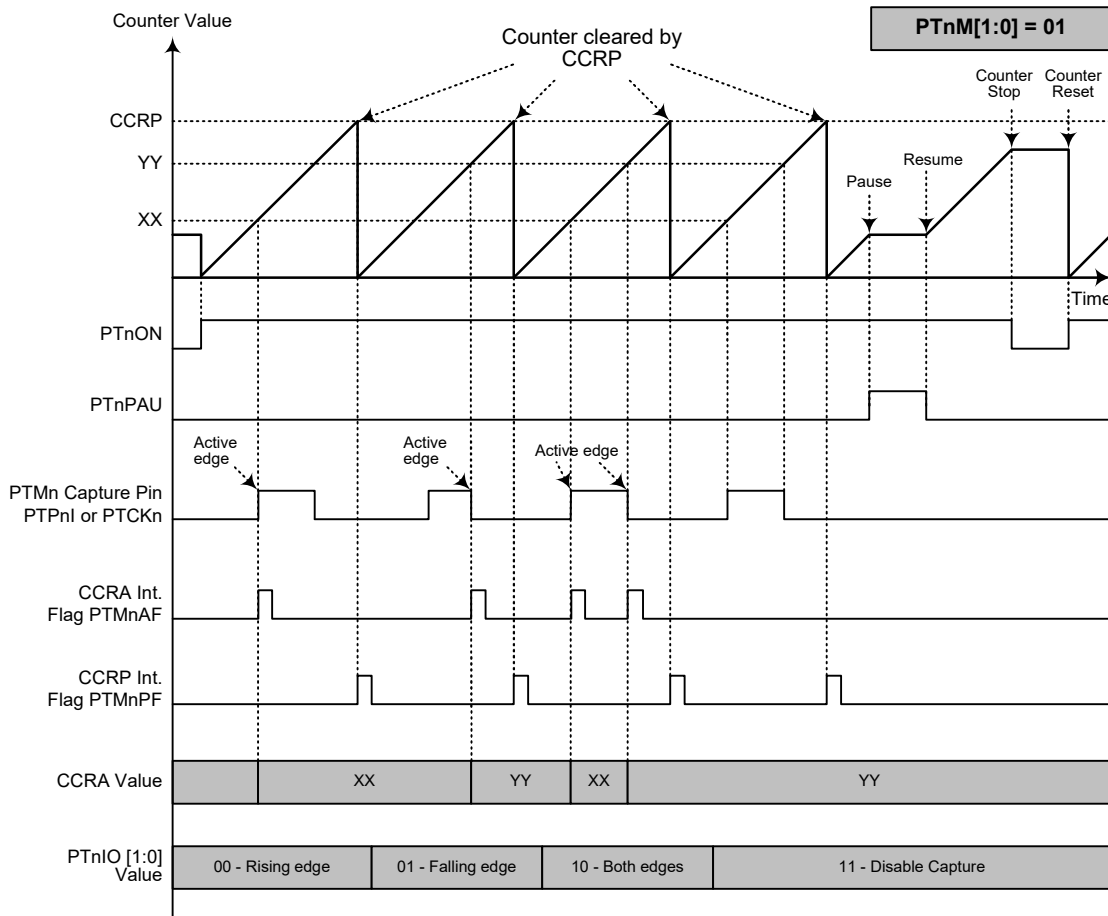
- Note: 1. PTnM[1:0]=01, PTnTCLR[1:0]=10 and active edge set by the PTnIO[1:0] bits
 2. A PTMn Capture input active edge transfers the counter value to CCRA or CCRB
 3. Comparator P match or PTMn capture input pin falling edge will clear the counter
 4. PTnCCLR bit is not used
 5. No output function – PTnOC and PTnPOL bits are not used
 6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero
 7. The capture input mode cannot be used if the selected PTM counter clock is not available

Capture Input Mode (n=3)

To select this mode bits PTnM1 and PTnM0 in the PTMnC1 register should be set to 01 respectively. This mode enables external signals to capture and store the present value of the internal counter and can therefore be used for applications such as pulse width measurements. The external signal is supplied on the PTPnI or PTCKn pin which is selected using the PTnCPTS bit in the PTMnC1 register. The input pin active edge can be either a rising edge, a falling edge or both rising and falling edges; the active edge transition type is selected using the PTnIO1 and PTnIO0 bits in the PTMnC1 register. The counter is started when the PTnON bit changes from low to high which is initiated using the application program.

When the required edge transition appears on the PTCKn or PTPnI pin the present value in the counter will be latched into the CCRA registers and a PTMn interrupt generated. Irrespective of what events occur on the PTCKn or PTPnI pin, the counter will continue to free run until the PTnON bit changes from high to low. When a CCRP compare match occurs the counter will reset back to zero; in this way the CCRP value can be used to control the maximum counter value. When a CCRP compare match occurs from Comparator P, a PTM interrupt will also be generated. Counting the number of overflow interrupt signals from the CCRP can be a useful method in measuring long pulse widths. The PTnIO1 and PTnIO0 bits can select the active trigger edge on the PTCnK or PTPnI pin to be a rising edge, falling edge or both edge types. If the PTnIO1 and PTnIO0 bits are both set high, then no capture operation will take place irrespective of what happens on the PTCKn or PTPnI pin, however it must be noted that the counter will continue to run. The PTnCCLR, PTnOC and PTnPOL bits are not used in this Mode.

There are some considerations that should be noted. If PTCKn is used as the capture input source, then it cannot be selected as the PTMn clock source. If the captured pulse width is less than 2 timer clock periods, it may be ignored by hardware. After the counter value is latched to the CCRA register by an active capture edge, the PTMnAF flag will be set high after 0.5 timer clock periods. The propagation time from the active capture edge received to the action of latching counter value to CCRA registers is less than 1.5 timer clock periods.



Capture Input Mode (n=3)

- Note: 1. PTnM[1:0]=01 and active edge set by the PTIO[1:0] bits
 2. A PTMn Capture input pin active edge transfers the counter value to CCRA
 3. PTnCCLR bit is not used
 4. No output function – PTnOC and PTnPOL bits are not used
 5. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero.
 6. The capture input mode cannot be used if the selected PTM counter clock is not available

Analog to Digital Converter

The need to interface to real world analog signals is a common requirement for many electronic systems. However, to properly process these signals by a microcontroller, they must first be converted into digital signals by A/D converters. By integrating the A/D conversion electronic circuitry into the microcontroller, the need for external components is reduced significantly with the corresponding follow-on benefits of lower costs and reduced component space requirements.

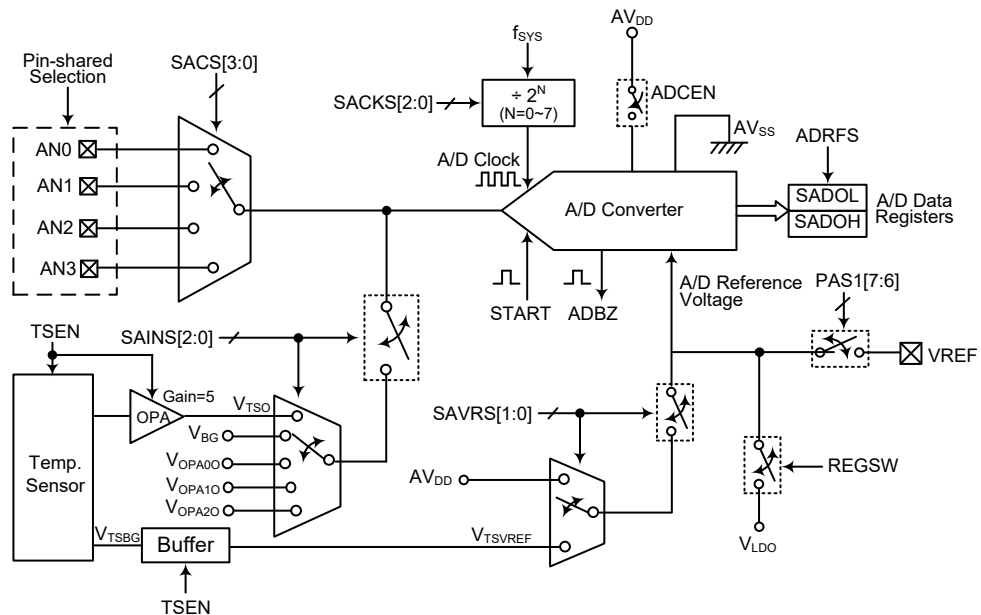
A/D Converter Overview

The device contains a multi-channel 12-bit analog to digital converter which can directly interface to external analog signals, such as that from sensors or other control signals and convert these signals directly into a 12-bit digital value. It also can convert the internal signals, such as the bandgap reference voltage V_{BG} , the DD operational amplifier 0 output signal OPA0O, the DD operational amplifier 1 output signal OPA1O, the DD operational amplifier 2 output signal OPA2O or the temperature sensor output voltage, V_{STO} , into a 12-bit digital value. The external or internal analog signal to be converted is determined by the SAINS2~SAINS0 bits together with the SACS3~SACS0 bits. More detailed information about the A/D input signal selection will be described in the “A/D Converter Input Signals” section.

This A/D converter also includes a temperature sensor circuitry which contains a temperature sensor, three operational amplifiers and an internal reference voltage. The temperature sensor can detect the temperature and then output a voltage proportional to the temperature. The output voltage can be amplified by the OPA and then converted to a 12-bit digital data using the A/D converter.

External Input Channels	Internal Signals	Channel Select Bits
4: AN0~AN3	5: V_{BG} , OPA0O, OPA1O, OPA2O, V_{TSTO}	SAINS2~SAINS0, SACS3~SACS0

The accompanying block diagram shows the overall internal structure of the A/D converter with temperature sensor, together with its associated registers.



A/D Converter with Temperature Sensor Diagram

A/D Converter Register Description

Overall operation of the A/D converter with Temperature Sensor is controlled using several registers. A read only register pair exists to store the A/D converter data 12-bit value. Two registers, SADC0 and SADC1, are control registers which setup the operating and control function of the A/D converter. The SADC2 is the temperature sensor circuitry control register.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SADOL (ADRFS=0)	D3	D2	D1	D0	—	—	—	—
SADOL (ADRFS=1)	D7	D6	D5	D4	D3	D2	D1	D0
SADOH (ADRFS=0)	D11	D10	D9	D8	D7	D6	D5	D4
SADOH (ADRFS=1)	—	—	—	—	D11	D10	D9	D8
SADC0	START	ADBZ	ADCEN	ADRFS	SACS3	SACS2	SACS1	SACS0
SADC1	SAINS2	SAINS1	SAINS0	SAVRS1	SAVRS0	SACKS2	SACKS1	SACKS0
SADC2	—	—	D5	D4	—	TSGS1	TSGS0	TSEN

A/D Converter Register List

A/D Converter Data Registers – SADOL, SADOH

As this device contains an internal 12-bit A/D converter, it requires two data registers to store the converted value. These are a high byte register, known as SADOH, and a low byte register, known as SADOL. After the conversion process takes place, these registers can be directly read by the microcontroller to obtain the digitised conversion value. As only 12 bits of the 16-bit register space is utilised, the format in which the data is stored is controlled by the ADRFS bit in the SADC0 register as shown in the accompanying table. D0~D11 are the A/D conversion result data bits. Any unused bits will be read as zero. Note that A/D data register contents will be unchanged if the A/D converter is disabled.

ADRFS	SADOH								SADOL							
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
0	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	0	0	0	0
1	0	0	0	0	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

A/D Data Registers

A/D Converter Control Registers – SADC0, SADC1

To control the function and operation of the A/D converter, two control registers known as SADC0 and SADC1 are provided. These 8-bit registers define functions such as the selection of which analog signal is connected to the internal A/D converter, the digitised data format, the A/D clock source as well as controlling the start function and monitoring the A/D converter busy status. As the device contains only one actual analog to digital converter hardware circuit, each of the external and internal analog signals must be routed to the converter. The SACS3~SACS0 bits in the SADC0 register are used to determine which external channel input is selected to be converted. The SAINS2~SAINS0 bits in the SADC1 register are used to determine that the analog signal to be converted comes from the internal analog signal or external analog channel input.

The relevant pin-shared function selection bits determine which pins on I/O Ports are used as analog inputs for the A/D converter input and which pins are not to be used as the A/D converter input. When the pin is selected to be an A/D input, its original function whether it is an I/O or other pin-shared function will be removed. In addition, any internal pull-high resistor connected to the pin will be automatically removed if the pin is selected to be an A/D converter input.

• **SADC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	START	ADBZ	ADCEN	ADRF5	SACS3	SACS2	SACS1	SACS0
R/W	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7** **START:** Start the A/D conversion
0→1→0: Start
This bit is used to initiate an A/D conversion process. The bit is normally low but if set high and then cleared low again, the A/D converter will initiate a conversion process.
- Bit 6** **ADBZ:** A/D converter busy flag
0: No A/D conversion is in progress
1: A/D conversion is in progress
This read only flag is used to indicate whether the A/D conversion is in progress or not. When the START bit is set from low to high and then to low again, the ADBZ flag will be set to 1 to indicate that the A/D conversion is initiated. The ADBZ flag will be cleared to 0 after the A/D conversion is complete.
- Bit 5** **ADCEN:** A/D converter function enable control
0: Disable
1: Enable
This bit controls the A/D internal function. This bit should be set to one to enable the A/D converter. If the bit is set low, then the A/D converter will be switched off reducing the device power consumption. When the A/D converter function is disabled, the contents of the A/D data register pair known as SADOH and SADOL will be unchanged.
- Bit 4** **ADRF5:** A/D converter data format select
0: A/D converter data format → SADOH=D[11:4]; SADOL=D[3:0]
1: A/D converter data format → SADOH=D[11:8]; SADOL=D[7:0]
This bit controls the format of the 12-bit converted A/D value in the two A/D data registers. Details are provided in the A/D data register section.
- Bit 3~0** **SACS3~SACS0:** A/D converter external analog channel input select
0000: AN0
0001: AN1
0010: AN2
0011: AN3
0100~1111: Undefined, input floating if selected

• **SADC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	SAINS2	SAINS1	SAINS0	SAVRS1	SAVRS0	SACKS2	SACKS1	SACKS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7~5** **SAINS2~SAINS0:** A/D converter input signal select
000: External source – External analog channel input, ANn
001: Internal source – Internal DD operational amplifier 0 output signal, OPA00
010: Internal source – Internal temperature sensor output voltage, V_{TSO}
011: Internal source – Internal DD operational amplifier 1 output signal, OPA10
100: External source – Internal DD operational amplifier 2 output signal, OPA20
101: Internal source – Internal bandgap reference voltage, V_{BG}
110~111: External source – External analog channel input, ANn
Care must be taken if the SAINS2~SAINS0 bits are set from “001~101” to select the internal analog signal to be converted. When the internal analog signal is selected to be converted, the external input pin must never be selected as the A/D input signal by properly setting the SACS3~SACS0 bits. Otherwise, the external channel input will be connected together with the internal analog signal. This will result in unpredictable situations such as an irreversible damage.

- Bit 4~3 **SAVRS1~SAVRS0**: A/D converter reference voltage select
 00: VREF pin input or LDO output
 01: Internal A/D converter power supply, AV_{DD}
 10: Internal Temperature Sensor reference voltage, V_{TSPREF}
 11: VREF pin input or LDO output

These bits are used to select the A/D converter reference voltage source. Care must be taken if the SAVRS1~SAVRS0 bits are set to “01~10” to select the internal A/D converter power or Temperature Sensor reference voltage as the reference voltage source. When the internal A/D converter power or Temperature Sensor reference voltage is selected as the reference voltage, the VREF pin cannot be configured as the reference voltage input by properly configuring the corresponding pin-shared function control bits. Additionally, the LDO output path to the A/D converter reference voltage must also be switched off by clearing the REGSW bit in the REGC register. Otherwise, the external input voltage on VREF pin or the LDO output voltage together with the selected internal reference voltage will be simultaneously connected to the A/D converter reference voltage input. This will result in unpredictable situations. Refer to the “A/D Converter Reference Voltage” section for more details.

- Bit 2~0 **SACKS2~SACKS0**: A/D conversion clock source select
 000: f_{SYS}
 001: $f_{SYS}/2$
 010: $f_{SYS}/4$
 011: $f_{SYS}/8$
 100: $f_{SYS}/16$
 101: $f_{SYS}/32$
 110: $f_{SYS}/64$
 111: $f_{SYS}/128$

Temperature Sensor Control Register – SADC2

To control the enable and disable of the integrated temperature sensor circuitry, a control register known as SADC2 is provided.

• SADC2 Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	D5	D4	—	TSGS1	TSGS0	TSEN
R/W	—	—	R/W	R/W	—	R/W	R/W	R/W
POR	—	—	0	0	—	1	0	0

- Bit 7~6 Unimplemented, read as “0”
 Bit 5~4 **D5~D4**: Reserved bits, should be fixed to “0”
 Bit 3 Unimplemented, read as “0”
 Bit 2~1 **TSGS1~TSGS0**: Temperature sensor gain selection bits
 00: 1x
 01: 4x
 10: 5x
 11: 6x
 These bits must be fixed at “10”.
 Bit 0 **TSEN**: Temperature sensor circuitry enable control
 0: Disable
 1: Enable

This bit controls the internal temperature sensor circuitry. If the temperature sensor output will be converted or the temperature sensor reference voltage will be selected as the A/D conversion reference voltage, the temperature sensor circuitry should be turned on by setting the TSEN bit high first. When the temperature sensor is enabled by setting the TSEN bit to 1, a time named as t_{TSS} should be allowed for the temperature sensor circuit to stabilise before implementing relevant temperature sensor operation.

A/D Converter Operation

The START bit in the SADC0 register is used to start the AD conversion. When the microcontroller sets this bit from low to high and then low again, an analog to digital conversion cycle will be initiated.

The ADBZ bit in the SADC0 register is used to indicate whether the analog to digital conversion process is in progress or not. This bit will be automatically set to 1 by the microcontroller after an A/D conversion is successfully initiated. When the A/D conversion is complete, the ADBZ will be cleared to 0. In addition, the corresponding A/D interrupt request flag will be set in the interrupt control register, and if the interrupts are enabled, an appropriate internal interrupt signal will be generated. This A/D internal interrupt signal will direct the program flow to the associated A/D internal interrupt address for processing. If the A/D internal interrupt is disabled, the microcontroller can poll the ADBZ bit in the SADC0 register to check whether it has been cleared as an alternative method of detecting the end of an A/D conversion cycle.

The clock source for the A/D converter, which originates from the system clock f_{SYS} , can be chosen to be either f_{SYS} or a subdivided version of f_{SYS} . The division ratio value is determined by the SACKS2~SACKS0 bits in the SADC1 register. Although the A/D clock source is determined by the system clock f_{SYS} and SACKS2~SACKS0 bits, there are some limitations on the maximum A/D clock source speed that can be selected. As the recommended range of permissible A/D clock period, t_{ADCK} , is from 0.5 μ s to 10 μ s for all input analog signals except the temperature sensor output, care must be taken for system clock frequencies. For example, as the system clock operates at a frequency of 8MHz and the analog input is not selected from the temperature sensor output, the SACKS2~SACKS0 bits should not be set to 000, 001 or 111. Doing so will give A/D clock periods that are less than the minimum A/D clock period or larger than the maximum A/D clock period, which may result in inaccurate A/D conversion values. Refer to the following table for examples, where values marked with an asterisk * show where special care must be taken.

If the input signal to be converted is the temperature sensor output voltage, the permissible A/D clock period is from 1 μ s to 2 μ s.

f_{SYS}	A/D Clock Period (t_{ADCK})							
	SACKS[2:0] = 000 (f_{SYS})	SACKS[2:0] = 001 ($f_{SYS}/2$)	SACKS[2:0] = 010 ($f_{SYS}/4$)	SACKS[2:0] = 011 ($f_{SYS}/8$)	SACKS[2:0] = 100 ($f_{SYS}/16$)	SACKS[2:0] = 101 ($f_{SYS}/32$)	SACKS[2:0] = 110 ($f_{SYS}/64$)	SACKS[2:0] = 111 ($f_{SYS}/128$)
1MHz	1 μ s	2 μ s	4 μ s	8 μ s	16 μ s*	32 μ s*	64 μ s*	128 μ s*
2MHz	500ns	1 μ s	2 μ s	4 μ s	8 μ s	16 μ s*	32 μ s*	64 μ s*
4MHz	250ns*	500ns	1 μ s	2 μ s	4 μ s	8 μ s	16 μ s*	32 μ s*
8MHz	125ns*	250ns*	500ns	1 μ s	2 μ s	4 μ s	8 μ s	16 μ s*
12MHz	83ns*	167ns*	333ns*	667ns	1.33 μ s	2.67 μ s	5.33 μ s	10.67 μ s*

A/D Clock Period Examples

Controlling the power on/off function of the A/D converter circuitry is implemented using the ADCEN bit in the SADC0 register. This bit must be set high to power on the A/D converter. When the ADCEN bit is set high to power on the A/D converter internal circuitry a certain delay, as indicated in the timing diagram, must be allowed before an A/D conversion is initiated. Even if no pins are selected for use as A/D inputs, if the ADCEN bit is high, then some power will still be consumed. In power conscious applications it is therefore recommended that the ADCEN is set low to reduce power consumption when the A/D converter function is not being used.

A/D Converter Reference Voltage

The A/D converter has its own external reference voltage input pin, VREF. However, the reference voltage can also be supplied from the LDO output, or from the A/D converter power supply, AV_{DD}, or from the temperature sensor reference voltage, V_{TSVREF}. The choice is made using the SAVRS1 and SAVRS0 bits in the SADC1 register together with other control bits.

If the external VREF pin input voltage is required to use, firstly the SAVRS bit field should be set to “00” to select “VREF pin input or LDO output” option. As the VREF pin is pin-shared with other functions, then the relevant pin-shared control bits PAS1[7:6] should be set as “11” to enable the VREF pin function. Additionally, the LDO output path to the A/D converter reference voltage must be switched off by clearing the REGSW bit in the REGC register.

If the LDO output is required to use, firstly the SAVRS bit field should be set to “00” or “11” to select “VREF pin input or LDO output” option. Then set the REGEN[2:0] bits in the REGC register to select the required LDO voltage as A/D reference voltage and set the REGSW bit high to switch on the LDO output path to the A/D converter reference voltage. Additionally, ensure that the VREF pin is not configured as the reference voltage input function by setting the VREF pin-shared control bits PAS1[7:6] to any other value except “11”.

If the A/D converter power supply, AV_{DD} is required to use, the SAVRS bit field should be set to “01”. If the temperature sensor reference voltage is required to use, the SAVRS bit field should be set to “10”. As the temperature sensor circuitry is controlled by the TSEN bit, the TSEN bit should be set high to enable the temperature sensor. However, it is important to note that even when the AV_{DD} or V_{TSVREF} has been selected as the A/D converter reference voltage by correctly setting the SAVRS bit field, the LDO output path to the A/D converter reference voltage must be switched off and the VREF pin should not be configured as the reference voltage input function by properly configuring the REGSW bit and the PAS1[7:6] bits. Otherwise these signals may be input to the A/D converter reference simultaneously, which will result in unpredictable situations such as an irreversible damage.

Note that the analog input values must not be allowed to exceed the value of the selected A/D conversion reference voltage.

SAVRS[1:0]	Other Relevant Bits	Reference	Description
00/11	PAS1[7:6]=11 & REGSW=0	VREF pin	External VREF pin input voltage
	PAS1[7:6]≠11 & REGSW=1 & REGEN[2:0]=010/011/11x	V _{LDO}	LDO output voltage
01	PAS1[7:6]≠11 & REGSW=0	AV _{DD}	Internal A/D converter power supply
10	TSEN=1 & PAS1[7:6]≠11 & REGSW=0	V _{TSVREF}	Temperature sensor reference voltage

A/D Converter Reference Voltage Selection

A/D Converter Input Signals

All of the external A/D analog channel input pins are pin-shared with the I/O pins as well as other functions. The corresponding control bits for each A/D external input pin in the PxS0 and PxS1 register determine whether the input pins are setup as A/D converter analog inputs or whether they have other functions. If the pin is setup to be as an A/D analog channel input, the original pin functions will be disabled. In this way, pins can be changed under program control to change their function between A/D inputs and other functions. All pull high resistors, which are setup through register programming, will be automatically disconnected if the pins are setup as A/D inputs. Note that it is not necessary to first setup the A/D pin as an input in the port control register to enable the A/D input as when the pin-shared function control bits enable an A/D input, the status of the port control register will be overridden.

If the SAINS2~SAINS0 bits are set to one value of “000” and “110~111”, the external analog channel input is selected to be converted and the SACS3~SACS0 bits can determine which actual external channel is selected to be converted. If the SAINS2~SAINS0 bits are set to “001~101”, one of the internal signals, including the internal Bandgap reference voltage, temperature sensor output voltage, Dust Detector operational amplifier output signal is selected to be converted. Note that if the internal analog signal is selected to be converted, the external input channel determined by the SACS3~SACS0 bits must be switched to a non-existent A/D input channel by properly setting the SACS bit field with a value from 0100 to 1111. Otherwise, the external channel input will be connected together with the internal analog signal, which will result in unpredictable errors.

SAINS[2:0]	SACS[3:0]	Input Signals	Description
000, 110~111	0000~0011	AN0~AN3	External pin analog input
	0100~1111	—	Non-existent channel, input is floating
001	1100~1111	OPA0O	Internal DD operational amplifier 0 output signal
010	1100~1111	V _{TSG}	Internal Temperature Sensor output voltage
011	1100~1111	OPA1O	Internal DD operational amplifier 1 output signal
100	1100~1111	OPA2O	Internal DD operational amplifier 2 output signal
101	1100~1111	V _{BG}	Internal Bandgap reference voltage

A/D Converter Input Signal Selection

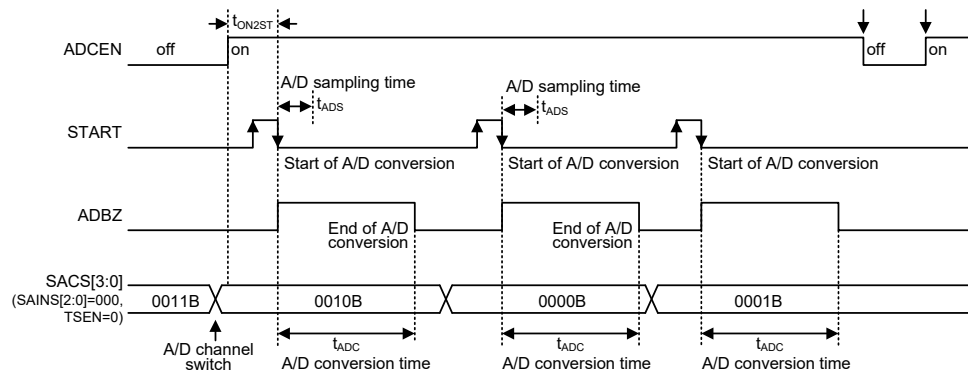
Conversion Rate and Timing Diagram

A complete A/D conversion contains two phases, data sampling and data conversion. If the conversion input signal is not the temperature sensor output, the data sampling which is defined as t_{ADS} takes 4 A/D clock periods and the data conversion takes 12 A/D clock periods. Therefore a total of 16 A/D clock periods for an A/D conversion which is defined as t_{ADC} are necessary. However, an A/D conversion for an internal temperature sensor signal will take a total of 58 A/D clock periods, which includes 46 A/D clock periods for data sampling and 12 A/D clock periods for data conversion.

Maximum single A/D conversion rate = $1/(A/D \text{ clock period} \times 16)$ (Temperature sensor output signal is not used)

Maximum single A/D conversion rate = $1/(A/D \text{ clock period} \times 58)$ (Internal Temperature sensor output signal is used)

The accompanying diagram shows graphically the various stages involved in an external channel input signal analog to digital conversion process and its associated timing. After an A/D conversion process has been initiated by the application program, the microcontroller internal hardware will begin to carry out the conversion, during which time the program can continue with other functions. The time taken for the A/D conversion is $16 t_{ADCK}$ where t_{ADCK} is equal to the A/D clock period.



A/D Conversion Timing – External Channel Inputs

Summary of A/D Conversion Steps

The following summarises the individual steps that should be executed in order to implement an A/D conversion process.

- Step 1
Select the required A/D conversion clock by correctly programming bits SACKS2~SACKS0 in the SADC1 register.
- Step 2
Enable the A/D by setting the ADCEN bit in the SADC0 register to one.
- Step 3
Select which signal is to be connected to the internal A/D converter by correctly configuring the SAINS2~SAINS0 bits
Select the external channel input to be converted, go to Step 4.
Select the internal analog signal to be converted, go to Step 5.
- Step 4
If the A/D input signal comes from the external channel input selected by configuring the SAINS bit field, the corresponding pins should be configured as A/D input function by configuring the relevant pin-shared function control bits. The desired analog channel then should be selected by configuring the SACS bit field. After this step, go to Step 6.
- Step 5
Before the A/D input signal is selected to come from the internal analog signal by configuring the SAINS2~SAINS0 bit field, the corresponding external input pin must be switched to a non-existent channel input by properly configured the SACS3~SACS0 bits. The desired internal analog signal then can be selected by configuring the SAINS2~SAINS0 bit field. After this step, go to Step 6.
- Step 6
Select the reference voltage source by configuring the SAVRS1~SAVRS0 bits in the SADC1 register. Care should be taken in this step which can refer to the A/D Converter Reference Voltage section for details.
- Step 7
Select A/D converter output data format by setting the ADRFS bit in the SADC0 register.
- Step 8
If the A/D conversion interrupt is used, the interrupt control registers must be correctly configured to ensure the A/D interrupt function is active. The master interrupt control bit, EMI, and the A/D conversion interrupt control bit, ADE, must both be set high in advance.
- Step 9
The A/D conversion procedure can now be initialized by setting the START bit from low to high and then low again.
- Step 10
If A/D conversion is in progress, the ADBZ flag will be set high. After the A/D conversion process is complete, the ADBZ flag will go low and then the output data can be read from SADOH and SADOL registers.

Note: When checking for the end of the conversion process, if the method of polling the ADBZ bit in the SADC0 register is used, the interrupt enable step above can be omitted.

Programming Considerations

During microcontroller operations where the A/D converter is not being used, the A/D internal circuitry can be switched off to reduce power consumption, by clearing bit ADCEN to 0 in the SADC0 register. When this happens, the internal A/D converter circuits will not consume power irrespective of what analog voltage is applied to their input lines. If the A/D converter input lines are used as normal I/Os, then care must be taken as if the input voltage is not at a valid logic level, then this may lead to some increase in power consumption.

A/D Conversion Function

As the device contains a 12-bit A/D converter, its full-scale converted digitised value is equal to FFFH. Since the full-scale analog input value is equal to the actual A/D converter reference voltage, V_{REF} , this gives a single bit analog input value of V_{REF} divided by 4096.

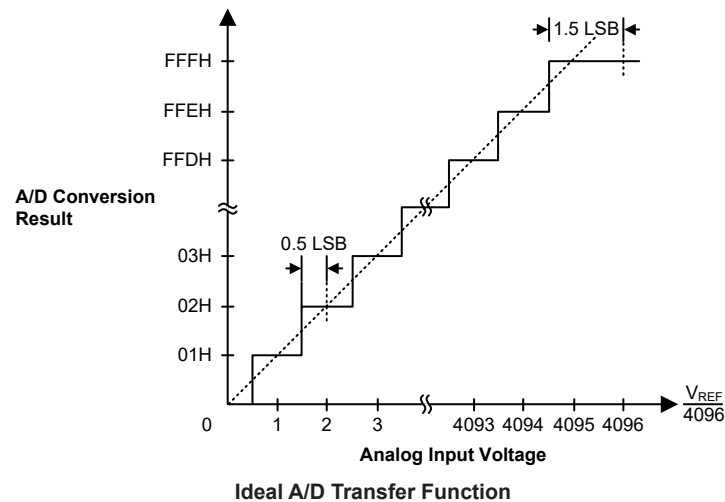
$$1 \text{ LSB} = V_{REF} \div 4096$$

The A/D converter input voltage value can be calculated using the following equation:

$$\text{A/D input voltage} = \text{A/D output digital value} \times (V_{REF} \div 4096)$$

The diagram shows the ideal transfer function between the analog input value and the digitised output value for the A/D converter. Except for the digitised zero value, the subsequent digitised values will change at a point 0.5 LSB below where they would change without the offset, and the last full scale digitised value will change at a point 1.5 LSB below the V_{REF} level.

Note that here the V_{REF} voltage is the actual A/D converter reference voltage determined by the SAVRS field.



Temperature Measurement Function

As the temperature sensor output voltage, V_{TSO} , has a linear relationship with temperature, the V_{TSO} A/D converted data value will also have a linear relationship with temperature. The current temperature T_x can be proportionally calculated from its A/D converted value ADC_x using the following formula.

$$T_x (^{\circ}\text{C}) = (\text{Slope} \times \text{ADC}_x) - T_{OS}; \text{ take the lower 12 bits of the final result}$$

The slope and T_{OS} code are stored in the Option Memory and can be read from the Program Memory last page using the table read instruction when the Option Memory mapping function is enabled.

At the end of every conversion or say MCU calculation, the final data Tx is in two's complement format, has a data width of 12 bits and a resolution of 0.0625(1/16)°C. The following Table shows multiple examples of binary or Hex data that can be read as temperature result.

Temperature	Digital Format (1 LSB = 1/16 = 0.0625°C)	
Tx(°C)	Binary	Hex
-40	1101 1000 0000	D80
-25	1110 0111 0000	E70
-10	1111 0110 0000	F60
-1	1111 1111 0000	FF0
-0.25	1111 1111 1100	FFC
-0.0625	1111 1111 1111	FFF
0	0000 0000 0000	000
0.0625	0000 0000 0001	001
0.25	0000 0000 0100	004
1	0000 0001 0000	010
10	0000 1010 0000	0A0
25	0001 1001 0000	190
40	0010 1000 0000	280
70	0100 0110 0000	460
85	0101 0101 0000	550

For example:

- Step 1
Read the Option Memory slope=0x0AB9, Tos=0x407.
- Step 2
Enable temperature sensor & A/D function, then start A/D and read back A/D data registers.
- Step 3
If ADCx=0x514, slope×ADCx=0x367374. Then remove the lower LSB 12 bits, get 0x0367.
- Step 4
Minus Tos, the result is 0x0367-0x407=FF60H(2's complement). Take the lower LSB 12 bits, then Tx=F60H=-10.0°C.

Name	Mapped Address in Program Memory	Description
Slope	FD3H	16-bit Slope value bit 15 ~ bit 8
	FD4H	16-bit Slope value bit 7 ~ bit 0
Tos	FD5H	12-bit Tos value bit 11 ~ bit 4
	FD6H	12-bit Tos value bit 3 ~ bit 0 (1 LSB = 1/16°C)

Temperature Measurement Reference Items

The Option Memory mapping function is enabled by using the ORMC register. For more details, refer to the “Option Memory Mapping Register – ORMC” in the Special Function Register Description section.

A/D Conversion Programming Examples

The following two programming examples illustrate how to setup and implement an A/D conversion. In the first example, the method of polling the ADBZ bit in the SADC0 register is used to detect when the conversion cycle is complete, whereas in the second example, the A/D interrupt is used to determine when the conversion is complete.

Example 1: using an ADBZ polling method to detect the end of conversion

```
clr ADE          ; disable ADC interrupt
clr TSEN         ; disable temperature sensor circuitry
mov a,0Bh        ; select fsys/8 as A/D clock, external channel as A/D input signal
mov SADC1,a      ; and A/D internal power as reference voltage
mov a,03h        ; setup PAS0 register to configure pin AN0
mov PAS0,a
mov a,20h
mov SADC0,a      ; enable and connect AN0 channel to A/D converter
:
start_conversion:
clr START        ; high pulse on start bit to initiate conversion
set START        ; reset A/D
clr START        ; start A/D
polling_EOC:
sz ADBZ          ; poll the SADC0 register ADBZ bit to detect end of A/D conversion
jmp polling_EOC  ; continue polling
mov a,SADOL      ; read low byte conversion result value
mov SADOL_buffer,a ; save result to user defined register
mov a,SAD0H      ; read high byte conversion result value
mov SADOH_buffer,a ; save result to user defined register
:
:
jmp start_conversion ; start next A/D conversion
```

Example 2: using the interrupt method to detect the end of conversion

```
clr ADE          ; disable ADC interrupt
clr TSEN         ; disable temperature sensor circuitry
mov a,0Bh        ; select fsys/8 as A/D clock, external channel as A/D input signal
mov SADC1,a      ; and A/D internal power as reference voltage
mov a,03h        ; setup PAS0 register to configure pin AN0
mov PAS0,a
mov a,20h
mov SADC0,a      ; enable and connect AN0 channel to A/D converter
:
start_conversion:
clr START        ; high pulse on START bit to initiate conversion
set START        ; reset A/D
clr START        ; start A/D
clr ADF          ; clear ADC interrupt request flag
set ADE          ; enable ADC interrupt
set EMI          ; enable global interrupt
:
:
; ADC interrupt service routine
ADC_ISR:
mov acc_stack,a  ; save ACC to user defined memory
mov a,STATUS
mov status_stack,a ; save STATUS to user defined memory
:
:
mov a,SADOL      ; read low byte conversion result value
mov SADOL_buffer,a ; save result to user defined register
mov a,SAD0H      ; read high byte conversion result value
mov SADOH_buffer,a ; save result to user defined register
:
:
EXIT_INT_ISR:
mov a,status_stack
mov STATUS,a     ; restore STATUS from user defined memory
mov a,acc_stack  ; restore ACC from user defined memory
reti
```

Universal Serial Interface Module – USIM

The device contains a Universal Serial Interface Module, which includes the four-line SPI interface, the two-line I²C interface and the two-line/single-wire UART interface types, to allow an easy method of communication with external peripheral hardware. Having relatively simple communication protocols, these serial interface types allow the microcontroller to interface to external SPI, I²C or UART based hardware such as sensors, Flash or EEPROM memory, etc. The USIM interface pins are pin-shared with other I/O pins therefore the USIM interface functional pins must first be selected using the corresponding pin-shared function selection bits. As all the interface types share the same pins and registers, the choice of whether the UART, SPI or I²C type is used is made using the UART mode selection bit, named UMD, and the SPI/I²C operating mode control bits, named SIM2~SIM0, in the SIMC0 register. These pull-high resistors of the USIM pin-shared I/O are selected using pull-high control registers when the USIM function is enabled and the corresponding pins are used as USIM input pins.

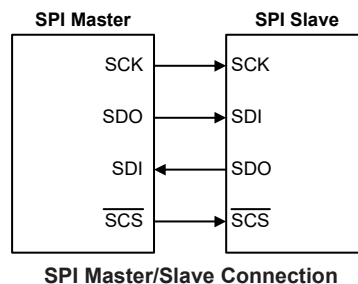
SPI Interface

The SPI interface is often used to communicate with external peripheral devices such as sensors, Flash or EEPROM memory devices etc. Originally developed by Motorola, the four line SPI interface is a synchronous serial data interface that has a relatively simple communication protocol simplifying the programming requirements when communicating with external hardware devices.

The communication is full duplex and operates as a slave/master type, where the device can be either master or slave. Although the SPI interface specification can control multiple slave devices from a single master, but the device provides only one \overline{SCS} pin. If the master needs to control multiple slave devices from a single master, the master can use I/O pin to select the slave devices.

SPI Interface Operation

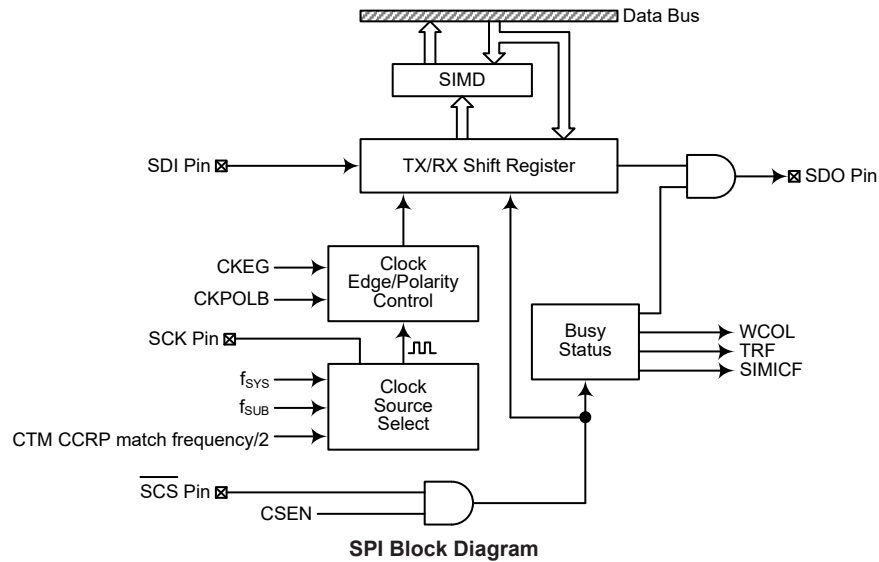
The SPI interface is a full duplex synchronous serial data link. It is a four line interface with pin names SDI, SDO, SCK and \overline{SCS} . Pins SDI and SDO are the Serial Data Input and Serial Data Output lines, the SCK pin is the Serial Clock line and \overline{SCS} is the Slave Select line. As the SPI interface pins are pin-shared with normal I/O pins and with the I²C/UART function pins, the SPI interface pins must first be selected by configuring the pin-shared function selection bits and setting the correct bits in the SIMC0 and SIMC2 registers. Communication between devices connected to the SPI interface is carried out in a slave/master mode with all data transfer initiations being implemented by the master. The Master also controls the clock signal. As the device only contains a single \overline{SCS} pin only one slave device can be utilized. The \overline{SCS} pin is controlled by software, set CSEN bit to 1 to enable \overline{SCS} pin function, set CSEN bit to 0 the \overline{SCS} pin will be floating state.



The SPI function in the device offers the following features:

- Full duplex synchronous data transfer
- Both Master and Slave modes
- LSB first or MSB first data transmission modes
- Transmission complete flag
- Rising or falling active clock edge

The status of the SPI interface pins is determined by a number of factors such as whether the device is in the master or slave mode and upon the condition of certain control bits such as CSEN and SIMEN.



SPI Registers

There are three internal registers which control the overall operation of the SPI interface. These are the SIMD data register and two control registers, SIMC0 and SIMC2. Note that the SIMC2 and SIMD registers and their POR values are only available when the SPI mode is selected by properly configuring the UMD and SIM2~SIM0 bits in the SIMC0 register.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SIMC0	SIM2	SIM1	SIM0	UMD	SIMDEB1	SIMDEB0	SIMEN	SIMICF
SIMC2	D7	D6	CKPOLB	CKEG	MLS	CSEN	WCOL	TRF
SIMD	D7	D6	D5	D4	D3	D2	D1	D0

SPI Register List

SPI Data Register

The SIMD register is used to store the data being transmitted and received. The same register is used by both the SPI and I²C functions. Before the device writes data to the SPI bus, the actual data to be transmitted must be placed in the SIMD register. After the data is received from the SPI bus, the device can read it from the SIMD register. Any transmission or reception of data from the SPI bus must be made via the SIMD register.

• **SIMD Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	x	x	x	x	x	x	x	x

“x”: unknown

Bit 7~0 **D7~D0**: USIM SPI/I²C data register bit 7 ~ bit 0

SPI Control Registers

There are also two control registers for the SPI interface, SIMC0 and SIMC2. The SIMC0 register is used to control the enable/disable function and to set the data transmission clock frequency. The SIMC2 register is used for other control functions such as LSB/MSB selection, write collision flag etc.

• **SIMC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	SIM2	SIM1	SIM0	UMD	SIMDEB1	SIMDEB0	SIMEN	SIMICF
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	1	1	1	0	0	0	0	0

Bit 7~5 **SIM2~SIM0**: USIM SPI/I²C Operating Mode Control

- 000: SPI master mode; SPI clock is $f_{SYS}/4$
- 001: SPI master mode; SPI clock is $f_{SYS}/16$
- 010: SPI master mode; SPI clock is $f_{SYS}/64$
- 011: SPI master mode; SPI clock is f_{SUB}
- 100: SPI master mode; SPI clock is CTM CCRP match frequency/2
- 101: SPI slave mode
- 110: I²C slave mode
- 111: Unused mode

When the UMD bit is cleared to zero, these bits setup the SPI or I²C operating mode of the USIM function. As well as selecting if the I²C or SPI function, they are used to control the SPI Master/Slave selection and the SPI Master clock frequency. The SPI clock is a function of the system clock but can also be chosen to be sourced from CTM and f_{SUB} . If the SPI Slave Mode is selected then the clock will be supplied by an external Master device.

Bit 4 **UMD**: UART mode selection bit

- 0: SPI or I²C mode
- 1: UART mode

This bit is used to select the UART mode. When this bit is cleared to zero, the actual SPI or I²C mode can be selected using the SIM2~SIM0 bits. Note that the UMD bit must be cleared to zero for SPI or I²C mode.

Bit 3~2 **SIMDEB1~SIMDEB0**: I²C Debounce Time Selection

These bits are only available when the USIM is configured to operate in the I²C mode. Refer to the I²C register section.

Bit 1 **SIMEN**: USIM SPI/I²C Enable Control

- 0: Disable
- 1: Enable

The bit is the overall on/off control for the USIM SPI/I²C interface. When the SIMEN bit is cleared to zero to disable the USIM SPI/I²C interface, the SDI, SDO, SCK and \overline{SCS} , or SDA and SCL lines will lose their SPI or I²C function and the USIM operating current will be reduced to a minimum value. When the bit is high the USIM SPI/I²C interface is enabled. If the USIM is configured to operate as an SPI interface via the UMD and SIM2~SIM0 bits, the contents of the SPI control registers will remain at the previous settings when the SIMEN bit changes from low to high and should therefore

be first initialised by the application program. If the USIM is configured to operate as an I²C interface via the UMD and SIM2~SIM0 bits and the SIMEN bit changes from low to high, the contents of the I²C control bits such as HTX and TXAK will remain at the previous settings and should therefore be first initialised by the application program while the relevant I²C flags such as HCF, HAAS, HBB, SRW and RXAK will be set to their default states.

- Bit 0 **SIMICF**: USIM SPI Incomplete Flag
 0: USIM SPI incomplete condition is not occurred
 1: USIM SPI incomplete condition is occurred

This bit is only available when the USIM is configured to operate in an SPI slave mode. If the SPI operates in the slave mode with the SIMEN and CSEN bits both being set high but the \overline{SCS} line is pulled high by the external master device before the SPI data transfer is completely finished, the SIMICF bit will be set high together with the TRF bit. When this condition occurs, the corresponding interrupt will occur if the interrupt function is enabled. However, the TRF bit will not be set high if the SIMICF bit is set high by software application program.

• **SIMC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	CKPOLB	CKEG	MLS	CSEN	WCOL	TRF
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7~6 **D7~D6**: Undefined bits

These bits can be read or written by application program.

- Bit 5 **CKPOLB**: SPI clock line base condition selection
 0: The SCK line will be high when the clock is inactive
 1: The SCK line will be low when the clock is inactive

The CKPOLB bit determines the base condition of the clock line, if the bit is high, then the SCK line will be low when the clock is inactive. When the CKPOLB bit is low, then the SCK line will be high when the clock is inactive.

- Bit 4 **CKEG**: SPI SCK active clock edge type selection
 CKPOLB=0
 0: SCK is high base level and data capture at SCK rising edge
 1: SCK is high base level and data capture at SCK falling edge
 CKPOLB=1
 0: SCK is low base level and data capture at SCK falling edge
 1: SCK is low base level and data capture at SCK rising edge

The CKEG and CKPOLB bits are used to setup the way that the clock signal outputs and inputs data on the SPI bus. These two bits must be configured before data transfer is executed otherwise an erroneous clock edge may be generated. The CKPOLB bit determines the base condition of the clock line, if the bit is high, then the SCK line will be low when the clock is inactive. When the CKPOLB bit is low, then the SCK line will be high when the clock is inactive. The CKEG bit determines active clock edge type which depends upon the condition of CKPOLB bit.

- Bit 3 **MLS**: SPI data shift order
 0: LSB first
 1: MSB first

This is the data shift select bit and is used to select how the data is transferred, either MSB or LSB first. Setting the bit high will select MSB first and low for LSB first.

- Bit 2 **CSEN**: SPI \overline{SCS} pin control
 0: Disable
 1: Enable

The CSEN bit is used as an enable/disable for the \overline{SCS} pin. If this bit is low, then the \overline{SCS} pin will be disabled and placed into a floating condition. If the bit is high the \overline{SCS} pin will be enabled and used as a select pin.

Bit 1 **WCOL**: SPI write collision flag
 0: No collision
 1: Collision

The WCOL flag is used to detect if a data collision has occurred. If this bit is high it means that data has been attempted to be written to the SIMD register during a data transfer operation. This writing operation will be ignored if data is being transferred. The bit can be cleared to zero by the application program.

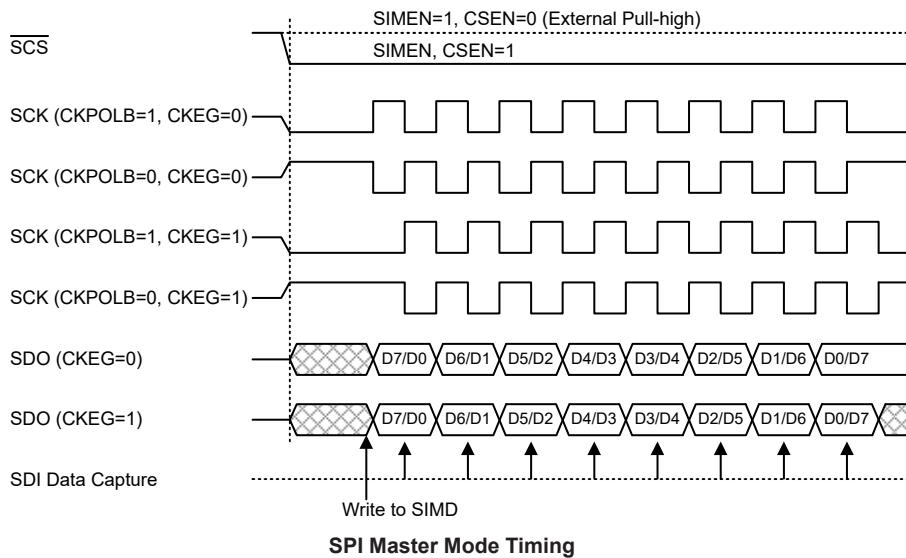
Bit 0 **TRF**: SPI Transmit/Receive complete flag
 0: SPI data is being transferred
 1: SPI data transmission is completed

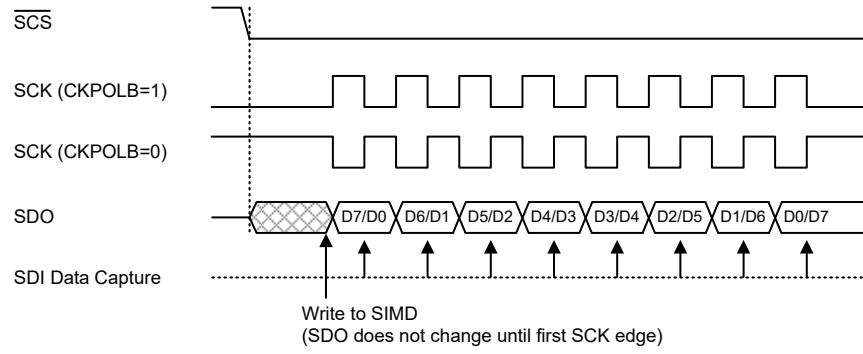
The TRF bit is the Transmit/Receive Complete flag and is set “1” automatically when an SPI data transmission is completed, but must set to “0” by the application program. It can be used to generate an interrupt.

SPI Communication

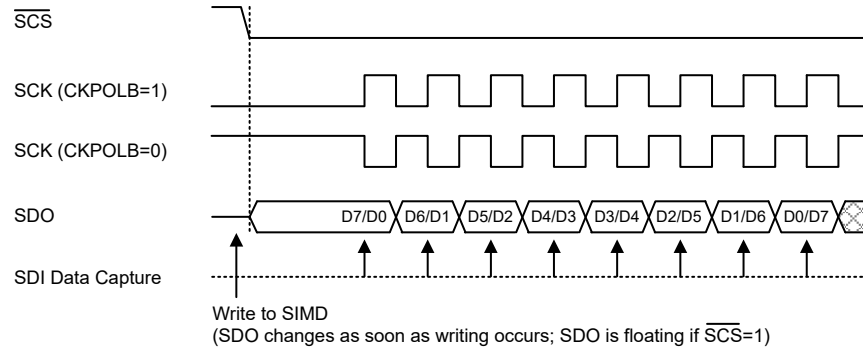
After the SPI interface is enabled by setting the SIMEN bit high, then in the Master Mode, when data is written to the SIMD register, transmission/reception will begin simultaneously. When the data transfer is completed, the TRF flag will be set high automatically, but must be cleared using the application program. In the Slave Mode, when the clock signal from the master has been received, any data in the SIMD register will be transmitted and any data on the SDI pin will be shifted into the SIMD register. The master should output an \overline{SCS} signal to enable the slave devices before a clock signal is provided. The slave data to be transferred should be well prepared at the appropriate moment relative to the SCK signal depending upon the configurations of the CKPOLB bit and CKEG bit. The accompanying timing diagram shows the relationship between the slave data and SCK signal for various configurations of the CKPOLB and CKEG bits.

The SPI Master mode will continue to function if the SPI clock is running.



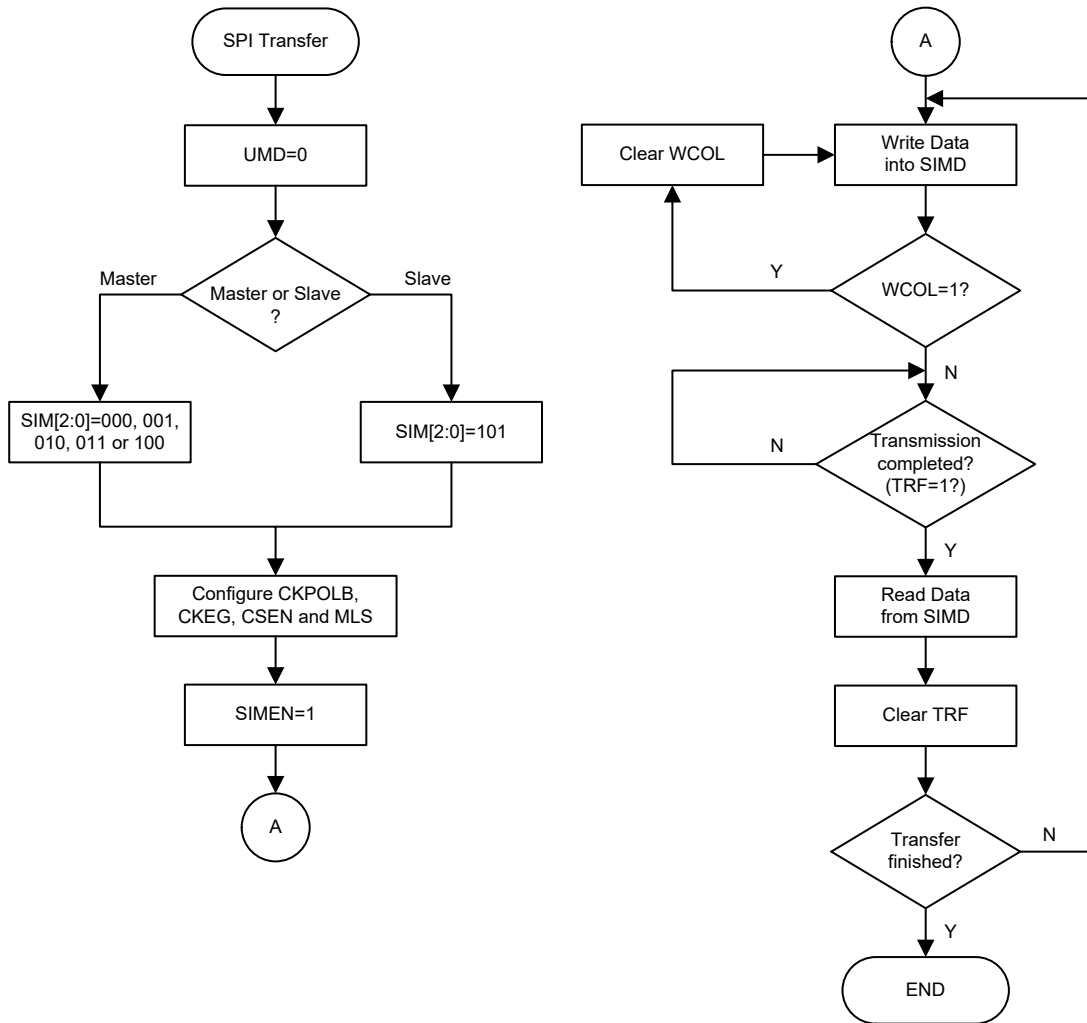


SPI Slave Mode Timing – CKEG=0



SPI Slave Mode Timing – CKEG=1

Note: For SPI slave mode, if $\overline{SIMEN}=1$ and $\overline{CSEN}=0$, SPI is always enabled and ignores the \overline{SCS} level.



SPI Transfer Control Flowchart

SPI Bus Enable/Disable

To enable the SPI bus, set CSEN=1 and \overline{SCS} =0, then wait for data to be written into the SIMD (TXRX buffer) register. For the Master Mode, after data has been written to the SIMD (TXRX buffer) register, then transmission or reception will start automatically. When all the data has been transferred, the TRF bit should be set. For the Slave Mode, when clock pulses are received on SCK, data in the TXRX buffer will be shifted out or data on SDI will be shifted in.

When the SPI bus is disabled, SCK, SDI, SDO and \overline{SCS} can become I/O pins or other pin-shared functions using the corresponding pin-shared control bits.

SPI Operation Steps

All communication is carried out using the 4-line interface for either Master or Slave Mode.

The CSEN bit in the SIMC2 register controls the \overline{SCS} pin function of the SPI interface. Setting this bit high will enable the SPI interface by allowing the \overline{SCS} line to be active, which can then be used to control the SPI interface. If the CSEN bit is low, the SPI interface will be disabled and the \overline{SCS} line will be in a floating condition and can therefore not be used for control of the SPI interface. If the CSEN bit and the SIMEN bit in the SIMC0 are set high, this will place the SDI

line in a floating condition and the SDO line high. If in Master Mode the SCK line will be either high or low depending upon the clock polarity selection bit CKPOLB in the SIMC2 register. If in Slave Mode the SCK line will be in a floating condition. If the SIMEN bit is low, then the bus will be disabled and \overline{SCS} , SDI, SDO and SCK will all become I/O pins or the other functions using the corresponding pin-shared control bits. In the Master Mode the Master will always generate the clock signal. The clock and data transmission will be initiated after data has been written into the SIMD register. In the Slave Mode, the clock signal will be received from an external master device for both data transmission and reception. The following sequences show the order to be followed for data transfer in both Master and Slave Mode.

Master Mode

- Step 1
Select the SPI Master mode and clock source using the UMD and SIM2~SIM0 bits in the SIMC0 control register.
- Step 2
Setup the CSEN bit and setup the MLS bit to choose if the data is MSB or LSB first, this setting must be the same with the Slave devices.
- Step 3
Setup the SIMEN bit in the SIMC0 control register to enable the SPI interface.
- Step 4
For write operations: write the data to the SIMD register, which will actually place the data into the TXRX buffer. Then use the SCK and SDO lines to output the data. After this, go to step 5.
For read operations: the data transferred in on the SDI line will be stored in the TXRX buffer until all the data has been received at which point it will be latched into the SIMD register.
- Step 5
Check the WCOL bit if set high then a collision error has occurred so return to step 4. If equal to zero then go to the following step.
- Step 6
Check the TRF bit or wait for a USIM SPI serial bus interrupt.
- Step 7
Read data from the SIMD register.
- Step 8
Clear TRF.
- Step 9
Go to step 4.

Slave Mode

- Step 1
Select the SPI Slave mode using the UMD and SIM2~SIM0 bits in the SIMC0 control register
- Step 2
Setup the CSEN bit and setup the MLS bit to choose if the data is MSB or LSB first, this setting must be the same with the Master devices.
- Step 3
Setup the SIMEN bit in the SIMC0 control register to enable the SPI interface.
- Step 4
For write operations: write the data to the SIMD register, which will actually place the data into the TXRX buffer. Then wait for the master clock SCK and \overline{SCS} signal. After this, go to step 5.

For read operations: the data transferred in on the SDI line will be stored in the TXRX buffer until all the data has been received at which point it will be latched into the SIMD register.

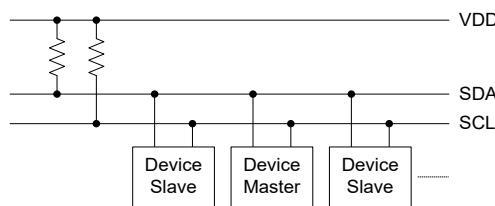
- Step 5
Check the WCOL bit if set high then a collision error has occurred so return to step 4. If equal to zero then go to the following step.
- Step 6
Check the TRF bit or wait for a USIM SPI serial bus interrupt.
- Step 7
Read data from the SIMD register.
- Step 8
Clear TRF.
- Step 9
Go to step 4.

Error Detection

The WCOL bit in the SIMC2 register is provided to indicate errors during data transfer. The bit is set by the SPI serial Interface but must be cleared by the application program. This bit indicates that a data collision has occurred which happens if a write to the SIMD register takes place during a data transfer operation and will prevent the write operation from continuing.

I²C Interface

The I²C interface is used to communicate with external peripheral devices such as sensors, EEPROM memory etc. Originally developed by Philips, it is a two line low speed serial interface for synchronous serial data transfer. The advantage of only two lines for communication, relatively simple communication protocol and the ability to accommodate multiple devices on the same bus has made it an extremely popular interface type for many applications.

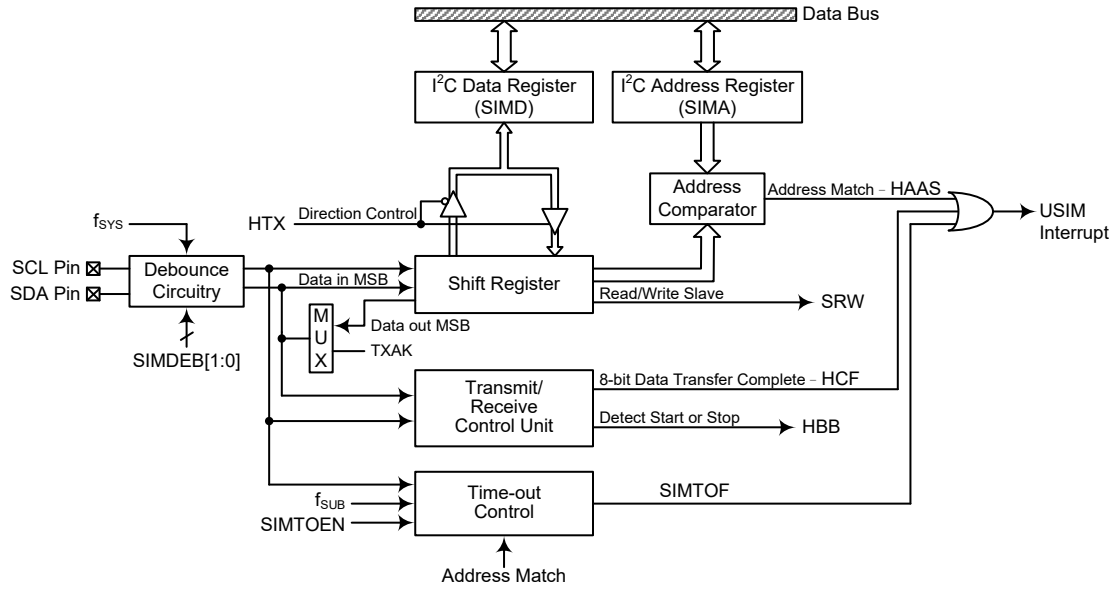


I²C Master Slave Bus Connection

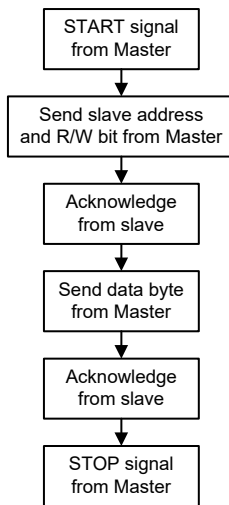
I²C Interface Operation

The I²C serial interface is a two line interface, a serial data line, SDA, and serial clock line, SCL. As many devices may be connected together on the same bus, their outputs are both open drain types. For this reason it is necessary that external pull-high resistors are connected to these outputs. Note that no chip select line exists, as each device on the I²C bus is identified by a unique address which will be transmitted and received on the I²C bus.

When two devices communicate with each other on the bidirectional I²C bus, one is known as the master device and one as the slave device. Both master and slave can transmit and receive data, however, it is the master device that has overall control of the bus. For the device, which only operates in slave mode, there are two methods of transferring data on the I²C bus, the slave transmit mode and the slave receive mode. The pull-high control function pin-shared with SCL/SDA pin is still applicable even if I²C device is activated and the related internal pull-high register could be controlled by its corresponding pull-high control register.



I²C Block Diagram



I²C Interface Operation

The SIMDEB1 and SIMDEB0 bits determine the debounce time of the I²C interface. This uses the internal clock to in effect add a debounce time to the external clock to reduce the possibility of glitches on the clock line causing erroneous operation. The debounce time, if selected, can be chosen to be either 2 or 4 system clocks. To achieve the required I²C data transfer speed, there exists a relationship between the system clock, f_{SYS} , and the I²C debounce time. For either the I²C Standard or Fast mode operation, users must take care of the selected system clock frequency and the configured debounce time to match the criterion shown in the following table.

I ² C Debounce Time Selection	I ² C Standard Mode (100kHz)	I ² C Fast Mode (400kHz)
No Debounce	$f_{SYS} > 2\text{MHz}$	$f_{SYS} > 4\text{MHz}$
2 system clock debounce	$f_{SYS} > 4\text{MHz}$	$f_{SYS} > 8\text{MHz}$
4 system clock debounce	$f_{SYS} > 4\text{MHz}$	$f_{SYS} > 8\text{MHz}$

I²C Minimum f_{SYS} Frequency Requirements

I²C Registers

There are three control registers associated with the I²C bus, SIMC0, SIMC1 and SIMTOC, one address register SIMA and one data register, SIMD. Note that the SIMC1, SIMD, SIMA and SIMTOC registers and their POR values are only available when the I²C mode is selected by properly configuring the UMD and SIM2~SIM0 bits in the SIMC0 register.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SIMC0	SIM2	SIM1	SIM0	UMD	SIMDEB1	SIMDEB0	SIMEN	SIMICF
SIMC1	HCF	HAAS	HBB	HTX	TXAK	SRW	IAMWU	RXAK
SIMD	D7	D6	D5	D4	D3	D2	D1	D0
SIMA	SIMA6	SIMA5	SIMA4	SIMA3	SIMA2	SIMA1	SIMA0	D0
SIMTOC	SIMTOEN	SIMTOF	SIMTOS5	SIMTOS4	SIMTOS3	SIMTOS2	SIMTOS1	SIMTOS0

I²C Register List

I²C Data Register

The SIMD register is used to store the data being transmitted and received. The same register is used by both the SPI and I²C functions. Before the device writes data to the I²C bus, the actual data to be transmitted must be placed in the SIMD register. After the data is received from the I²C bus, the device can read it from the SIMD register. Any transmission or reception of data from the I²C bus must be made via the SIMD register.

• SIMD Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	x	x	x	x	x	x	x	x

"x": unknown

Bit 7~0 **D7~D0**: USIM SPI/I²C data register bit 7 ~ bit 0

I²C Address Register

The SIMA register is also used by the SPI interface but has the name SIMC2. The SIMA register is the location where the 7-bit slave address of the slave device is stored. Bits 7~1 of the SIMA register define the device slave address. Bit 0 is not defined. When a master device, which is connected to the I²C bus, sends out an address, which matches the slave address in the SIMA register, the slave device will be selected.

• SIMA Register

Bit	7	6	5	4	3	2	1	0
Name	SIMA6	SIMA5	SIMA4	SIMA3	SIMA2	SIMA1	SIMA0	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~1 **SIMA6~SIMA0**: I²C slave address
SIMA6~SIMA0 is the 7-bit I²C slave address.

Bit 0 **D0**: Reserved bit, can be read or written by application program

I²C Control Registers

There are three control registers for the I²C interface, SIMC0, SIMC1 and SIMTOC. The SIMC0 register is used to control the enable/disable function and to select the I²C slave mode and debounce time. The SIMC1 register contains the relevant flags which are used to indicate the I²C communication status. Another register, SIMTOC, is used to control the I²C time-out function and is described in the corresponding section.

• SIMC0 Register

Bit	7	6	5	4	3	2	1	0
Name	SIM2	SIM1	SIM0	UMD	SIMDEB1	SIMDEB0	SIMEN	SIMICF
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	1	1	1	0	0	0	0	0

Bit 7~5 **SIM2~SIM0**: USIM SPI/I²C Operating Mode Control
 000: SPI master mode; SPI clock is $f_{SYS}/4$
 001: SPI master mode; SPI clock is $f_{SYS}/16$
 010: SPI master mode; SPI clock is $f_{SYS}/64$
 011: SPI master mode; SPI clock is f_{SUB}
 100: SPI master mode; SPI clock is CTM CCRP match frequency/2
 101: SPI slave mode
 110: I²C slave mode
 111: Unused mode

When the UMD bit is cleared to zero, these bits setup the SPI or I²C operating mode of the USIM function. As well as selecting if the I²C or SPI function, they are used to control the SPI Master/Slave selection and the SPI Master clock frequency. The SPI clock is a function of the system clock but can also be chosen to be sourced from PTM and f_{SUB} . If the SPI Slave Mode is selected then the clock will be supplied by an external Master device.

Bit 4 **UMD**: UART mode selection bit
 0: SPI or I²C mode
 1: UART mode

This bit is used to select the UART mode. When this bit is cleared to zero, the actual SPI or I²C mode can be selected using the SIM2~SIM0 bits. Note that the UMD bit must be set low for SPI or I²C mode.

Bit 3~2 **SIMDEB1~SIMDEB0**: I²C Debounce Time Selection
 00: No debounce
 01: 2 system clock debounce
 10: 4 system clock debounce
 11: 4 system clock debounce

These bits are used to select the I²C debounce time when the USIM is configured as the I²C interface function by setting the UMD bit to “0” and SIM2~SIM0 bits to “110”.

Bit 1 **SIMEN**: USIM SPI/I²C Enable Control
 0: Disable
 1: Enable

The bit is the overall on/off control for the USIM SPI/I²C interface. When the SIMEN bit is cleared to zero to disable the USIM SPI/I²C interface, the SDI, SDO, SCK and SCS, or SDA and SCL lines will lose their SPI or I²C function and the USIM operating current will be reduced to a minimum value. When the bit is high the USIM SPI/I²C interface is enabled. If the USIM is configured to operate as an SPI interface via the UMD and SIM2~SIM0 bits, the contents of the SPI control registers will remain at the previous settings when the SIMEN bit changes from low to high and should therefore be first initialised by the application program. If the USIM is configured to operate as an I²C interface via the UMD and SIM2~SIM0 bits and the SIMEN bit changes from low to high, the contents of the I²C control bits such as HTX and TXAK will remain

at the previous settings and should therefore be first initialised by the application program while the relevant I²C flags such as HCF, HAAS, HBB, SRW and RXAK will be set to their default states.

Bit 0 **SIMICF**: USIM SPI Incomplete Flag
This bit is only available when the USIM is configured to operate in an SPI slave mode. Refer to the SPI register section.

• **SIMC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	HCF	HAAS	HBB	HTX	TXAK	SRW	IAMWU	RXAK
R/W	R	R	R	R/W	R/W	R	R/W	R
POR	1	0	0	0	0	0	0	1

Bit 7 **HCF**: I²C Bus data transfer completion flag
0: Data is being transferred
1: Completion of an 8-bit data transfer
The HCF flag is the data transfer flag. This flag will be zero when data is being transferred. Upon completion of an 8-bit data transfer the flag will go high and an interrupt will be generated.

Bit 6 **HAAS**: I²C Bus address match flag
0: Not address match
1: Address match
The HAAS flag is the address match flag. This flag is used to determine if the slave device address is the same as the master transmit address. If the addresses match then this bit will be high, if there is no match then the flag will be low.

Bit 5 **HBB**: I²C Bus busy flag
0: I²C Bus is not busy
1: I²C Bus is busy
The HBB flag is the I²C busy flag. This flag will be “1” when the I²C bus is busy which will occur when a START signal is detected. The flag will be set to “0” when the bus is free which will occur when a STOP signal is detected.

Bit 4 **HTX**: I²C slave device is transmitter or receiver selection
0: Slave device is the receiver
1: Slave device is the transmitter

Bit 3 **TXAK**: I²C Bus transmit acknowledge flag
0: Slave send acknowledge flag
1: Slave do not send acknowledge flag
The TXAK bit is the transmit acknowledge flag. After the slave device receipt of 8 bits of data, this bit will be transmitted to the bus on the 9th clock from the slave device. The slave device must always set TXAK bit to “0” before further data is received.

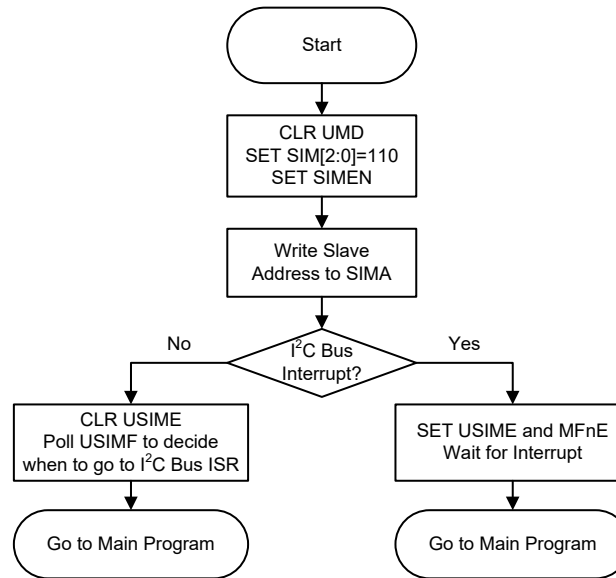
Bit 2 **SRW**: I²C Slave Read/Write flag
0: Slave device should be in receive mode
1: Slave device should be in transmit mode
The SRW flag is the I²C Slave Read/Write flag. This flag determines whether the master device wishes to transmit or receive data from the I²C bus. When the transmitted address and slave address is match, that is when the HAAS flag is set high, the slave device will check the SRW flag to determine whether it should be in transmit mode or receive mode. If the SRW flag is high, the master is requesting to read data from the bus, so the slave device should be in transmit mode. When the SRW flag is zero, the master will write data to the bus, therefore the slave device should be in receive mode to read this data.

Bit 1	IAMWU: I ² C Address Match Wake-up control 0: Disable 1: Enable This bit should be set high to enable the I ² C address match wake up from the SLEEP or IDLE Mode. If the IAMWU bit has been set before entering either the SLEEP or IDLE mode to enable the I ² C address match wake up, then this bit must be cleared to zero by the application program after wake-up to ensure correction device operation.
Bit 0	RXAK: I ² C Bus Receive acknowledge flag 0: Slave receive acknowledge flag 1: Slave does not receive acknowledge flag The RXAK flag is the receiver acknowledge flag. When the RXAK flag is “0”, it means that a acknowledge signal has been received at the 9th clock, after 8 bits of data have been transmitted. When the slave device in the transmit mode, the slave device checks the RXAK flag to determine if the master receiver wishes to receive the next byte. The slave transmitter will therefore continue sending out data until the RXAK flag is “1”. When this occurs, the slave transmitter will release the SDA line to allow the master to send a STOP signal to release the I ² C Bus.

I²C Bus Communication

Communication on the I²C bus requires four separate steps, a START signal, a slave device address transmission, a data transmission and finally a STOP signal. When a START signal is placed on the I²C bus, all devices on the bus will receive this signal and be notified of the imminent arrival of data on the bus. The first seven bits of the data will be the slave address with the first bit being the MSB. If the address of the slave device matches that of the transmitted address, the HAAS bit in the SIMC1 register will be set and an USIM interrupt will be generated. After entering the interrupt service routine, the slave device must first check the condition of the HAAS and SIMTOF bits to determine whether the interrupt source originates from an address match or from the completion of an 8-bit data transfer completion or from the I²C bus time-out occurrence. During a data transfer, note that after the 7-bit slave address has been transmitted, the following bit, which is the 8th bit, is the read/write bit whose value will be placed in the SRW bit. This bit will be checked by the slave device to determine whether to go into transmit or receive mode. Before any transfer of data to or from the I²C bus, the microcontroller must initialise the bus, the following are steps to achieve this:

- Step 1
Set the UMD, SIM2~SIM0 and SIMEN bits in the SIMC0 register to “0”, “110” and “1” respectively to enable the I²C bus.
- Step 2
Write the slave address of the device to the I²C bus address register SIMA.
- Step 3
Set the USIME interrupt enable bit of the interrupt control register to enable the USIM interrupt.



I²C Bus Initialisation Flow Chart

I²C Bus Start Signal

The START signal can only be generated by the master device connected to the I²C bus and not by the slave device. This START signal will be detected by all devices connected to the I²C bus. When detected, this indicates that the I²C bus is busy and therefore the HBB bit will be set. A START condition occurs when a high to low transition on the SDA line takes place when the SCL line remains high.

I²C Slave Address

The transmission of a START signal by the master will be detected by all devices on the I²C bus. To determine which slave device the master wishes to communicate with, the address of the slave device will be sent out immediately following the START signal. All slave devices, after receiving this 7-bit address data, will compare it with their own 7-bit slave address. If the address sent out by the master matches the internal address of the microcontroller slave device, then an internal USIM I²C bus interrupt signal will be generated. The next bit following the address, which is the 8th bit, defines the read/write status and will be saved to the SRW bit of the SIMC1 register. The slave device will then transmit an acknowledge bit, which is a low level, as the 9th bit. The slave device will also set the status flag HAAS when the addresses match.

As an USIM I²C bus interrupt signal can come from three sources, when the program enters the interrupt subroutine, the HAAS and SIMTOF bits should be examined to see whether the interrupt source has come from a matching slave address or from the completion of a data byte transfer or from the I²C bus time-out occurrence. When a slave address is matched, the device must be placed in either the transmit mode and then write data to the SIMD register, or in the receive mode where it must implement a dummy read from the SIMD register to release the SCL line.

I²C Bus Read/Write Signal

The SRW bit in the SIMC1 register defines whether the master device wishes to read data from the I²C bus or write data to the I²C bus. The slave device should examine this bit to determine if it is to be a transmitter or a receiver. If the SRW flag is “1” then this indicates that the master device wishes to read data from the I²C bus, therefore the slave device must be setup to send data to the I²C bus as a transmitter. If the SRW flag is “0” then this indicates that the master wishes to send data to the I²C bus, therefore the slave device must be setup to read data from the I²C bus as a receiver.

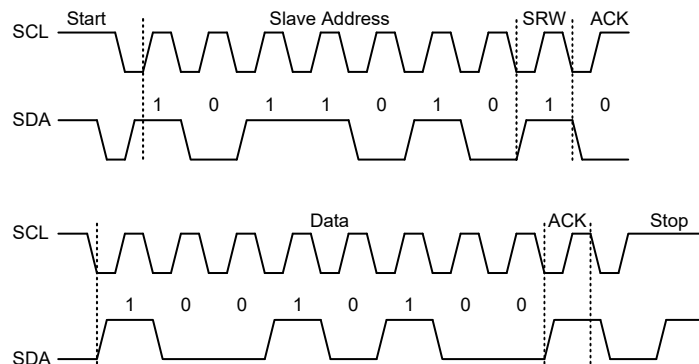
I²C Bus Slave Address Acknowledge Signal

After the master has transmitted a calling address, any slave device on the I²C bus, whose own internal address matches the calling address, must generate an acknowledge signal. The acknowledge signal will inform the master that a slave device has accepted its calling address. If no acknowledge signal is received by the master then a STOP signal must be transmitted by the master to end the communication. When the HAAS flag is high, the addresses have matched and the slave device must check the SRW flag to determine if it is to be a transmitter or a receiver. If the SRW flag is high, the slave device should be setup to be a transmitter so the HTX bit in the SIMC1 register should be set to “1”. If the SRW flag is low, then the microcontroller slave device should be setup as a receiver and the HTX bit in the SIMC1 register should be set to “0”.

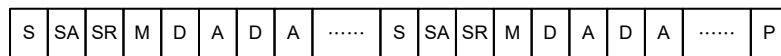
I²C Bus Data and Acknowledge Signal

The transmitted data is 8-bit wide and is transmitted after the slave device has acknowledged receipt of its slave address. The order of serial bit transmission is the MSB first and the LSB last. After receipt of 8 bits of data, the receiver must transmit an acknowledge signal, level “0”, before it can receive the next data byte. If the slave transmitter does not receive an acknowledge bit signal from the master receiver, then the slave transmitter will release the SDA line to allow the master to send a STOP signal to release the I²C Bus. The corresponding data will be stored in the SIMD register. If setup as a transmitter, the slave device must first write the data to be transmitted into the SIMD register. If setup as a receiver, the slave device must read the transmitted data from the SIMD register.

When the slave receiver receives the data byte, it must generate an acknowledge bit, known as TXAK, on the 9th clock. The slave device, which is setup as a transmitter will check the RXAK bit in the SIMC1 register to determine if it is to send another data byte, if not then it will release the SDA line and await the receipt of a STOP signal from the master.

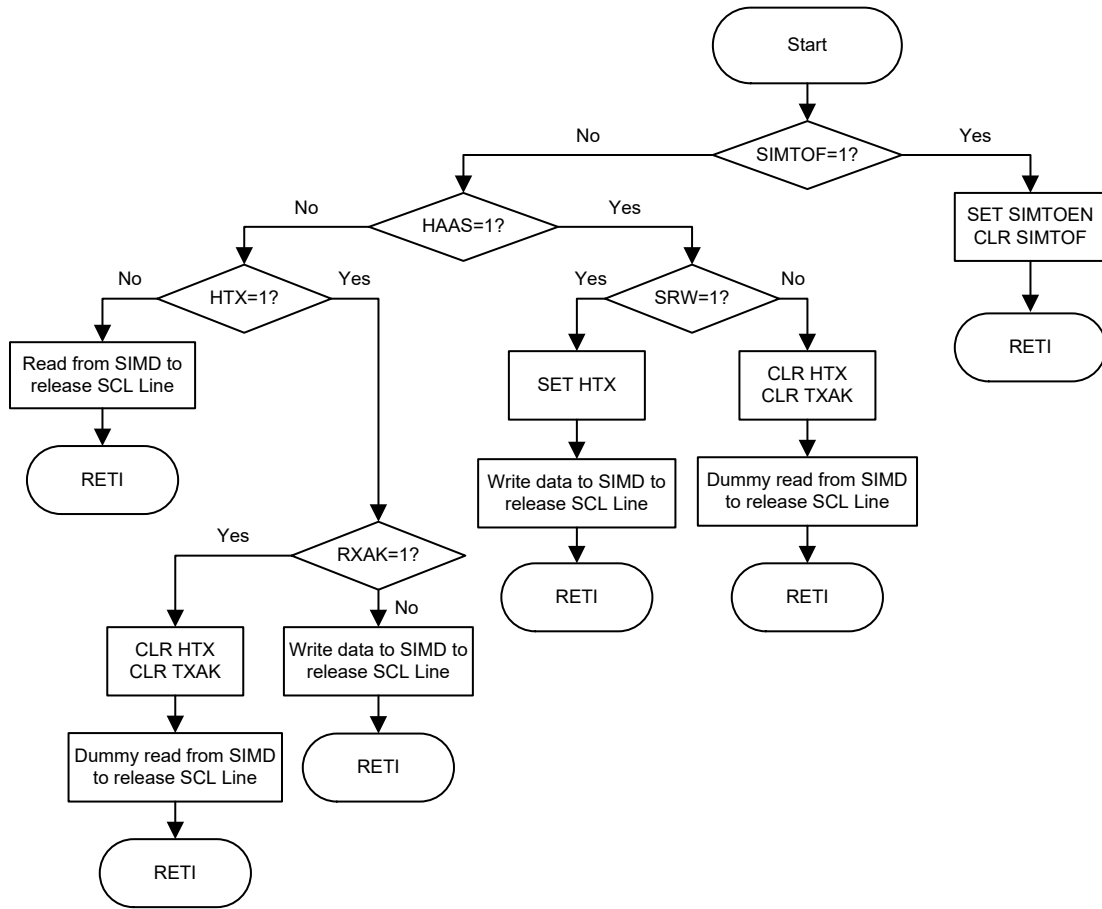


- S=Start (1 bit)
- SA=Slave Address (7 bits)
- SR=SRW bit (1 bit)
- M=Slave device send acknowledge bit (1 bit)
- D=Data (8 bits)
- A=ACK (RXAK bit for transmitter, TXAK bit for receiver, 1 bit)
- P=Stop (1 bit)



I²C Communication Timing Diagram

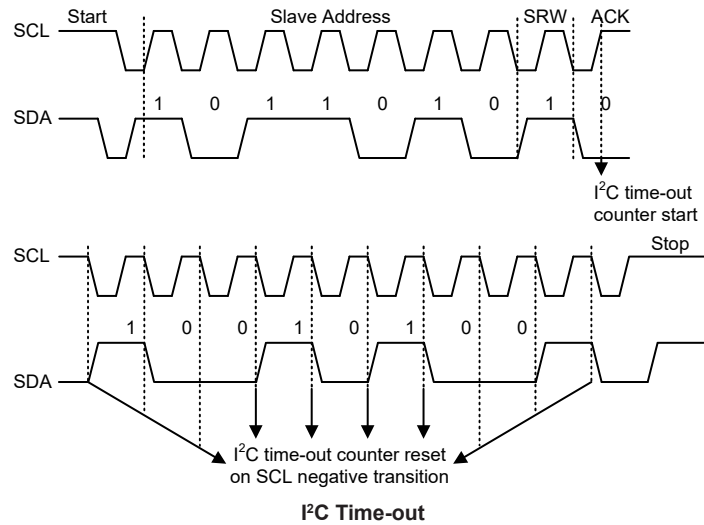
Note: When a slave address is matched, the device must be placed in either the transmit mode and then write data to the SIMD register, or in the receive mode where it must implement a dummy read from the SIMD register to release the SCL line.



I²C Bus ISR Flow Chart

I²C Time-out Control

In order to reduce the problem of I²C lockup due to reception of erroneous clock sources, a time-out function is provided. If the clock source to the I²C is not received for a while, then the I²C circuitry and registers will be reset after a certain time-out period. The time-out counter starts counting on an I²C bus “START” & “address match” condition, and is cleared by an SCL falling edge. Before the next SCL falling edge arrives, if the time elapsed is greater than the time-out setup by the SIMTOC register, then a time-out condition will occur. The time-out function will stop when an I²C “STOP” condition occurs.



When an I²C time-out counter overflow occurs, the counter will stop and the SIMTOEN bit will be cleared to zero and the SIMTOF bit will be set high to indicate that a time-out condition has occurred. The time-out condition will also generate an interrupt which uses the USIM interrupt vector. When an I²C time-out occurs, the I²C internal circuitry will be reset and the registers will be reset into the following condition:

Registers	After I ² C Time-out
SIMD, SIMA, SIMC0	No change
SIMC1	Reset to POR condition

I²C Registers after Time-out

The SIMTOF flag can be cleared by the application program. There are 64 time-out periods which can be selected using SIMTOS bit field in the SIMTOC register. The time-out time is given by the formula: $((1\sim64)\times32)/f_{SUB}$. This gives a time-out period which ranges from about 1ms to 64ms.

• SIMTOC Register

Bit	7	6	5	4	3	2	1	0
Name	SIMTOEN	SIMTOF	SIMTOS5	SIMTOS4	SIMTOS3	SIMTOS2	SIMTOS1	SIMTOS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **SIMTOEN**: USIM I²C Time-out control
 0: Disable
 1: Enable

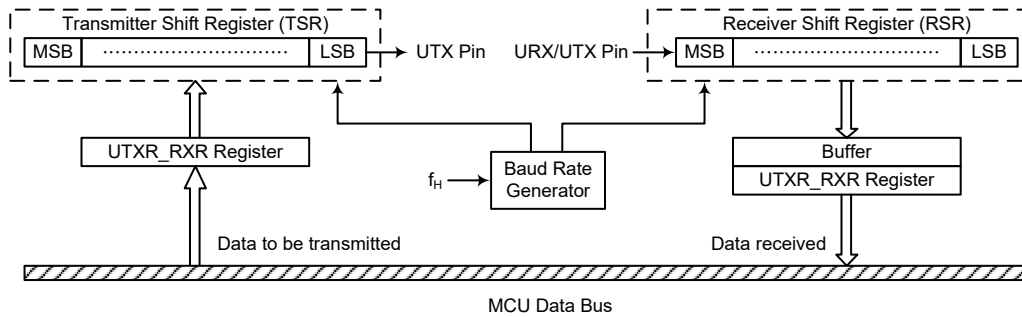
- Bit 6 **SIMTOF**: USIM I²C Time-out flag
 0: No time-out occurred
 1: Time-out occurred
 This bit is set high when time-out occurs and can only be cleared to zero by application program.
- Bit 5~0 **SIMTOS5~SIMTOS0**: USIM I²C Time-out period selection
 I²C time-out clock source is $f_{SUB}/32$.
 I²C time-out time is equal to $(SIMTOS[5:0]+1) \times (32/f_{SUB})$.

UART Interface

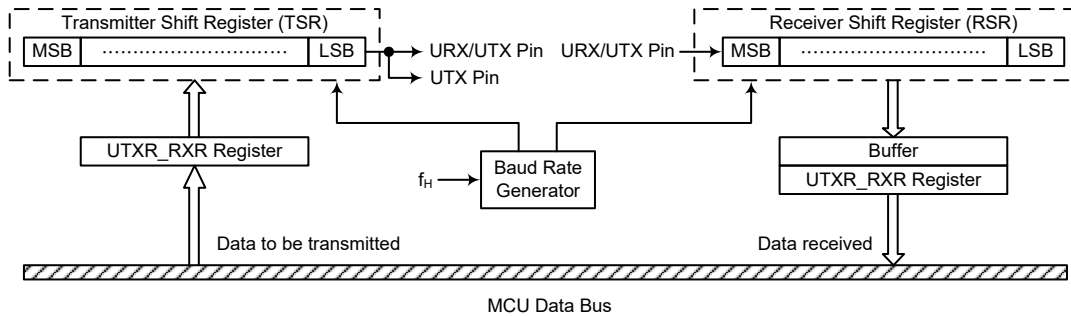
The device contains an integrated full-duplex or half-duplex asynchronous serial communication UART interface that enables communication with external devices that contain a serial interface. The UART function has many features and can transmit and receive data serially by transferring a frame of data with eight or nine data bits per transmission as well as being able to detect errors when the data is overwritten or incorrectly framed. The UART function shares the same internal interrupt vector with the SPI and I²C interfaces which can be used to indicate when a reception occurs or when a transmission terminates.

The integrated UART function contains the following features:

- Full-duplex or half-duplex (single wire mode) asynchronous communication
- 8 or 9 bits character length
- Even, odd or no parity options
- One or two stop bits
- Baud rate generator with 8-bit prescaler
- Parity, framing, noise and overrun error detection
- Support for interrupt on address detect (last character bit=1)
- Separately enabled transmitter and receiver
- 2-byte Deep FIFO Receive Data Buffer
- URX/UTX pin wake-up function
- Transmit and receive interrupts
- Interrupts can be triggered by the following conditions:
 - ♦ Transmitter Empty
 - ♦ Transmitter Idle
 - ♦ Receiver Full
 - ♦ Receiver Overrun
 - ♦ Address Mode Detect



UART Data Transfer Block Diagram – USWM=0



UART Data Transfer Block Diagram – USWM=1

UART External Pins

To communicate with an external serial interface, the internal UART has two external pins known as UTX pin and URX/UTX pin, which are pin-shared with I/O or other pin functions. The UTX and URX/UTX pin function should first be selected by the corresponding pin-shared function selection register before the UART function is used. Along with the UMD bit, the UREN bit, the UTXEN or URXEN bits, if set, will configure these pins to transmitter output and receiver input conditions. At this time the internal pull-high resistor related to the transmitter output pin will be disabled, while the internal pull-high resistor related to the receiver input pin is controlled by the corresponding I/O pull-high function control bit. When the UTX or URX/UTX pin function is disabled by clearing the UMD, UREN, UTXEN or URXEN bit, the UTX or URX/UTX pin will be set to a floating state. At this time whether the internal pull-high resistor is connected to the UTX or URX/UTX pin or not is determined by the corresponding I/O pull-high function control bit.

UART Single Wire Mode

The UART function also supports a Single Wire Mode communication which is selected using the USWM bit in the UUCR3 register. When the USWM bit is set high, the UART function will be in the single wire mode. In the single wire mode, a single URX/UTX pin can be used to transmit and receive data depending upon the corresponding control bits. When the URXEN bit is set high, the URX/UTX pin is used as a receiver pin. When the URXEN bit is cleared to zero and the UTXEN bit is set high, the URX/UTX pin will act as a transmitter pin.

It is recommended not to set both the URXEN and UTXEN bits high in the single wire mode. If both the URXEN and UTXEN bits are set high, the URXEN bit will have the priority and the UART will act as a receiver.

It is important to note that the functional description in this UART chapter, which is described from the full-duplex communication standpoint, also applies to the half-duplex (single wire mode) communication except the pin usage. In the single wire mode, the UTX pin mentioned in this chapter should be replaced by the URX/UTX pin to understand the whole UART single wire mode function.

In the single wire mode, the data can also be transmitted on the UTX pin in a transmission operation with proper software configurations. Therefore, the data will be output on the URX/UTX and UTX pins.

UART Data Transfer Scheme

The UART Data Transfer Block Diagram shows the overall data transfer structure arrangement for the UART. The actual data to be transmitted from the MCU is first transferred to the UTXR_RXR register by the application program. The data will then be transferred to the Transmit Shift Register from where it will be shifted out, LSB first, onto the UTX pin at a rate controlled by the Baud Rate Generator. Only the UTXR_RXR register is mapped onto the MCU Data Memory, the Transmit Shift Register is not mapped and is therefore inaccessible to the application program.

Data to be received by the UART is accepted on the external URX/UTX pin, from where it is shifted in, LSB first, to the Receiver Shift Register at a rate controlled by the Baud Rate Generator. When the shift register is full, the data will then be transferred from the shift register to the internal UTXR_RXR register, where it is buffered and can be manipulated by the application program. Only the UTXR_RXR register is mapped onto the MCU Data Memory, the Receiver Shift Register is not mapped and is therefore inaccessible to the application program.

It should be noted that the actual register for data transmission and reception only exists as a single shared register in the Data Memory. This shared register known as the UTXR_RXR register is used for both data transmission and data reception.

UART Status and Control Registers

There are seven control registers associated with the UART function. The UMD bit in the SIMC0 register can be used to select the UART interface. The USWM bit in the UUCR3 register is used to enable/disable the UART Single Wire Mode. The UUSR, UUCR1 and UUCR2 registers control the overall function of the UART, while the UBRG register controls the Baud rate. The actual data to be transmitted and received on the serial interface is managed through the UTXR_RXR data register. Note that UART related registers and their POR values are only available when the UART mode is selected by setting the UMD bit in the SIMC0 register to “1”.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SIMC0	SIM2	SIM1	SIM0	UMD	SIMDEB1	SIMDEB0	SIMEN	SIMICF
UUSR	UPERR	UNF	UFERR	UOERR	URIDLE	URXIF	UTIDLE	UTXIF
UUCR1	UREN	UBNO	UPREN	UPRT	USTOPS	UTXBRK	URX8	UTX8
UUCR2	—	—	—	—	—	—	—	UTEIE
UUCR3	—	—	—	—	—	—	—	USWM
UTXR_RXR	UTXRX7	UTXRX6	UTXRX5	UTXRX4	UTXRX3	UTXRX2	UTXRX1	UTXRX0
UBRG	UBRG7	UBRG6	UBRG5	UBRG4	UBRG3	UBRG2	UBRG1	UBRG0

UART Register List

• **SIMC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	SIM2	SIM1	SIM0	UMD	SIMDEB1	SIMDEB0	SIMEN	SIMICF
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	1	1	1	0	0	0	0	0

- Bit 7~5 **SIM2~SIM0**: USIM SPI/I²C Operating Mode Control
 When the UMD bit is cleared to zero, these bits setup the SPI or I²C operating mode of the USIM function. Refer to the SPI or I²C register section for more details.
- Bit 4 **UMD**: UART mode selection bit
 0: SPI or I²C mode
 1: UART mode
 This bit is used to select the UART mode. When this bit is cleared to zero, the actual SPI or I²C mode can be selected using the SIM2~SIM0 bits. Note that the UMD bit must be set low for SPI or I²C mode.
- Bit 3~2 **SIMDEB1~SIMDEB0**: I²C Debounce Time Selection
 Refer to the I²C register section.
- Bit 1 **SIMEN**: USIM SPI/I²C Enable Control
 This bit is only available when the USIM is configured to operate in an SPI or I²C mode with the UMD bit set low. Refer to the SPI or I²C register section for more details.
- Bit 0 **SIMICF**: USIM SPI Incomplete Flag
 Refer to the SPI register section.

• **UUSR Register**

The UUSR register is the status register for the UART, which can be read by the program to determine the present status of the UART. All flags within the UUSR register are read only. Further explanation on each of the flags is given below:

Bit	7	6	5	4	3	2	1	0
Name	UPERR	UNF	UFERR	UOERR	URIDLE	URXIF	UTIDLE	UTXIF
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	1	0	1	1

- Bit 7 **UPERR**: Parity error flag
 0: No parity error is detected
 1: Parity error is detected
 The UPERR flag is the parity error flag. When this read only flag is “0”, it indicates a parity error has not been detected. When the flag is “1”, it indicates that the parity of the received word is incorrect. This error flag is applicable only if Parity mode (odd or even) is selected. The flag can also be cleared to zero by a software sequence which involves a read to the status register UUSR followed by an access to the UTXR_RXR data register.
- Bit 6 **UNF**: Noise flag
 0: No noise is detected
 1: Noise is detected
 The UNF flag is the noise flag. When this read only flag is “0”, it indicates no noise condition. When the flag is “1”, it indicates that the UART has detected noise on the receiver input. The UNF flag is set during the same cycle as the URXIF flag but will not be set in the case of as overrun. The UNF flag can be cleared to zero by a software sequence which will involve a read to the status register UUSR followed by an access to the UTXR_RXR data register.
- Bit 5 **UFERR**: Framing error flag
 0: No framing error is detected
 1: Framing error is detected

The UFERR flag is the framing error flag. When this read only flag is “0”, it indicates that there is no framing error. When the flag is “1”, it indicates that a framing error has been detected for the current character. The flag can also be cleared to zero by a software sequence which will involve a read to the status register UUSR followed by an access to the UTXR_RXR data register.

- Bit 4 **UOERR:** Overrun error flag
 0: No overrun error is detected
 1: Overrun error is detected

The UOERR flag is the overrun error flag which indicates when the receiver buffer has overflowed. When this read only flag is “0”, it indicates that there is no overrun error. When the flag is “1”, it indicates that an overrun error occurs which will inhibit further transfers to the UTXR_RXR receive data register. The flag is cleared to zero by a software sequence, which is a read to the status register UUSR followed by an access to the UTXR_RXR data register.

- Bit 3 **URIDLE:** Receiver status
 0: Data reception is in progress (Data being received)
 1: No data reception is in progress (Receiver is idle)

The URIDLE flag is the receiver status flag. When this read only flag is “0”, it indicates that the receiver is between the initial detection of the start bit and the completion of the stop bit. When the flag is “1”, it indicates that the receiver is idle. Between the completion of the stop bit and the detection of the next start bit, the URIDLE bit is “1” indicating that the UART receiver is idle and the URX/UTX pin stays in logic high condition.

- Bit 2 **URXIF:** Receive UTXR_RXR data register status
 0: UTXR_RXR data register is empty
 1: UTXR_RXR data register has available data

The URXIF flag is the receive data register status flag. When this read only flag is “0”, it indicates that the UTXR_RXR read data register is empty. When the flag is “1”, it indicates that the UTXR_RXR read data register contains new data. When the contents of the shift register are transferred to the UTXR_RXR register, an interrupt is generated if URIE=1 in the UUCR2 register. If one or more errors are detected in the received word, the appropriate receive-related flags UNF, UFERR, and/or UPERR are set within the same clock cycle. The URXIF flag will eventually be cleared to zero when the UUSR register is read with URXIF set, followed by a read from the UTXR_RXR register, and if the UTXR_RXR register has no more new data available.

- Bit 1 **UTIDLE:** Transmission idle
 0: Data transmission is in progress (Data being transmitted)
 1: No data transmission is in progress (Transmitter is idle)

The UTIDLE flag is known as the transmission complete flag. When this read only flag is “0”, it indicates that a transmission is in progress. This flag will be set high when the UTXIF flag is “1” and when there is no transmit data or break character being transmitted. When UTIDLE is equal to “1”, the UTX pin becomes idle with the pin state in logic high condition. The UTIDLE flag is cleared to zero by reading the UUSR register with UTIDLE set and then writing to the UTXR_RXR register. The flag is not generated when a data character or a break is queued and ready to be sent.

- Bit 0 **UTXIF:** Transmit UTXR_RXR data register status
 0: Character is not transferred to the transmit shift register
 1: Character has transferred to the transmit shift register (UTXR_RXR data register is empty)

The UTXIF flag is the transmit data register empty flag. When this read only flag is “0”, it indicates that the character is not transferred to the transmitter shift register. When the flag is “1”, it indicates that the transmitter shift register has received a character from the UTXR_RXR data register. The UTXIF flag is cleared to zero by reading the UART status register (UUSR) with UTXIF set and then writing to the UTXR_RXR data register. Note that when the UTXEN bit is set, the UTXIF flag bit will also be set since the transmit data register is not yet full.

• **UUCR1 Register**

The UUCR1 register together with the UUCR2 and UUCR3 registers are the three UART control registers that are used to set the various options for the UART function, such as overall on/off control, parity control, data transfer bit length, single wire mode communication etc. Further explanation on each of the bits is given below:

Bit	7	6	5	4	3	2	1	0
Name	UREN	UBNO	UPREN	UPRT	USTOPS	UTXBRK	URX8	UTX8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R	W
POR	0	0	0	0	0	0	x	0

“x”: unknown

Bit 7 **UREN**: UART function enable control

- 0: Disable UART. UTX and URX/UTX pins are in a floating state
- 1: Enable UART. UTX and URX/UTX pins function as UART pins

The UREN bit is the UART enable bit. When this bit is equal to “0”, the UART will be disabled and the URX/UTX pin as well as the UTX pin will be set in a floating state. When the bit is equal to “1”, the UART will be enabled if the UMD bit is set and the UTX and URX/UTX pins will function as defined by the USWM mode selection bit together with the UTXEN and URXEN enable control bits.

When the UART is disabled, it will empty the buffer so any character remaining in the buffer will be discarded. In addition, the value of the baud rate counter will be reset. If the UART is disabled, all error and status flags will be reset. Also the UTXEN, URXEN, UTXBRK, URXIF, UOERR, UFERR, UPERR and UNF bits will be cleared to zero, while the UTIDLE, UTXIF and URIDLE bits will be set high. Other control bits in UUCR1, UUCR2, UUCR3 and UBRG registers will remain unaffected. If the UART is active and the UREN bit is cleared to zero, all pending transmissions and receptions will be terminated and the module will be reset as defined above. When the UART is re-enabled, it will restart in the same configuration.

Bit 6 **UBNO**: Number of data transfer bits selection

- 0: 8-bit data transfer
- 1: 9-bit data transfer

This bit is used to select the data length format, which can have a choice of either 8-bit or 9-bit format. When this bit is equal to “1”, a 9-bit data length format will be selected. If the bit is equal to “0”, then an 8-bit data length format will be selected. If 9-bit data length format is selected, then bits URX8 and UTX8 will be used to store the 9th bit of the received and transmitted data respectively.

Bit 5 **UPREN**: Parity function enable control

- 0: Parity function is disabled
- 1: Parity function is enabled

This is the parity enable bit. When this bit is equal to “1”, the parity function will be enabled. If the bit is equal to “0”, then the parity function will be disabled.

Bit 4 **UPRT**: Parity type selection bit

- 0: Even parity for parity generator
- 1: Odd parity for parity generator

This bit is the parity type selection bit. When this bit is equal to “1”, odd parity type will be selected. If the bit is equal to “0”, then even parity type will be selected.

Bit 3 **USTOPS**: Number of Stop bits selection

- 0: One stop bit format is used
- 1: Two stop bits format is used

This bit determines if one or two stop bits are to be used. When this bit is equal to “1”, two stop bits are used. If this bit is equal to “0”, then only one stop bit is used.

Bit 2 **UTXBRK**: Transmit break character

- 0: No break character is transmitted
- 1: Break characters transmit

The UTXBRK bit is the Transmit Break Character bit. When this bit is “0”, there are no break characters and the UTX pin operates normally. When the bit is “1”, there are transmit break characters and the transmitter will send logic zeros. When this bit is equal to “1”, after the buffered data has been transmitted, the transmitter output is held low for a minimum of a 13-bit length and until the UTXBRK bit is reset.

- Bit 1 **URX8**: Receive data bit 8 for 9-bit data transfer format (read only)
This bit is only used if 9-bit data transfers are used, in which case this bit location will store the 9th bit of the received data known as URX8. The UBNO bit is used to determine whether data transfers are in 8-bit or 9-bit format.
- Bit 0 **UTX8**: Transmit data bit 8 for 9-bit data transfer format (write only)
This bit is only used if 9-bit data transfers are used, in which case this bit location will store the 9th bit of the transmitted data known as UTX8. The UBNO bit is used to determine whether data transfers are in 8-bit or 9-bit format.

• **UUCR2 Register**

The UUCR2 register is the second of the UART control registers and serves several purposes. One of its main functions is to control the basic enable/disable operation of the UART Transmitter and Receiver as well as enabling the various USIM UART mode interrupt sources. The register also serves to control the baud rate speed, receiver wake-up enable and the address detect enable. Further explanation on each of the bits is given below:

Bit	7	6	5	4	3	2	1	0
Name	UTXEN	URXEN	UBRGH	UADDEN	UWAKE	URIE	UTIIE	UTEIE
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7 **UTXEN**: UART Transmitter enabled control
0: UART transmitter is disabled
1: UART transmitter is enabled

The bit named UTXEN is the Transmitter Enable Bit. When this bit is equal to “0”, the transmitter will be disabled with any pending data transmissions being aborted. In addition the buffers will be reset. In this situation the UTX pin will be set in a floating state. If the UTXEN bit is equal to “1” and the UMD and UREN bit are also equal to “1”, the transmitter will be enabled and the UTX pin will be controlled by the UART. Clearing the UTXEN bit during a transmission will cause the data transmission to be aborted and will reset the transmitter. If this situation occurs, the UTX pin will be set in a floating state.
- Bit 6 **URXEN**: UART Receiver enabled control
0: UART receiver is disabled
1: UART receiver is enabled

The bit named URXEN is the Receiver Enable Bit. When this bit is equal to “0”, the receiver will be disabled with any pending data receptions being aborted. In addition the receive buffers will be reset. In this situation the URX/UTX pin will be set in a floating state. If the URXEN bit is equal to “1” and the UMD and UREN bit are also equal to “1”, the receiver will be enabled and the URX/UTX pin will be controlled by the UART. Clearing the URXEN bit during a reception will cause the data reception to be aborted and will reset the receiver. If this situation occurs, the URX/UTX pin will be set in a floating state.
- Bit 5 **UBRGH**: Baud Rate speed selection
0: Low speed baud rate
1: High speed baud rate

The bit named UBRGH selects the high or low speed mode of the Baud Rate Generator. This bit, together with the value placed in the baud rate register UBRG, controls the Baud Rate of the UART. If this bit is equal to “1”, the high speed mode is selected. If the bit is equal to “0”, the low speed mode is selected.

- Bit 4 **UADDEN**: Address detect function enable control
 0: Address detect function is disabled
 1: Address detect function is enabled
The bit named UADDEN is the address detect function enable control bit. When this bit is equal to “1”, the address detect function is enabled. When it occurs, if the 8th bit, which corresponds to UTXRX7 if UBNO=0 or the 9th bit, which corresponds to URX8 if UBNO=1, has a value of “1”, then the received word will be identified as an address, rather than data. If the corresponding interrupt is enabled, an interrupt request will be generated each time the received word has the address bit set, which is the 8th or 9th bit depending on the value of UBNO. If the address bit known as the 8th or 9th bit of the received word is “0” with the address detect function being enabled, an interrupt will not be generated and the received data will be discarded.
- Bit 3 **UWAKE**: URX/UTX pin wake-up UART function enable control
 0: URX/UTX pin wake-up UART function is disabled
 1: URX/UTX pin wake-up UART function is enabled
This bit is used to control the wake-up UART function when a falling edge on the URX/UTX pin occurs. Note that this bit is only available when the UART clock (f_{H}) is switched off. There will be no URX/UTX pin wake-up UART function if the UART clock (f_{H}) exists. If the UWAKE bit is set high as the UART clock (f_{H}) is switched off, a UART wake-up request will be initiated when a falling edge on the URX/UTX pin occurs. When this request happens and the corresponding interrupt is enabled, an URX/UTX pin wake-up UART interrupt will be generated to inform the MCU to wake up the UART function by switching on the UART clock (f_{H}) via the application program. Otherwise, the UART function cannot resume even if there is a falling edge on the URX/UTX pin when the UWAKE bit is cleared to zero.
- Bit 2 **URIE**: Receiver interrupt enable control
 0: Receiver related interrupt is disabled
 1: Receiver related interrupt is enabled
This bit enables or disables the receiver interrupt. If this bit is equal to “1” and when the receiver overrun flag UOERR or receive data available flag URXIF is set, the USIM interrupt request flag USIMF will be set. If this bit is equal to “0”, the USIM interrupt request flag USIMF will not be influenced by the condition of the UOERR or URXIF flags.
- Bit 1 **UTIE**: Transmitter Idle interrupt enable control
 0: Transmitter idle interrupt is disabled
 1: Transmitter idle interrupt is enabled
This bit enables or disables the transmitter idle interrupt. If this bit is equal to “1” and when the transmitter idle flag UTIDLE is set, due to a transmitter idle condition, the USIM interrupt request flag USIMF will be set. If this bit is equal to “0”, the USIM interrupt request flag USIMF will not be influenced by the condition of the UTIDLE flag.
- Bit 0 **UTEIE**: Transmitter Empty interrupt enable control
 0: Transmitter empty interrupt is disabled
 1: Transmitter empty interrupt is enabled
This bit enables or disables the transmitter empty interrupt. If this bit is equal to “1” and when the transmitter empty flag UTXIF is set, due to a transmitter empty condition, the USIM interrupt request flag USIMF will be set. If this bit is equal to “0”, the USIM interrupt request flag USIMF will not be influenced by the condition of the UTXIF flag.

• UUCR3 Register

The UUCR3 register is used to enable the UART Single Wire Mode communication. As the name suggests in the single wire mode the UART communication can be implemented in one single line, URX/UTX, together with the control of the URXEN and UTXEN bits in the UUCR2 register.

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	USWM
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as “0”

Bit 0 **USWM**: Single Wire Mode enable control

0: Disable, the URX/UTX pin is used as UART receiver function only

1: Enable, the URX/UTX pin can be used as UART receiver or transmitter function controlled by the URXEN and UTXEN bits

Note that when the Single Wire Mode is enabled, if both the URXEN and UTXEN bits are high, the URX/UTX pin will just be used as UART receiver input.

• UTXR_RXR Register

The UTXR_RXR register is the data register which is used to store the data to be transmitted on the UTX pin or being received from the URX/UTX pin.

Bit	7	6	5	4	3	2	1	0
Name	UTXRX7	UTXRX6	UTXRX5	UTXRX4	UTXRX3	UTXRX2	UTXRX1	UTXRX0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	x	x	x	x	x	x	x	x

“x”: unknown

Bit 7~0 **UTXRX7~UTXRX0**: UART Transmit/Receive Data bit 7 ~ bit 0

• UBRG Register

Bit	7	6	5	4	3	2	1	0
Name	UBRG7	UBRG6	UBRG5	UBRG4	UBRG3	UBRG2	UBRG1	UBRG0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	x	x	x	x	x	x	x	x

“x”: unknown

Bit 7~0 **UBRG7~UBRG0**: Baud Rate values

By programming the UBRGH bit in UUCR2 register which allows selection of the related formula described above and programming the required value in the UBRG register, the required baud rate can be setup.

Note: Baud rate = $f_{in}/[64 \times (N+1)]$ if UBRGH=0.

Baud rate = $f_{in}/[16 \times (N+1)]$ if UBRGH=1.

Baud Rate Generator

To setup the speed of the serial data communication, the UART function contains its own dedicated baud rate generator. The baud rate is controlled by its own internal free running 8-bit timer, the period of which is determined by two factors. The first of these is the value placed in the baud rate register UBRG and the second is the value of the UBRGH bit in the control register UUCR2. The UBRGH bit decides if the baud rate generator is to be used in a high speed mode or low speed mode, which in turn determines the formula that is used to calculate the baud rate. The value N in the UBRG register which is used in the following baud rate calculation formula determines the division factor. Note that N is the decimal value placed in the UBRG register and has a range of between 0 and 255.

UUCR2 UBRGH Bit	0	1
Baud Rate (BR)	$f_{H}/[64(N+1)]$	$f_{H}/[16(N+1)]$

By programming the UBRGH bit which allows selection of the related formula and programming the required value in the UBRG register, the required baud rate can be setup. Note that because the actual baud rate is determined using a discrete value, N, placed in the UBRG register, there will be an error associated between the actual and requested value. The following example shows how the UBRG register value N and the error value can be calculated.

Calculating the Baud Rate and Error Values

For a clock frequency of 4MHz, and with UBRGH cleared to zero determine the UBRG register value N, the actual baud rate and the error value for a desired baud rate of 4800.

From the above table the desired baud rate $BR = f_{H}/[64(N+1)]$

Re-arranging this equation gives $N = [f_{H}/(BR \times 64)] - 1$

Giving a value for N = $[4000000/(4800 \times 64)] - 1 = 12.0208$

To obtain the closest value, a decimal value of 12 should be placed into the UBRG register. This gives an actual or calculated baud rate value of $BR = 4000000/[64 \times (12+1)] = 4808$

Therefore the error is equal to $(4808-4800)/4800 = 0.16\%$

UART Setup and Control

For data transfer, the UART function utilizes a non-return-to-zero, more commonly known as NRZ, format. This is composed of one start bit, eight or nine data bits, and one or two stop bits. Parity is supported by the UART hardware, and can be setup to be even, odd or no parity. For the most common data format, 8 data bits along with no parity and one stop bit, denoted as 8, N, 1, is used as the default setting, which is the setting at power-on. The number of data bits and stop bits, along with the parity, are setup by programming the corresponding UBNO, UPRT, UPREN, and USTOPS bits in the UUCR1 register. The baud rate used to transmit and receive data is setup using the internal 8-bit baud rate generator, while the data is transmitted and received LSB first. Although the UART transmitter and receiver are functionally independent, they both use the same data format and baud rate. In all cases stop bits will be used for data transmission.

Enabling/Disabling the UART Interface

The basic on/off function of the internal UART function is controlled using the UREN bit in the UUCR1 register. When the UART mode is selected by setting the UMD bit in the SIMC0 register to "1", if the UREN, UTXEN and URXEN bits are set, then these two UART pins will act as normal UTX output pin and URX/UTX input pin respectively. If no data is being transmitted on the UTX pin, then it will default to a logic high value.

Clearing the UREN bit will disable the UTX and URX/UTX pin and allow these pins to be used as normal I/O or other pin-shared functional pins by configuring the corresponding pin-shared control bits. When the UART function is disabled the buffer will be reset to an empty condition, at the same time discarding any remaining residual data. Disabling the UART will also reset the error and status flags with bits UTXEN, URXEN, UTXBRK, URXIF, UOERR, UFERR, UPERR and UNF being cleared while bits UTIDLE, UTXIF and URIDLE will be set. The remaining control bits in the UUCR1, UUCR2, UUCR3 and UBRG registers will remain unaffected. If the UREN bit in the UUCR1 register is cleared while the UART is active, then all pending transmissions and receptions will be immediately suspended and the UART will be reset to a condition as defined above. If the UART is then subsequently re-enabled, it will restart again in the same configuration.

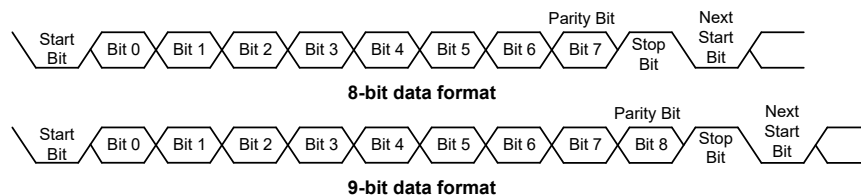
Data, Parity and Stop Bit Selection

The format of the data to be transferred is composed of various factors such as data bit length, parity on/off, parity type, address bits and the number of stop bits. These factors are determined by the setup of various bits within the UUCR1 register. The UBNO bit controls the number of data bits which can be set to either 8 or 9, the UPRT bit controls the choice of odd or even parity, the UPREN bit controls the parity on/off function and the USTOPS bit decides whether one or two stop bits are to be used. The following table shows various formats for data transmission. The address bit, which is the MSB of the data byte, identifies the frame as an address character or data if the address detect function is enabled. The number of stop bits, which can be either one or two, is independent of the data length and is only used for the transmitter. There is only one stop bit for the receiver.

Start Bit	Data Bits	Address Bit	Parity Bit	Stop Bit
Example of 8-bit Data Formats				
1	8	0	0	1
1	7	0	1	1
1	7	1	0	1
Example of 9-bit Data Formats				
1	9	0	0	1
1	8	0	1	1
1	8	1	0	1

Transmitter Receiver Data Format

The following diagram shows the transmit and receive waveforms for both 8-bit and 9-bit data formats.



UART Transmitter

Data word lengths of either 8 or 9 bits can be selected by programming the UBNO bit in the UUCR1 register. When UBNO bit is set, the word length will be set to 9 bits. In this case the 9th bit, which is the MSB, needs to be stored in the UTX8 bit in the UUCR1 register. At the transmitter core lies the Transmitter Shift Register, more commonly known as the TSR, whose data is obtained from the transmit data register, which is known as the UTXR_RXR register. The data to be transmitted is loaded into this UTXR_RXR register by the application program. The TSR register is not written to with new data until the stop bit from the previous transmission has been sent out. As soon as this stop bit has been transmitted, the TSR can then be loaded with new data from the UTXR_RXR register, if it is available. It should be noted that the TSR register, unlike many other registers, is not directly mapped into the Data Memory area and as such is not available to the application program for direct read/write operations. An actual transmission of data will normally be enabled when the UTXEN bit is set, but the data will not be transmitted until the UTXR_RXR register has been loaded with data and the baud rate generator has defined a shift clock source. However, the transmission can also be initiated by first loading data into the UTXR_RXR register, after which the UTXEN bit can be set. When a transmission of data begins, the TSR is normally empty, in which case a transfer to the UTXR_RXR register will result in an immediate transfer to the TSR. If during a transmission the UTXEN bit is cleared, the transmission will immediately cease and the transmitter will be reset. The UTX output pin can then be configured as the I/O or other pin-shared function by configuring the corresponding pin-shared control bits.

Transmitting Data

When the UART is transmitting data, the data is shifted on the UTX pin from the shift register, with the least significant bit first. In the transmit mode, the UTXR_RXR register forms a buffer between the internal bus and the transmitter shift register. It should be noted that if 9-bit data format has been selected, then the MSB will be taken from the UTX8 bit in the UUCR1 register. The steps to initiate a data transfer can be summarized as follows:

- Make the correct selection of the UBNO, UPRT, UPREN and USTOPS bits to define the required word length, parity type and number of stop bits.
- Setup the UBRG register to select the desired baud rate.
- Set the UTXEN bit ensure that the UTX pin is used as a UART transmitter pin.
- Access the UUSR register and write the data that is to be transmitted into the UTXR_RXR register. Note that this step will clear the UTXIF bit.

This sequence of events can now be repeated to send additional data.

It should be noted that when UTXIF=0, data will be inhibited from being written to the UTXR_RXR register. Clearing the UTXIF flag is always achieved using the following software sequence:

1. A UUSR register access
2. A UTXR_RXR register write execution

The read-only UTXIF flag is set by the UART hardware and if set indicates that the UTXR_RXR register is empty and that other data can now be written into the UTXR_RXR register without overwriting the previous data. If the UTEIE bit is set then the UTXIF flag will generate an interrupt.

During a data transmission, a write instruction to the UTXR_RXR register will place the data into the UTXR_RXR register, which will be copied to the shift register at the end of the present transmission. When there is no data transmission in progress, a write instruction to the UTXR_RXR register will place the data directly into the shift register, resulting in the commencement of data transmission, and the UTXIF bit being immediately set. When a frame transmission is complete, which happens after stop bits are sent or after the break frame, the UTIDLE bit will be set. To clear the UTIDLE bit the following software sequence is used:

1. A UUSR register access
2. A UTXR_RXR register write execution

Note that both the UTXIF and UTIDLE bits are cleared by the same software sequence.

Transmitting Break

If the UTXBRK bit is set high and the state keeps for a time greater than $[(BRG+1) \times t_{th}]$ while UTIDLE=1, then the break characters will be sent on the next transmission. Break character transmission consists of a start bit, followed by $13 \times N$ '0' bits and stop bits, where $N=1, 2$, etc. If a break character is to be transmitted then the UTXBRK bit must be first set by the application program, and then cleared to generate the stop bits. Transmitting a break character will not generate a transmit interrupt. Note that a break condition length is at least 13 bits long. If the UTXBRK bit is continually kept at a logic high level then the transmitter circuitry will transmit continuous break characters. After the application program has cleared the UTXBRK bit, the transmitter will finish transmitting the last break character and subsequently send out one or two stop bits. The automatic logic highs at the end of the last break character will ensure that the start bit of the next frame is recognized.

UART Receiver

The UART is capable of receiving word lengths of either 8 or 9 bits. If the UBNO bit is set, the word length will be set to 9 bits with the MSB being stored in the URX8 bit of the UUCR1 register. At the receiver core lies the Receive Serial Shift Register, commonly known as the RSR. The data which is received on the URX/UTX pin input is sent to the data recovery block. The data recovery block operating speed is 16 times that of the baud rate, while the main receive serial shifter operates at the baud rate. After the URX/UTX pin is sampled for the stop bit, the received data in RSR is transferred to the receive data register, if the register is empty. The data which is received on the external URX/UTX pin input is sampled three times by a majority detect circuit to determine the logic level that has been placed onto the URX/UTX pin. It should be noted that the RSR register, unlike many other registers, is not directly mapped into the Data Memory area and as such is not available to the application program for direct read/write operations.

Receiving Data

When the UART receiver is receiving data, the data is serially shifted in on the external URX/UTX pin input, LSB first. In the read mode, the UTXR_RXR register forms a buffer between the internal bus and the receiver shift register. The UTXR_RXR register is a two byte deep FIFO data buffer, where two bytes can be held in the FIFO while a third byte can continue to be received. Note that the application program must ensure that the data is read from UTXR_RXR before the third byte has been completely shifted in, otherwise this third byte will be discarded and an overrun error UOERR will be subsequently indicated. The steps to initiate a data transfer can be summarized as follows:

- Make the correct selection of UBNO, UPRT and UPREN bits to define the word length, parity type.
- Setup the UBRG register to select the desired baud rate.
- Set the URXEN bit to ensure that the URX/UTX pin is used as a UART receiver pin.

At this point the receiver will be enabled which will begin to look for a start bit.

When a character is received the following sequence of events will occur:

- The URXIF bit in the UUSR register will be set when the UTXR_RXR register has data available. There will be at most one more character available before an overrun error occurs.
- When the contents of the shift register have been transferred to the UTXR_RXR register, then if the URIF bit is set, an interrupt will be generated.
- If during reception, a frame error, noise error, parity error, or an overrun error has been detected, then the error flags can be set.

The URXIF bit can be cleared using the following software sequence:

1. A UUSR register access
2. A UTXR_RXR register read execution

Receiving Break

Any break character received by the UART will be managed as a framing error. The receiver will count and expect a certain number of bit times as specified by the values programmed into the UBNO bit plus one stop bit. If the break is much longer than 13 bit times, the reception will be considered as complete after the number of bit times specified by UBNO plus one stop bit. The URXIF bit is set, UFERR is set, zeros are loaded into the receive data register, interrupts are generated if appropriate and the URIDLE bit is set. A break is regarded as a character that contains only zeros with the UFERR flag set. If a long break signal has been detected, the receiver will regard it as a data frame including a start bit, data bits and the invalid stop bit and the UFERR flag will be set. The receiver must wait for a valid stop bit before looking for the next start bit. The receiver will not make the assumption that the break condition on the line is the next start bit. The break character

will be loaded into the buffer and no further data will be received until stop bits are received. It should be noted that the URIDLE read only flag will go high when the stop bits have not yet been received. The reception of a break character on the UART registers will result in the following:

- The framing error flag, UFERR, will be set.
- The receive data register, UTXR_RXR, will be cleared.
- The UOERR, UNF, UPERR, URIDLE or URXIF flags will possibly be set.

Idle Status

When the receiver is reading data, which means it will be in between the detection of a start bit and the reading of a stop bit, the receiver status flag in the UUSR register, otherwise known as the URIDLE flag, will have a zero value. In between the reception of a stop bit and the detection of the next start bit, the URIDLE flag will have a high value, which indicates the receiver is in an idle condition.

Receiver Interrupt

The read only receive interrupt flag URXIF in the UUSR register is set by an edge generated by the receiver. An interrupt is generated if URIE=1, when a word is transferred from the Receive Shift Register, RSR, to the Receive Data Register, UTXR_RXR. An overrun error can also generate an interrupt if URIE=1.

Managing Receiver Errors

Several types of reception errors can occur within the UART module, the following section describes the various types and how they are managed by the UART.

Overrun Error – UOERR

The UTXR_RXR register is composed of a two byte deep FIFO data buffer, where two bytes can be held in the FIFO register, while a third byte can continue to be received. Before this third byte has been entirely shifted in, the data should be read from the UTXR_RXR register. If this is not done, the overrun error flag UOERR will be consequently indicated.

In the event of an overrun error occurring, the following will happen:

- The UOERR flag in the UUSR register will be set.
- The UTXR_RXR contents will not be lost.
- The shift register will be overwritten.
- An interrupt will be generated if the URIE bit is set.

The UOERR flag can be cleared by an access to the UUSR register followed by a read to the UTXR_RXR register.

Noise Error – UNF

Over-sampling is used for data recovery to identify valid incoming data and noise. If noise is detected within a frame the following will occur:

- The read only noise flag, UNF, in the UUSR register will be set on the rising edge of the URXIF bit.
- Data will be transferred from the Shift register to the UTXR_RXR register.
- No interrupt will be generated. However this bit rises at the same time as the URXIF bit which itself generates an interrupt.

Note that the UNF flag is reset by a UUSR register read operation followed by a UTXR_RXR register read operation.

Framing Error – UFERR

The read only framing error flag, UFERR, in the UUSR register, is set if a zero is detected instead of stop bits. If two stop bits are selected, both stop bits must be high; otherwise the UFERR flag will be set. The UFERR flag and the received data will be recorded in the UUSR and UTXR_RXR registers respectively, and the flag is cleared in any reset.

Parity Error – UPERR

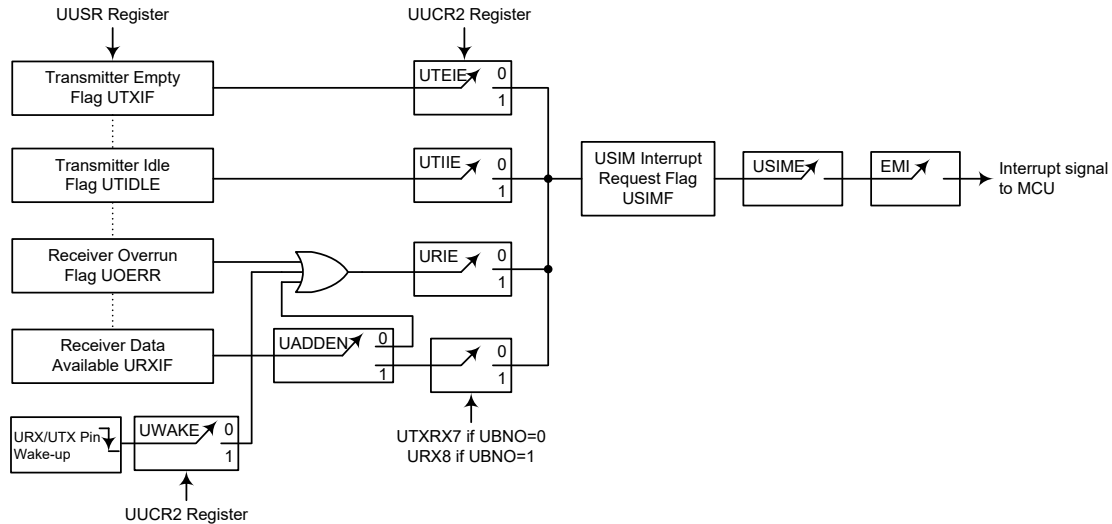
The read only parity error flag, UPERR, in the UUSR register, is set if the parity of the received word is incorrect. This error flag is only applicable if the parity is enabled, UPREN=1, and if the parity type, odd or even is selected. The read only UPERR flag and the received data will be recorded in the UUSR and UTXR_RXR registers respectively. It is cleared on any reset, it should be noted that the flags, UFERR and UPERR, in the UUSR register should first be read by the application program before reading the data word.

UART Interrupt Structure

Several individual UART conditions can trigger an USIM interrupt. When these conditions exist, a low pulse will be generated to get the attention of the microcontroller. These conditions are a transmitter data register empty, transmitter idle, receiver data available, receiver overrun, address detect and an URX/UTX pin wake-up. When any of these conditions are created, if the global interrupt enable bit and the USIM interrupt control bit are enabled and the stack is not full, the program will jump to its corresponding interrupt vector where it can be serviced before returning to the main program. Four of these conditions have the corresponding UUSR register flags which will generate an USIM interrupt if its associated interrupt enable control bit in the UUCR2 register is set. The two transmitter interrupt conditions have their own corresponding enable control bits, while the two receiver interrupt conditions have a shared enable control bit. These enable bits can be used to mask out individual USIM UART mode interrupt sources.

The address detect condition, which is also an USIM UART mode interrupt source, does not have an associated flag, but will generate an USIM interrupt when an address detect condition occurs if its function is enabled by setting the UADDEN bit in the UUCR2 register. An URX/UTX pin wake-up, which is also an USIM UART mode interrupt source, does not have an associated flag, but will generate an USIM interrupt if the UART clock (f_{H}) source is switched off and the UWAKE and URIE bits in the UUCR2 register are set when a falling edge on the URX/UTX pin occurs. Note that in the event of an URX/UTX wake-up interrupt occurring, there will be a certain period of delay, commonly known as the System Start-up Time, for the oscillator to restart and stabilize before the system resumes normal operation.

Note that the UUSR register flags are read only and cannot be cleared or set by the application program, neither will they be cleared when the program jumps to the corresponding interrupt servicing routine, as is the case for some of the other interrupts. The flags will be cleared automatically when certain actions are taken by the UART, the details of which are given in the UART register section. The overall UART interrupt can be disabled or enabled by the USIM interrupt enable control bit in the interrupt control register of the microcontroller to decide whether the interrupt requested by the UART module is masked out or allowed.



UART Interrupt Structure

Address Detect Mode

Setting the Address Detect Mode bit, UADDEN, in the UUCR2 register, enables this special mode. If this bit is enabled then an additional qualifier will be placed on the generation of a Receiver Data Available interrupt, which is requested by the URXIF flag. If the UADDEN bit is enabled, then when data is available, an interrupt will only be generated, if the highest received bit has a high value. Note that the USIME and EMI interrupt enable bits must also be enabled for correct interrupt generation. This highest address bit is the 9th bit if UBNO=1 or the 8th bit if UBNO=0. If this bit is high, then the received word will be defined as an address rather than data. A Data Available interrupt will be generated every time the last bit of the received word is set. If the UADDEN bit is not enabled, then a Receiver Data Available interrupt will be generated each time the URXIF flag is set, irrespective of the data last bit status. The address detect mode and parity enable are mutually exclusive functions. Therefore if the address detect mode is enabled, then to ensure correct operation, the parity function should be disabled by resetting the parity enable bit UPREN to zero.

UADDEN	9th Bit if UBNO=1 8th Bit if UBNO=0	USIM Interrupt Generated
0	0	√
	1	√
1	0	×
	1	√

UADDEN Bit Function

UART Power Down and Wake-up

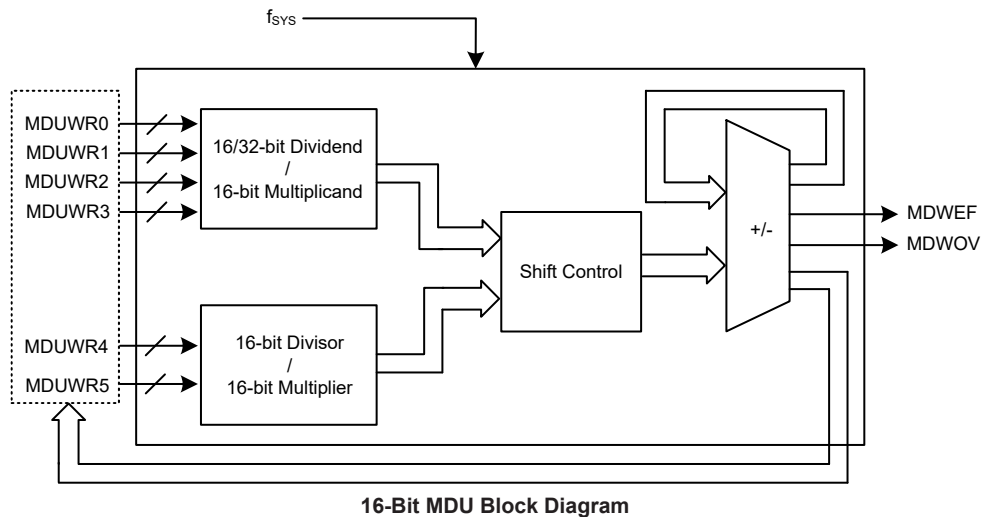
When the UART clock (f_{H}) is off, the UART will cease to function, all clock sources to the module are shutdown. If the UART clock (f_{H}) is off while a transmission is still in progress, then the transmission will be paused until the UART clock source derived from the microcontroller is activated. In a similar way, if the MCU enters the IDLE or SLEEP mode while receiving data, then the reception of data will likewise be paused. When the MCU enters the IDLE or SLEEP mode, note that the UUSR, UUCR1, UUCR2, UUCR3, transmit and receive registers, as well as the UBRG register will not be affected. It is recommended to make sure first that the UART data transmission or reception has been finished before the microcontroller enters the IDLE or SLEEP mode.

The UART function contains a receiver URX/UTX pin wake-up function, which is enabled or disabled by the UWAKE bit in the UUCR2 register. If this bit, along with the UART mode selection bit, UMD, the UART enable bit, UREN, the receiver enable bit, URXEN and the receiver interrupt bit, URIE, are all set when the UART clock (f_{H}) is off, then a falling edge on the URX/UTX pin will trigger an URX/UTX pin wake-up UART interrupt. Note that as it takes certain system clock cycles after a wake-up, before normal microcontroller operation resumes, any data received during this time on the URX/UTX pin will be ignored.

For a UART wake-up interrupt to occur, in addition to the bits for the wake-up being set, the global interrupt enable bit, EMI, and the USIM interrupt enable bit, USIME, must be set. If the EMI and USIME bits are not set then only a wake up event will occur and no interrupt will be generated. Note also that as it takes certain system clock cycles after a wake-up before normal microcontroller resumes, the USIM interrupt will not be generated until after this time has elapsed.

16-bit Multiplication Division Unit – MDU

The device has a 16-bit Multiplication Division Unit, MDU, which integrates a 16-bit unsigned multiplier and a 32-bit/16-bit divider. The MDU, in replacing the software multiplication and division operations, can therefore save large amounts of computing time as well as the Program and Data Memory space. It also reduces the overall microcontroller loading and results in the overall system performance improvements.



MDU Registers

The multiplication and division operations are implemented in a specific way, a specific write access sequence of a series of MDU data registers. The status register, MDUWCTRL, provides the indications for the MDU operation. The data register each is used to store the data regarded as the different operand corresponding to different MDU operations.

Register Name	Bit							
	7	6	5	4	3	2	1	0
MDUWR0	D7	D6	D5	D4	D3	D2	D1	D0
MDUWR1	D7	D6	D5	D4	D3	D2	D1	D0
MDUWR2	D7	D6	D5	D4	D3	D2	D1	D0
MDUWR3	D7	D6	D5	D4	D3	D2	D1	D0
MDUWR4	D7	D6	D5	D4	D3	D2	D1	D0
MDUWR5	D7	D6	D5	D4	D3	D2	D1	D0
MDUWCTRL	MDWEF	MDWOV	—	—	—	—	—	—

MDU Register List

• **MDUWRn Register (n=0~5)**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	x	x	x	x	x	x	x	x

“x”: unknown

Bit 7~0 **D7~D0**: 16-bit MDU data register n

• **MDUWCTRL Register**

Bit	7	6	5	4	3	2	1	0
Name	MDWEF	MDWOV	—	—	—	—	—	—
R/W	R	R	—	—	—	—	—	—
POR	0	0	—	—	—	—	—	—

Bit 7 **MDWEF**: 16-bit MDU error flag
 0: Normal
 1: Abnormal

This bit will be set to 1 if the data register MDUWRn is written or read as the MDU operation is executing. This bit should be cleared to 0 by reading the MDUWCTRL register if it is equal to 1 and the MDU operation is completed.

Bit 6 **MDWOV**: 16-bit MDU overflow flag
 0: No overflow occurs

1: Multiplication product > FFFFH or Divisor = 0

When an operation is completed, this bit will be updated by hardware to a new value corresponding to the current operation situation.

Bit 5~0 Unimplemented, read as “0”

MDU Operation

For this MDU the multiplication or division operation is carried out in a specific way and is determined by the write access sequence of the six MDU data registers, MDUWR0~MDUWR5. The low byte data, regardless of the dividend, multiplicand, divisor or multiplier, must first be written into the corresponding MDU data register followed by the high byte data. All MDU operations will be executed after the MDUWR5 register is write-accessed together with the correct specific write access sequence of the MDUWRn. Note that it is not necessary to consecutively write data into the MDU data registers but must be in a correct write access sequence. Therefore, a non-write MDUWRn instruction or an interrupt, etc., can be inserted into the correct write access sequence without destroying the write operation. The relationship between the write access sequence and the MDU operation is shown in the following.

- 32-bit/16-bit division operation: Write data sequentially into the six MDU data registers from MDUWR0 to MDUWR5.
- 16-bit/16-bit division operation: Write data sequentially into the specific four MDU data registers in a sequence of MDUWR0, MDUWR1, MDUWR4 and MDUWR5 with no write access to MDUWR2 and MDUWR3.
- 16-bit×16-bit multiplication operation: Write data sequentially into the specific four MDU data register in a sequence of MDUWR0, MDUWR4, MDUWR1 and MDUWR5 with no write access to MDUWR2 and MDUWR3.

After the specific write access sequence is determined, the MDU will start to perform the corresponding operation. The calculation time necessary for these MDU operations are different. During the calculation time any read/write access to the six MDU data registers is forbidden. After the completion of each operation, it is necessary to check the operation status in the MDUWCTRL register to make sure that whether the operation is correct or not. Then the operation result can be read out from the corresponding MDU data registers in a specific read access sequence if the operation is correctly finished. The necessary calculation time for different MDU operations is listed in the following.

- 32-bit/16-bit division operation: $17 \times t_{SYS}$.
- 16-bit/16-bit division operation: $9 \times t_{SYS}$.
- 16-bit×16-bit multiplication operation: $11 \times t_{SYS}$.

The operation results will be stored in the corresponding MDU data registers and should be read out from the MDU data registers in a specific read access sequence after the operation is completed. Note that it is not necessary to consecutively read data out from the MDU data registers but must be in a correct read access sequence. Therefore, a non-read MDUWRn instruction or an interrupt, etc., can be inserted into the correct read access sequence without destroying the read operation. The relationship between the operation result read access sequence and the MDU operation is shown in the following.

- 32-bit/16-bit division operation: Read the quotient from MDUWR0 to MDUWR3 and remainder from MDUWR4 and MDUWR5 sequentially.
- 16-bit/16-bit division operation: Read the quotient from MDUWR0 and MDUWR1 and remainder from MDUWR4 and MDUWR5 sequentially.
- 16-bit×16-bit multiplication operation: Read the product sequentially from MDUWR0 to MDUWR3.

The overall important points for the MDU read/write access sequence and calculation time are summarized in the following table.

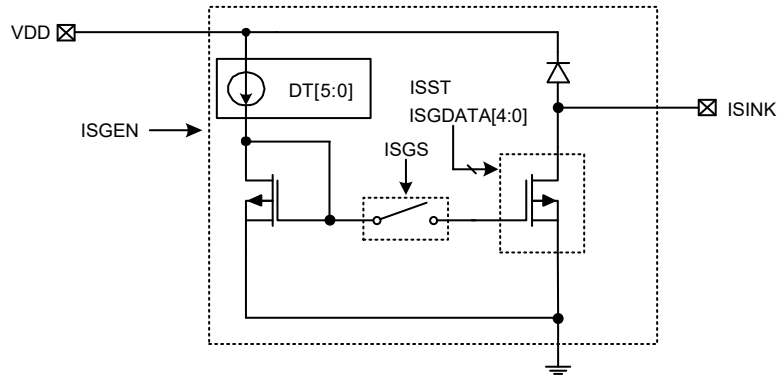
Note that the device should not enter the IDLE or SLEEP mode until the MDU operation is totally completed, otherwise the MDU operation will fail.

Operations Items	32-bit / 16-bit Division	16-bit / 16-bit Division	16-bit × 16-bit Multiplication
Write Sequence First write ↓ ↓ ↓ ↓ Last write	Dividend Byte 0 written to MDUWR0 Dividend Byte 1 written to MDUWR1 Dividend Byte 2 written to MDUWR2 Dividend Byte 3 written to MDUWR3 Divisor Byte 0 written to MDUWR4 Divisor Byte 1 written to MDUWR5	Dividend Byte 0 written to MDUWR0 Dividend Byte 1 written to MDUWR1 Divisor Byte 0 written to MDUWR4 Divisor Byte 1 written to MDUWR5	Multiplicand Byte 0 written to MDUWR0 Multiplier Byte 0 written to MDUWR4 Multiplicand Byte 1 written to MDUWR1 Multiplier Byte 1 written to MDUWR5
Calculation Time	$17 \times t_{SYS}$	$9 \times t_{SYS}$	$11 \times t_{SYS}$
Read Sequence First read ↓ ↓ ↓ ↓ Last read	Quotient Byte 0 read from MDUWR0 Quotient Byte 1 read from MDUWR1 Quotient Byte 2 read from MDUWR2 Quotient Byte 3 read from MDUWR3 Remainder Byte 0 read from MDUWR4 Remainder Byte 1 read from MDUWR5	Quotient Byte 0 read from MDUWR0 Quotient Byte 1 read from MDUWR1 Remainder Byte 0 read from MDUWR4 Remainder Byte 1 read from MDUWR5	Product Byte 0 read from MDUWR0 Product Byte 1 read from MDUWR1 Product Byte 2 read from MDUWR2 Product Byte 3 read from MDUWR3

MDU Operations Summary

Sink Current Generator

The sink current source generator could provide constant current no matter what V_{ISINK} voltage is from 1.0V~4.5V. The constant current value is controlled by the ISGDATA register, and the sink current range can be selected as 5mA~80mA or 50mA~360mA by the ISST bit in the ISGDATA register.



Sink Current Generator Registers

There are a series of registers control the overall operation of the Sink Current Generator function.

Register Name	Bit							
	7	6	5	4	3	2	1	0
ISGENC	ISGEN	—	—	—	—	—	—	ISGS
ISGDATA	—	—	ISST	D4	D3	D2	D1	D0

Sink Current Generator Register List

• ISGENC Register

Bit	7	6	5	4	3	2	1	0
Name	ISGEN	—	—	—	—	—	—	ISGS
R/W	R/W	—	—	—	—	—	—	R/W
POR	0	—	—	—	—	—	—	0

Bit 7 **ISGEN**: Sink current generator enable control
 0: Disable
 1: Enable

When the ISGEN bit is cleared to zero to disable the sink current generator, the ISINK pin status is V_{ISINK} =floating, I_{SINK} =0.

Bit 6~1 Unimplemented, read as “0”

Bit 0 **ISGS**: ISINK switch on or off control
 0: Off
 1: On

• ISGDATA Register

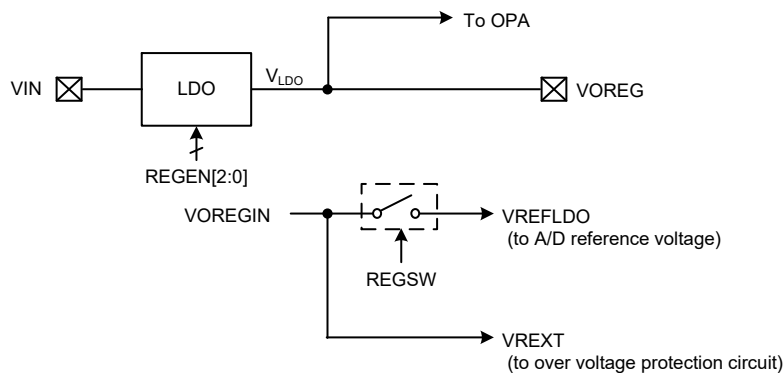
Bit	7	6	5	4	3	2	1	0
Name	—	—	ISST	D4	D3	D2	D1	D0
R/W	—	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

Bit 7~6 Unimplemented, read as “0”

- Bit 5 **ISST**: Switch first stage or second stage current control
0: First stage
1: Second stage
- Bit 4~0 **D4~D0**: Sink current generator control for ISINK pin
When the ISST bit is cleared to zero, the current value= $5+5 \times (D[4:0]=00000\sim 01111)$, 5mA/step. It should be noted that the $D[4:0]=10000B\sim 11111$ bits are reserved and can not be used.
When the ISST is set high, the current value= $50+10 \times (D[4:0]=00000\sim 11111)$, 10mA/step. Refer to “Sink Current Generator Electrical Characteristics” table for more details.

Voltage Regulator – LDO

The device includes a voltage regulator, LDO. The REGC register controls the regulator module to work in six modes. In the Hi-impedance mode, the LDO will be turned off and the VOREG pin will be floating. In the bypass mode, the LDO is turned off and the VIN pin will be connected to the VOREG pin directly. In the third mode the regulator is turned on, when the input voltage is larger than 2.5V, the LDO will output a fixed voltage of 2.2V on the VOREG pin. In the fourth mode the regulator is turned on, when the input voltage is larger than 2.8V, the LDO will output a fixed voltage of 2.5V. In the fifth mode the regulator is turned on, when the input voltage is larger than 3.6V, the LDO will output a fixed voltage of 3.3V. In the sixth mode the regulator is turned on, when the input voltage is larger than 3.9V, the LDO will output a fixed voltage of 3.6V.



LDO Regulator Block Diagram

Note: The VOREGIN signal is double bond with VOREG pin and used for internal circuit.

• REGC Register

Bit	7	6	5	4	3	2	1	0
Name	REGSW	—	—	—	—	REGEN2	REGEN1	REGEN0
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

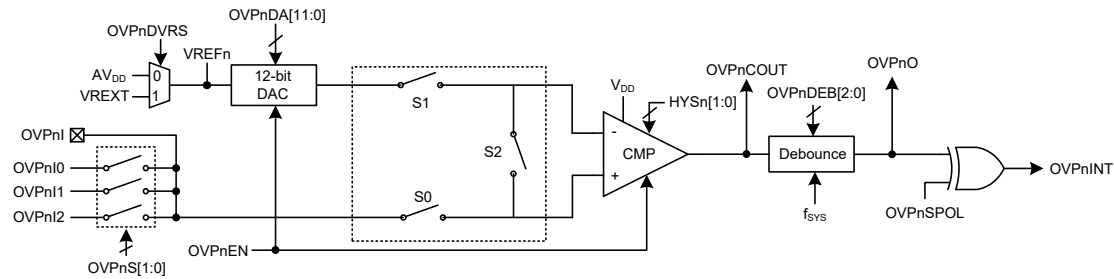
- Bit 7 **REGSW**: Switch on/off control
0: Off
1: On

When the A/D converter reference voltage is selected to come from V_{LDO}, this bit should be set high. However when the A/D converter reference voltage is selected to come from any other voltage, other than V_{LDO}, this bit should be cleared to zero to turn off the switch, otherwise V_{LDO} will be connected together with other selected A/D reference voltage to the A/D converter simultaneously, which will result in unpredictable situations such as an irreversible damage.

- Bit 6~3 Unimplemented, read as “0”
- Bit 2~0 **REGEN2~REGEN0**: Regulator mode selection
 - x00: Regulator off in Hi-impedance mode, VOREG output is floating
 - x01: Regulator off in Bypass mode, VOREG output = V_{IN} input voltage
 - 010: Regulator on, V_{LDO}=2.2V
 - 011: Regulator on, V_{LDO}=2.5V
 - 110: Regulator on, V_{LDO}=3.3V
 - 111: Regulator on, V_{LDO}=3.6V

Over Voltage Protection – OVP

The device includes the over voltage protection circuit, which provides protection mechanisms or generate output signals for different applications. To prevent the operating voltage from exceeding a specific level, the voltage on the OVP input is compared with a reference voltage generated by an 12-bit D/A converter. When a preset over voltage event occurs, the OVP output will be reversed. An OVP interrupt signal OVPnINT can be used to trigger an OVPn interrupt.



Over Voltage Protection Circuit

- Note: 1. If the input source is supplied on OVPnI pin, as the OVPnI pin is pin-shared with I/O or other pin functions, before turning on the OVP function, make sure the OVPnI pin function is selected using the corresponding Pin-shared Function Selection Registers.
2. The OVPnI0, OVPnI1 and OVPnI2 input sources are from the OPA00, OPA10 and OPA20 pin respectively. The VREXT signal is from the voltage regulator, LDO.
3. The on/off control for the switches S0, S1 and S2 is summarised below.

OVPnCOFM	OVPnCRS	S0	S1	S2
0	x	ON	ON	OFF
1	0	OFF	ON	ON
1	1	ON	OFF	OFF

“x”: Don't care

Over Voltage Protection Operation

The source voltage is supplied on the OVPnI or OVPnI0~OVPnI3 lines and then connected to a non-invert input of the comparator. A D/A converter is used to generate a reference voltage. The comparator compares the reference voltage with the input voltage to produce the OVPnO signal.

Over Voltage Protection Control Registers

The overall operation of the over voltage protection is controlled using several registers. One register is used to provide the reference voltages for the over voltage protection circuit. The remaining registers are control registers which are used to control the OVP function, D/A converter reference voltage selection, comparator debounce time, comparator hysteresis function, OVP input selection together with the comparator input offset calibration.

Register Name	Bit							
	7	6	5	4	3	2	1	0
OVPnC0	OVPnO	OVPnSPOL	OVPnEN	—	OVPnDVRS	OVPnDEB2	OVPnDEB1	OVPnDEB0
OVPnC1	OVPnCOUT	OVPnCOFM	OVPnCRS	OVPnCOF4	OVPnCOF3	OVPnCOF2	OVPnCOF1	OVPnCOF0
OVPnC2	—	—	—	—	HYSn1	HYSn0	OVPnS1	OVPnS0
OVPnDAL	D7	D6	D5	D4	D3	D2	D1	D0
OVPnDAH	—	—	—	—	D11	D10	D9	D8

OVP Register List
• OVPnC0 Register

Bit	7	6	5	4	3	2	1	0
Name	OVPnO	OVPnSPOL	OVPnEN	—	OVPnDVRS	OVPnDEB2	OVPnDEB1	OVPnDEB0
R/W	R	R/W	R/W	—	R/W	R/W	R/W	R/W
POR	0	0	0	—	0	0	0	0

- Bit 7 **OVPnO**: OVPn comparator output bit
0: Positive input voltage < negative input voltage
1: Positive input voltage > negative input voltage
- Bit 6 **OVPnSPOL**: OVPnO polarity Control
0: Non-invert
1: Invert
This bit will determine the OVPn interrupt occurrence condition when the OVPnO bit changes state from low to high or high to low.
- Bit 5 **OVPnEN**: OVPn function control bit
0: Disable
1: Enable
If the OVPnEN bit is cleared to 0, the over voltage protection function is disabled and no power will be consumed. This results in the comparator and D/A converter of OVPn both being switched off.
- Bit 4 Unimplemented, read as “0”
- Bit 3 **OVPnDVRS**: OVPn D/A converter reference voltage selection
0: D/A converter reference voltage comes from AV_{DD}
1: D/A converter reference voltage comes from VREXT
- Bit 2~0 **OVPnDEB2~OVPnDEB0**: OVPn comparator debounce time control bits
000: No debounce
001: $(3\sim4) \times t_{DEB}$
010: $(7\sim8) \times t_{DEB}$
011: $(15\sim16) \times t_{DEB}$
100: $(31\sim32) \times t_{DEB}$
101: $(63\sim64) \times t_{DEB}$
110: $(127\sim128) \times t_{DEB}$
111: $(255\sim256) \times t_{DEB}$
Note: $t_{DEB} = 1/f_{SYS}$

• **OVPnC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	OVPnCOUT	OVPnCOFM	OVPnCRS	OVPnCOF4	OVPnCOF3	OVPnCOF2	OVPnCOF1	OVPnCOF0
R/W	R	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	1	0	0	0	0

- Bit 7 **OVPnCOUT**: OVPn comparator output before debounce
 0: Positive input voltage < negative input voltage
 1: Positive input voltage > negative input voltage
- Bit 6 **OVPnCOFM**: OVPn comparator normal operation or input offset voltage calibration mode selection
 0: Normal operation
 1: Input offset voltage calibration mode
- Bit 5 **OVPnCRS**: OVPn comparator input offset voltage calibration reference selection bit
 0: Input reference voltage comes from negative input
 1: Input reference voltage comes from positive input
- Bit 4~0 **OVPnCOF4~OVPnCOF0**: OVPn comparator input offset voltage calibration control bits

• **OVPnC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	HYSn1	HYSn0	OVPnS1	OVPnS0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

- Bit 7~4 Unimplemented, read as “0”
- Bit 3~2 **HYSn1~HYSn0**: OVPn comparator hysteresis voltage window control bits
 Refer to “Over Voltage Protection Electrical Characteristics” table for details.
- Bit 1~0 **OVPnS1~OVPnS0**: OVPn input selection bits
 00: OVPnI
 01: OVPnI and OVPnI0
 10: OVPnI and OVPnI1
 11: OVPnI and OVPnI2
 Note that in this device the OVPnI0, OVPnI1 and OVPnI2 input sources are from the OPA00, OPA10 and OPA20 pin respectively.

• **OVPnDAH&OVPnDAL Register**

Register	OVPnDAH								OVPnDAL							
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
Name	—	—	—	—	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
R/W	—	—	—	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0	0	0	0	0	0	0	0	0

“—”: Unimplemented, read as “0”

- D11~D8**: OVPn DAC reference level selection high byte
- D7~D0**: OVPn DAC reference level selection low byte
- OVPn DAC Output = (OVPn DAC $V_{REF}/4096$) \times D[11:0]
- Note: Write OVPnDAL register only write to shadow buffer, and until write OVPnDAH register will also copy the shadow buffer data to OVPnDAL register

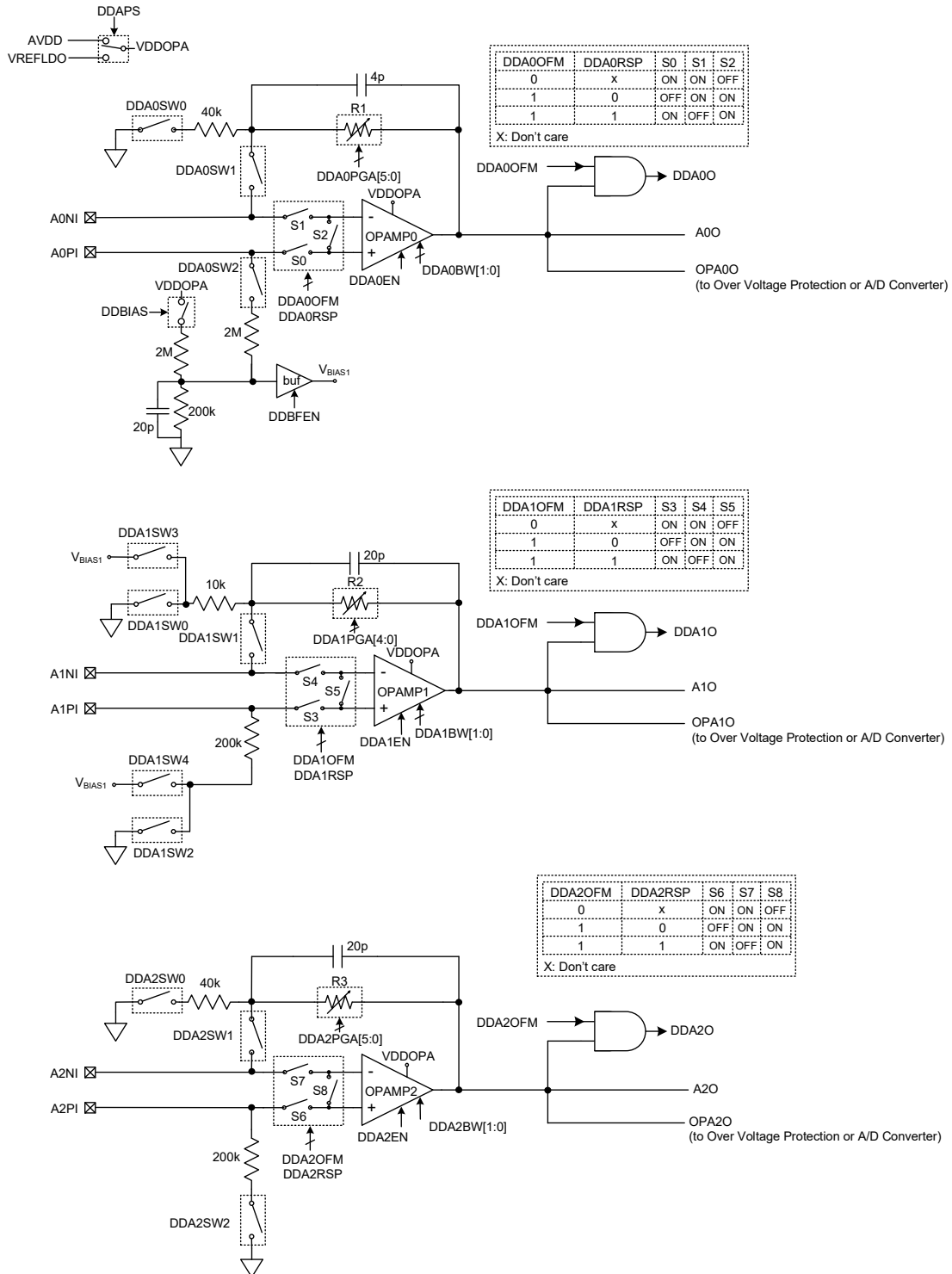
OVP Comparator Offset Calibration Function

The OVPnCOFM bit in the OVPnC1 register is used to select the OVPn comparator operating mode, normal operation or offset calibration mode. If set the bit high, the comparator will enter the offset voltage calibration mode. It is need to note that before offset calibration, the hysteresis voltage should be zero by set HYSn[1:0]=00B. If the source voltage is supplied on OVPnI0~OVPnI2 pin which are pin-shared with I/O, it must also be setup as an input by setting the corresponding bit in the I/O port control register. For OVP comparator input offset calibration, the procedures are summarised in the following steps

- Step 1
Set OVPnCOFM=1, OVPnCRS=1, the OVPn is now in the comparator calibration mode, S1 and S2 on. To make sure V_{OS} as minimize as possible after calibration, the input reference voltage in calibration should be the same as the input DC operating voltage in normal mode operation.
- Step 2
Set OVPnCOF[4:0]=00000 then read OVPnCOUT bit status after a certain delay.
- Step 3
Let OVPnCOF[4:0]=OVPnCOF[4:0]+1 then read the OVPnCOUT bit status after a certain delay. If OVPnCOUT bit state has not changed, then repeat Step 3 until the OVPnCOUT bit state changes.
If the OVPnCOUT bit state has changed, record the OVPnCOF[4:0] data as V_{OS1} and then go to Step 4.
- Step 4
Set OVPnCOF[4:0]=11111 then read the OVPnCOUT bit status after a certain delay.
- Step 5
Let OVPnCOF[4:0]=OVPnCOF[4:0]-1 then read the OVPnCOUT bit status after a certain delay. If the OVPnCOUT bit state has not changed, then repeat Step 5 until the OVPnCOUT bit state changes.
If the OVPnCOUT bit state has changed, record the OVPnCOF[4:0] value as V_{OS2} and then go to Step 6.
- Step 6
Restore $V_{OS}=(V_{OS1}+V_{OS2})/2$ to the OVPnCOF[4:0] bits. The calibration is finished.
If $(V_{OS1}+V_{OS2})/2$ is not an integral, discard the decimal.

Dust Detector AFE

The device provides a Dust Detector AFE circuit which can be used for dust width detection in Dust Detector applications. The circuit consists of three fully integrated Operational Amplifiers.



Dust Detector AFE Block Diagram

Note that although the DD OPAm bandwidth is determined by the DDAmBW1~DDAmBW0 bits there are some limitations when using the OPAm together with the A/D converter. As the OPAMPm bandwidth will result in a small current output, care must be taken for DD OPAm bandwidths. Refer to the following table for examples, where values marked with an asterisk \checkmark are usable and ensure that the values read by the 12-bit A/D converter are less than 1 LSB.

DD OPAMPm Bandwidth Selection	A/D Converter Clock Frequency (kHz)							
	15.625	31.25	62.5	125	250	500	1000	2000
DDAmBW[1:0]=00	\checkmark	—	—	—	—	—	—	—
DDAmBW[1:0]=01	\checkmark	\checkmark	\checkmark	\checkmark	—	—	—	—
DDAmBW[1:0]=10	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
DDAmBW[1:0]=11	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark

Dust Detector AFE DD OPAMPm Bandwidth Examples (m=0~2)

Dust Detector AFE Registers

Overall operation of the Dust Detector AFE circuit is controlled using a series of registers. The DDOC register is used to select the voltage source. The DDAnC register where m=0~2, is used to control the DD OPAn enable/disable and bandwidth functions as well as stores the output status. The DDPGAC0, DDPGAC1 and DDPGAC2 registers are used to select the R1, R2 and R3 resistance. The DDAnVOS register where n=0~2, is used to select and control the DD OPAn input offset voltage calibration function.

Register Name	Bit							
	7	6	5	4	3	2	1	0
DDOC	DDAPS	—	—	—	DDBFEN	DDA1SW4	DDA1SW3	DDBIAS
DDA0C	DDA0EN	DDA0O	DDA0BW1	DDA0BW0	—	DDA0SW0	DDA0SW1	DDA0SW2
DDA1C	DDA1EN	DDA1O	DDA1BW1	DDA1BW0	—	DDA1SW0	DDA1SW1	DDA1SW2
DDA2C	DDA2EN	DDA2O	DDA2BW1	DDA2BW0	—	DDA2SW0	DDA2SW1	DDA2SW2
DDPGAC0	—	—	DDA0PGA5	DDA0PGA4	DDA0PGA3	DDA0PGA2	DDA0PGA1	DDA0PGA0
DDPGAC1	—	—	—	DDA1PGA4	DDA1PGA3	DDA1PGA2	DDA1PGA1	DDA1PGA0
DDPGAC2	—	—	DDA2PGA5	DDA2PGA4	DDA2PGA3	DDA2PGA2	DDA2PGA1	DDA2PGA0
DDA0VOS	DDA0OFM	DDA0RSP	DDA0OF5	DDA0OF4	DDA0OF3	DDA0OF2	DDA0OF1	DDA0OF0
DDA1VOS	DDA1OFM	DDA1RSP	DDA1OF5	DDA1OF4	DDA1OF3	DDA1OF2	DDA1OF1	DDA1OF0
DDA2VOS	DDA2OFM	DDA2RSP	DDA2OF5	DDA2OF4	DDA2OF3	DDA2OF2	DDA2OF1	DDA2OF0

Dust Detector AFE Register List

• DDOC Register

Bit	7	6	5	4	3	2	1	0
Name	DDAPS	—	—	—	DDBFEN	DDA1SW4	DDA1SW3	DDBIAS
R/W	R/W	—	—	—	R/W	R/W	R/W	R/W
POR	0	—	—	—	0	0	0	0

Bit 7 **DDAPS**: Dust Detector AFE power selection bit

0: AV_{DD}
1: VREFLDO

When this bit is set high, the LDO function should be enabled first. Refer to the “Voltage Regulator – LDO” section for details.

Bit 6~4 Unimplemented, read as “0”

- Bit 3 **DDBFEN**: VBias buffer enable/disable control bit
 0: disable
 1: enable
 Note: Before the DDA1SW3 or DDA1SW4 bit is set to "1", users must set the DDBFEN bit to "1" first for normal operation.
- Bit 2 **DDA1SW4**: DDA1SW4 on/off control bit
 0: off
 1: on
 Note: the DDA1SW4 and DDA1SW2 bits cannot be set as "1" at the same time.
- Bit 1 **DDA1SW3**: DDA1SW3 on/off control bit
 0: off
 1: on
 Note: the DDA1SW3 and DDA1SW0 bits cannot be set as "1" at the same time.
- Bit 0 **DDBIAS**: Bias voltage selection bit
 0: Reserved
 1: VDDOPA

• **DDA0C Register**

Bit	7	6	5	4	3	2	1	0
Name	DDA0EN	DDA0O	DDA0BW1	DDA0BW0	—	DDA0SW0	DDA0SW1	DDA0SW2
R/W	R/W	R	R/W	R/W	—	R/W	R/W	R/W
POR	0	0	0	0	—	0	0	0

- Bit 7 **DDA0EN**: DD OPA0 enable or disable control
 0: Disable
 1: Enable
- Bit 6 **DDA0O**: DD OPA0 output status (positive logic)
 This bit is read only.
 When the DDA0OFM bit is set to 1, DDA0O is defined as DD OPA0 output status, refer to the “Operational Amplifier Input Offset Calibration” section for details.
 When the DDA0OFM bit is cleared to 0, this bit will be fixed at a low level.
- Bit 5~4 **DDA0BW1~DDA0BW0**: DD OPA0 bandwidth control
 00: 5kHz
 01: 40kHz
 10: 600kHz
 11: 2MHz
 Refer to “Operational Amplifier Electrical Characteristics” for details.
- Bit 3 Unimplemented, read as “0”
- Bit 2 **DDA0SW0**: DDA0SW0 switch on/off control
 0: Off
 1: On
- Bit 1 **DDA0SW1**: DDA0SW1 switch on/off control
 0: Off
 1: On
- Bit 0 **DDA0SW2**: DDA0SW2 switch on/off control
 0: Off
 1: On

• **DDA1C Register**

Bit	7	6	5	4	3	2	1	0
Name	DDA1EN	DDA1O	DDA1BW1	DDA1BW0	—	DDA1SW0	DDA1SW1	DDA1SW2
R/W	R/W	R	R/W	R/W	—	R/W	R/W	R/W
POR	0	0	0	0	—	0	0	0

- Bit 7 **DDA1EN**: DD OPA1 enable or disable control
0: Disable
1: Enable
- Bit 6 **DDA1O**: DD OPA1 output status (positive logic)
This bit is read only.
When the DDA1OFM bit is set to 1, DDA1O is defined as DD OPA1 output status, refer to the “Operational Amplifier Input Offset Calibration” section for details.
When the DDA1OFM bit is cleared to 0, this bit will be fixed at a low level.
- Bit 5~4 **DDA1BW1~DDA1BW0**: DD OPA1 bandwidth control
00: 5kHz
01: 40kHz
10: 600kHz
11: 2MHz
Refer to “Operational Amplifier Electrical Characteristics” for details.
- Bit 3 Unimplemented, read as “0”
- Bit 2 **DDA1SW0**: DDA1SW0 switch on/off control
0: Off
1: On
- Bit 1 **DDA1SW1**: DDA1SW1 switch on/off control
0: Off
1: On
- Bit 0 **DDA1SW2**: DDA1SW2 switch on/off control
0: Off
1: On

• **DDA2C Register**

Bit	7	6	5	4	3	2	1	0
Name	DDA2EN	DDA2O	DDA2BW1	DDA2BW0	—	DDA2SW0	DDA2SW1	DDA2SW2
R/W	R/W	R	R/W	R/W	—	R/W	R/W	R/W
POR	0	0	0	0	—	0	0	0

- Bit 7 **DDA2EN**: DD OPA2 enable or disable control
0: Disable
1: Enable
- Bit 6 **DDA2O**: DD OPA2 output status (positive logic)
This bit is read only.
When the DDA2OFM bit is set to 1, DDA2O is defined as DD OPA2 output status, refer to the “Operational Amplifier Input Offset Calibration” section for details.
When the DDA2OFM bit is cleared to 0, this bit will be fixed at a low level.
- Bit 5~4 **DDA2BW1~DDA2BW0**: DD OPA2 bandwidth control
00: 5kHz
01: 40kHz
10: 600kHz
11: 2MHz
Refer to “Operational Amplifier Electrical Characteristics” for details.
- Bit 3 Unimplemented, read as “0”

- Bit 2 **DDA2SW0**: DDA1SW0 switch on/off control
 0: Off
 1: On
- Bit 1 **DDA2SW1**: DDA1SW1 switch on/off control
 0: Off
 1: On
- Bit 0 **DDA2SW2**: DDA2SW2 switch on/off control
 0: Off
 1: On

• **DDPGAC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	DDA0PGA5	DDA0PGA4	DDA0PGA3	DDA0PGA2	DDA0PGA1	DDA0PGA0
R/W	—	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

- Bit 7~6 Unimplemented, read as “0”
- Bit 5~0 **DDA0PGA5~DDA0PGA0**: R1 control
 $R1=(DDA0PGA[5:0] \times 100k\Omega)$

• **DDPGAC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	DDA1PGA4	DDA1PGA3	DDA1PGA2	DDA1PGA1	DDA1PGA0
R/W	—	—	—	R/W	R/W	R/W	R/W	R/W
POR	—	—	—	0	0	0	0	0

- Bit 7~5 Unimplemented, read as “0”
- Bit 4~0 **DDA1PGA4~DDA1PGA0**: R2 control
 $R2=(DDA1PGA[4:0] \times 100k\Omega)$

• **DDPGAC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	DDA2PGA5	DDA2PGA4	DDA2PGA3	DDA2PGA2	DDA2PGA1	DDA2PGA0
R/W	—	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

- Bit 7~6 Unimplemented, read as “0”
- Bit 5~0 **DDA2PGA5~DDA2PGA0**: R3 control
 $R3=(DDA2PGA[5:0] \times 100k\Omega)$

• **DDA0VOS Register**

Bit	7	6	5	4	3	2	1	0
Name	DDA0OFM	DDA0RSP	DDA0OF5	DDA0OF4	DDA0OF3	DDA0OF2	DDA0OF1	DDA0OF0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	1	0	0	0	0	0

- Bit 7 **DDA0OFM**: DD OPA0 normal operation or input offset voltage calibration mode selection
 0: Normal operation
 1: Offset calibration mode
- Bit 6 **DDA0RSP**: DD OPA0 input offset voltage calibration reference selection
 0: Input reference voltage comes from A0NI
 1: Input reference voltage comes from A0PI

Bit 5~0 **DDA0OF5~DDA0OF0**: DD OPA0 input offset voltage calibration control
 This 6-bit field is used to perform the operational amplifier input offset calibration operation and the value for the DD OPA0 input offset Calibration can be restored into this bit field. More detailed information is described in the “Operational Amplifier Input Offset Calibration” section.

• **DDA1VOS Register**

Bit	7	6	5	4	3	2	1	0
Name	DDA1OFM	DDA1RSP	DDA1OF5	DDA1OF4	DDA1OF3	DDA1OF2	DDA1OF1	DDA1OF0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	1	0	0	0	0	0

Bit 7 **DDA1OFM**: DD OPA1 normal operation or input offset voltage calibration mode selection
 0: Normal operation
 1: Offset calibration mode

Bit 6 **DDA1RSP**: DD OPA1 input offset voltage calibration reference selection
 0: Input reference voltage comes from A1NI
 1: Input reference voltage comes from A1PI

Bit 5~0 **DDA1OF5~DDA1OF0**: DD OPA1 input offset voltage calibration control
 This 6-bit field is used to perform the operational amplifier input offset calibration operation and the value for the DD OPA1 input offset Calibration can be restored into this bit field. More detailed information is described in the “Operational Amplifier Input Offset Calibration” section.

• **DDA2VOS Register**

Bit	7	6	5	4	3	2	1	0
Name	DDA2OFM	DDA2RSP	DDA2OF5	DDA2OF4	DDA2OF3	DDA2OF2	DDA2OF1	DDA2OF0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	1	0	0	0	0	0

Bit 7 **DDA2OFM**: DD OPA2 normal operation or input offset voltage calibration mode selection
 0: Normal operation
 1: Offset calibration mode

Bit 6 **DDA2RSP**: DD OPA2 input offset voltage calibration reference selection
 0: Input reference voltage comes from A2NI
 1: Input reference voltage comes from A2PI

Bit 5~0 **DDA2OF5~DDA2OF0**: DD OPA2 input offset voltage calibration control
 This 6-bit field is used to perform the operational amplifier input offset calibration operation and the value for the DD OPA2 input offset Calibration can be restored into this bit field. More detailed information is described in the “Operational Amplifier Input Offset Calibration” section.

Operational Amplifier Operation

There are three fully integrated Operational Amplifiers in the device, OPA2, OPA1 and OPA0. These OPAs can be used for signal amplification according to specific user requirements. The OPAs can be disabled or enabled entirely under software control using internal registers. With specific control registers, some OPA related applications can be more flexible and easier to be implemented, such as Unit Gain Buffer, Non-Inverting Amplifier, Inverting Amplifier and various kinds of filters, etc.

Operational Amplifier Input Offset Calibration

Note that if the DD Operational Amplifier inputs are pin-shared with I/O pins, they should be configured as the DD Operational Amplifier input function before the Input Offset Calibration.

- Step 1
Set $DDAnOFM=1$ and $DDAnRSP=1$, the DD Operational Amplifier n is now under the input offset Calibration mode, S0 and S2 on. To make sure the V_{AnOS} as minimal as possible after calibration, the input reference voltage in calibration should be the same as input DC operating voltage in normal operation.
- Step 2
Set $DDAnOF[5:0]=000000$ and then read the $DDAnO$ bit.
- Step 3
Increase the $DDAnOF[5:0]$ value by 1 and then read the $DDAnO$ bit.
If the $DDAnO$ bit state has not changed, then repeat Step 3 until the $DDAnO$ bit state has changed.
If the $DDAnO$ bit state has changed, record the $DDAnOF[5:0]$ value as V_{AnOS1} and then go to Step 4.
- Step 4
Set $DDAnOF[5:0]=111111$ and read the $DDAnO$ bit.
- Step 5
Decrease the $DDAnOF[5:0]$ value by 1 and then read the $DDAnO$ bit.
If the $DDAnO$ bit state has not changed, then repeat Step 5 until the $DDAnO$ bit state has changed.
If the $DDAnO$ bit state has changed, record the $DDAnOF[5:0]$ value as V_{AnOS2} and then go to Step 6.
- Step 6
Restore the DD Operational Amplifier n input offset calibration value V_{OnS} into the $DDAnOF[5:0]$ bit field. The offset Calibration procedure is now finished.
$$V_{AnOS} = (V_{AnOS1} + V_{AnOS2}) / 2.$$

If $(V_{AnOS1} + V_{AnOS2}) / 2$ is not integral, discard the decimal.

Low Voltage Detector – LVD

The device has a Low Voltage Detector function, also known as LVD. This enabled the device to monitor the power supply voltage, VDD, or the LVDIN input voltage, and provide a warning signal should it fall below a certain level. This function may be especially useful in battery applications where the supply voltage will gradually reduce as the battery ages, as it allows an early warning battery low signal to be generated. The Low Voltage Detector also has the capability of generating an interrupt signal.

LVD Register

The Low Voltage Detector function is controlled using a single register with the name LVDC. Three bits in this register, VLVD2~VLVD0, are used to select one of eight fixed voltages below which a low voltage condition will be determined. A low voltage condition is indicated when the LVDO bit is set. If the LVDO bit is low, this indicates that the V_{DD} voltage or the LVDIN input voltage is above the preset low voltage value. The LVDEN bit is used to control the overall on/off function of the low voltage detector. Setting the bit high will enable the low voltage detector. Clearing the bit to zero will switch off the internal low voltage detector circuits. As the low voltage detector will consume a certain amount of power, it may be desirable to switch off the circuit when not in use, an important consideration in power sensitive battery powered applications.

• LVDC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	LVDO	LVDEN	VBGEN	VLVD2	VLVD1	VLVD0
R/W	—	—	R	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

Bit 7~6 Unimplemented, read as “0”

Bit 5 **LVDO**: LVD output flag
0: No Low Voltage Detected
1: Low Voltage Detected

Bit 4 **LVDEN**: Low Voltage Detector control
0: Disable
1: Enable

Bit 3 **VBGEN**: Bandgap buffer control
0: Disable
1: Enable

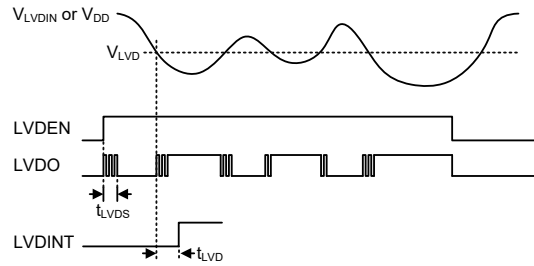
Note that the Bandgap circuit is enabled when the LVD or LVR function is enabled or when the VBGEN bit is set high.

Bit 2~0 **VLVD2~VLVD0**: Select LVD reference voltage
000: V_{LVDIN} ≤ 1.23V
001: 2.2V
010: 2.4V
011: 2.7V
100: 3.0V
101: 3.3V
110: 3.6V
111: 4.0V

When the VLVD bit field is set to 000, the LVD function will be implemented by comparing the LVD reference voltage with a voltage value of 1.23V which is derived from the LVDIN pin. Otherwise, the LVD function will operate by comparing the LVD reference voltage with a specific voltage value which is generated by the internal LVD circuit when the VLVD bit field is set to any other value except 000.

LVD Operation

The Low Voltage Detector function operates by comparing the power supply voltage, V_{DD} , or the V_{LVDIN} input voltage, with a pre-specified voltage level stored in the LVDC register. This has a range of between 1.23V and 4.0V. When the power supply voltage, V_{DD} , falls below this pre-determined value, the LVDO bit will be set high indicating a low power supply voltage condition. When the device is in the SLEEP mode, the low voltage detector will be disabled even if the LVDEN bit is high. After enabling the Low Voltage Detector, a time delay t_{LVDS} should be allowed for the circuitry to stabilise before reading the LVDO bit. Note also that as the V_{DD} or V_{LVDIN} voltage may rise and fall rather slowly, at the voltage nears that of V_{LVD} , there may be multiple bit LVDO transitions.



LVD Operation

The Low Voltage Detector also has its own interrupt which is contained within one of the Multi-function interrupts, providing an alternative means of low voltage detection, in addition to polling the LVDO bit. The interrupt will only be generated after a delay of t_{LVD} after the LVDO bit has been set high by a low voltage condition. In this case, the LVF interrupt request flag will be set, causing an interrupt to be generated if V_{DD} or V_{LVDIN} falls below the preset LVD voltage. This will cause the device to wake-up from the IDLE Mode, however if the Low Voltage Detector wake up function is not required then the LVF flag should be first set high before the device enters the IDLE Mode.

Interrupts

Interrupts are an important part of any microcontroller system. When an external event or an internal function such as a Timer Module or an A/D converter requires microcontroller attention, their corresponding interrupt will enforce a temporary suspension of the main program allowing the microcontroller to direct attention to their respective needs. The device contains several external interrupt and internal interrupt functions. The external interrupts are generated by the action of the external INT0~INT1 pins, while the internal interrupts are generated by various internal functions such as the Timer Modules, Time Bases, Low Voltage Detector, EEPROM, USIM and the A/D converter, etc.

Interrupt Registers

Overall interrupt control, which basically means the setting of request flags when certain microcontroller conditions occur and the setting of interrupt enable bits by the application program, is controlled by a series of registers, located in the Special Purpose Data Memory. The registers fall into three categories. The first is the INTC0~INTC2 registers which setup the primary interrupts, the second is the MF10~MF15 registers which setup the Multi-function interrupts. Finally there is an INTEG register to setup the external interrupts trigger edge type.

Each register contains a number of enable bits to enable or disable individual registers as well as interrupt flags to indicate the presence of an interrupt request. The naming convention of these follows a specific pattern. First is listed an abbreviated interrupt type, then the (optional) number of that interrupt followed by either an "E" for enable/disable bit or "F" for request flag.

Function	Enable Bit	Request Flag	Notes
Global	EMI	—	—
INTn Pin	INTnE	INTnF	n=0~1
A/D Converter	ADE	ADF	—
Multi-function	MFnE	MFnF	n=0~5
Time Base	TBnE	TBnF	n=0~1
LVD	LVE	LVF	—
EEPROM	DEE	DEF	—
USIM	USIME	USIMF	—
Over Voltage Protection	OVPnE	OVPnF	n=0~2
CTM	CTMnPE	CTMnPF	n=0~1
	CTMnAE	CTMnAF	
PTM	PTMnPE	PTMnPF	n=0~3
	PTMnAE	PTMnAF	

Interrupt Register Bit Naming Conventions

Register Name	Bit							
	7	6	5	4	3	2	1	0
INTEG	—	—	—	—	INT1S1	INT1S0	INT0S1	INT0S0
INTC0	—	ADF	INT1F	INT0F	ADE	INT1E	INT0E	EMI
INTC1	MF3F	MF2F	MF1F	MF0F	MF3E	MF2E	MF1E	MF0E
INTC2	MF5F	MF4F	TB1F	TB0F	MF5E	MF4E	TB1E	TB0E
MF10	—	—	PTM0AF	PTM0PF	—	—	PTM0AE	PTM0PE
MF11	—	—	PTM1AF	PTM1PF	—	—	PTM1AE	PTM1PE
MF12	—	—	PTM2AF	PTM2PF	—	—	PTM2AE	PTM2PE
MF13	LVF	DEF	PTM3AF	PTM3PF	LVE	DEE	PTM3AE	PTM3PE
MF14	OVP2F	OVP1F	OVP0F	USIMF	OVP2E	OVP1E	OVP0E	USIME
MF15	CTM1AF	CTM1PF	CTM0AF	CTM0PF	CTM1AE	CTM1PE	CTM0AE	CTM0PE

Interrupt Register List

• **INTEG Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	INT1S1	INT1S0	INT0S1	INT0S0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as “0”

Bit 3~2 **INT1S1~INT1S0**: Interrupt edge control for INT1 pin

- 00: Disable
- 01: Rising edge
- 10: Falling edge
- 11: Rising and falling edges

Bit 1~0 **INT0S1~INT0S0**: Interrupt edge control for INT0 pin

- 00: Disable
- 01: Rising edge
- 10: Falling edge
- 11: Rising and falling edges

• **INTC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	ADF	INT1F	INT0F	ADE	INT1E	INT0E	EMI
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	0	0	0	0	0	0	0

- Bit 7 Unimplemented, read as “0”
- Bit 6 **ADF**: A/D Converter interrupt request flag
 0: No request
 1: Interrupt request
- Bit 5 **INT1F**: External interrupt 1 request flag
 0: No request
 1: Interrupt request
- Bit 4 **INT0F**: External interrupt 0 request flag
 0: No request
 1: Interrupt request
- Bit 3 **ADE**: A/D Converter interrupt control
 0: Disable
 1: Enable
- Bit 2 **INT1E**: External interrupt 1 control
 0: Disable
 1: Enable
- Bit 1 **INT0E**: External interrupt 0 control
 0: Disable
 1: Enable
- Bit 0 **EMI**: Global interrupt control
 0: Disable
 1: Enable

• **INTC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	MF3F	MF2F	MF1F	MF0F	MF3E	MF2E	MF1E	MF0E
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7 **MF3F**: Multi-function 3 interrupt request flag
 0: No request
 1: Interrupt request
- Bit 6 **MF2F**: Multi-function 2 interrupt request flag
 0: No request
 1: Interrupt request
- Bit 5 **MF1F**: Multi-function 1 interrupt request flag
 0: No request
 1: Interrupt request
- Bit 4 **MF0F**: Multi-function 0 interrupt request flag
 0: No request
 1: Interrupt request
- Bit 3 **MF3E**: Multi-function 3 interrupt control
 0: Disable
 1: Enable
- Bit 2 **MF2E**: Multi-function 2 interrupt control
 0: Disable
 1: Enable

- Bit 1 **MF1E**: Multi-function 1 interrupt control
0: Disable
1: Enable
- Bit 0 **MF0E**: Multi-function 0 interrupt control
0: Disable
1: Enable

• **INTC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	MF5F	MF4F	TB1F	TB0F	MF5E	MF4E	TB1E	TB0E
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7 **MF5F**: Multi-function 5 interrupt request flag
0: No request
1: Interrupt request
- Bit 6 **MF4F**: Multi-function 4 interrupt request flag
0: No request
1: Interrupt request
- Bit 5 **TB1F**: Time Base 1 interrupt request flag
0: No request
1: Interrupt request
- Bit 4 **TB0F**: Time Base 0 interrupt request flag
0: No request
1: Interrupt request
- Bit 3 **MF5E**: Multi-function interrupt 5 control
0: Disable
1: Enable
- Bit 2 **MF4E**: Multi-function interrupt 4 control
0: Disable
1: Enable
- Bit 1 **TB1E**: Time Base 1 interrupt control
0: Disable
1: Enable
- Bit 0 **TB0E**: Time Base 0 interrupt control
0: Disable
1: Enable

• **MFIO Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	PTM0AF	PTM0PF	—	—	PTM0AE	PTM0PE
R/W	—	—	R/W	R/W	—	—	R/W	R/W
POR	—	—	0	0	—	—	0	0

- Bit 7~6 Unimplemented, read as “0”
- Bit 5 **PTM0AF**: PTM0 CCRA comparator interrupt request flag
0: No request
1: Interrupt request
- Bit 4 **PTM0PF**: PTM0 CCRP comparator interrupt request flag
0: No request
1: Interrupt request
- Bit 3~2 Unimplemented, read as “0”

- Bit 1 **PTM0AE**: PTM0 CCRA comparator interrupt control
 0: Disable
 1: Enable
- Bit 0 **PTM0PE**: PTM0 CCRP comparator interrupt control
 0: Disable
 1: Enable

• **MFI1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	PTM1AF	PTM1PF	—	—	PTM1AE	PTM1PE
R/W	—	—	R/W	R/W	—	—	R/W	R/W
POR	—	—	0	0	—	—	0	0

- Bit 7~6 Unimplemented, read as “0”
- Bit 5 **PTM1AF**: PTM1 CCRA comparator interrupt request flag
 0: No request
 1: Interrupt request
- Bit 4 **PTM1PF**: PTM1 CCRP comparator interrupt request flag
 0: No request
 1: Interrupt request
- Bit 3~2 Unimplemented, read as “0”
- Bit 1 **PTM1AE**: PTM1 CCRA comparator interrupt control
 0: Disable
 1: Enable
- Bit 0 **PTM1PE**: PTM1 CCRP comparator interrupt control
 0: Disable
 1: Enable

• **MFI2 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	PTM2AF	PTM2PF	—	—	PTM2AE	PTM2PE
R/W	—	—	R/W	R/W	—	—	R/W	R/W
POR	—	—	0	0	—	—	0	0

- Bit 7~6 Unimplemented, read as “0”
- Bit 5 **PTM2AF**: PTM2 CCRA comparator interrupt request flag
 0: No request
 1: Interrupt request
- Bit 4 **PTM2PF**: PTM2 CCRP comparator interrupt request flag
 0: No request
 1: Interrupt request
- Bit 3~2 Unimplemented, read as “0”
- Bit 1 **PTM2AE**: PTM2 CCRA comparator interrupt control
 0: Disable
 1: Enable
- Bit 0 **PTM2PE**: PTM2 CCRP comparator interrupt control
 0: Disable
 1: Enable

• **MF13 Register**

Bit	7	6	5	4	3	2	1	0
Name	LVF	DEF	PTM3AF	PTM3PF	LVE	DEE	PTM3AE	PTM3PE
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7 **LVF**: LVD interrupt request flag
0: No request
1: Interrupt request
- Bit 6 **DEF**: Data EEPROM interrupt request flag
0: No request
1: Interrupt request
- Bit 5 **PTM3AF**: PTM3 CCRA comparator interrupt request flag
0: No request
1: Interrupt request
- Bit 4 **PTM3PF**: PTM3 CCRP comparator interrupt request flag
0: No request
1: Interrupt request
- Bit 3 **LVE**: LVD interrupt control
0: Disable
1: Enable
- Bit 2 **DEE**: Data EEPROM interrupt control
0: Disable
1: Enable
- Bit 1 **PTM3AE**: PTM3 CCRA comparator interrupt control
0: Disable
1: Enable
- Bit 0 **PTM3PE**: PTM3 CCRP comparator interrupt control
0: Disable
1: Enable

• **MF14 Register**

Bit	7	6	5	4	3	2	1	0
Name	OVP2F	OVP1F	OVP0F	USIMF	OVP2E	OVP1E	OVP0E	USIME
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7 **OVP2F**: OVP2 interrupt request flag
0: No request
1: Interrupt request
- Bit 6 **OVP1F**: OVP1 interrupt request flag
0: No request
1: Interrupt request
- Bit 5 **OVP0F**: OVP0 interrupt request flag
0: No request
1: Interrupt request
- Bit 4 **USIMF**: USIM interrupt request flag
0: No request
1: Interrupt request
- Bit 3 **OVP2E**: OVP2 interrupt control
0: Disable
1: Enable

- Bit 2 **OVP1E**: OVP1 interrupt control
 0: Disable
 1: Enable
- Bit 1 **OVP0E**: OVP0 interrupt control
 0: Disable
 1: Enable
- Bit 0 **USIME**: USIM interrupt control
 0: Disable
 1: Enable

• **MF15 Register**

Bit	7	6	5	4	3	2	1	0
Name	CTM1AF	CTM1PF	CTM0AF	CTM0PF	CTM1AE	CTM1PE	CTM0AE	CTM0PE
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7 **CTM1AF**: CTM1 CCRA comparator interrupt request flag
 0: No request
 1: Interrupt request
- Bit 6 **CTM1PF**: CTM1 CCRP comparator interrupt request flag
 0: No request
 1: Interrupt request
- Bit 5 **CTM0AF**: CTM0 CCRA comparator interrupt request flag
 0: No request
 1: Interrupt request
- Bit 4 **CTM0PF**: CTM0 CCRP comparator interrupt request flag
 0: No request
 1: Interrupt request
- Bit 3 **CTM1AE**: CTM1 CCRA comparator interrupt control
 0: Disable
 1: Enable
- Bit 2 **CTM1PE**: CTM1 CCRP comparator interrupt control
 0: Disable
 1: Enable
- Bit 1 **CTM0AE**: CTM0 CCRA comparator interrupt control
 0: Disable
 1: Enable
- Bit 0 **CTM0PE**: CTM0 CCRP comparator interrupt control
 0: Disable
 1: Enable

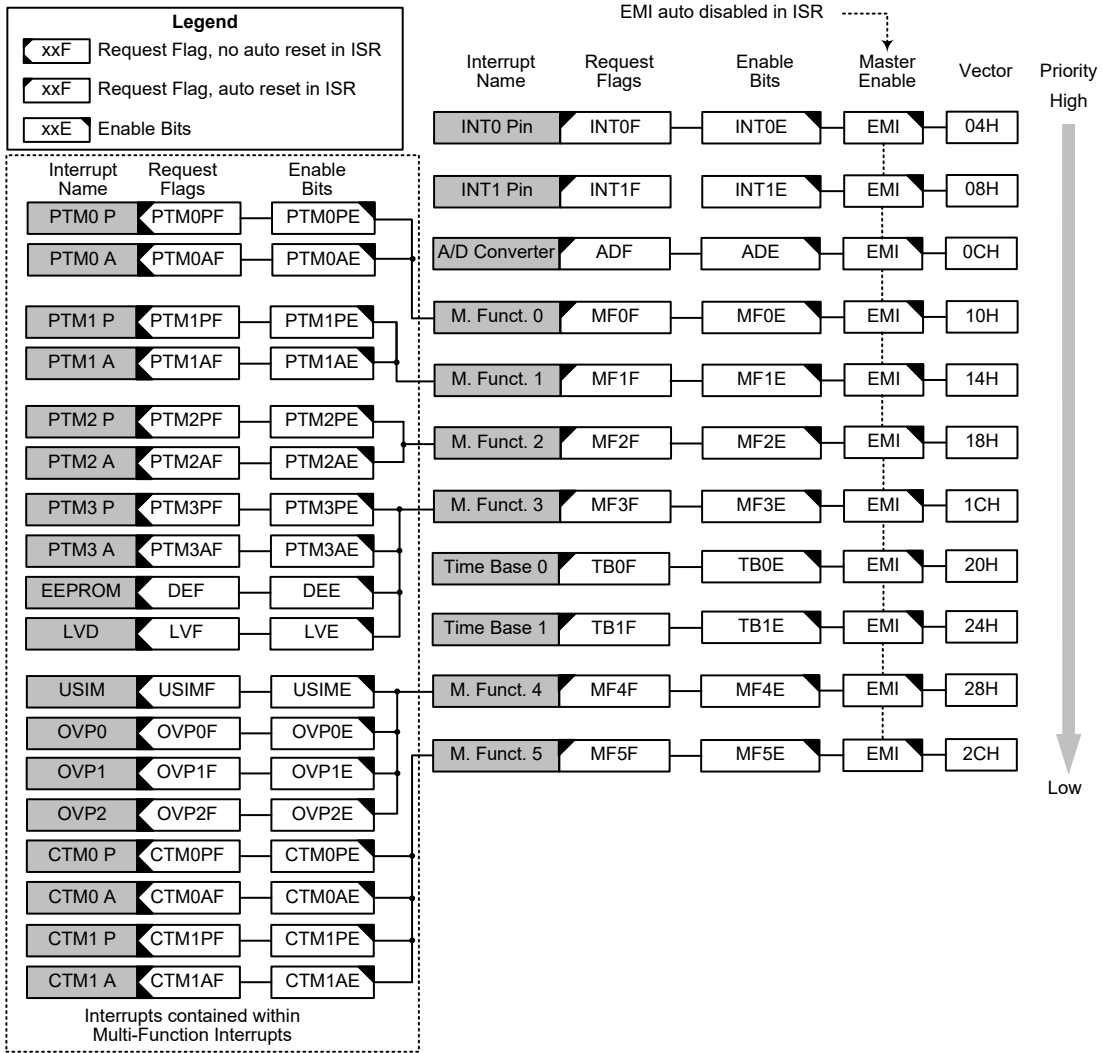
Interrupt Operation

When the conditions for an interrupt event occur, such as a TM Comparator P, Comparator A match or A/D conversion completion etc., the relevant interrupt request flag will be set. Whether the request flag actually generates a program jump to the relevant interrupt vector is determined by the condition of the interrupt enable bit. If the enable bit is set high then the program will jump to its relevant vector; if the enable bit is zero then although the interrupt request flag is set an actual interrupt will not be generated and the program will not jump to the relevant interrupt vector. The global interrupt enable bit, if cleared to zero, will disable all interrupts.

When an interrupt is generated, the Program Counter, which stores the address of the next instruction to be executed, will be transferred onto the stack. The Program Counter will then be loaded with a new address which will be the value of the corresponding interrupt vector. The microcontroller will then fetch its next instruction from this interrupt vector. The instruction at this vector will usually be a “JMP” which will jump to another section of program which is known as the interrupt service routine. Here is located the code to control the appropriate interrupt. The interrupt service routine must be terminated with an “RETI”, which retrieves the original Program Counter address from the stack and allows the microcontroller to continue with normal execution at the point where the interrupt occurred.

The various interrupt enable bits, together with their associated request flags, are shown in the accompanying diagrams with their order of priority. Some interrupt sources have their own individual vector while others share the same multi-function interrupt vector. Once an interrupt subroutine is serviced, all the other interrupts will be blocked, as the global interrupt enable bit, EMI bit will be cleared automatically. This will prevent any further interrupt nesting from occurring. However, if other interrupt requests occur during this interval, although the interrupt will not be immediately serviced, the request flag will still be recorded.

If an interrupt requires immediate servicing while the program is already in another interrupt service routine, the EMI bit should be set after entering the routine, to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even if the related interrupt is enabled, until the Stack Pointer is decremented. If immediate service is desired, the stack must be prevented from becoming full. In case of simultaneous requests, the accompanying diagram shows the priority that is applied. All of the interrupt request flags when set will wake-up the device if it is in SLEEP or IDLE Mode, however to prevent a wake-up from occurring the corresponding flag should be set before the device is in SLEEP or IDLE Mode.



Interrupt Structure

External Interrupt

The external interrupts are controlled by signal transitions on the pins INT0~INT1. An external interrupt request will take place when the external interrupt request flags, INT0F~INT1F, are set, which will occur when a transition, whose type is chosen by the edge select bits, appears on the external interrupt pins. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and respective external interrupt enable bit, INT0E~INT1E, must first be set. Additionally the correct interrupt edge type must be selected using the INTEG register to enable the external interrupt function and to choose the trigger edge type. As the external interrupt pins are pin-shared with I/O pins, they can only be configured as external interrupt pins if their external interrupt enable bit in the corresponding interrupt register has been set and the external interrupt pin is selected by the corresponding pin-shared function selection bits. The pin must also be setup as an input by setting the corresponding bit in the port control register.

When the interrupt is enabled, the stack is not full and the correct transition type appears on the external interrupt pin, a subroutine call to the external interrupt vector, will take place. When the interrupt is serviced, the external interrupt request flags, INT0F~INT1F, will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts. Note that any pull-high resistor selections on the external interrupt pins will remain valid even if the pin is used as an external interrupt input. The INTEG register is used to select the type of active edge that will trigger the external interrupt. A choice of either rising or falling or both edge types can be chosen to trigger an external interrupt. Note that the INTEG register can also be used to disable the external interrupt function.

A/D Converter Interrupt

The A/D Converter Interrupt is controlled by the termination of an A/D conversion process. An A/D Converter Interrupt request will take place when the A/D Converter Interrupt request flag, ADF, is set, which occurs when the A/D conversion process finishes. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and A/D Converter Interrupt enable bit, ADE, must first be set. When the interrupt is enabled, the stack is not full and the A/D conversion process has ended, a subroutine call to the A/D Converter Interrupt vector, will take place. When the interrupt is serviced, the A/D Converter Interrupt flag, ADF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

Multi-function Interrupts

Within this device there are several multi-function interrupts. Unlike the other independent interrupts, these interrupts have no independent source, but rather are formed from other existing interrupt sources, namely the TM interrupts, LVD interrupt, EEPROM interrupt, USIM interface interrupt and OVP interrupts.

A multi-function interrupt request will take place when any of the multi-function interrupt request flags, MFnF are set. The multi-function interrupt flags will be set when any of their included functions generate an interrupt request flag. When the multi-function interrupt is enabled and the stack is not full, and either one of the interrupts contained within each of multi-function interrupt occurs, a subroutine call to one of the multi-function interrupt vectors will take place. When the interrupt is serviced, the related multi-function request flag will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts.

However, it must be noted that, although the multi-function Interrupt flags will be automatically reset when the interrupt is serviced, the request flags from the original source of the multi-function interrupts will not be automatically reset and must be manually reset by the application program.

Timer Module Interrupts

Each of the Compact and Periodic Type TM has two interrupts. All of the TM interrupts are contained within the Multi-function Interrupts. For all of the TM types there are two interrupt request flags of CTMnPF, CTMnAF and PTMnPF, PTMnAF, and two enable bits of CTMnPE, CTMnAE and PTMnPE, PTMnAE. A TM interrupt request will take place when any of the TM request flags are set, a situation which occurs when a TM comparator P or A match situation happens.

To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, respective TM interrupt enable bit, and relevant multi-function interrupt enable bit, MFnE, must first be set. When the interrupt is enabled, the stack is not full and a TM comparator match situation occurs, a subroutine call to the relevant multi-function interrupt vector locations, will take place. When the TM interrupt is serviced, the EMI bit will be automatically cleared to disable other interrupts, however only the related MFnF flag will be automatically cleared. As the TM interrupt request flags will not be automatically cleared, they have to be cleared by the application program.

LVD Interrupt

The Low Voltage Detector Interrupt is contained within the Multi-function Interrupt. An LVD Interrupt request will take place when the LVD Interrupt request flag, LVF, is set, which occurs when the Low Voltage Detector function detects a low power supply voltage or a low LVDIN input voltage. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, Low Voltage Interrupt enable bit, LVE, and associated Multi-function interrupt enable bit, must first be set. When the interrupt is enabled, the stack is not full and a low voltage condition occurs, a subroutine call to the Multi-function Interrupt vector, will take place. When the Low Voltage Interrupt is serviced, the EMI bit will be automatically cleared to disable other interrupts, however only the Multi-function interrupt request flag will be also automatically cleared. As the LVF flag will not be automatically cleared, it has to be cleared by the application program.

EEPROM Interrupt

The EEPROM interrupt is contained within the multi-function interrupt. An EEPROM interrupt request will take place when the EEPROM interrupt request flag, DEF, is set, which occurs when an EEPROM erase/write cycle ends. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, EEPROM interrupt enable bit, DEE, and associated multi-function interrupt enable bit, must first be set. When the interrupt is enabled, the stack is not full and an EEPROM erase/write cycle ends, a subroutine call to the respective EEPROM interrupt vector will take place. When the EEPROM interrupt is serviced, the EMI bit will be automatically cleared to disable other interrupts, however only the multi-function interrupt request flag will be also automatically cleared. As the DEF flag will not be automatically cleared, it has to be cleared by the application program.

USIM Interrupt

The Universal Serial Interface Module Interrupt, as known as the USIM Interrupt, is contained within the Multi-function Interrupt. As the USIM interface can operate in three modes which are SPI mode, I²C mode and UART mode, the USIMF flag can be set by different conditions depending on the selected interface mode.

If the SPI or I²C mode is selected, the USIM interrupt can be triggered when a byte of data has been received or transmitted by the SPI/I²C interface, or an I²C slave address match occurs, or an I²C bus time-out occurs. If the UART mode is selected, several individual UART conditions including a transmitter data register empty, transmitter idle, receiver data available, receiver overrun, address detect and an URX/UTX pin wake-up, can generate a USIM interrupt with the USIMF flag bit set high.

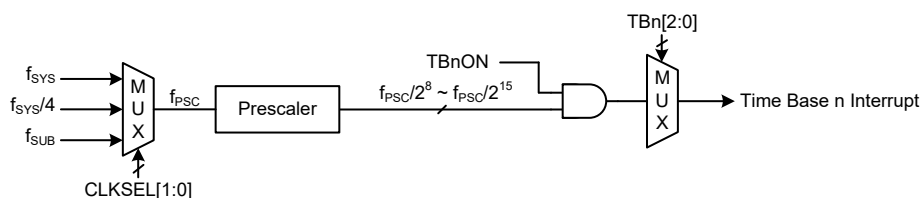
To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and the Serial Interface Interrupt enable bit, USIME, and Multi-function interrupt enable bit must first be set. When the interrupt is enabled, the stack is not full and any of the above described situations occurs, a subroutine call to the respective Interrupt vector, will take place. When the interrupt is serviced, the Universal Serial Interface Interrupt flag, USIMF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

Note that if the USIM interrupt is triggered by the UART interface, after the interrupt has been serviced, the UUSR register flags will only be cleared when certain actions are taken by the UART, the details of which are given in the UART section.

Time Base Interrupts

The function of the Time Base interrupts is to provide regular time signal in the form of an internal interrupt. They are controlled by the overflow signals from their respective timer functions. When these happen their respective interrupt request flags, TB0F or TB1F will be set. To allow the program to branch to their respective interrupt vector addresses, the global interrupt enable bit, EMI and Time Base enable bits, TB0E or TB1E, must first be set. When the interrupt is enabled, the stack is not full and the Time Base overflows, a subroutine call to their respective vector locations will take place. When the interrupt is serviced, the respective interrupt request flag, TB0F or TB1F, will be automatically reset and the EMI bit will be cleared to disable other interrupts.

The purpose of the Time Base interrupt is to provide an interrupt signal at fixed time periods. Its clock source, f_{PSC} , originates from the internal clock source f_{SYS} , $f_{SYS}/4$ or f_{SUB} and then passes through a divider, the division ratio of which is selected by programming the appropriate bits in the TB0C and TB1C registers to obtain longer interrupt periods whose value ranges. The clock source which in turn controls the Time Base interrupt period is selected using the CLKSEL[1:0] bits in the PSCR register.



Time Base Interrupt (n=0 or 1)

• PSCR Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	CLKSEL1	CLKSEL0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”

Bit 1~0 **CLKSEL1~CLKSEL0**: Prescaler clock source f_{PSC} selection
 00: f_{SYS}
 01: $f_{SYS}/4$
 1x: f_{SUB}

• TBnC Register (n=0 or 1)

Bit	7	6	5	4	3	2	1	0
Name	TBnON	—	—	—	—	TBn2	TBn1	TBn0
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TBnON**: Time Base n control
 0: Disable
 1: Enable

Bit 6~3 Unimplemented, read as “0”

Bit 2~0 **TBn2~TBn0**: Select Time Base n time-out period
 000: $2^8/f_{PSC}$
 001: $2^9/f_{PSC}$
 010: $2^{10}/f_{PSC}$
 011: $2^{11}/f_{PSC}$
 100: $2^{12}/f_{PSC}$
 101: $2^{13}/f_{PSC}$
 110: $2^{14}/f_{PSC}$
 111: $2^{15}/f_{PSC}$

Over Voltage Protection Interrupt

The OVPn Interrupt is contained within the Multi-function Interrupt, which is controlled by detecting the OVPn input voltage. An OVPn Interrupt request will take place when the OVPn Interrupt request flag, OVPnF, is set, which occurs when the Over Voltage Protection circuit detects an over voltage condition. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and OVPn Interrupt enable bit, OVPnE, must first be set. When the interrupt is enabled, the stack is not full and an over voltage is detected, a subroutine call to the OVP Interrupt vector, will take place. When the interrupt is serviced, the OVPn Interrupt flag, OVPnF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts, however only the Multi-function interrupt request flag will be also automatically cleared.

Interrupt Wake-up Function

Each of the interrupt functions has the capability of waking up the microcontroller when in the SLEEP or IDLE Mode. A wake-up is generated when an interrupt request flag changes from low to high and is independent of whether the interrupt is enabled or not. Therefore, even though the device is in the SLEEP or IDLE Mode and its system oscillator stopped, situations such as edge transitions on the external interrupt pins or a low power supply voltage may cause their respective interrupt flag to be set high and consequently generate an interrupt. Care must therefore be taken if spurious wake-up situations are to be avoided. If an interrupt wake-up function is to be disabled then the corresponding interrupt request flag should be set high before the device enters the SLEEP or IDLE Mode. The interrupt enable bits have no effect on the interrupt wake-up function.

Programming Considerations

By disabling the relevant interrupt enable bits, a requested interrupt can be prevented from being serviced, however, once an interrupt request flag is set, it will remain in this condition in the interrupt register until the corresponding interrupt is serviced or until the request flag is cleared by the application program.

It is recommended that programs do not use the “CALL” instruction within the interrupt service subroutine. Interrupts often occur in an unpredictable manner or need to be serviced immediately. If only one stack is left and the interrupt is not well controlled, the original control sequence will be damaged once a CALL subroutine is executed in the interrupt subroutine.

Every interrupt has the capability of waking up the microcontroller when it is in the SLEEP or IDLE Mode, the wake up being generated when the interrupt request flag changes from low to high. If it is required to prevent a certain interrupt from waking up the microcontroller then its respective request flag should be first set high before enter SLEEP or IDLE Mode.

As only the Program Counter is pushed onto the stack, then when the interrupt is serviced, if the contents of the accumulator, status register or other registers are altered by the interrupt service program, their contents should be saved to the memory at the beginning of the interrupt service routine.

To return from an interrupt subroutine, either a RET or RETI instruction may be executed. The RETI instruction in addition to executing a return to the main program also automatically sets the EMI bit high to allow further interrupts. The RET instruction however only executes a return to the main program leaving the EMI bit in its present zero state and therefore disabling the execution of further interrupts.

Configuration Options

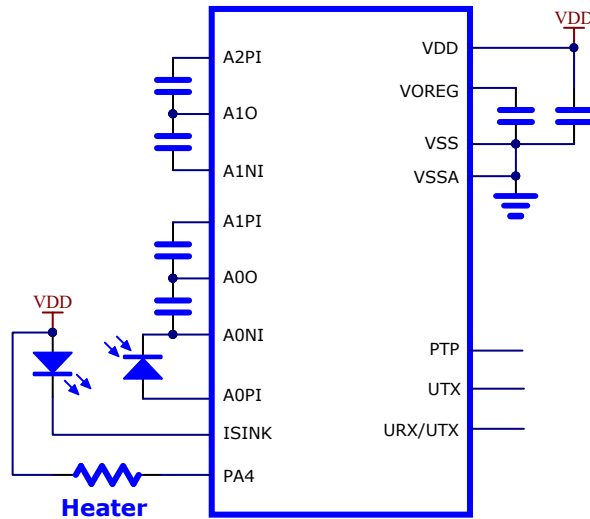
Configuration options refer to certain options within the MCU that are programmed into the device during the programming process. During the development process, these options are selected using the HT-IDE software development tools. As these options are programmed into the device using the hardware programming tools, once they are selected they cannot be changed later using the application program. All options must be defined for proper system function, the details of which are shown in the table.

No.	Options
Oscillator Options	
1	HIRC frequency selection – f_{HIRC} 4MHz, 8MHz or 12MHz
Temperature Sensor Options	
2	Temperature calibration selection: 1: Don't need 2: Need

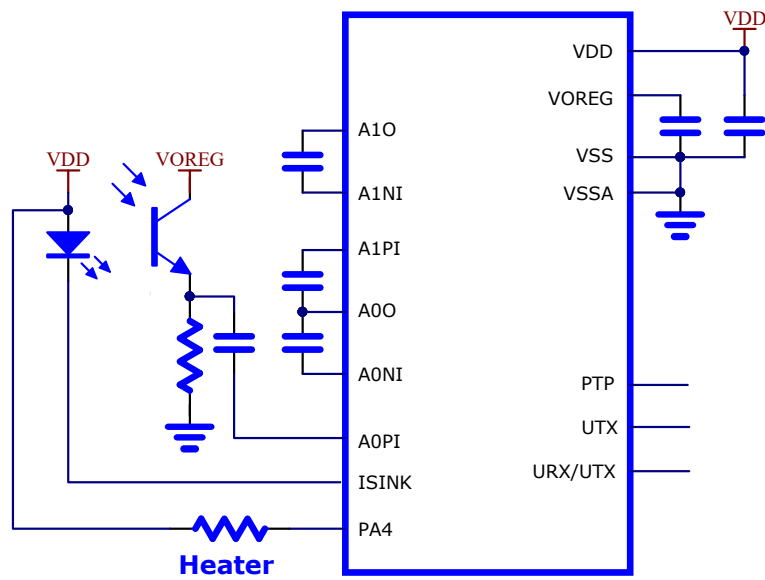
- Note: 1. When the HIRC has been configured at a frequency shown in this table, the HIRC1 and HIRC0 bits should also be set to select the same frequency to achieve the HIRC frequency accuracy specified in the A.C. Characteristics.
2. If need the temperature calibration selection, when using the writer for programming, it will detect whether the temperature module (EMDE001A) is connected or not. If it is not connected, it indicates an error and cannot be programming.

Application Circuits

Application for Photo Diode Receive Circuit



Application for Photo Transistor Receive Circuit



Instruction Set

Introduction

Central to the successful operation of any microcontroller is its instruction set, which is a set of program instruction codes that directs the microcontroller to perform certain operations. In the case of Holtek microcontroller, a comprehensive and flexible set of over 60 instructions is provided to enable programmers to implement their application with the minimum of programming overheads.

For easier understanding of the various instruction codes, they have been subdivided into several functional groupings.

Instruction Timing

Most instructions are implemented within one instruction cycle. The exceptions to this are branch, call, or table read instructions where two instruction cycles are required. One instruction cycle is equal to 4 system clock cycles, therefore in the case of an 8MHz system oscillator, most instructions would be implemented within 0.5 μ s and branch or call instructions would be implemented within 1 μ s. Although instructions which require one more cycle to implement are generally limited to the JMP, CALL, RET, RETI and table read instructions, it is important to realize that any other instructions which involve manipulation of the Program Counter Low register or PCL will also take one more cycle to implement. As instructions which change the contents of the PCL will imply a direct jump to that new address, one more cycle will be required. Examples of such instructions would be “CLR PCL” or “MOV PCL, A”. For the case of skip instructions, it must be noted that if the result of the comparison involves a skip operation then this will also take one more cycle, if no skip is involved then only one cycle is required.

Moving and Transferring Data

The transfer of data within the microcontroller program is one of the most frequently used operations. Making use of several kinds of MOV instructions, data can be transferred from registers to the Accumulator and vice-versa as well as being able to move specific immediate data directly into the Accumulator. One of the most important data transfer applications is to receive data from the input ports and transfer data to the output ports.

Arithmetic Operations

The ability to perform certain arithmetic operations and data manipulation is a necessary feature of most microcontroller applications. Within the Holtek microcontroller instruction set are a range of add and subtract instruction mnemonics to enable the necessary arithmetic to be carried out. Care must be taken to ensure correct handling of carry and borrow data when results exceed 255 for addition and less than 0 for subtraction. The increment and decrement instructions such as INC, INCA, DEC and DECA provide a simple means of increasing or decreasing by a value of one of the values in the destination specified.

Logical and Rotate Operation

The standard logical operations such as AND, OR, XOR and CPL all have their own instruction within the Holtek microcontroller instruction set. As with the case of most instructions involving data manipulation, data must pass through the Accumulator which may involve additional programming steps. In all logical data operations, the zero flag may be set if the result of the operation is zero. Another form of logical data manipulation comes from the rotate instructions such as RR, RL, RRC and RLC which provide a simple means of rotating one bit right or left. Different rotate instructions exist depending on program requirements. Rotate instructions are useful for serial port programming applications where data can be rotated from an internal register into the Carry bit from where it can be examined and the necessary serial bit set high or low. Another application which rotate data operations are used is to implement multiplication and division calculations.

Branches and Control Transfer

Program branching takes the form of either jumps to specified locations using the JMP instruction or to a subroutine using the CALL instruction. They differ in the sense that in the case of a subroutine call, the program must return to the instruction immediately when the subroutine has been carried out. This is done by placing a return instruction “RET” in the subroutine which will cause the program to jump back to the address right after the CALL instruction. In the case of a JMP instruction, the program simply jumps to the desired location. There is no requirement to jump back to the original jumping off point as in the case of the CALL instruction. One special and extremely useful set of branch instructions are the conditional branches. Here a decision is first made regarding the condition of a certain data memory or individual bits. Depending upon the conditions, the program will continue with the next instruction or skip over it and jump to the following instruction. These instructions are the key to decision making and branching within the program perhaps determined by the condition of certain input switches or by the condition of internal data bits.

Bit Operations

The ability to provide single bit operations on Data Memory is an extremely flexible feature of all Holtek microcontrollers. This feature is especially useful for output port bit programming where individual bits or port pins can be directly set high or low using either the “SET [m].i” or “CLR [m].i” instructions respectively. The feature removes the need for programmers to first read the 8-bit output port, manipulate the input data to ensure that other bits are not changed and then output the port with the correct new data. This read-modify-write process is taken care of automatically when these bit operation instructions are used.

Table Read Operations

Data storage is normally implemented by using registers. However, when working with large amounts of fixed data, the volume involved often makes it inconvenient to store the fixed data in the Data Memory. To overcome this problem, Holtek microcontrollers allow an area of Program Memory to be setup as a table where data can be directly stored. A set of easy to use instructions provides the means by which this fixed data can be referenced and retrieved from the Program Memory.

Other Operations

In addition to the above functional instructions, a range of other instructions also exist such as the “HALT” instruction for Power-down operations and instructions to control the operation of the Watchdog Timer for reliable program operations under extreme electric or electromagnetic environments. For their relevant operations, refer to the functional related sections.

Instruction Set Summary

The instructions related to the data memory access in the following table can be used when the desired data memory is located in Data Memory sector 0.

Table Conventions

x: Bits immediate data
m: Data Memory address
A: Accumulator
i: 0~7 number of bits
addr: Program memory address

Mnemonic	Description	Cycles	Flag Affected
Arithmetic			
ADD A,[m]	Add Data Memory to ACC	1	Z, C, AC, OV, SC
ADDM A,[m]	Add ACC to Data Memory	1 ^{Note}	Z, C, AC, OV, SC
ADD A,x	Add immediate data to ACC	1	Z, C, AC, OV, SC
ADC A,[m]	Add Data Memory to ACC with Carry	1	Z, C, AC, OV, SC
ADCM A,[m]	Add ACC to Data memory with Carry	1 ^{Note}	Z, C, AC, OV, SC
SUB A,x	Subtract immediate data from the ACC	1	Z, C, AC, OV, SC, CZ
SUB A,[m]	Subtract Data Memory from ACC	1	Z, C, AC, OV, SC, CZ
SUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	1 ^{Note}	Z, C, AC, OV, SC, CZ
SBC A,x	Subtract immediate data from ACC with Carry	1	Z, C, AC, OV, SC, CZ
SBC A,[m]	Subtract Data Memory from ACC with Carry	1	Z, C, AC, OV, SC, CZ
SBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	1 ^{Note}	Z, C, AC, OV, SC, CZ
DAA [m]	Decimal adjust ACC for Addition with result in Data Memory	1 ^{Note}	C
Logic Operation			
AND A,[m]	Logical AND Data Memory to ACC	1	Z
OR A,[m]	Logical OR Data Memory to ACC	1	Z
XOR A,[m]	Logical XOR Data Memory to ACC	1	Z
ANDM A,[m]	Logical AND ACC to Data Memory	1 ^{Note}	Z
ORM A,[m]	Logical OR ACC to Data Memory	1 ^{Note}	Z
XORM A,[m]	Logical XOR ACC to Data Memory	1 ^{Note}	Z
AND A,x	Logical AND immediate Data to ACC	1	Z
OR A,x	Logical OR immediate Data to ACC	1	Z
XOR A,x	Logical XOR immediate Data to ACC	1	Z
CPL [m]	Complement Data Memory	1 ^{Note}	Z
CPLA [m]	Complement Data Memory with result in ACC	1	Z
Increment & Decrement			
INCA [m]	Increment Data Memory with result in ACC	1	Z
INC [m]	Increment Data Memory	1 ^{Note}	Z
DECA [m]	Decrement Data Memory with result in ACC	1	Z
DEC [m]	Decrement Data Memory	1 ^{Note}	Z
Rotate			
RRA [m]	Rotate Data Memory right with result in ACC	1	None
RR [m]	Rotate Data Memory right	1 ^{Note}	None
RRCA [m]	Rotate Data Memory right through Carry with result in ACC	1	C
RRC [m]	Rotate Data Memory right through Carry	1 ^{Note}	C
RLA [m]	Rotate Data Memory left with result in ACC	1	None
RL [m]	Rotate Data Memory left	1 ^{Note}	None
RLCA [m]	Rotate Data Memory left through Carry with result in ACC	1	C
RLC [m]	Rotate Data Memory left through Carry	1 ^{Note}	C

Mnemonic	Description	Cycles	Flag Affected
Data Move			
MOV A,[m]	Move Data Memory to ACC	1	None
MOV [m],A	Move ACC to Data Memory	1 ^{Note}	None
MOV A,x	Move immediate data to ACC	1	None
Bit Operation			
CLR [m].i	Clear bit of Data Memory	1 ^{Note}	None
SET [m].i	Set bit of Data Memory	1 ^{Note}	None
Branch Operation			
JMP addr	Jump unconditionally	2	None
SZ [m]	Skip if Data Memory is zero	1 ^{Note}	None
SZA [m]	Skip if Data Memory is zero with data movement to ACC	1 ^{Note}	None
SZ [m].i	Skip if bit i of Data Memory is zero	1 ^{Note}	None
SNZ [m]	Skip if Data Memory is not zero	1 ^{Note}	None
SNZ [m].i	Skip if bit i of Data Memory is not zero	1 ^{Note}	None
SIZ [m]	Skip if increment Data Memory is zero	1 ^{Note}	None
SDZ [m]	Skip if decrement Data Memory is zero	1 ^{Note}	None
SIZA [m]	Skip if increment Data Memory is zero with result in ACC	1 ^{Note}	None
SDZA [m]	Skip if decrement Data Memory is zero with result in ACC	1 ^{Note}	None
CALL addr	Subroutine call	2	None
RET	Return from subroutine	2	None
RET A,x	Return from subroutine and load immediate data to ACC	2	None
RETI	Return from interrupt	2	None
Table Read Operation			
TABRD [m]	Read table (specific page) to TBLH and Data Memory	2 ^{Note}	None
TABRDL [m]	Read table (last page) to TBLH and Data Memory	2 ^{Note}	None
ITABRD [m]	Increment table pointer TBLP first and Read table (specific page) to TBLH and Data Memory	2 ^{Note}	None
ITABRDL [m]	Increment table pointer TBLP first and Read table (last page) to TBLH and Data Memory	2 ^{Note}	None
Miscellaneous			
NOP	No operation	1	None
CLR [m]	Clear Data Memory	1 ^{Note}	None
SET [m]	Set Data Memory	1 ^{Note}	None
CLR WDT	Clear Watchdog Timer	1	TO, PDF
SWAP [m]	Swap nibbles of Data Memory	1 ^{Note}	None
SWAPA [m]	Swap nibbles of Data Memory with result in ACC	1	None
HALT	Enter power down mode	1	TO, PDF

Note: 1. For skip instructions, if the result of the comparison involves a skip then two cycles are required, if no skip takes place only one cycle is required.

2. Any instruction which changes the contents of the PCL will also require 2 cycles for execution.

Extended Instruction Set

The extended instructions are used to support the full range address access for the data memory. When the accessed data memory is located in any data memory sector except sector 0, the extended instruction can be used to directly access the data memory instead of using the indirect addressing access. This can not only reduce the use of Flash memory space but also improve the CPU execution efficiency.

Mnemonic	Description	Cycles	Flag Affected
Arithmetic			
LADD A,[m]	Add Data Memory to ACC	2	Z, C, AC, OV, SC
LADDM A,[m]	Add ACC to Data Memory	2 ^{Note}	Z, C, AC, OV, SC
LADC A,[m]	Add Data Memory to ACC with Carry	2	Z, C, AC, OV, SC
LADCM A,[m]	Add ACC to Data memory with Carry	2 ^{Note}	Z, C, AC, OV, SC
LSUB A,[m]	Subtract Data Memory from ACC	2	Z, C, AC, OV, SC, CZ
LSUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	2 ^{Note}	Z, C, AC, OV, SC, CZ
LSBC A,[m]	Subtract Data Memory from ACC with Carry	2	Z, C, AC, OV, SC, CZ
LSBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	2 ^{Note}	Z, C, AC, OV, SC, CZ
LDAA [m]	Decimal adjust ACC for Addition with result in Data Memory	2 ^{Note}	C
Logic Operation			
LAND A,[m]	Logical AND Data Memory to ACC	2	Z
LOR A,[m]	Logical OR Data Memory to ACC	2	Z
LXOR A,[m]	Logical XOR Data Memory to ACC	2	Z
LANDM A,[m]	Logical AND ACC to Data Memory	2 ^{Note}	Z
LORM A,[m]	Logical OR ACC to Data Memory	2 ^{Note}	Z
LXORM A,[m]	Logical XOR ACC to Data Memory	2 ^{Note}	Z
LCPL [m]	Complement Data Memory	2 ^{Note}	Z
LCPLA [m]	Complement Data Memory with result in ACC	2	Z
Increment & Decrement			
LINCA [m]	Increment Data Memory with result in ACC	2	Z
LINC [m]	Increment Data Memory	2 ^{Note}	Z
LDECA [m]	Decrement Data Memory with result in ACC	2	Z
LDEC [m]	Decrement Data Memory	2 ^{Note}	Z
Rotate			
LRRRA [m]	Rotate Data Memory right with result in ACC	2	None
LRR [m]	Rotate Data Memory right	2 ^{Note}	None
LRRCA [m]	Rotate Data Memory right through Carry with result in ACC	2	C
LRRC [m]	Rotate Data Memory right through Carry	2 ^{Note}	C
LRLA [m]	Rotate Data Memory left with result in ACC	2	None
LRL [m]	Rotate Data Memory left	2 ^{Note}	None
LRLCA [m]	Rotate Data Memory left through Carry with result in ACC	2	C
LRLC [m]	Rotate Data Memory left through Carry	2 ^{Note}	C
Data Move			
LMOV A,[m]	Move Data Memory to ACC	2	None
LMOV [m],A	Move ACC to Data Memory	2 ^{Note}	None
Bit Operation			
LCLR [m].i	Clear bit of Data Memory	2 ^{Note}	None
LSET [m].i	Set bit of Data Memory	2 ^{Note}	None

Mnemonic	Description	Cycles	Flag Affected
Branch			
LSZ [m]	Skip if Data Memory is zero	2 ^{Note}	None
LSZA [m]	Skip if Data Memory is zero with data movement to ACC	2 ^{Note}	None
LSNZ [m]	Skip if Data Memory is not zero	2 ^{Note}	None
LSZ [m].i	Skip if bit i of Data Memory is zero	2 ^{Note}	None
LSNZ [m].i	Skip if bit i of Data Memory is not zero	2 ^{Note}	None
LSIZ [m]	Skip if increment Data Memory is zero	2 ^{Note}	None
LSDZ [m]	Skip if decrement Data Memory is zero	2 ^{Note}	None
LSIZA [m]	Skip if increment Data Memory is zero with result in ACC	2 ^{Note}	None
LSDZA [m]	Skip if decrement Data Memory is zero with result in ACC	2 ^{Note}	None
Table Read			
LTABRD [m]	Read table (specific page) to TBLH and Data Memory	3 ^{Note}	None
LTABRDL [m]	Read table (last page) to TBLH and Data Memory	3 ^{Note}	None
LITABRD [m]	Increment table pointer TBLP first and Read table (specific page) to TBLH and Data Memory	3 ^{Note}	None
LITABRDL [m]	Increment table pointer TBLP first and Read table (last page) to TBLH and Data Memory	3 ^{Note}	None
Miscellaneous			
LCLR [m]	Clear Data Memory	2 ^{Note}	None
LSET [m]	Set Data Memory	2 ^{Note}	None
LSWAP [m]	Swap nibbles of Data Memory	2 ^{Note}	None
LSWAPA [m]	Swap nibbles of Data Memory with result in ACC	2	None

- Note: 1. For these extended skip instructions, if the result of the comparison involves a skip then three cycles are required, if no skip takes place two cycles is required.
2. Any extended instruction which changes the contents of the PCL register will also require three cycles for execution.

Instruction Definition

ADC A,[m]	Add Data Memory to ACC with Carry
Description	The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC + [m] + C$
Affected flag(s)	OV, Z, AC, C, SC
ADCM A,[m]	Add ACC to Data Memory with Carry
Description	The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the specified Data Memory.
Operation	$[m] \leftarrow ACC + [m] + C$
Affected flag(s)	OV, Z, AC, C, SC
ADD A,[m]	Add Data Memory to ACC
Description	The contents of the specified Data Memory and the Accumulator are added. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC + [m]$
Affected flag(s)	OV, Z, AC, C, SC
ADD A,x	Add immediate data to ACC
Description	The contents of the Accumulator and the specified immediate data are added. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC + x$
Affected flag(s)	OV, Z, AC, C, SC
ADDM A,[m]	Add ACC to Data Memory
Description	The contents of the specified Data Memory and the Accumulator are added. The result is stored in the specified Data Memory.
Operation	$[m] \leftarrow ACC + [m]$
Affected flag(s)	OV, Z, AC, C, SC
AND A,[m]	Logical AND Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical AND operation. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC \text{ "AND" } [m]$
Affected flag(s)	Z
AND A,x	Logical AND immediate data to ACC
Description	Data in the Accumulator and the specified immediate data perform a bit wise logical AND operation. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC \text{ "AND" } x$
Affected flag(s)	Z
ANDM A,[m]	Logical AND ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical AND operation. The result is stored in the Data Memory.
Operation	$[m] \leftarrow ACC \text{ "AND" } [m]$
Affected flag(s)	Z

CALL addr	Subroutine call
Description	Unconditionally calls a subroutine at the specified address. The Program Counter then increments by 1 to obtain the address of the next instruction which is then pushed onto the stack. The specified address is then loaded and the program continues execution from this new address. As this instruction requires an additional operation, it is a two cycle instruction.
Operation	Stack \leftarrow Program Counter + 1 Program Counter \leftarrow addr
Affected flag(s)	None
CLR [m]	Clear Data Memory
Description	Each bit of the specified Data Memory is cleared to 0.
Operation	[m] \leftarrow 00H
Affected flag(s)	None
CLR [m].i	Clear bit of Data Memory
Description	Bit i of the specified Data Memory is cleared to 0.
Operation	[m].i \leftarrow 0
Affected flag(s)	None
CLR WDT	Clear Watchdog Timer
Description	The TO, PDF flags and the WDT are all cleared.
Operation	WDT cleared TO \leftarrow 0 PDF \leftarrow 0
Affected flag(s)	TO, PDF
CPL [m]	Complement Data Memory
Description	Each bit of the specified Data Memory is logically complemented (1's complement). Bits which previously contained a 1 are changed to 0 and vice versa.
Operation	[m] \leftarrow $\overline{[m]}$
Affected flag(s)	Z
CPLA [m]	Complement Data Memory with result in ACC
Description	Each bit of the specified Data Memory is logically complemented (1's complement). Bits which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC \leftarrow $\overline{[m]}$
Affected flag(s)	Z
DAA [m]	Decimal-Adjust ACC for addition with result in Data Memory
Description	Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value resulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is greater than 100, it allows multiple precision decimal addition.
Operation	[m] \leftarrow ACC + 00H or [m] \leftarrow ACC + 06H or [m] \leftarrow ACC + 60H or [m] \leftarrow ACC + 66H
Affected flag(s)	C

DEC [m]	Decrement Data Memory
Description	Data in the specified Data Memory is decremented by 1.
Operation	$[m] \leftarrow [m] - 1$
Affected flag(s)	Z
DECA [m]	Decrement Data Memory with result in ACC
Description	Data in the specified Data Memory is decremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	$ACC \leftarrow [m] - 1$
Affected flag(s)	Z
HALT	Enter power down mode
Description	This instruction stops the program execution and turns off the system clock. The contents of the Data Memory and registers are retained. The WDT and prescaler are cleared. The power down flag PDF is set and the WDT time-out flag TO is cleared.
Operation	$TO \leftarrow 0$ $PDF \leftarrow 1$
Affected flag(s)	TO, PDF
INC [m]	Increment Data Memory
Description	Data in the specified Data Memory is incremented by 1.
Operation	$[m] \leftarrow [m] + 1$
Affected flag(s)	Z
INCA [m]	Increment Data Memory with result in ACC
Description	Data in the specified Data Memory is incremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	$ACC \leftarrow [m] + 1$
Affected flag(s)	Z
JMP addr	Jump unconditionally
Description	The contents of the Program Counter are replaced with the specified address. Program execution then continues from this new address. As this requires the insertion of a dummy instruction while the new address is loaded, it is a two cycle instruction.
Operation	Program Counter \leftarrow addr
Affected flag(s)	None
MOV A,[m]	Move Data Memory to ACC
Description	The contents of the specified Data Memory are copied to the Accumulator.
Operation	$ACC \leftarrow [m]$
Affected flag(s)	None
MOV A,x	Move immediate data to ACC
Description	The immediate data specified is loaded into the Accumulator.
Operation	$ACC \leftarrow x$
Affected flag(s)	None
MOV [m],A	Move ACC to Data Memory
Description	The contents of the Accumulator are copied to the specified Data Memory.
Operation	$[m] \leftarrow ACC$
Affected flag(s)	None

NOP	No operation
Description	No operation is performed. Execution continues with the next instruction.
Operation	No operation
Affected flag(s)	None
OR A,[m]	Logical OR Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical OR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC "OR" [m]
Affected flag(s)	Z
OR A,x	Logical OR immediate data to ACC
Description	Data in the Accumulator and the specified immediate data perform a bitwise logical OR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC "OR" x
Affected flag(s)	Z
ORM A,[m]	Logical OR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical OR operation. The result is stored in the Data Memory.
Operation	[m] ← ACC "OR" [m]
Affected flag(s)	Z
RET	Return from subroutine
Description	The Program Counter is restored from the stack. Program execution continues at the restored address.
Operation	Program Counter ← Stack
Affected flag(s)	None
RET A,x	Return from subroutine and load immediate data to ACC
Description	The Program Counter is restored from the stack and the Accumulator loaded with the specified immediate data. Program execution continues at the restored address.
Operation	Program Counter ← Stack ACC ← x
Affected flag(s)	None
RETI	Return from interrupt
Description	The Program Counter is restored from the stack and the interrupts are re-enabled by setting the EMI bit. EMI is the master interrupt global enable bit. If an interrupt was pending when the RETI instruction is executed, the pending Interrupt routine will be processed before returning to the main program.
Operation	Program Counter ← Stack EMI ← 1
Affected flag(s)	None
RL [m]	Rotate Data Memory left
Description	The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0.
Operation	[m].(i+1) ← [m].i; (i=0~6) [m].0 ← [m].7
Affected flag(s)	None

RLA [m]	Rotate Data Memory left with result in ACC
Description	The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC.(i+1) ← [m].i; (i=0~6) ACC.0 ← [m].7
Affected flag(s)	None
RLC [m]	Rotate Data Memory left through Carry
Description	The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into bit 0.
Operation	[m].(i+1) ← [m].i; (i=0~6) [m].0 ← C C ← [m].7
Affected flag(s)	C
RLCA [m]	Rotate Data Memory left through Carry with result in ACC
Description	Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC.(i+1) ← [m].i; (i=0~6) ACC.0 ← C C ← [m].7
Affected flag(s)	C
RR [m]	Rotate Data Memory right
Description	The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into bit 7.
Operation	[m].i ← [m].(i+1); (i=0~6) [m].7 ← [m].0
Affected flag(s)	None
RRA [m]	Rotate Data Memory right with result in ACC
Description	Data in the specified Data Memory is rotated right by 1 bit with bit 0 rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC.i ← [m].(i+1); (i=0~6) ACC.7 ← [m].0
Affected flag(s)	None
RRC [m]	Rotate Data Memory right through Carry
Description	The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7.
Operation	[m].i ← [m].(i+1); (i=0~6) [m].7 ← C C ← [m].0
Affected flag(s)	C

RRCA [m]	Rotate Data Memory right through Carry with result in ACC
Description	Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC.i ← [m].(i+1); (i=0~6) ACC.7 ← C C ← [m].0
Affected flag(s)	C
SBC A,[m]	Subtract Data Memory from ACC with Carry
Description	The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	ACC ← ACC – [m] – \bar{C}
Affected flag(s)	OV, Z, AC, C, SC, CZ
SBC A, x	Subtract immediate data from ACC with Carry
Description	The immediate data and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	ACC ← ACC – [m] – \bar{C}
Affected flag(s)	OV, Z, AC, C, SC, CZ
SBCM A,[m]	Subtract Data Memory from ACC with Carry and result in Data Memory
Description	The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	[m] ← ACC – [m] – \bar{C}
Affected flag(s)	OV, Z, AC, C, SC, CZ
SDZ [m]	Skip if decrement Data Memory is 0
Description	The contents of the specified Data Memory are first decremented by 1. If the result is 0 the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	[m] ← [m] – 1 Skip if [m]=0
Affected flag(s)	None
SDZA [m]	Skip if decrement Data Memory is zero with result in ACC
Description	The contents of the specified Data Memory are first decremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.
Operation	ACC ← [m] – 1 Skip if ACC=0
Affected flag(s)	None

SET [m]	Set Data Memory
Description	Each bit of the specified Data Memory is set to 1.
Operation	$[m] \leftarrow FFH$
Affected flag(s)	None
SET [m].i	Set bit of Data Memory
Description	Bit i of the specified Data Memory is set to 1.
Operation	$[m].i \leftarrow 1$
Affected flag(s)	None
SIZ [m]	Skip if increment Data Memory is 0
Description	The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$[m] \leftarrow [m] + 1$ Skip if $[m]=0$
Affected flag(s)	None
SIZA [m]	Skip if increment Data Memory is zero with result in ACC
Description	The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$ACC \leftarrow [m] + 1$ Skip if $ACC=0$
Affected flag(s)	None
SNZ [m].i	Skip if Data Memory is not 0
Description	If the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.
Operation	Skip if $[m].i \neq 0$
Affected flag(s)	None
SNZ [m]	Skip if Data Memory is not 0
Description	If the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.
Operation	Skip if $[m] \neq 0$
Affected flag(s)	None
SUB A,[m]	Subtract Data Memory from ACC
Description	The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$ACC \leftarrow ACC - [m]$
Affected flag(s)	OV, Z, AC, C, SC, CZ

SUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory
Description	The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$[m] \leftarrow ACC - [m]$
Affected flag(s)	OV, Z, AC, C, SC, CZ
SUB A,x	Subtract immediate data from ACC
Description	The immediate data specified by the code is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$ACC \leftarrow ACC - x$
Affected flag(s)	OV, Z, AC, C, SC, CZ
SWAP [m]	Swap nibbles of Data Memory
Description	The low-order and high-order nibbles of the specified Data Memory are interchanged.
Operation	$[m].3 \sim [m].0 \leftrightarrow [m].7 \sim [m].4$
Affected flag(s)	None
SWAPA [m]	Swap nibbles of Data Memory with result in ACC
Description	The low-order and high-order nibbles of the specified Data Memory are interchanged. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	$ACC.3 \sim ACC.0 \leftarrow [m].7 \sim [m].4$ $ACC.7 \sim ACC.4 \leftarrow [m].3 \sim [m].0$
Affected flag(s)	None
SZ [m]	Skip if Data Memory is 0
Description	If the contents of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	Skip if $[m]=0$
Affected flag(s)	None
SZA [m]	Skip if Data Memory is 0 with data movement to ACC
Description	The contents of the specified Data Memory are copied to the Accumulator. If the value is zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$ACC \leftarrow [m]$ Skip if $[m]=0$
Affected flag(s)	None
SZ [m].i	Skip if bit i of Data Memory is 0
Description	If bit i of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.
Operation	Skip if $[m].i=0$
Affected flag(s)	None

TABRD [m]	Read table (specific page) to TBLH and Data Memory
Description	The low byte of the program code (specific page) addressed by the table pointer (TBLP and TBHP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
TABRDL [m]	Read table (last page) to TBLH and Data Memory
Description	The low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
ITABRD [m]	Increment table pointer low byte first and read table (specific page) to TBLH and Data Memory
Description	Increment table pointer low byte, TBLP, first and then the program code (specific page) addressed by the table pointer (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
ITABRDL [m]	Increment table pointer low byte first and read table (last page) to TBLH and Data Memory
Description	Increment table pointer low byte, TBLP, first and then the low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
XOR A,[m]	Logical XOR Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC "XOR" [m]
Affected flag(s)	Z
XORM A,[m]	Logical XOR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR operation. The result is stored in the Data Memory.
Operation	[m] ← ACC "XOR" [m]
Affected flag(s)	Z
XOR A,x	Logical XOR immediate data to ACC
Description	Data in the Accumulator and the specified immediate data perform a bitwise logical XOR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC "XOR" x
Affected flag(s)	Z

Extended Instruction Definition

The extended instructions are used to directly access the data stored in any data memory sections.

LADC A,[m]	Add Data Memory to ACC with Carry
Description	The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC + [m] + C$
Affected flag(s)	OV, Z, AC, C, SC
LADCM A,[m]	Add ACC to Data Memory with Carry
Description	The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the specified Data Memory.
Operation	$[m] \leftarrow ACC + [m] + C$
Affected flag(s)	OV, Z, AC, C, SC
LADD A,[m]	Add Data Memory to ACC
Description	The contents of the specified Data Memory and the Accumulator are added. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC + [m]$
Affected flag(s)	OV, Z, AC, C, SC
LADDM A,[m]	Add ACC to Data Memory
Description	The contents of the specified Data Memory and the Accumulator are added. The result is stored in the specified Data Memory.
Operation	$[m] \leftarrow ACC + [m]$
Affected flag(s)	OV, Z, AC, C, SC
LAND A,[m]	Logical AND Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical AND operation. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC \text{ "AND" } [m]$
Affected flag(s)	Z
LANDM A,[m]	Logical AND ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical AND operation. The result is stored in the Data Memory.
Operation	$[m] \leftarrow ACC \text{ "AND" } [m]$
Affected flag(s)	Z
LCLR [m]	Clear Data Memory
Description	Each bit of the specified Data Memory is cleared to 0.
Operation	$[m] \leftarrow 00H$
Affected flag(s)	None
LCLR [m].i	Clear bit of Data Memory
Description	Bit i of the specified Data Memory is cleared to 0.
Operation	$[m].i \leftarrow 0$
Affected flag(s)	None

LCPL [m]	Complement Data Memory
Description	Each bit of the specified Data Memory is logically complemented (1's complement). Bits which previously contained a 1 are changed to 0 and vice versa.
Operation	$[m] \leftarrow \overline{[m]}$
Affected flag(s)	Z
LCPLA [m]	Complement Data Memory with result in ACC
Description	Each bit of the specified Data Memory is logically complemented (1's complement). Bits which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	$ACC \leftarrow \overline{[m]}$
Affected flag(s)	Z
LDAA [m]	Decimal-Adjust ACC for addition with result in Data Memory
Description	Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value resulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is greater than 100, it allows multiple precision decimal addition.
Operation	$[m] \leftarrow ACC + 00H$ or $[m] \leftarrow ACC + 06H$ or $[m] \leftarrow ACC + 60H$ or $[m] \leftarrow ACC + 66H$
Affected flag(s)	C
LDEC [m]	Decrement Data Memory
Description	Data in the specified Data Memory is decremented by 1.
Operation	$[m] \leftarrow [m] - 1$
Affected flag(s)	Z
LDECA [m]	Decrement Data Memory with result in ACC
Description	Data in the specified Data Memory is decremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	$ACC \leftarrow [m] - 1$
Affected flag(s)	Z
LINC [m]	Increment Data Memory
Description	Data in the specified Data Memory is incremented by 1.
Operation	$[m] \leftarrow [m] + 1$
Affected flag(s)	Z
LINCA [m]	Increment Data Memory with result in ACC
Description	Data in the specified Data Memory is incremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	$ACC \leftarrow [m] + 1$
Affected flag(s)	Z

LMOV A,[m]	Move Data Memory to ACC
Description	The contents of the specified Data Memory are copied to the Accumulator.
Operation	$ACC \leftarrow [m]$
Affected flag(s)	None
LMOV [m],A	Move ACC to Data Memory
Description	The contents of the Accumulator are copied to the specified Data Memory.
Operation	$[m] \leftarrow ACC$
Affected flag(s)	None
LOR A,[m]	Logical OR Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical OR operation. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC \text{ "OR" } [m]$
Affected flag(s)	Z
LORM A,[m]	Logical OR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical OR operation. The result is stored in the Data Memory.
Operation	$[m] \leftarrow ACC \text{ "OR" } [m]$
Affected flag(s)	Z
LRL [m]	Rotate Data Memory left
Description	The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0.
Operation	$[m].(i+1) \leftarrow [m].i; (i=0\sim 6)$ $[m].0 \leftarrow [m].7$
Affected flag(s)	None
LRLA [m]	Rotate Data Memory left with result in ACC
Description	The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	$ACC.(i+1) \leftarrow [m].i; (i=0\sim 6)$ $ACC.0 \leftarrow [m].7$
Affected flag(s)	None
LRLC [m]	Rotate Data Memory left through Carry
Description	The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into bit 0.
Operation	$[m].(i+1) \leftarrow [m].i; (i=0\sim 6)$ $[m].0 \leftarrow C$ $C \leftarrow [m].7$
Affected flag(s)	C
LRLCA [m]	Rotate Data Memory left through Carry with result in ACC
Description	Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	$ACC.(i+1) \leftarrow [m].i; (i=0\sim 6)$ $ACC.0 \leftarrow C$ $C \leftarrow [m].7$
Affected flag(s)	C

LRR [m]	Rotate Data Memory right
Description	The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into bit 7.
Operation	$[m].i \leftarrow [m].(i+1); (i=0\sim6)$ $[m].7 \leftarrow [m].0$
Affected flag(s)	None
LRRRA [m]	Rotate Data Memory right with result in ACC
Description	Data in the specified Data Memory is rotated right by 1 bit with bit 0 rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	$ACC.i \leftarrow [m].(i+1); (i=0\sim6)$ $ACC.7 \leftarrow [m].0$
Affected flag(s)	None
LRRRC [m]	Rotate Data Memory right through Carry
Description	The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7.
Operation	$[m].i \leftarrow [m].(i+1); (i=0\sim6)$ $[m].7 \leftarrow C$ $C \leftarrow [m].0$
Affected flag(s)	C
LRRCA [m]	Rotate Data Memory right through Carry with result in ACC
Description	Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	$ACC.i \leftarrow [m].(i+1); (i=0\sim6)$ $ACC.7 \leftarrow C$ $C \leftarrow [m].0$
Affected flag(s)	C
LSBC A,[m]	Subtract Data Memory from ACC with Carry
Description	The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$ACC \leftarrow ACC - [m] - \bar{C}$
Affected flag(s)	OV, Z, AC, C, SC, CZ
LSBCM A,[m]	Subtract Data Memory from ACC with Carry and result in Data Memory
Description	The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$[m] \leftarrow ACC - [m] - \bar{C}$
Affected flag(s)	OV, Z, AC, C, SC, CZ

LSDZ [m]	Skip if decrement Data Memory is 0
Description	The contents of the specified Data Memory are first decremented by 1. If the result is 0 the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$[m] \leftarrow [m] - 1$ Skip if $[m]=0$
Affected flag(s)	None
LSDZA [m]	Skip if decrement Data Memory is zero with result in ACC
Description	The contents of the specified Data Memory are first decremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0, the program proceeds with the following instruction.
Operation	$ACC \leftarrow [m] - 1$ Skip if $ACC=0$
Affected flag(s)	None
LSET [m]	Set Data Memory
Description	Each bit of the specified Data Memory is set to 1.
Operation	$[m] \leftarrow FFH$
Affected flag(s)	None
LSET [m].i	Set bit of Data Memory
Description	Bit i of the specified Data Memory is set to 1.
Operation	$[m].i \leftarrow 1$
Affected flag(s)	None
LSIZ [m]	Skip if increment Data Memory is 0
Description	The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$[m] \leftarrow [m] + 1$ Skip if $[m]=0$
Affected flag(s)	None
LSIZA [m]	Skip if increment Data Memory is zero with result in ACC
Description	The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$ACC \leftarrow [m] + 1$ Skip if $ACC=0$
Affected flag(s)	None
LSNZ [m].i	Skip if Data Memory is not 0
Description	If the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is 0 the program proceeds with the following instruction.
Operation	Skip if $[m].i \neq 0$
Affected flag(s)	None

LSNZ [m]	Skip if Data Memory is not 0
Description	If the content of the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is 0 the program proceeds with the following instruction.
Operation	Skip if [m] ≠ 0
Affected flag(s)	None
LSUB A,[m]	Subtract Data Memory from ACC
Description	The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	ACC ← ACC – [m]
Affected flag(s)	OV, Z, AC, C, SC, CZ
LSUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory
Description	The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	[m] ← ACC – [m]
Affected flag(s)	OV, Z, AC, C, SC, CZ
LSWAP [m]	Swap nibbles of Data Memory
Description	The low-order and high-order nibbles of the specified Data Memory are interchanged.
Operation	[m].3~[m].0 ↔ [m].7~[m].4
Affected flag(s)	None
LSWAPA [m]	Swap nibbles of Data Memory with result in ACC
Description	The low-order and high-order nibbles of the specified Data Memory are interchanged. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	ACC.3~ACC.0 ← [m].7~[m].4 ACC.7~ACC.4 ← [m].3~[m].0
Affected flag(s)	None
LSZ [m]	Skip if Data Memory is 0
Description	If the contents of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	Skip if [m]=0
Affected flag(s)	None
LSZA [m]	Skip if Data Memory is 0 with data movement to ACC
Description	The contents of the specified Data Memory are copied to the Accumulator. If the value is zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	ACC ← [m] Skip if [m]=0
Affected flag(s)	None

LSZ [m].i	Skip if bit i of Data Memory is 0
Description	If bit i of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0, the program proceeds with the following instruction.
Operation	Skip if [m].i=0
Affected flag(s)	None
LTABRD [m]	Read table (specific page) to TBLH and Data Memory
Description	The low byte of the program code (specific page) addressed by the table pointer (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
LTABRDL [m]	Read table (last page) to TBLH and Data Memory
Description	The low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
LITABRD [m]	Increment table pointer low byte first and read table (specific page) to TBLH and Data Memory
Description	Increment table pointer low byte, TBLP, first and then the program code (specific page) addressed by the table pointer (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
LITABRDL [m]	Increment table pointer low byte first and read table (last page) to TBLH and Data Memory
Description	Increment table pointer low byte, TBLP, first and then the low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
LXOR A,[m]	Logical XOR Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC "XOR" [m]
Affected flag(s)	Z
LXORM A,[m]	Logical XOR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR operation. The result is stored in the Data Memory.
Operation	[m] ← ACC "XOR" [m]
Affected flag(s)	Z

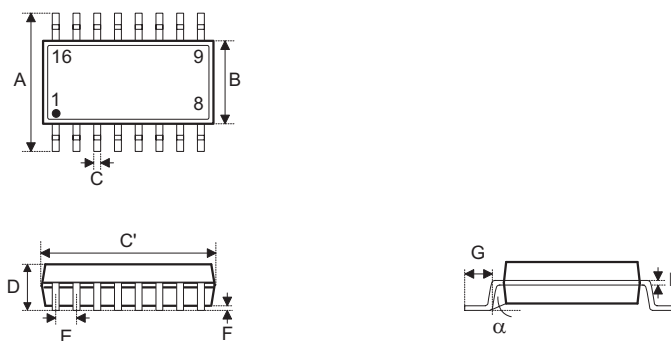
Package Information

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the [Holtek website](#) for the latest version of the [Package/Carton Information](#).

Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

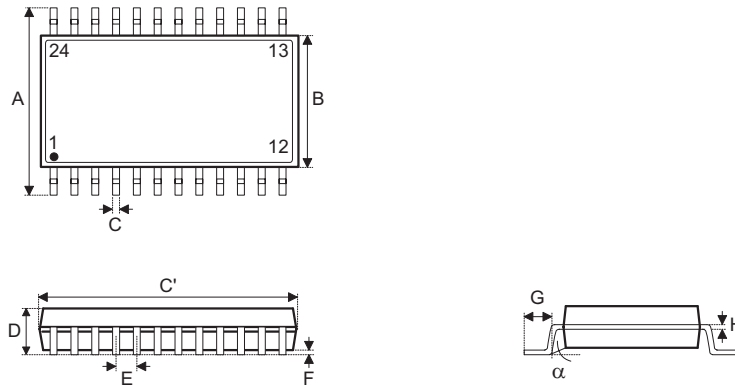
- [Package Information \(include Outline Dimensions, Product Tape and Reel Specifications\)](#)
- [The Operation Instruction of Packing Materials](#)
- [Carton information](#)

16-pin NSOP (150mil) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.236 BSC		
B	0.154 BSC		
C	0.012	—	0.020
C'	0.390 BSC		
D	—	—	0.069
E	0.050 BSC		
F	0.004	—	0.010
G	0.016	—	0.050
H	0.004	—	0.010
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	6.00 BSC		
B	3.90 BSC		
C	0.31	—	0.51
C'	9.90 BSC		
D	—	—	1.75
E	1.27 BSC		
F	0.10	—	0.25
G	0.40	—	1.27
H	0.10	—	0.25
α	0°	—	8°

24-pin SSOP (150mil) Outline Dimensions


Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.236 BSC		
B	0.154 BSC		
C	0.008	—	0.012
C'	0.341 BSC		
D	—	—	0.069
E	0.025 BSC		
F	0.004	—	0.010
G	0.016	—	0.050
H	0.004	—	0.010
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	6.00 BSC		
B	3.90 BSC		
C	0.20	—	0.30
C'	8.66 BSC		
D	—	—	1.75
E	0.635 BSC		
F	0.10	—	0.25
G	0.41	—	1.27
H	0.10	—	0.25
α	0°	—	8°

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